

RFIC & MMIC Selection and data sheet



2016.04

Products Summary

- RF Gain-block MMIC

Part No.	Frequency [MHz]	Gain [dB]	P1dB [dBm]	OIP3 [dBm]	NF [dB]	Vcc [V]	Id [mA]	PKG Type
RG201	850	23.5	20.5	33.4	2.9	5	65	SOT89
	1850	21.6	19.1	32.4	3.0	5	65	
	2140	20.9	18.6	31.2	3.0	5	65	
	2450	20.2	17.7	30.2	3.0	5	65	
	2600	19.6	19.0	30.0	3.0	5	65	
RG206	850	21.0	18.1	34.2	5.5	5	61	SOT89
	1850	20.0	19.0	34.3	5.6	5	61	
	2140	19.9	18.5	32.2	5.6	5	61	
	2450	19.7	17.7	31.6	5.6	5	61	
	2600	18.9	19.0	31.0	5.6	5	61	
RG301	850	17.6	17.3	31.1	3.2	5	44	SOT89
	1850	17.0	15.5	28.7	3.3	5	44	
	2140	16.8	14.3	27.5	3.3	5	44	
	2450	16.5	13.3	25.7	3.3	5	44	
	2600	16.5	15.5	25.5	3.3	5	44	

- 3.3V Gain-block MMIC

Part No.	Frequency [MHz]	Gain [dB]	P1dB [dBm]	OIP3 [dBm]	NF [dB]	Vcc [V]	Id [mA]	PKG Type
RG511	70	25.8	19.0	31.0	1.63	3.3	49	SC70-6L
	700	20.2	19.8	32.7	1.61	3.3	49	
	1900	13.6	19.7	33.1	1.60	3.3	49	
	2140	12.8	19.8	33.3	1.65	3.3	49	
RG512	700	19.2	15.0	24.0	1.65	3.3	27	SC70-6L
	900	18.9	17.0	25.7	1.62	3.3	27	
	1900	14.2	20.0	30.0	1.62	3.3	27	
	2140	13.5	20.6	30.3	1.63	3.3	27	

Products Summary

- IF Gain-block MMIC

Part No.	Frequency [MHz]	Gain [dB]	P1dB [dBm]	OIP3 [dBm]	NF [dB]	Vcc [V]	Id [mA]	PKG Type
RG614	70	27.1	21.0	38.2	3.2	5	90	SOT89
	140	26.9	21.0	37.9	3.2	5	90	
	240	26.6	21.0	37.7	3.5	5	90	
	500	26.2	21.0	37.3	3.5	5	90	
RG625	70	18.8	24.0	44.0	4.6	5	84	SOT89
	140	18.6	24.3	42.0	4.8	5	84	
	240	18.6	24.7	43.0	4.9	5	84	
	500	18.1	24.2	38.5	4.6	5	84	

- Driver Amplifier

Part No.	Frequency [MHz]	Gain [dB]	P1dB [dBm]	OIP3 [dBm]	NF [dB]	Vcc [V]	Id [mA]	PKG Type
RA031	850	20.7	24.1	44.1	4.4	5	82	SOT89
	1850	16.6	24.0	40.0	4.4	5	82	
	2140	15.2	23.9	39.0	4.5	5	82	
	2350	14.4	24.3	39.1	4.4	5	82	
	2600	13.4	25.0	37.0	4.4	5	82	

- 2-way RF Power Divider

Part No.	Frequency [MHz]	Insertion Loss [dB]	Isolation [dB]	Return loss [dB]		Amplitude Balance [dB]	Phase Balance [deg]	PKG Type
				IN	Out			
RD103	700	3.64	17.0	22.3	21.9	0.03	0.2	SOT26
	800	3.62	24.6	38.7	23.3	0.02	0.2	
	900	3.65	23.2	22.2	24.5	0.03	0.2	
	1000	3.72	16.5	15.8	25.8	0.03	0.1	
RD104	1700	3.59	15.0	17.7	22.1	0.03	0.2	SOT26
	2000	3.59	26.6	17.1	29.7	0.02	0.1	
	2300	3.64	28.0	14.8	34.9	0.01	0.1	
	2500	3.86	16.2	10.9	20.4	0.06	0.1	

Products Summary

- Low Noise Amplifier MMIC

Part No.	Frequency [MHz]	Gain [dB]	P1dB [dBm]	OIP3 [dBm]	NF [dB]	Vcc [V]	Id [mA]	PKG Type
RL101	850	19.8/19.5	23.0/21.5	37.0/34.0	0.85/0.85	5/3.3	79/55	SOT89
	1850	14.5/14.3	22.5/19.0	39.0/33.0	0.82/0.82			
	2140	13.5/13.2	22.5/19.0	39.2/33.2	0.91/0.90			
	2600	11.8/11.5	22.5/18.0	39.5/31.3	0.96/0.94			
RL102	850	20.4/19.8	21.0/16.0	31.0/28.5	1.15/1.10	5/3.3	46/28	SOT89
	1850	15.5/15.2	23.5/19.0	35.0/28.4	0.95/0.93			
	2140	14.5/14.1	24.0/19.5	35.0/28.1	1.13/1.10			
	2600	12.7/12.5	24.6/20.0	36.0/29.3	1.14/1.12			

- RF Mixer MMIC

LO power = 0dBm, IF = 70MHz, T_L=25°C, Z_s=Z_L=50

Part No.	LO & RF Frequency [GHz]	IF Frequency [MHz]	Conversion Loss [dB]	IIP3 [dBm]	LO - RF Isolation [dB]	Input P1dB [dBm]	Vcc/Id [V][mA]	PKG Type
RM101	0.8 - 1.1	DC - 350	9.2	32.1	-14.0	24.0	3.3/22	MSOP8
	0.7 - 1.5		9.1	32.3	-12.8	22.0		
	0.8 - 1.1		8.8	30.0	-14.6	24.2	5/34	
	0.7 - 1.5		9.2	31.0	-15.6	23.6		
RM102	1.7 - 1.9	50 - 300	9	28.5	-7.8	20.5	3.3/23	MSOP8
	1.9 - 2.1		9	30.5	-6.8	20.0		
	2.1 - 2.4		9	30.0	-7.0	18.0		
	1.7 - 1.9		8.5	27.6	-8.0	22.0	5/35	
	1.9 - 2.1		8.8	29.5	-8.0	20.0		
	2.1 - 2.4		9.2	29.5	-8.6	18.0		
RM210	0.85/0.71	140	6.7	24.0	10.0	19.0	3.3/5	SC70-6L
	1.80/1.66		5.4	26.5	6.6	17.5		
	2.10/1.96		4.7	29.5	4.8	18.0		
	2.6/2.46		5.2	25.0	5.2	17.5		

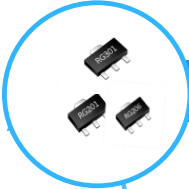
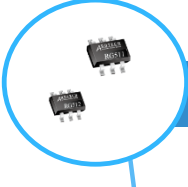
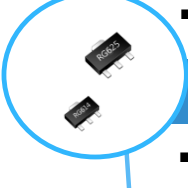
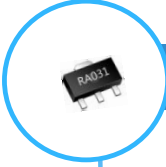
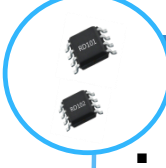
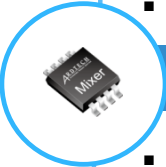

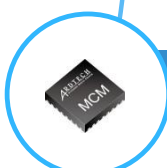
Products Summary

5V/3.3V Performance

- Multi functional Module

Part No.	Frequency Range RF/IF[MHz]	Test Frequency [MHz]	Gain [dB]	P1dB [dBm]	OIP3 [dBm]	NF [dB]	Vcc [V]	Id [mA]	PKG Type
RUC093	700-1200/DC-350	850	31.2	20.5	33.4	-	5	184	QFN4X4 -24L
RDC095			25.1	24.0	42.0	0.95		164	
RDC105	1700-2400/50-300	1800	33.4	22.0	38.5	1.07		170	
RDC106			25.3	25.0	45.0	1.07		164	
RUC122			39.5	19.2	32.5	-		190	
RUC123			31.4	19.2	32.5	-		184	

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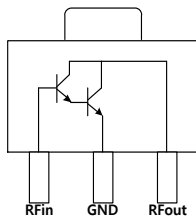
RG201

50-6000MHz InGaP HBT Gain Block MMIC Amplifier

Product Description

RG201 is a high performance InGaP HBT MMIC gain block amplifier utilizing a Darlington pair configuration with an active bias circuit and it can be used as a cascadable 50 ohm RF gain block applications that require high gain and excellent stable amplification. It's housed in a lead-free/green/RoHS-compliant SOT-89 industry-standard SMT package and internally matched to minimize number of external bias component

Component Diagram



Features

- High gain 23.5dB at 850MHz
- P1dB=20.5dBm at 850MHz
- Unconditionally stable
- Single fixed 5V supply
- Industry standard SOT-89 package
- Lead-free, RoHS compliant, Green

Applications

- PA driver amplifier
- Wireless infrastructure
- Cellular, PCS, GSM, WCDMA, LTE
- Wireless data system, Satellite terminals



Parameter	Specification			Condition	Units
	Min.	Typ.	Max.		
Small Signal Gain	22.0	23.5		850MHz	dB
	20.1	21.6		1850MHz	dB
	19.4	20.9		2140MHz	dB
Output power at 1-dB Compression	19.0	20.5		850MHz	dBm
	17.6	19.1		1850MHz	dBm
Third Order Intercept Point	31.4	33.4		850MHz	dBm
	30.4	32.4		1850MHz	dBm
Input Return Loss		-18.0		850MHz	dB
Output Return Loss		-18.4		850MHz	dB
Reverse Isolation		-26.2		850MHz	dB
Noise Figure		2.9		850MHz	dB
Device Voltage		5			V
Device current (Icq)	57	65	75		mA
Thermal Resistance		66		Junction to lead	°C/W

Test condition: Vcc=5V, I_b=65mA Typ., OIP₃ Tone Spacing=1MHz, P_{out} per tone=7dBm T_L=25°C, Z_S=Z_L=50

RG201
50-6000MHz
InGap HBT Gain Block MMIC Amplifier

Absolute Maximum Ratings

Parameter	Rating	Unit
Max Device Voltage(V_D)	5.5	V
Max Device Current(I_D)	100	mA
Max RF Input Power	20	dBm
Max Operating Dissipated Power	0.55	W
Junction Temperature(T_J)	+150	°C
Operating Temperature(T_L)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 1C	
Moisture Sensitivity Level	MSL1	

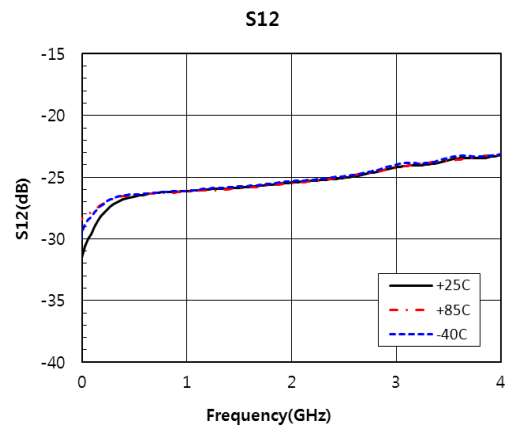
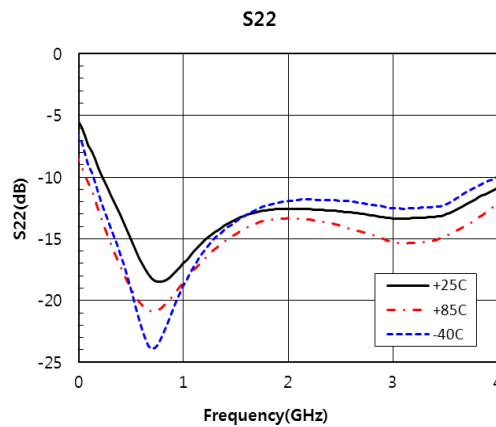
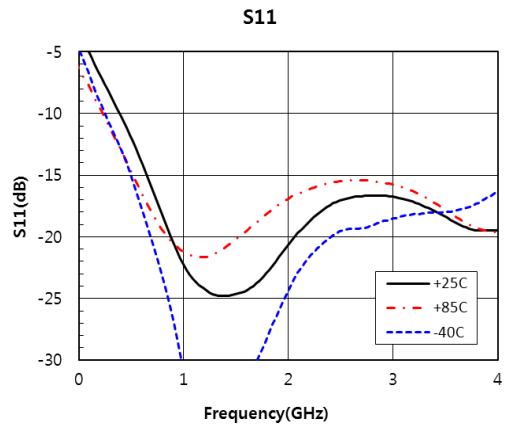
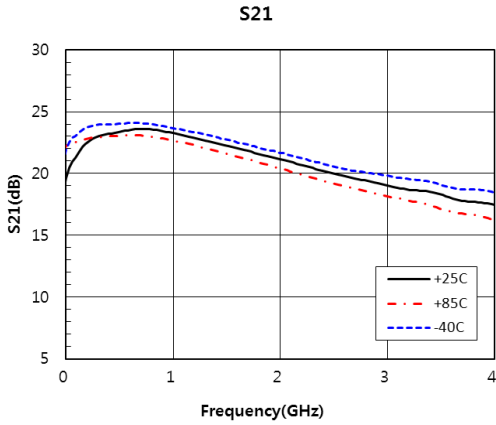


Typical Electrical Specification

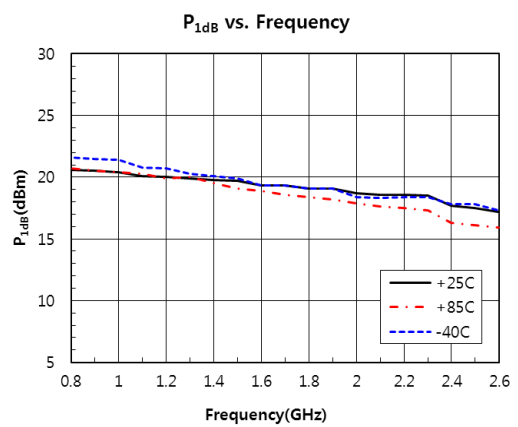
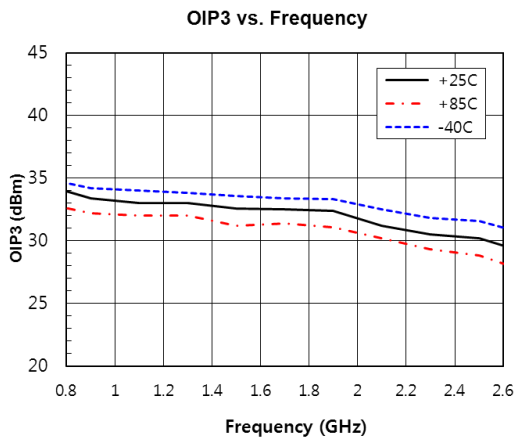
Parameter	850MHz	1850MHz	2140MHz	2450MHz	Unit
S21	23.5	21.6	20.9	20.2	dB
OIP3	33.4	32.4	31.2	30.2	dBm
P1dB	20.5	19.1	18.6	17.7	dBm
S11	-18.0	-22.6	-19.7	-17.4	dB
S22	-18.4	-12.6	-12.5	-12.7	dB
S12	-26.2	-25.5	-25.3	-25.1	dB
NF	2.9	3.0	3.0	3.0	dB

Test condition: $V_{CC}=5V$, $I_D=65mA$ Typ., OIP_3 Tone Spacing=1MHz, P_{out} per tone=7dBm $T_L=25^\circ C$, $Z_S=Z_L=50$

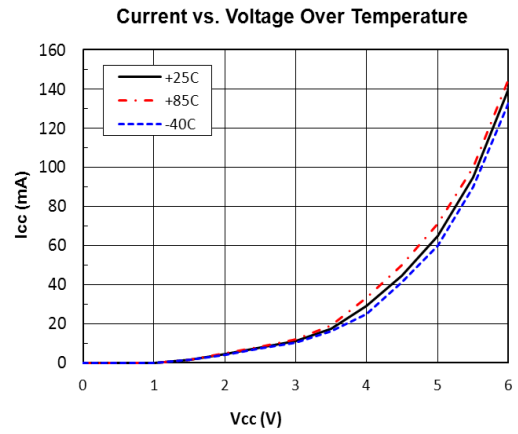
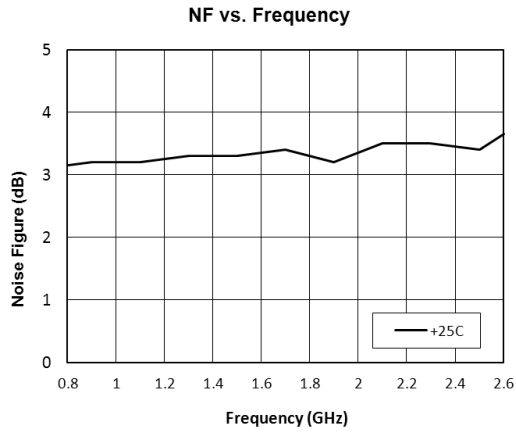
S-Parameter Over Temperature



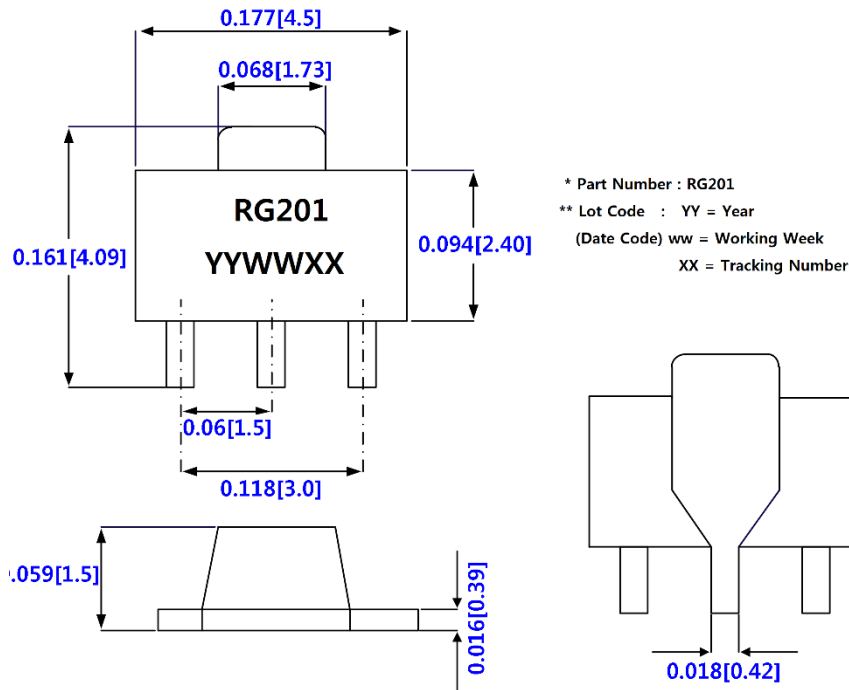
P1dB and OIP3 vs. Frequency



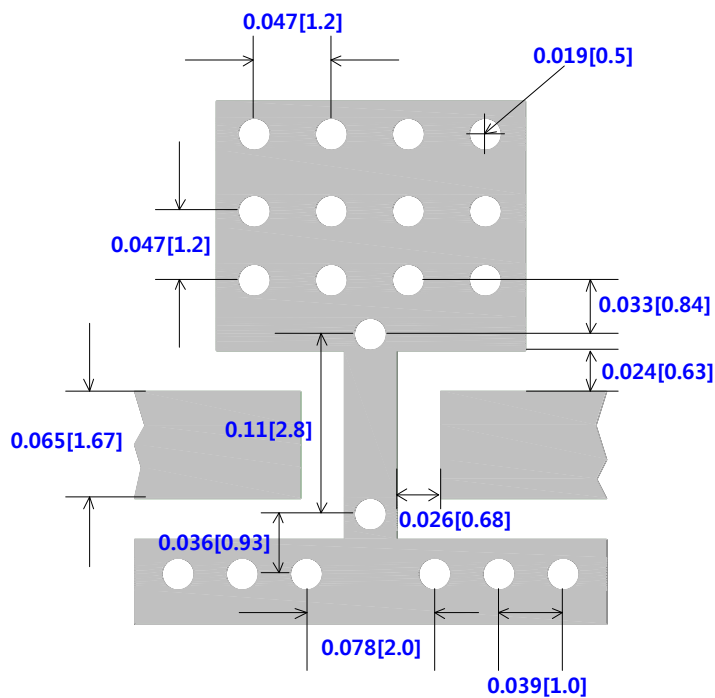
Icc vs. Vcc Over Temperature and Noise Figure



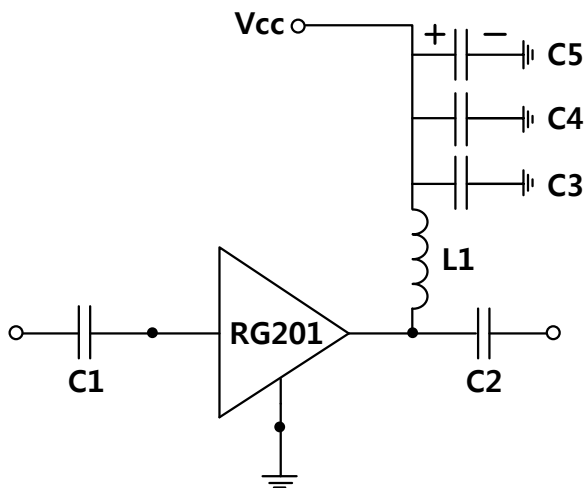
Package Mark and Dimensions
 Dimension in inches[Millimeters]



Recommended PCB Pad Pattern
 Dimension in inches[Millimeters]

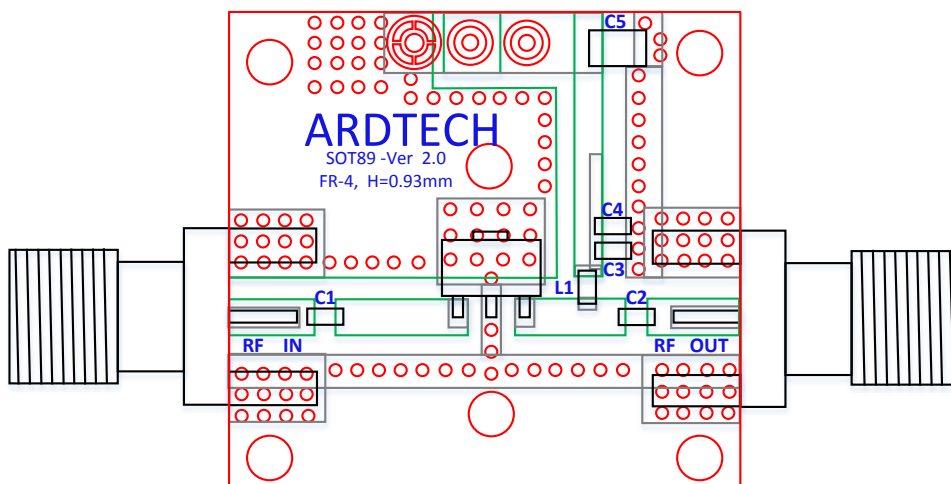


Application Schematic & BOM



Reference BOM	
C1	100pF Capacitor, 0603 type
C2	100pF Capacitor, 0603 type
C3	100pF Capacitor, 0603 type
C4	1000pF Capacitor, 0603 type
C5	10uF Capacitor, Tantalum
L1	39nH Chip inductor, 0805 type

Evaluation PCB Layout



PCB Substrate Information[mm]	
Dielectric Constant	FR-4/4.6
Dielectric Height	0.036[0.93]
Copper Thickness	1 oz.

RG206

50-6000MHz InGaP HBT Gain Block MMIC Amplifier

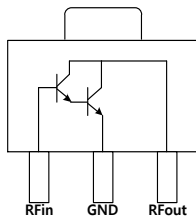
Product Description

RG206 is a high performance InGaP HBT MMIC gain block amplifier utilizing a Darlington pair configuration with an active bias circuit and it can be used as a cascadable 50 ohm RF gain block applications that require high gain and excellent stable amplification. It's housed in a lead-free/green/RoHS-compliant SOT-89 industry-standard SMT package and internally matched to minimize number of external bias component

Features

- High OIP3 = 34.2dBm at 850MHz
- P1dB=18.1dBm at 850MHz
- Unconditionally stable
- Single fixed 5V supply
- Industry standard SOT-89 package
- Lead-free, RoHS compliant, Green

Component Diagram



Applications

- PA driver amplifier
- Wireless infrastructure
- Cellular, PCS, GSM, WCDMA, LTE
- Wireless data system, Satellite terminals



Parameter	Specification			Condition	Units
	Min.	Typ.	Max.		
Small Signal Gain	19.5	21.0		850MHz	dB
	18.5	20.0		1850MHz	dB
	18.2	19.7		2140MHz	dB
Output power at 1-dB Compression	16.6	18.1		850MHz	dBm
	17.5	19.0		1850MHz	dBm
Third Order Intercept Point	32.2	34.2		850MHz	dBm
	32.3	34.3		1850MHz	dBm
Input Return Loss		-18.0		850MHz	dB
Output Return Loss		-12.1		850MHz	dB
Reverse Isolation		-28.9		850MHz	dB
Noise Figure		5.5		850MHz	dB
Device Voltage		5			V
Device current (Icq)	53	61	71		mA
Thermal Resistance		66		Junction to lead	°C/W

Test condition: Vcc=5V, I_b=61mA Typ., OIP₃ Tone Spacing=1MHz, P_{out} per tone=7dBm T_L=25°C, Z_S=Z_L=50

RG206
50-6000MHz
InGap HBT Gain Block MMIC Amplifier

Absolute Maximum Ratings

Parameter	Rating	Unit
Max Device Voltage(V_D)	5.5	V
Max Device Current(I_D)	100	mA
Max RF Input Power	24	dBm
Max Operating Dissipated Power	0.55	W
Junction Temperature(T_J)	+150	°C
Operating Temperature(T_L)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 1C	
Moisture Sensitivity Level	MSL1	

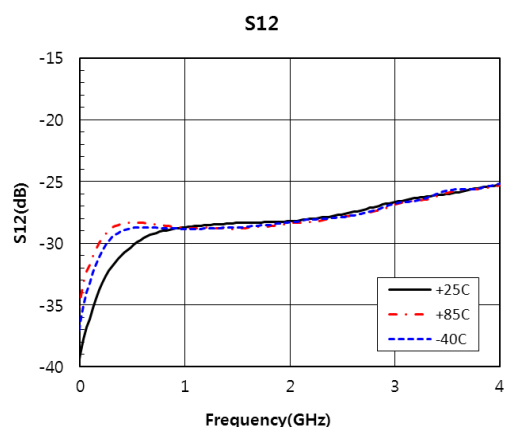
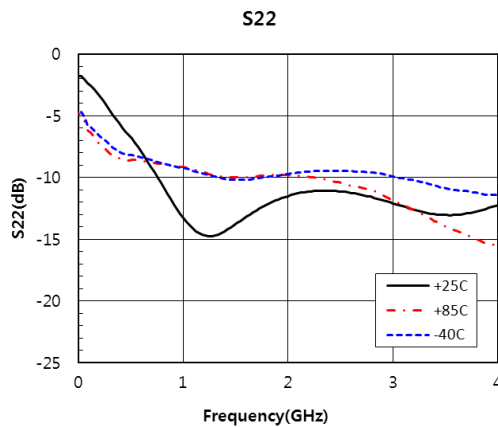
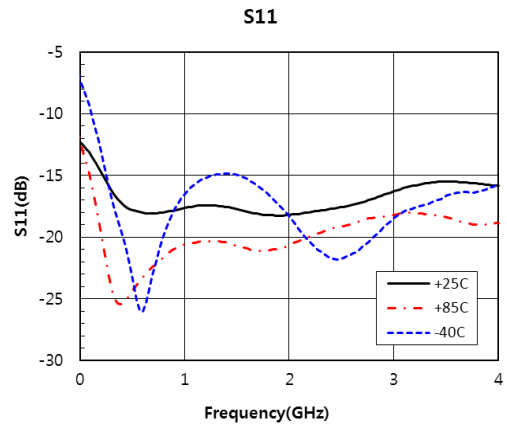
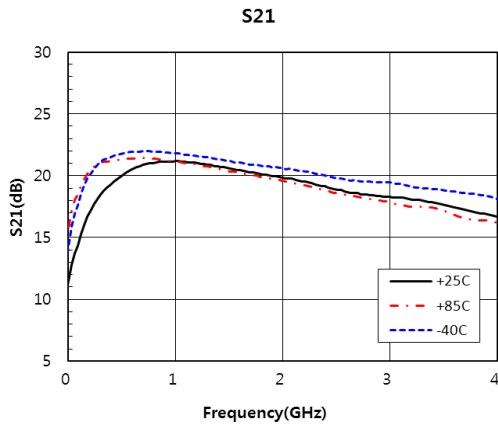


Typical Electrical Specification

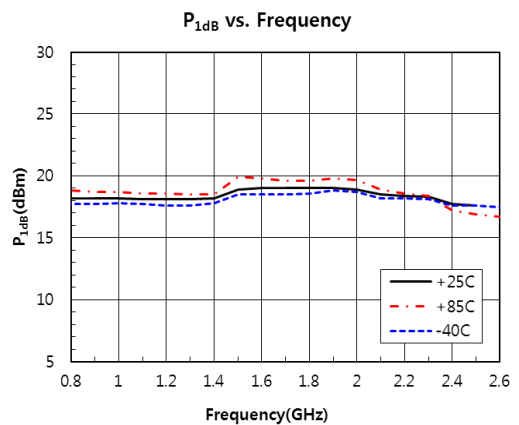
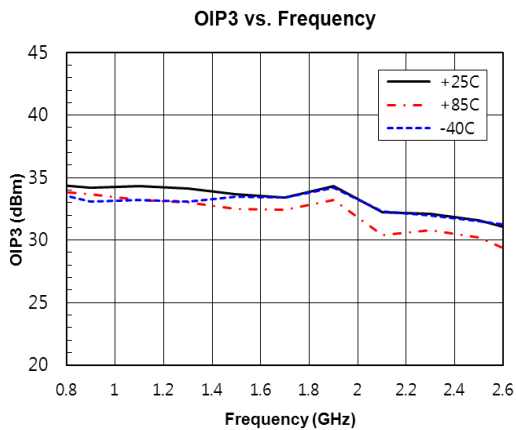
Parameter	850MHz	1850MHz	2140MHz	2450MHz	Unit
S21	21.0	20.0	19.9	19.7	dB
OIP3	34.2	34.3	32.2	31.6	dBm
P1dB	18.1	19.0	18.5	17.7	dBm
S11	-18.0	-18.2	-18.1	-17.6	dB
S22	-10.4	-12.1	-11.2	-11.0	dB
S12	-28.9	-28.2	-28.1	-27.7	dB
NF	5.5	5.6	5.6	5.6	dB

Test condition: $V_{CC}=5V$, $I_D=61mA$ Typ., OIP_3 Tone Spacing=1MHz, P_{out} per tone=7dBm $T_L=25^\circ C$, $Z_S=Z_L=50$

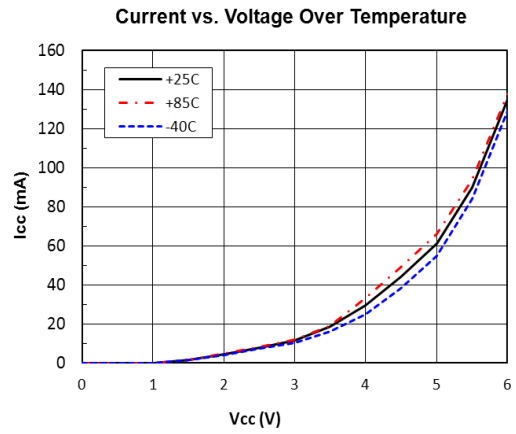
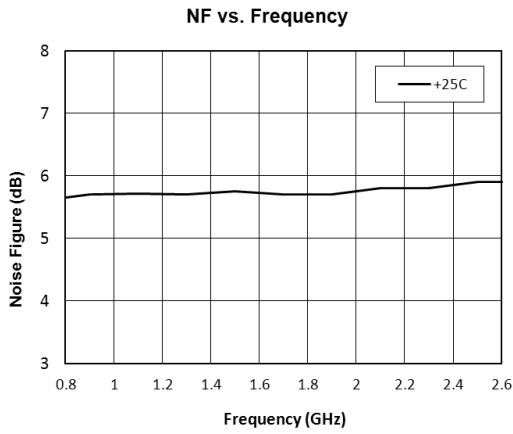
S-Parameter Over Temperature



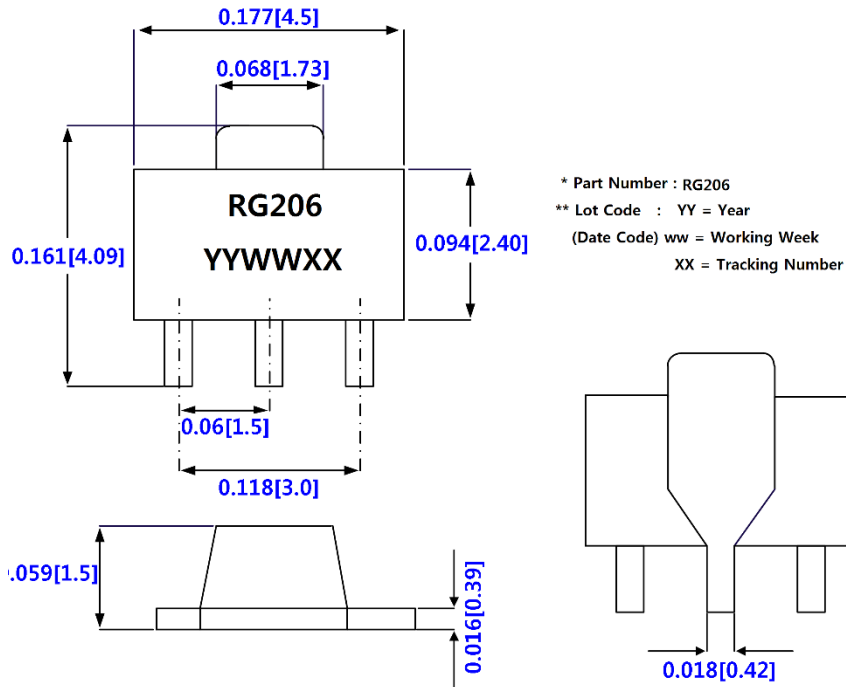
P1dB and OIP3 vs. Frequency



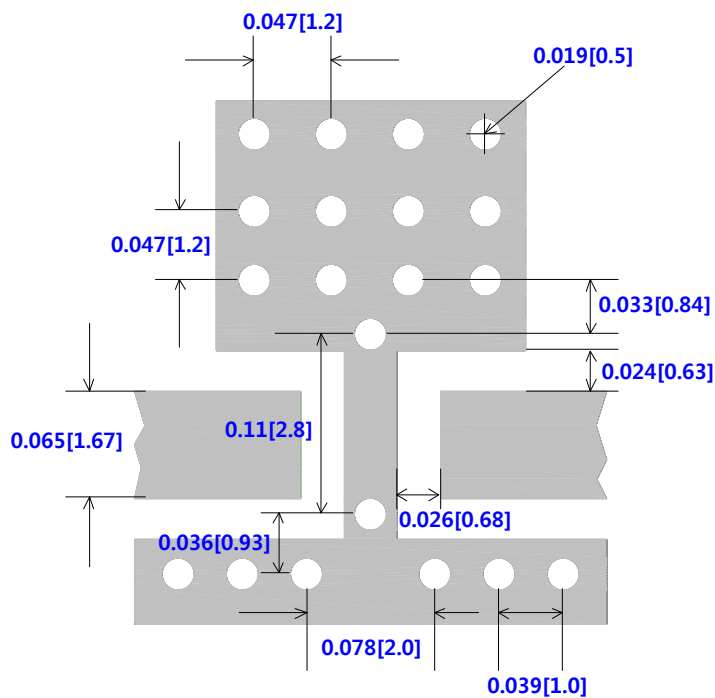
Icc vs. Vcc Over Temperature and Noise Figure



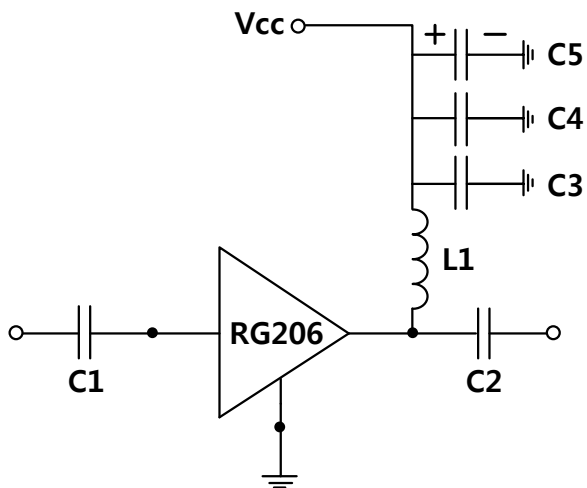
Package Mark and Dimensions
 Dimension in inches[Millimeters]



Recommended PCB Pad Pattern
 Dimension in inches[Millimeters]

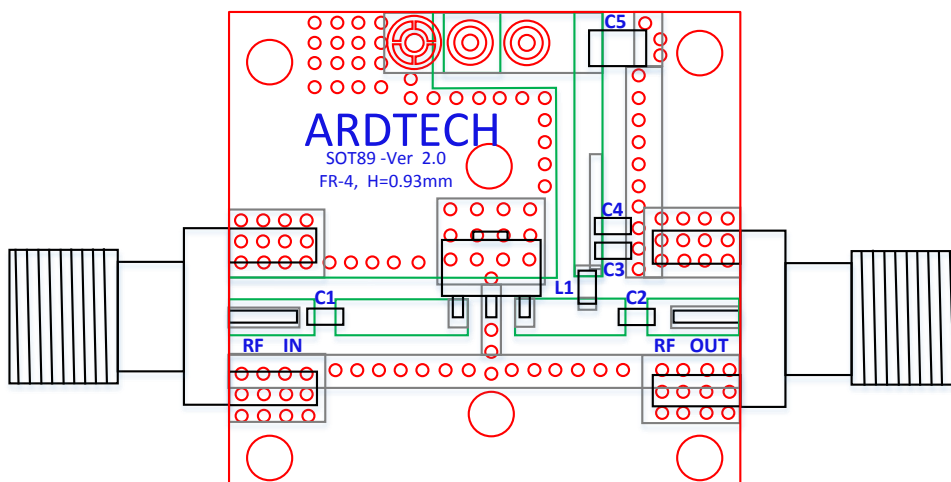


Application Schematic & BOM



Reference BOM	
C1	100pF Capacitor, 0603 type
C2	100pF Capacitor, 0603 type
C3	100pF Capacitor, 0603 type
C4	1000pF Capacitor, 0603 type
C5	10uF Capacitor, Tantalum
L1	12nH Chip inductor, 0805 type

Evaluation PCB Layout



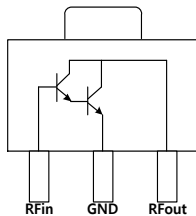
PCB Substrate Information[mm]	
Dielectric Constant	FR-4/4.6
Dielectric Height	0.036[0.93]
Copper Thickness	1 oz.

InGaP HBT Gain Block MMIC Amplifier

Product Description

RG301 is a high performance InGaP HBT MMIC gain block amplifier utilizing a Darlington pair configuration with an active bias circuit and it can be used as a cascadable 50 ohm RF gain block applications that require high gain and excellent stable amplification. It's housed in a lead-free/green/RoHS-compliant SOT-89 industry-standard SMT package and internally matched to minimize number of external bias component

Component Diagram



Features

- High OIP3 versus Low current value at 850MHz
- P1dB=17.9dBm at 850MHz
- Unconditionally stable
- Single fixed 5V supply
- Industry standard SOT-89 package
- Robust ESD, Class 1C
- Lead-free, RoHS compliant, Green

Applications

- PA driver amplifier
- Wireless infrastructure
- Cellular, PCS, GSM, WCDMA, LTE
- Wireless data system, Satellite terminals



Parameter	Specification			Condition	Units
	Min.	Typ.	Max.		
Small Signal Gain	16.3	17.8		850MHz	dB
	15.5	17.0		1850MHz	dB
	15.0	16.5		2140MHz	dB
Output power at 1-dB Compression	16.4	17.9		850MHz	dBm
	14.7	16.2		1850MHz	dBm
Third Order Intercept Point	29.1	31.1		850MHz	dBm
	26.7	28.7		1850MHz	dBm
Input Return Loss		-24.9		850MHz	dB
Output Return Loss		-23.6		850MHz	dB
Reverse Isolation		-20.7		850MHz	dB
Noise Figure		3.2		850MHz	dB
Device Voltage		5			V
Device current (Icq)	38	44	50		mA
Thermal Resistance		66		Junction to lead	°C/W

Test condition: Vcc=5V, I_b=44mA Typ., OIP₃ Tone Spacing=1MHz, P_{out} per tone=7dBm T_L=25°C, Z_S=Z_L=50

RG301
50-6000MHz
InGaP HBT Gain Block MMIC Amplifier

Absolute Maximum Ratings

Parameter	Rating	Unit
Max Device Voltage(V_D)	5.5	V
Max Device Current(I_D)	75	mA
Max RF Input Power	18	dBm
Max Operating Dissipated Power	0.41	W
Junction Temperature(T_J)	+150	°C
Operating Temperature(T_L)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 1C	
Moisture Sensitivity Level	MSL1	

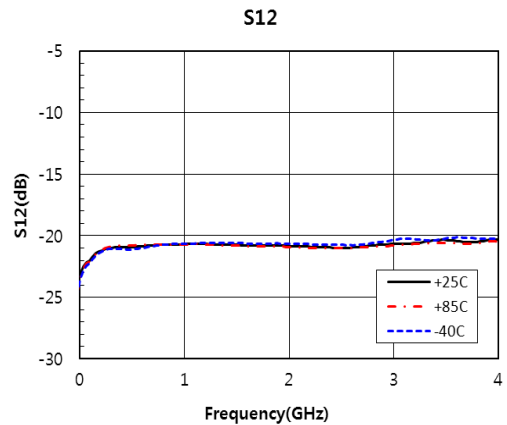
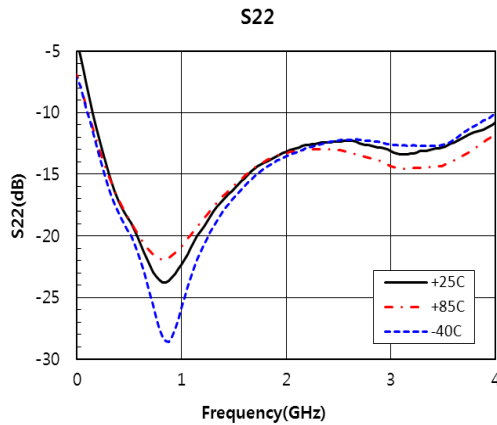
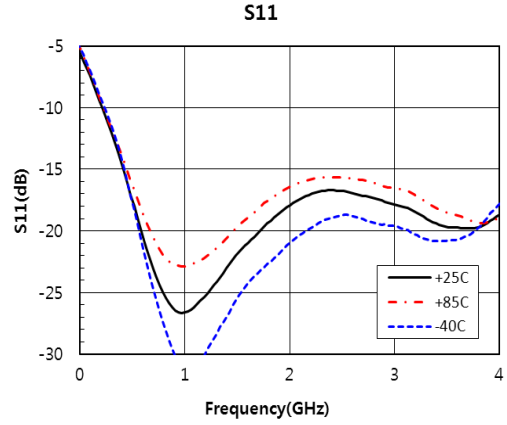
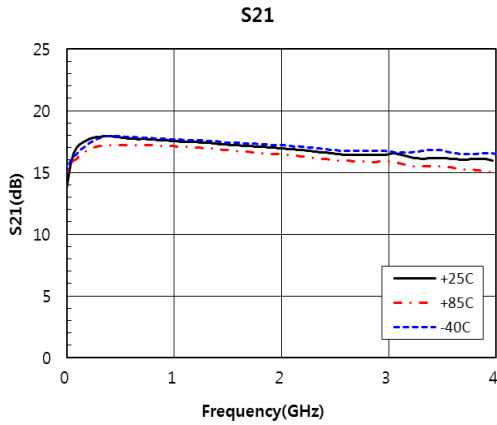


Typical Electrical Specification

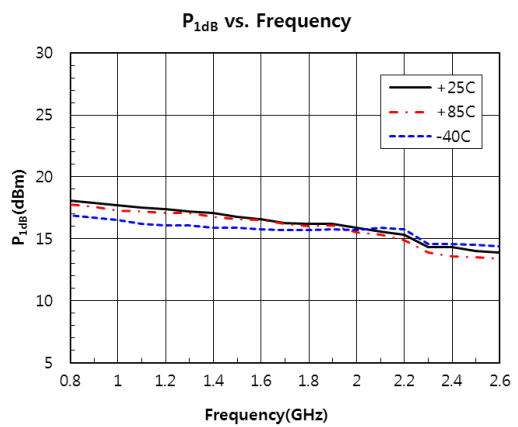
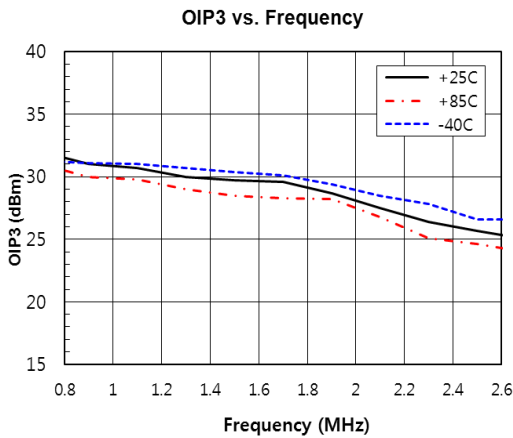
Parameter	850MHz	1850MHz	2140MHz	2450MHz	Unit
S21	17.6	17.0	16.8	16.5	dB
OIP3	31.1	28.7	27.5	25.7	dBm
P1dB	17.3	15.5	14.3	13.3	dBm
S11	-24.9	-19.0	-17.4	-16.7	dB
S22	-23.6	-13.9	-12.9	-12.4	dB
S12	-20.7	-20.7	-20.8	-20.9	dB
NF	3.2	3.3	3.3	3.3	dB

Test condition: $V_{CC}=5V$, $I_D=44mA$ Typ., OIP_3 Tone Spacing=1MHz, P_{out} per tone=7dBm $T_L=25^\circ C$, $Z_S=Z_L=50$

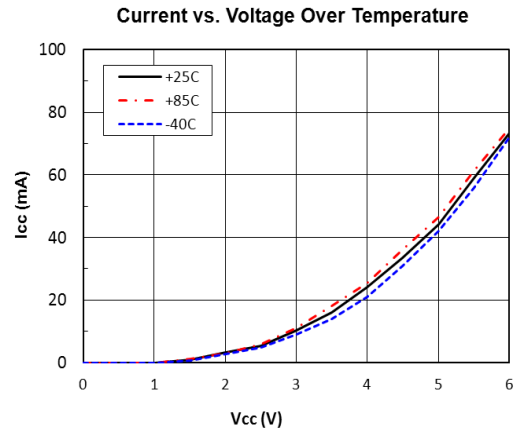
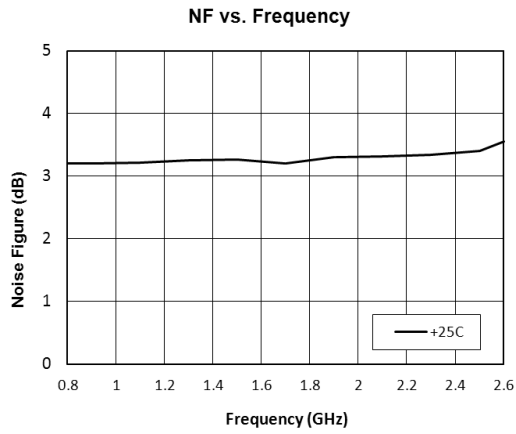
S-Parameter Over Temperature



P1dB and OIP3 vs. Frequency

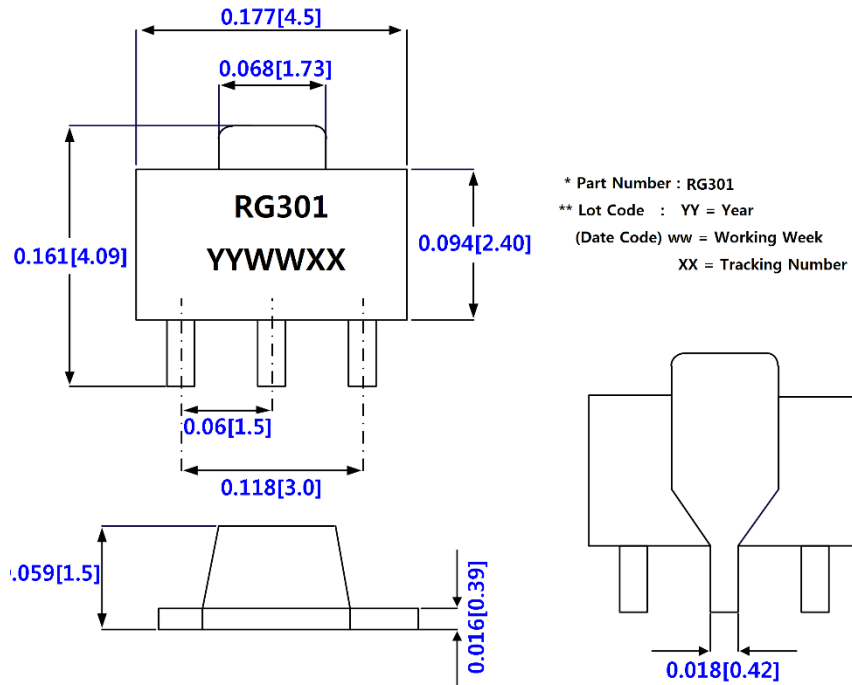


Icc vs. Vcc Over Temperature and Noise Figure



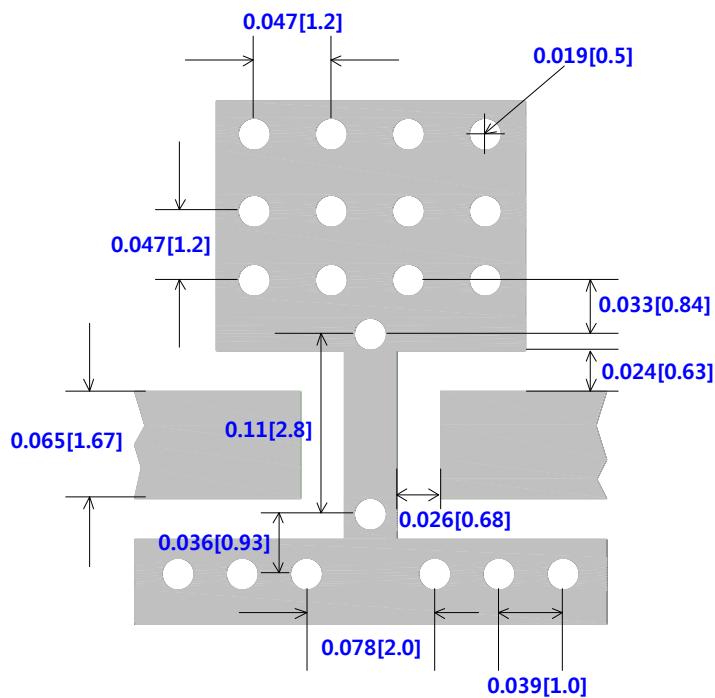
Package Mark and Dimensions

Dimension in inches[Millimeters]

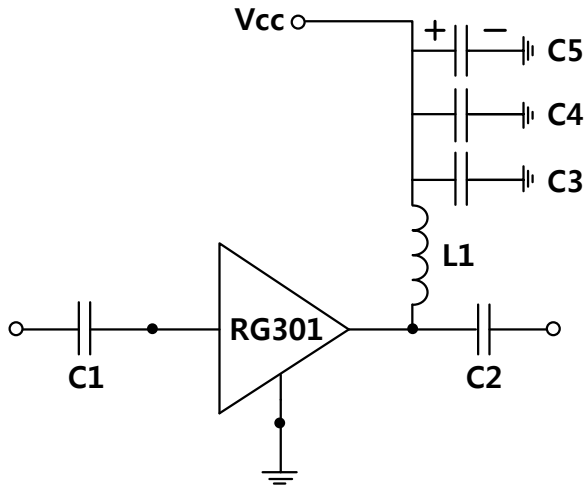


Recommended PCB Pad Pattern

Dimension in inches[Millimeters]

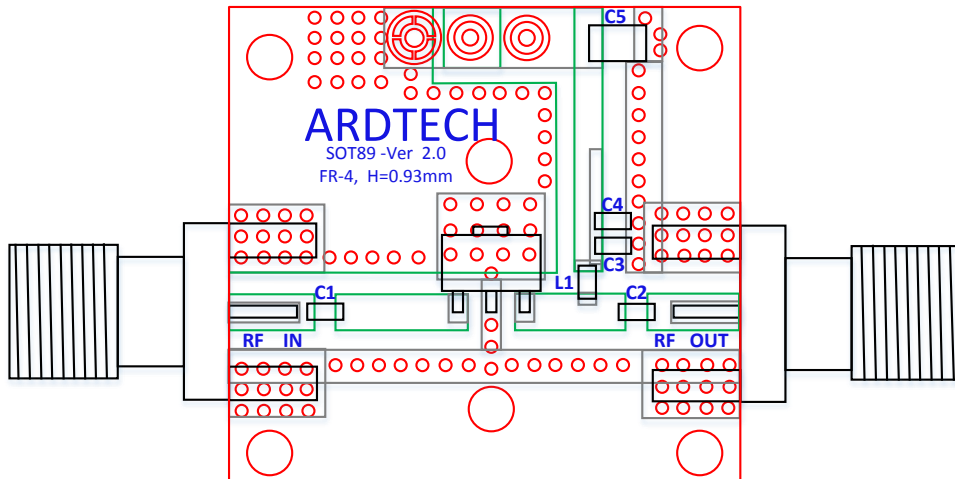


Application Schematic & BOM



Reference BOM	
C1	100pF Capacitor, 0603 type
C2	100pF Capacitor, 0603 type
C3	100pF Capacitor, 0603 type
C4	1000pF Capacitor, 0603 type
C5	10uF Capacitor, Tantalum
L1	39nH Chip inductor, 0805 type

Evaluation PCB Layout



PCB Substrate Information[mm]	
Dielectric Constant	FR-4/4.6
Dielectric Height	0.036[0.93]
Copper Thickness	1 oz.

High Linearity 3V Gain Block Amplifier

Product Description

RG511 is a high linearity and low noise Gain Block Amplifier in a low-cost surface mount package and provides 33.5dBm high OIP3 and 1.6dB Noise Figure at 900MHz. It is fabricated on a compound semiconductor material and conventional device technology. RG511 is available in a lead-free / green / RoHS-compliant SOT363(SC70) package. The performance target is designed for use as a receiver and transmitter in wireless infrastructure system where high linearity and low noise is required. Internal active bias circuitry allows RG511 to maintain high linearity and gain performance over temperature and operate directly off a single +3.3V supply. All devices are 100% RF and DC tested.

Features

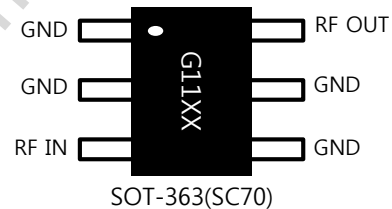
- High OIP3 33.5dBm at 900MHz
- 19dB Gain at 900MHz
- P1dB=20dBm at 900MHz
- 1.6dB Noise Figure at 900MHz
- Unconditionally stable
- Single 3.3V supply, 50mA current
- No dropping resistor required
- Industry standard SOT363(SC70) package
- Lead-free, RoHS compliant, Green



Applications

- Broadband Gain Block
- Wireless infrastructure
- Cellular, PCS, GSM, WCDMA, WiBro, LTE

Component Diagram



Parameter	Specification			Condition	Units
	Min.	Typ.	Max.		
Small Signal Gain	17.6	19.0		900MHz	dB
	12.3	13.6		1900MHz	dB
	11.5	12.8		2140MHz	dB
Output power at 1-dB Compression	18.5	20.0		900MHz	dBm
	18.2	19.7		1900MHz	dBm
Third Order Intercept Point	31.5	33.5		900MHz	dBm
	31.1	33.1		1900MHz	dBm
Input Return Loss		-19.8		900MHz	dB
Output Return Loss		-16.7		900MHz	dB
Reverse Isolation		-25.3		900MHz	dB
Noise Figure		1.6		900MHz	dB
Device Voltage		3.3			V
Device current (Icq)	35	49			mA
Thermal Resistance		41.6		Junction to lead	°C/W

Test condition: Vcc=3.3V, I_b=49mA Typ., OIP₃ Tone Spacing=1MHz, P_{out} per tone=6dBm T_L=25°C, Z_s=Z_L=50

Absolute Maximum Ratings

Parameter	Rating	Unit
Max Device Voltage(V_D)	5.0	V
Max Device Current(I_D)	100	mA
Max RF Input Power	10	dBm
Max Operating Dissipated Power	0.5	W
Junction Temperature(T_J)	+150	°C
Operating Temperature(T_L)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 1B	
Moisture Sensitivity Level	MSL1	



Typical Electrical Specification

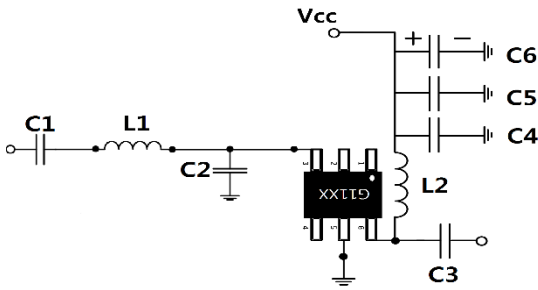
Parameter	70MHz	150MHz	700MHz	900MHz	Unit
S21	25.8	25.1	20.2	19.0	dB
OIP3	31.0	31.2	32.7	33.5	dBm
P1dB	19.0	18.8	19.8	20.0	dBm
S11	-17.8	-20.1	-19.8	-19.8	dB
S22	-18.2	-27.8	-17.2	-16.3	dB
S12	-30.1	-29.9	-26.6	-25.3	dB
NF	1.63	16.2	1.61	1.60	dB

Parameter	1900MHz	2140MHz	2650MHz		Unit
S21	13.6	12.8	11.3		dB
OIP3	33.1	33.3	31.7		dBm
P1dB	19.7	19.8	19.7		dBm
S11	-16.7	-16.8	-28.7		dB
S22	-16.9	-22.1	-18.4		dB
S12	-20.0	-19.3	-17.6		dB
NF	1.60	1.65	1.70		dB

Test condition: $V_{CC}=3.3V$, $I_D=49mA$ Typ., OIP_3 Tone Spacing=1MHz, P_{out} per tone=6dBm $T_L=25^\circ C$, $Z_S=Z_L=50$

RG511
50-4000MHz
High Linearity 3V Gain Block Amplifier

60~80MHz Reference Application Circuit



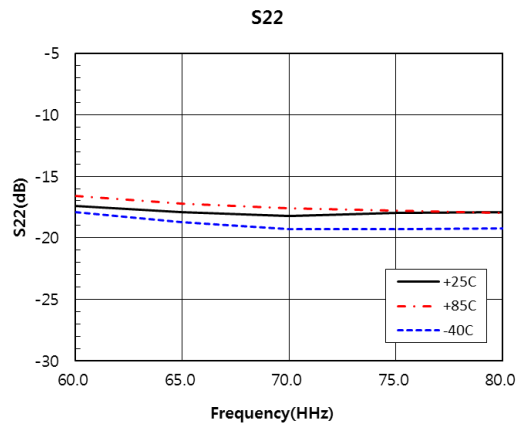
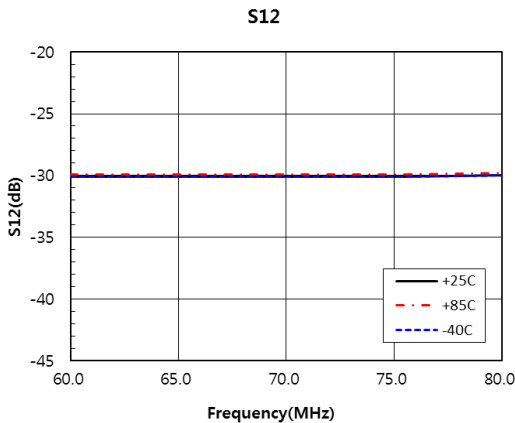
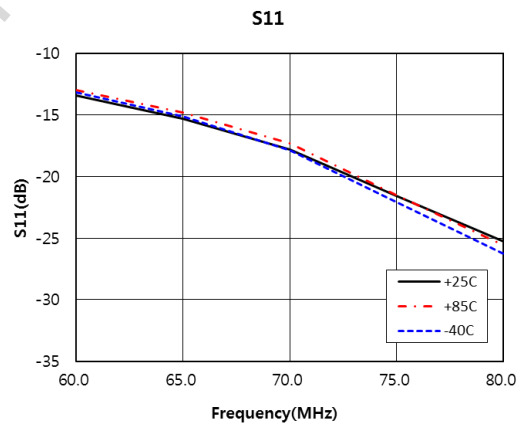
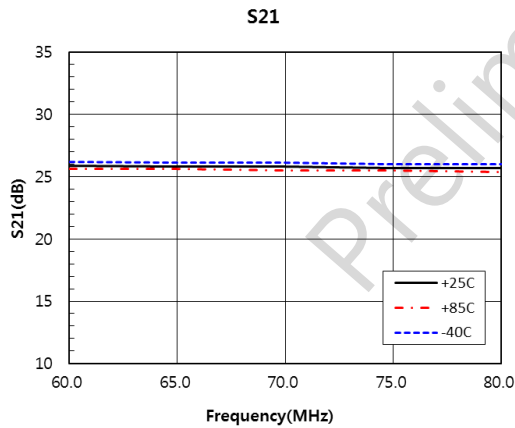
BOM	Value	BOM	Value	BOM	Value
C1	8200pF	C4	100pF	L1	120nH
C2	10pF	C5	1000pF	L2	560nH
C3	8200pF	C6	10uF		

*Width and Length of Micro-strip line dimension in mm[mil]

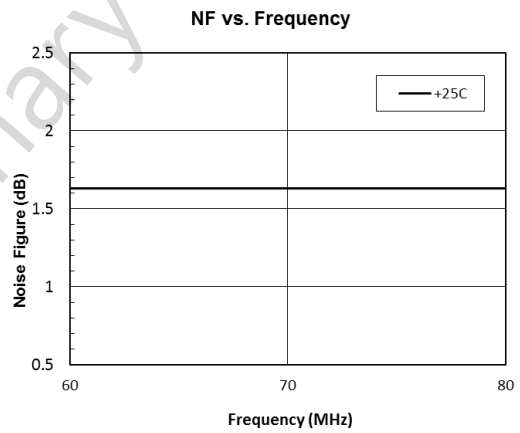
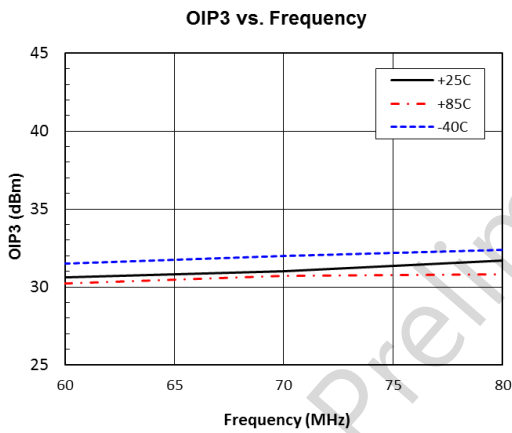
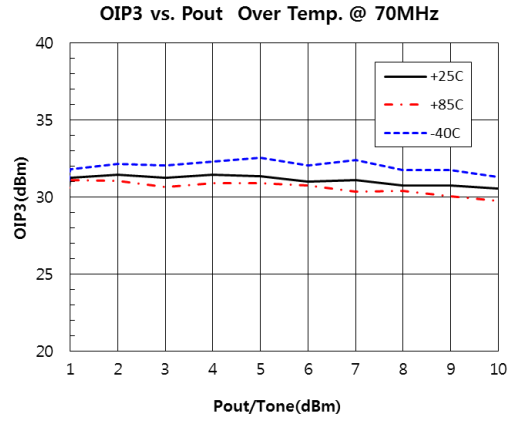
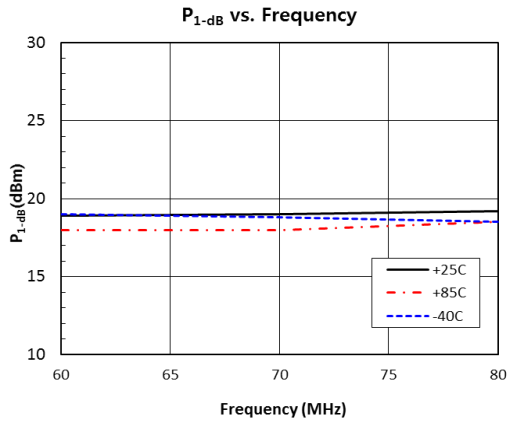
Parameter/Freq.(MHz)	60	70	80	Unit
Small Signal Gain	25.9	25.8	25.7	dB
S11	-13.4	-17.8	-25.3	dB
S22	-17.4	-18.2	-17.9	dB
Output P1dB	18.9	19.0	19.2	dBm
Output OIP3*	30.6	31.0	31.7	dBm
Noise Figure	1.63	1.63	1.63	dB
Icq	51			mA
Vcc	3.3			V

* Pout=6dBm/tone

S-Parameter Over Temperature vs. Freq. at 60~80MHz



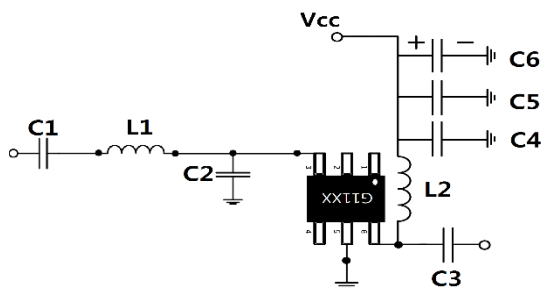
P1dB, OIP3 and Noise Figure Performance at 60~80MHz



RG511

50-4000MHz High Linearity 3V Gain Block Amplifier

140~150MHz Reference Application Circuit



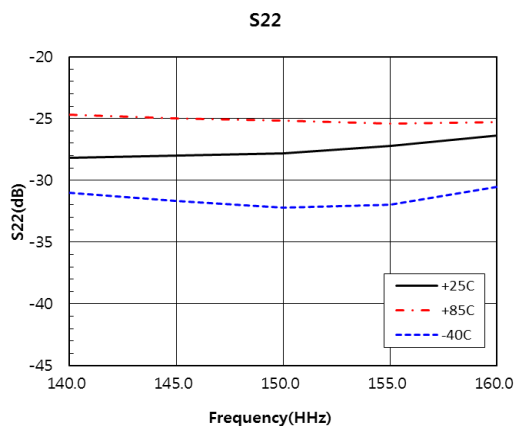
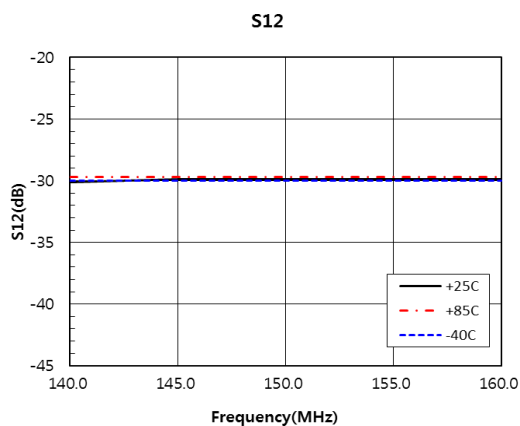
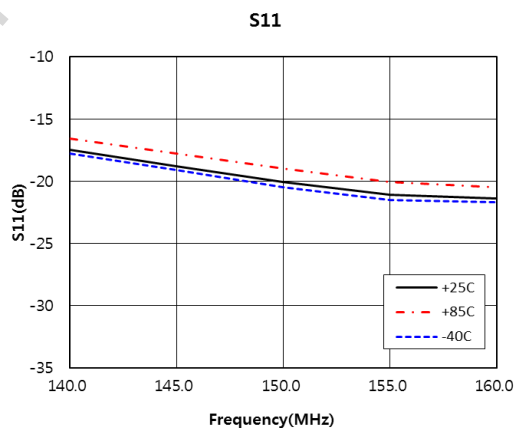
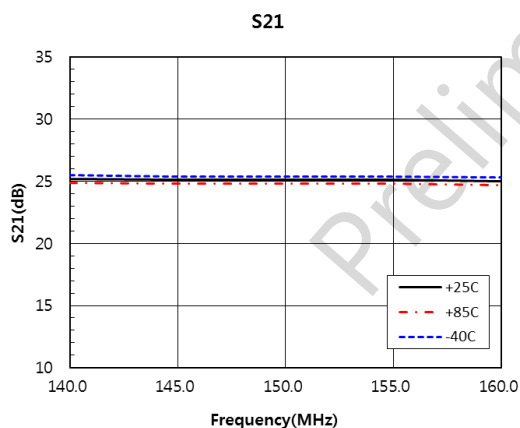
BOM	Value	BOM	Value	BOM	Value
C1	8200pF	C4	100pF	L1	47nH
C2	6pF	C5	1000pF	L2	560nH
C3	8200pF	C6	10uF		

*Width and Length of Micro-strip line dimension in mm[mil]

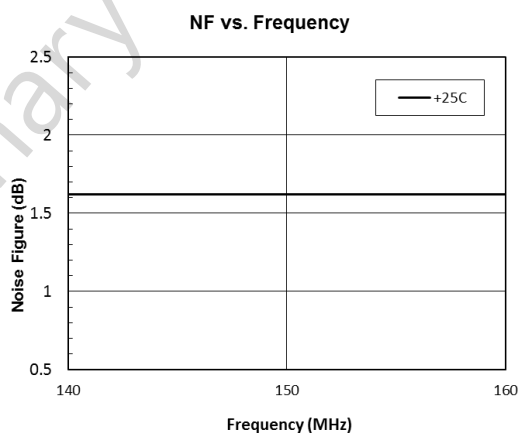
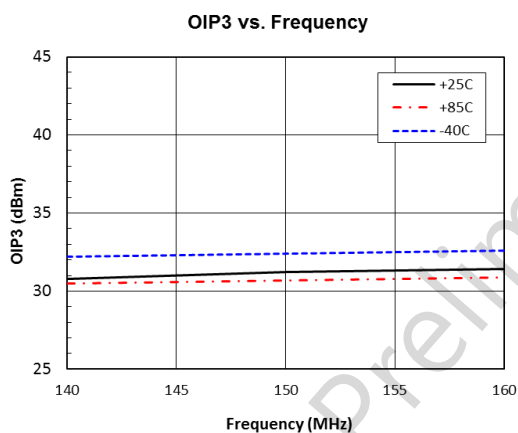
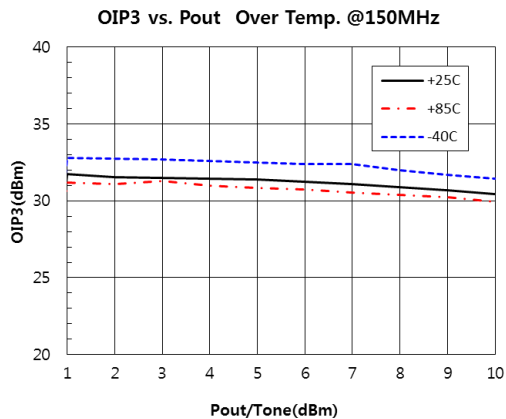
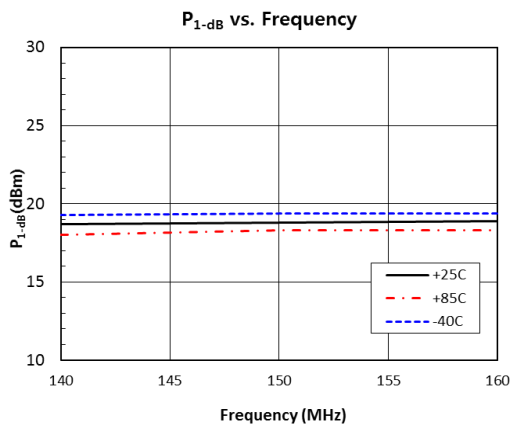
Parameter/Freq.(MHz)	140	150	160	Unit
Small Signal Gain	25.2	25.1	25	dB
S11	-17.5	-20.1	-21.4	dB
S22	-28.2	-27.8	-26.4	dB
Output P1dB	18.7	18.8	18.9	dBm
Output OIP3*	30.8	31.2	61.4	dBm
Noise Figure	1.62	1.62	1.62	dB
Icq	51			mA
Vcc	3.3			V

* Pout=6dBm/tone

S-Parameter Over Temperature vs. Freq. at 140~150MHz

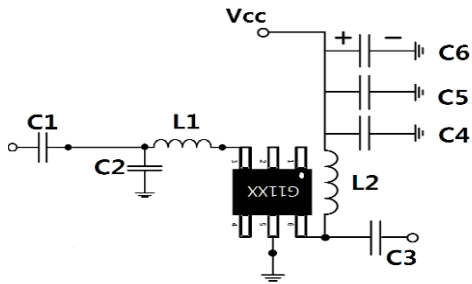


P1dB, OIP3 and Noise Figure Performance at 140~150MHz



RG511
50-4000MHz
High Linearity 3V Gain Block Amplifier

600~800MHz Reference Application Circuit



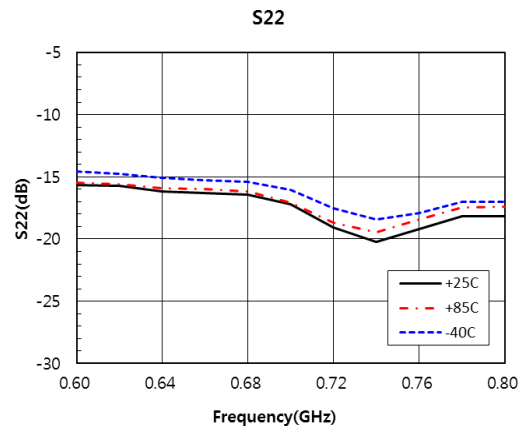
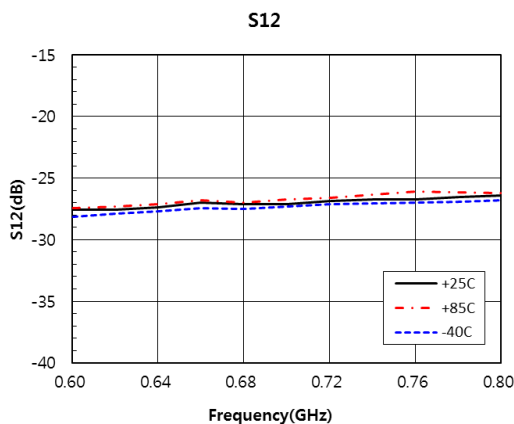
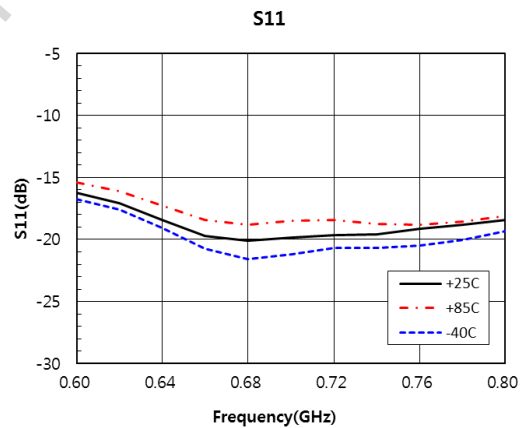
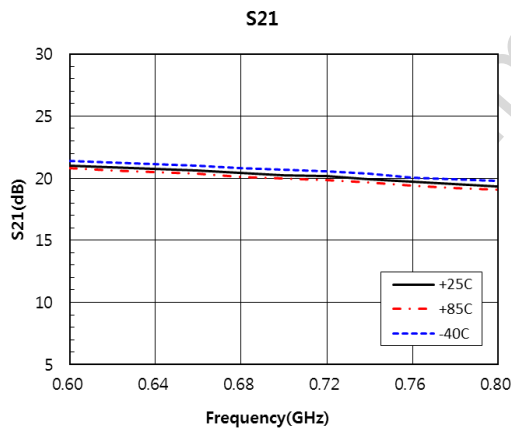
BOM	Value	BOM	Value	BOM	Value
C1	100pF	C4	100pF	L1	10nH
C2	1.8pF	C5	1000pF	L2	56nH
C3	100pF	C6	10uF		

*Width and Length of Micro-strip line dimension in mm[mil]

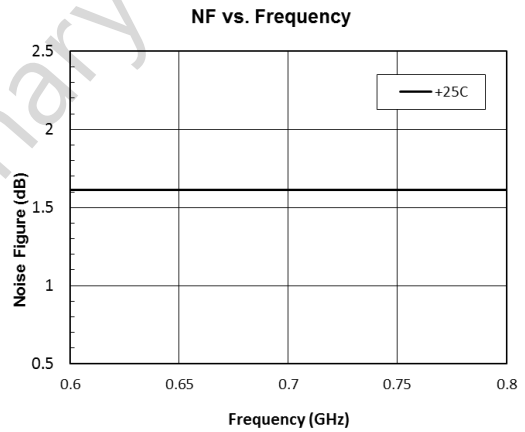
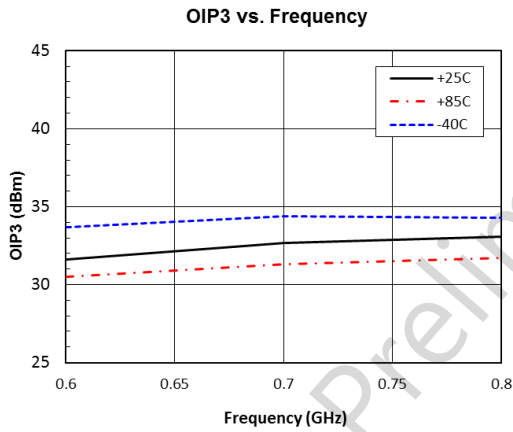
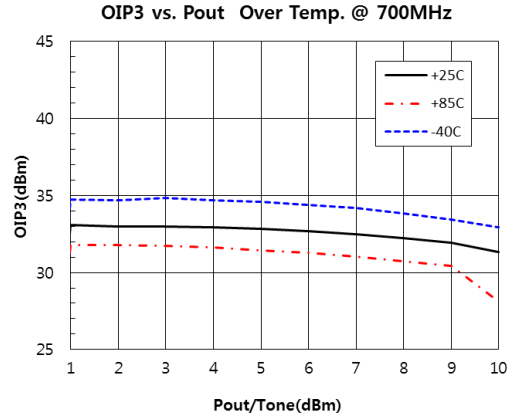
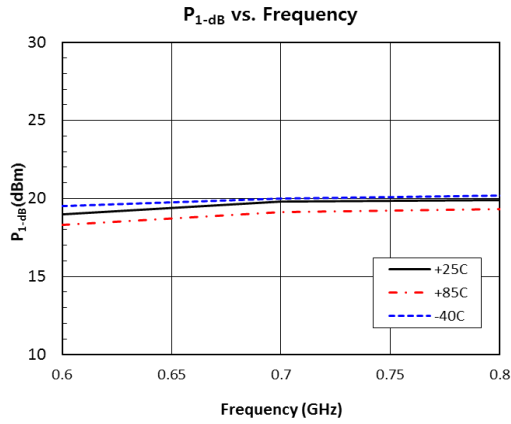
Parameter/Freq.(MHz)	600	700	800	Unit
Small Signal Gain	21.0	20.2	19.3	dB
S11	-16.2	-19.8	-18.4	dB
S22	-15.6	-17.2	-18.1	dB
Output P1dB	19.0	19.8	19.9	dBm
Output OIP3*	31.6	32.7	33.1	dBm
Noise Figure	1.61	1.61	1.61	dB
Icq	49			mA
Vcc	3.3			V

* Pout=6dBm/tone

S-Parameter Over Temperature vs. Freq. at 600~800MHz



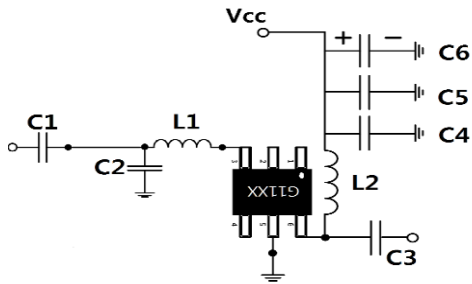
P1dB, OIP3 and Noise Figure Performance at 600~800MHz



RG511

50-4000MHz High Linearity 3V Gain Block Amplifier

850~950MHz Reference Application Circuit



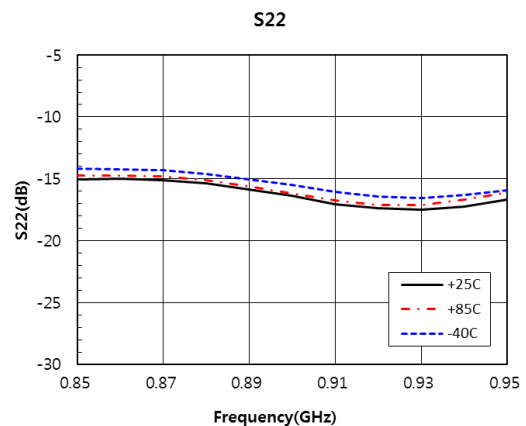
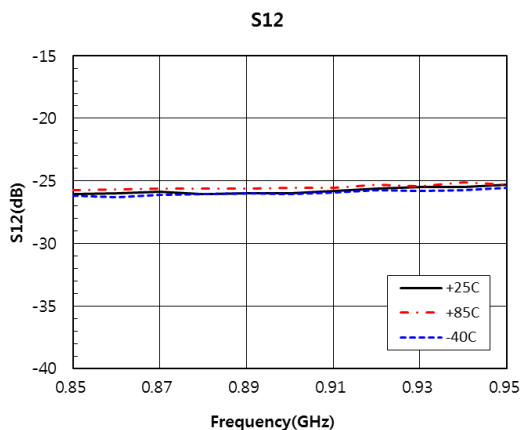
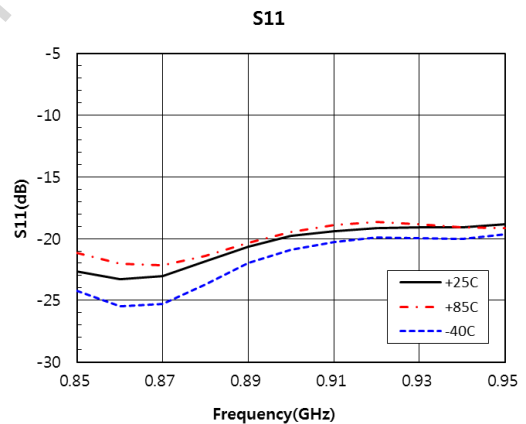
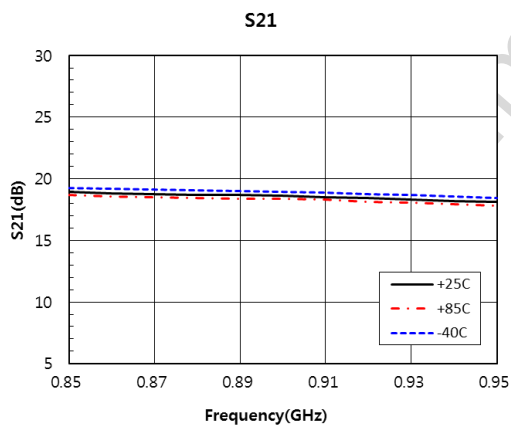
BOM	Value	BOM	Value	BOM	Value
C1	100pF	C4	100pF	L1	8.2nH
C2	1.8pF	C5	1000pF	L2	39nH
C3	100pF	C6	10uF		

*Width and Length of Micro-strip line dimension in mm[mil]

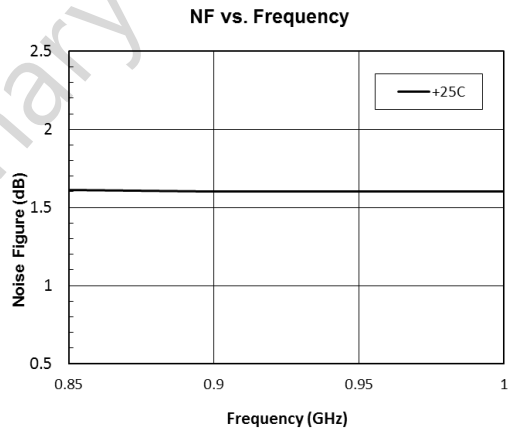
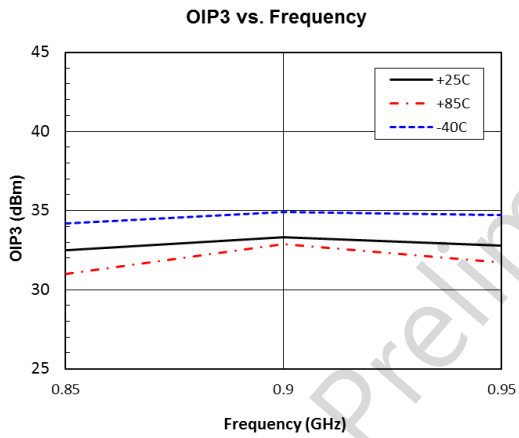
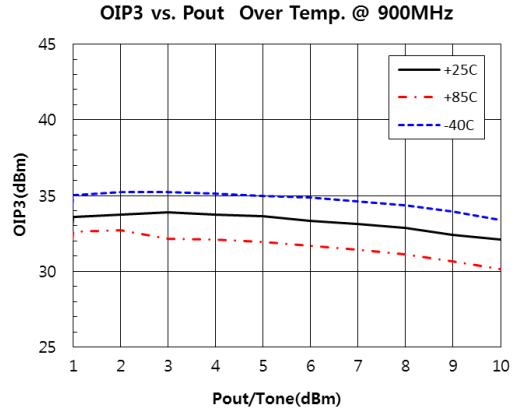
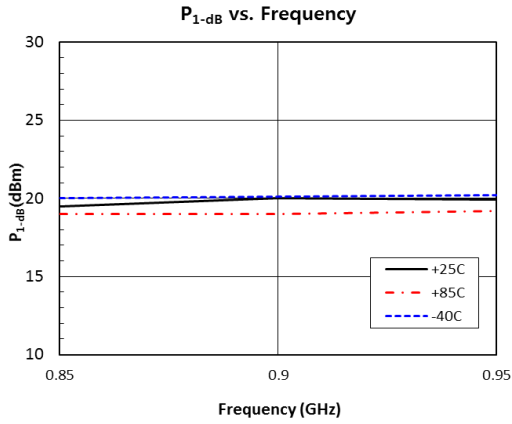
Parameter/Freq.(MHz)	850	900	950	Unit
Small Signal Gain	19.3	19.0	18.1	dB
S11	-22.6	-19.8	-19.2	dB
S22	-15.0	-16.3	-16.6	dB
Output P1dB	19.5	20.0	19.9	dBm
Output OIP3*	32.5	33.5	32.8	dBm
Noise Figure	1.60	1.60	1.60	dB
Icq	49			mA
Vcc	3.3			V

* Pout=6dBm/tone

S-Parameter Over Temperature vs. Freq. at 850~950MHz

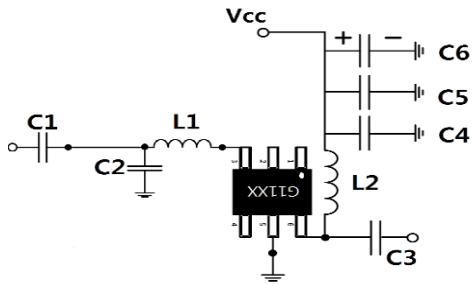


P1dB, OIP3 and Noise Figure Performance at 850~950MHz



RG511
50-4000MHz
High Linearity 3V Gain Block Amplifier

1800~2200MHz Reference Application Circuit



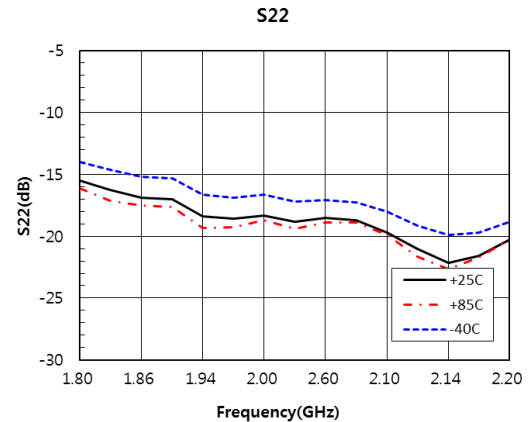
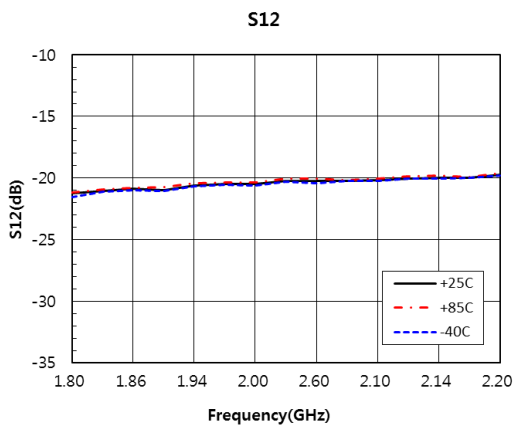
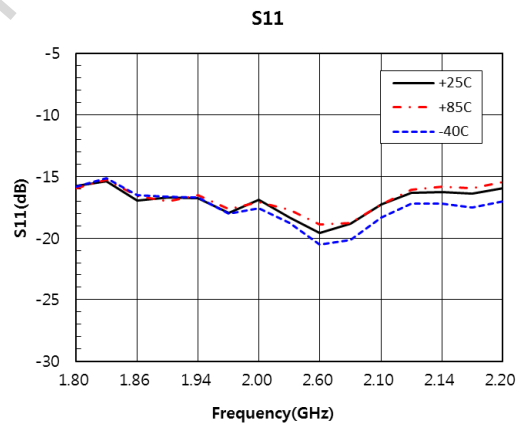
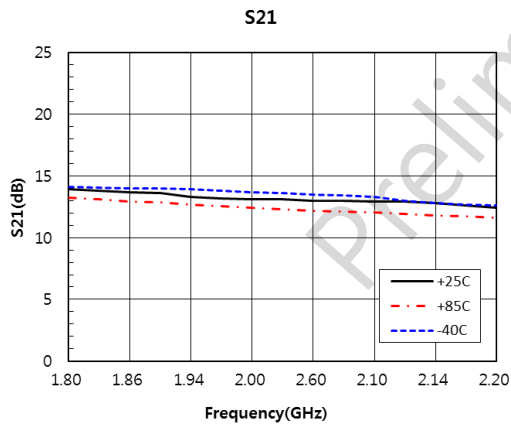
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C1	100pF	C4	100pF	L1	1.5nH
C2	1pF	C5	1000pF	L2	8.2nH
C3	100pF	C6	10uF		

*Width and Length of Micro-strip line dimension in mm[mil]

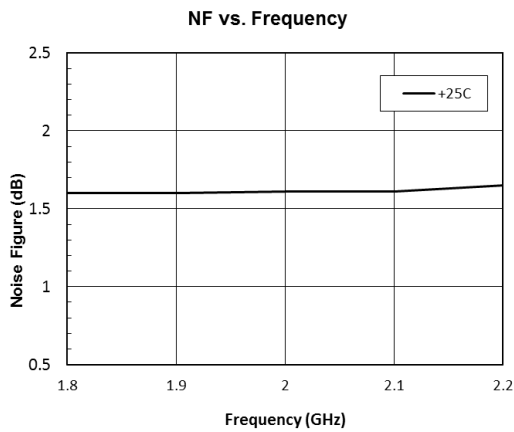
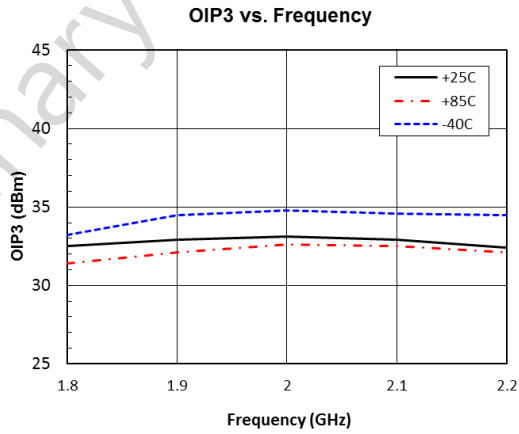
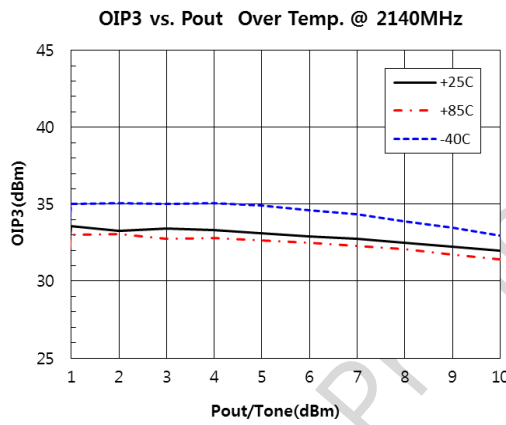
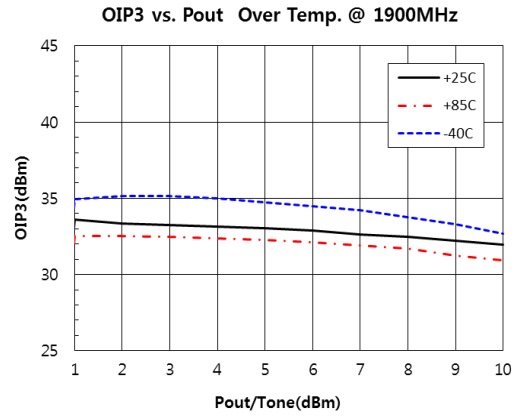
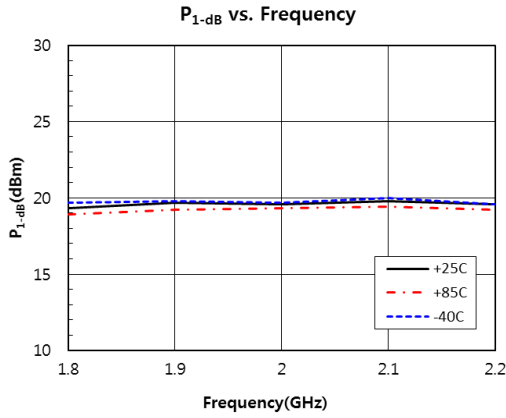
Parameter/Freq.(MHz)	1800	1900	2140	Unit
Small Signal Gain	13.9	13.6	12.8	dB
S11	-15.7	-16.7	-16.8	dB
S22	-15.5	-16.9	-22.1	dB
Output P1dB	19.3	19.7	19.8	dBm
Output OIP3*	32.7	33.1	33.3	dBm
Noise Figure	1.60	1.60	1.61	dB
Icq	50			mA
Vcc	3.3			V

* Pout=6dBm/tone

S-Parameter Over Temperature vs. Freq. at 1800~2200MHz

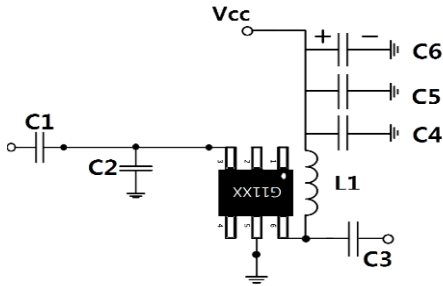


P1dB, OIP3 and Noise Figure Performance at 1800~2200MHz



RG511
50-4000MHz
High Linearity 3V Gain Block Amplifier

2300~2700MHz Reference Application Circuit



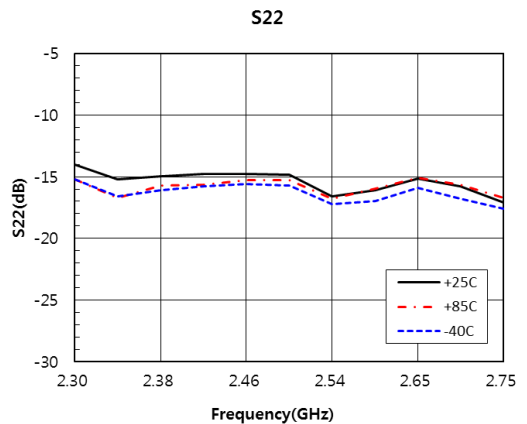
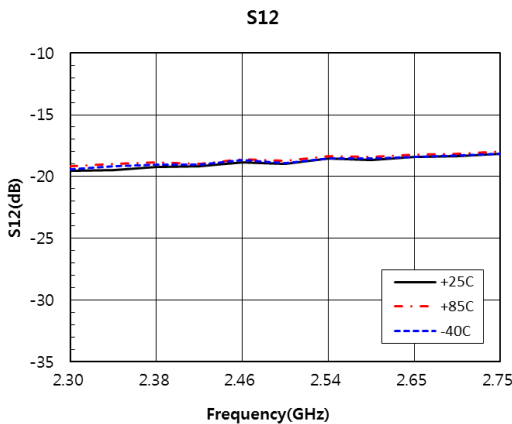
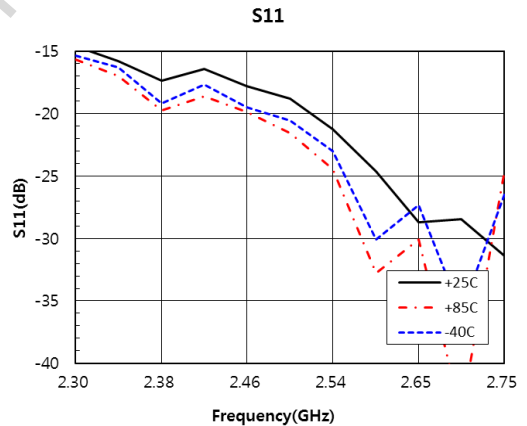
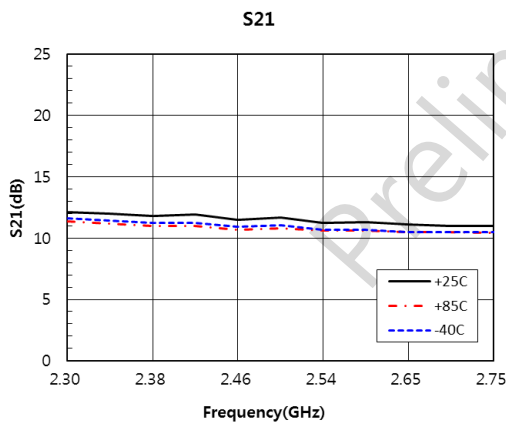
BOM	Value	BOM	Value	BOM	Value
C1	100pF	C4	100pF	L1	47nH
C2	1.0pF	C5	1000pF		
C3	100pF	C6	10uF		

*Width and Length of Micro-strip line dimension in mm[mil]

Parameter/Freq.(MHz)	2300	2650	2750	Unit
Small Signal Gain	12.4	11.3	11.0	dB
S11	-14.5	-28.7	-31.4	dB
S22	-19.5	-18.4	-18.1	dB
Output P1dB	19.6	19.7	19.9	dBm
Output OIP3*	32.6	31.7	31.0	dBm
Noise Figure	1.69	1.70	1.71	dB
Icq	51			mA
Vcc	3.3			V

* Pout=6dBm/tone

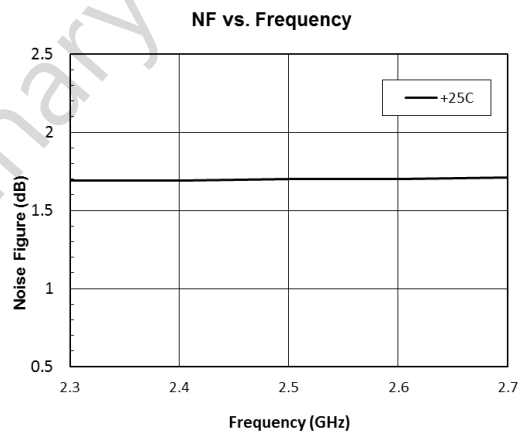
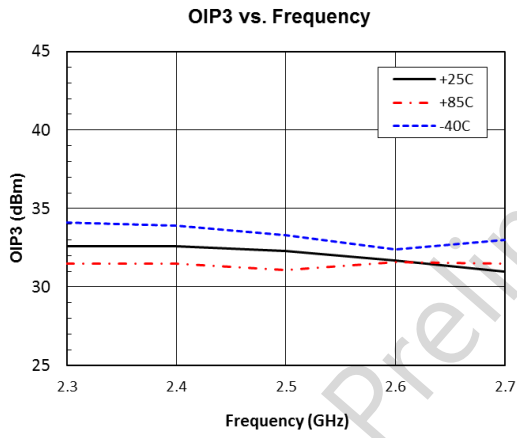
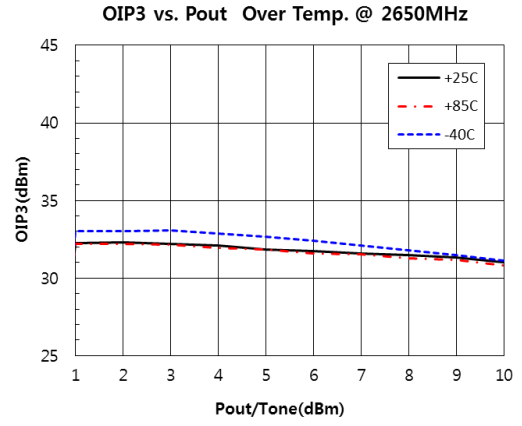
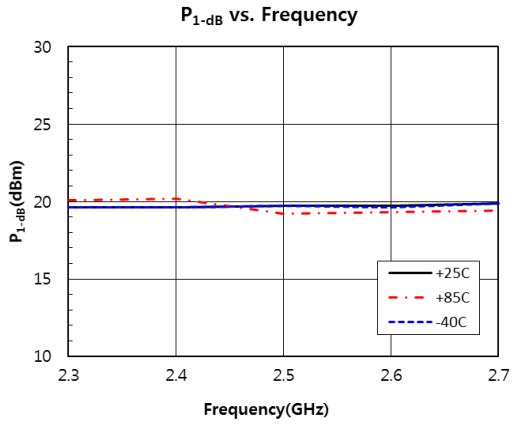
S-Parameter Over Temperature vs. Freq. at 2300~2700MHz



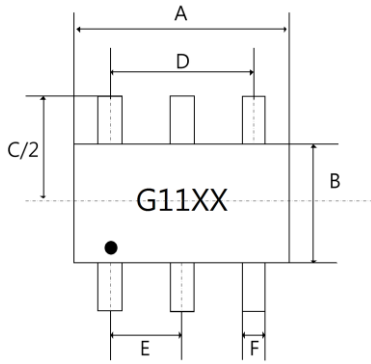
RG511
50-4000MHz
High Linearity 3V Gain Block Amplifier



P1dB, OIP3 and Noise Figure Performance at 2300~2700MHz

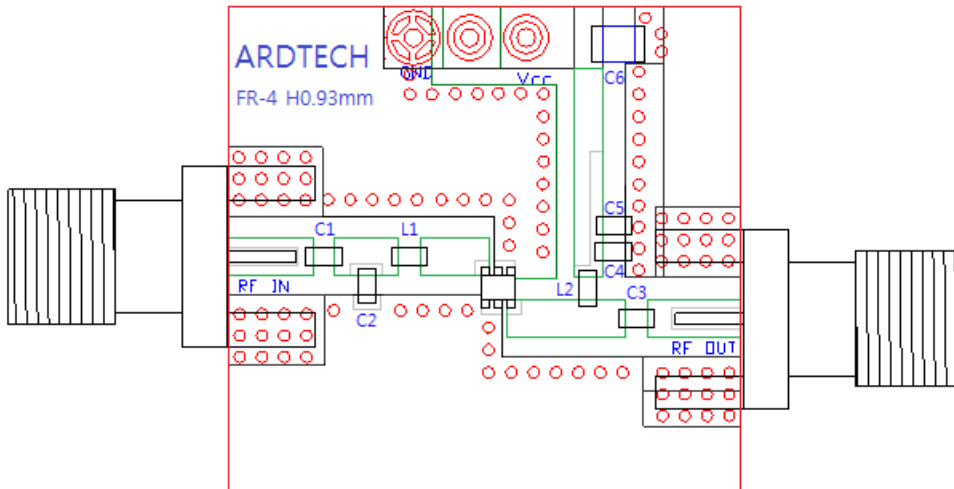


Package Mark and Dimensions



Symbol	DIMENSIONS MILLIMETER			DIMENSIONS INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.90	2.10	2.15	0.074	0.082	0.084
B	1.15	1.25	1.35	0.045	0.050	0.055
C	2.00	2.10	2.20	0.078	0.082	0.086
D	1.3			0.0512		
E	0.65			0.0255		
F	0.15	-	0.30	0.006	-	0.012

Evaluation PCB Layout



PCB Substrate Information[mm]	
Dielectric Constant	FR-4/4.6
Dielectric Height	0.037[0.93]
Copper Thickness	1 oz.

Product Description

RG512 is a low current and low noise Gain Block Amplifier in a low-cost surface mount package and provides 30dBm high OIP3 and 1.62dB Noise Figure at 1900MHz. It is fabricated on a compound semiconductor material and conventional device technology. RG512 is available in a lead-free / green / RoHS-compliant SOT363(SC70) package. The performance is targeted for use as a receiver and transmitter in wireless infrastructure system where high linearity and low noise is required. Internal active bias circuitry allows RG512 to maintain high linearity and gain performance over temperature and operate directly off a single +3V supply. All devices are 100% RF and DC tested and internally matched to 50 ohms without additional external components.

Features

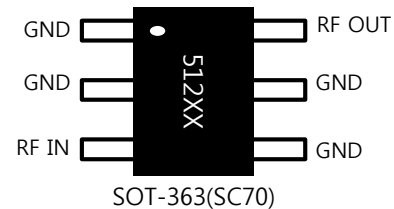
- High OIP3 30dBm at 1900MHz
- 18.9dB Gain at 900MHz
- P1dB=20dBm at 1900MHz
- 1.62dB Noise Figure at 1900MHz
- Unconditionally stable
- Single 3.3V supply, 27mA current
- No dropping resistor required
- Industry standard SOT363(SC70) package
- Lead-free, RoHS compliant, Green



Applications

- Broadband Gain Block
- Wireless infrastructure
- Cellular, PCS, GSM, WCDMA, WiBro, LTE

Component Diagram



Parameter	Specification			Condition	Units
	Min.	Typ.	Max.		
Small Signal Gain	17.4	18.9		900MHz	dB
	12.7	14.2		1900MHz	dB
	11.0	13.5		2140MHz	dB
Output power at 1-dB Compression	18.5	20.0		1900MHz	dBm
	19.0	20.6		2140MHz	dBm
Third Order Intercept Point	23.7	25.7		1900MHz	dBm
	28.3	30.3		2140MHz	dBm
Input Return Loss		-22.1		1900MHz	dB
Output Return Loss		-16.8		1900MHz	dB
Reverse Isolation		-22.5		1900MHz	dB
Noise Figure		1.62		1900MHz	dB
Device Voltage		3.3			V
Device current (Icq)	17	27			mA
Thermal Resistance		41.6		Junction to lead	°C/W

Test condition: Vcc=3.3V, I_b=27mA Typ., OIP₃ Tone Spacing=1MHz, P_{out} per tone=6dBm T_l=25°C, Z_s=Z_l=50

Absolute Maximum Ratings

Parameter	Rating	Unit
Max Device Voltage(V_D)	5.0	V
Max Device Current(I_D)	60	mA
Max RF Input Power	10	dBm
Max Operating Dissipated Power	0.3	W
Junction Temperature(T_J)	+150	°C
Operating Temperature(T_I)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 1B	
Moisture Sensitivity Level	MSL1	



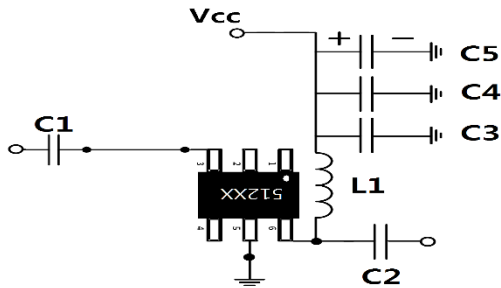
Typical Electrical Specification

Parameter	700MHz	900MHz	1900MHz	2140MHz	2650MHz	Unit
S21	19.2	18.9	14.2	13.5	11.7	dB
OIP3	24.0	25.7	30.0	30.3	31.4	dBm
P1dB	15.0	17.0	20.0	20.6	21.6	dBm
S11	-8.8	-14.4	-22.1	-19.8	-17.7	dB
S22	-7.7	-10.7	-16.8	-17.0	-16.3	dB
S12	-28.2	-25.9	-22.5	-22.3	-21.4	dB
NF	1.65	1.62	1.62	1.63	1.65	dB

Test condition: $V_{cc}=3.3V$, $I_D=27mA$ Typ., OIP_3 Tone Spacing=1MHz, P_{out} per tone=6dBm $T_L=25^\circ C$, $Z_S=Z_L=50$

RG512
500-4000MHz
High Linearity 3V Gain Block Amplifier

700~900MHz Reference Application Circuit



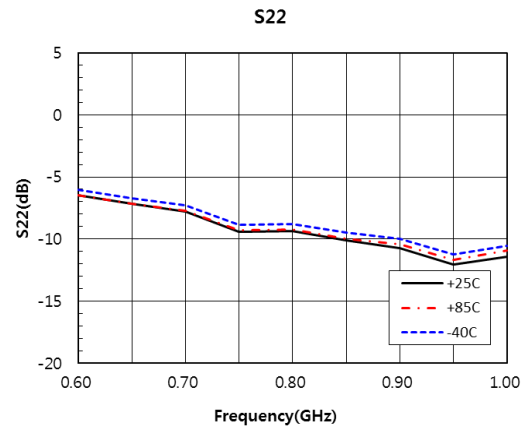
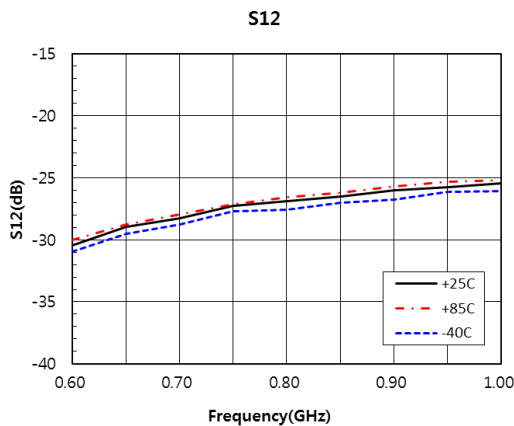
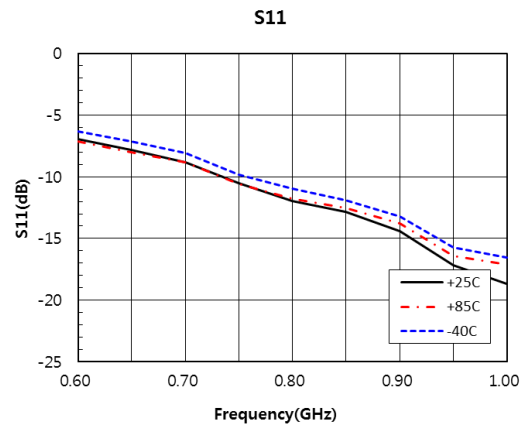
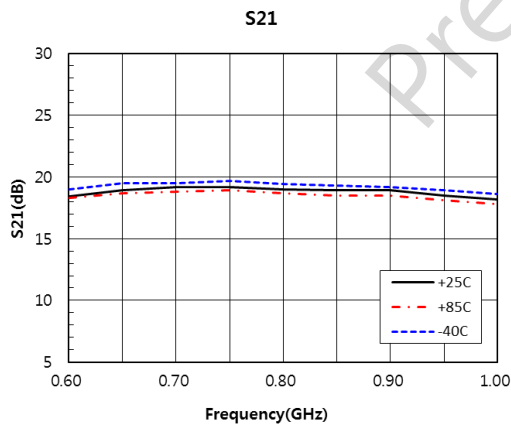
BOM	Value	BOM	Value	BOM	Value
C1	100pF	C4	1000pF	L1	22nH
C2	100pF	C5	10uF		
C3	100pF				

*Width and Length of Micro-strip line dimension in mm[mil]

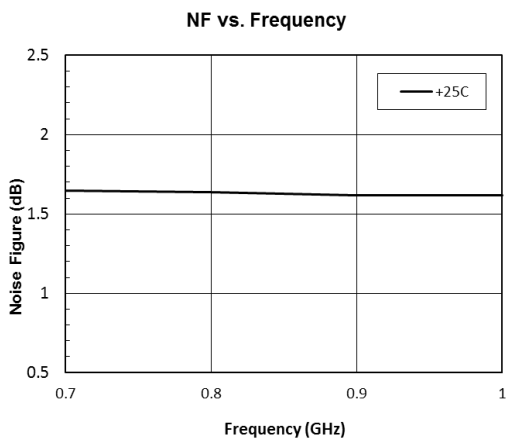
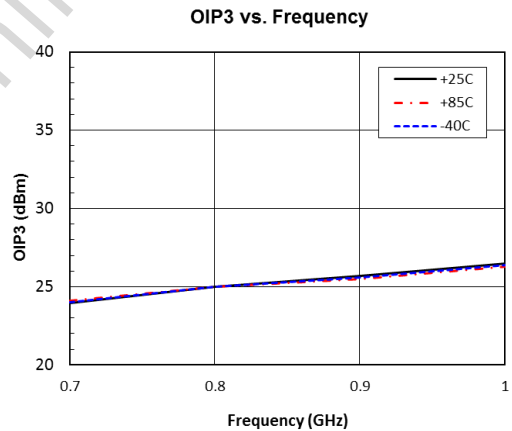
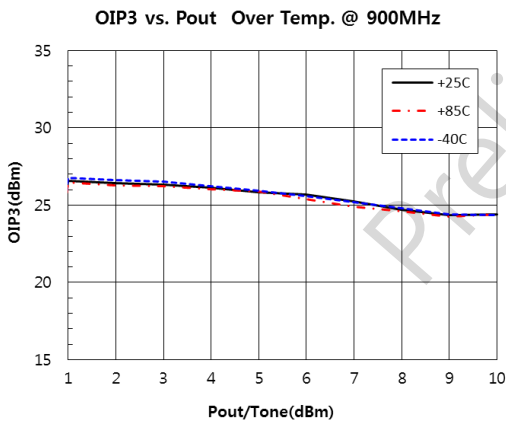
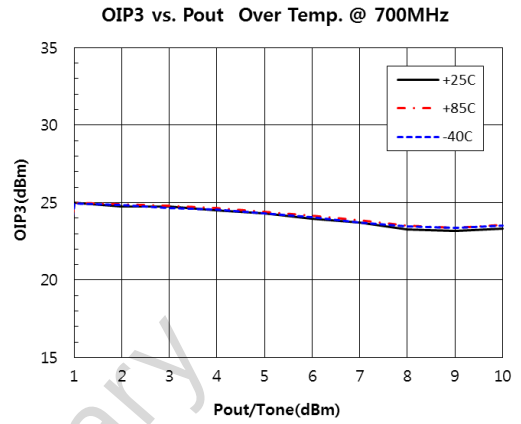
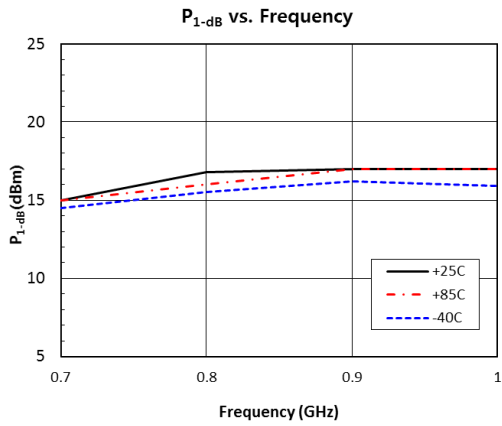
Parameter/Freq.(MHz)	700	800	900	Unit
Small Signal Gain	19.2	19.0	18.9	dB
S11	-8.8	-11.9	-14.4	dB
S22	-7.7	-9.3	-10.7	dB
Output P1dB	15	16.8	17	dBm
Output OIP3*	24.0	25.0	25.7	dBm
Noise Figure	1.65	1.64	1.62	dB
Icq	27			mA
Vcc	3.3			V

* Pout=6dBm/tone

S-Parameter Over Temperature vs. Freq. at 700~900MHz

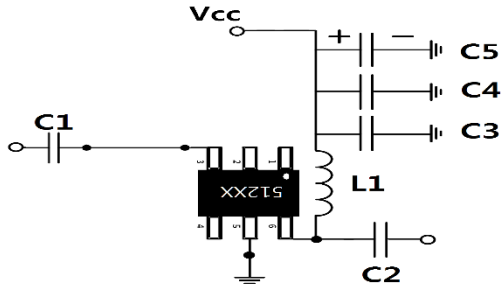


P1dB, OIP3 and Noise Figure Performance at 700~900MHz



RG512
 500-4000MHz
 High Linearity 3V Gain Block Amplifier

1800~2200MHz Reference Application Circuit



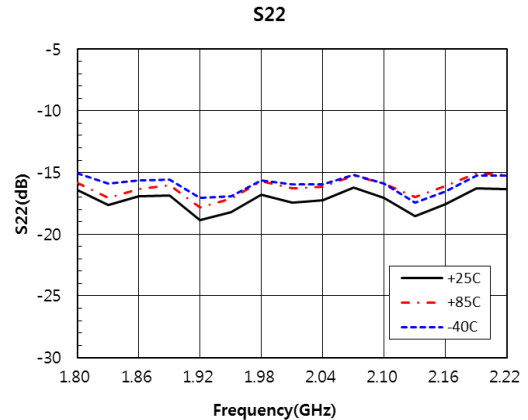
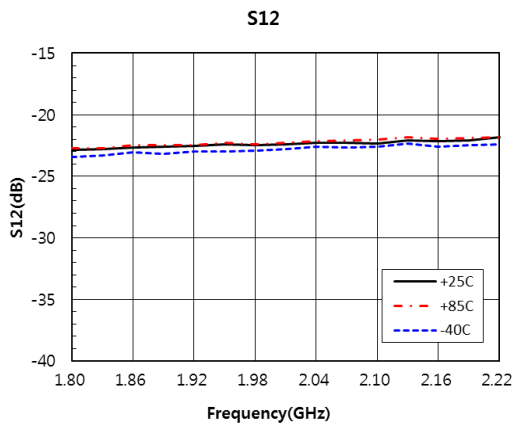
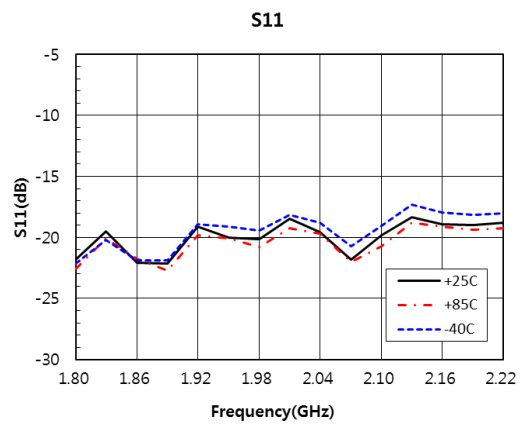
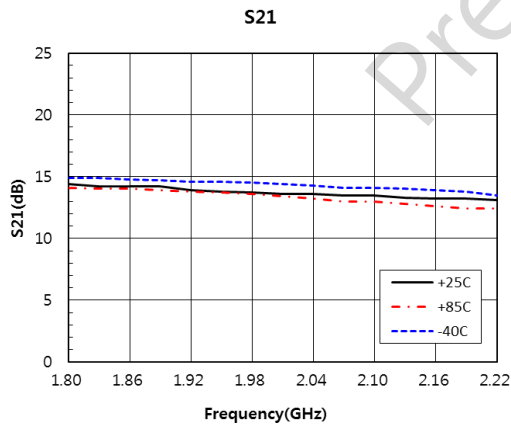
BOM	Value	BOM	Value	BOM	Value
C1	100pF	C4	1000pF	L1	10nH
C2	100pF	C5	10uF		
C3	100pF				

*Width and Length of Micro-strip line dimension in mm[mil]

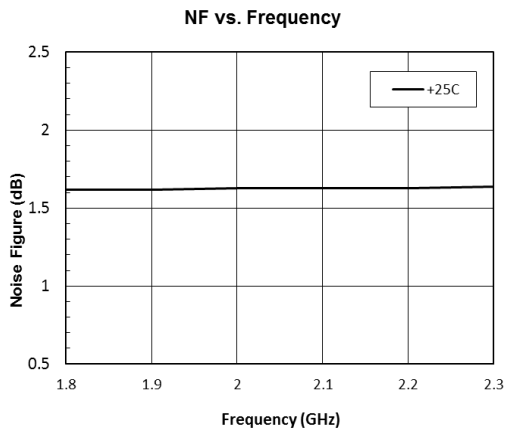
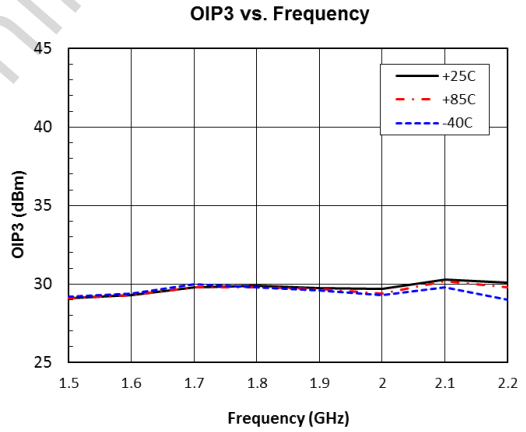
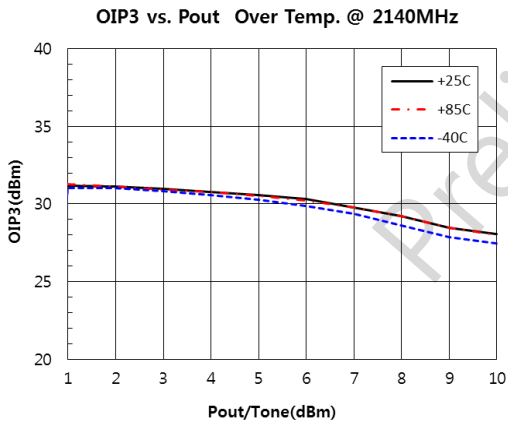
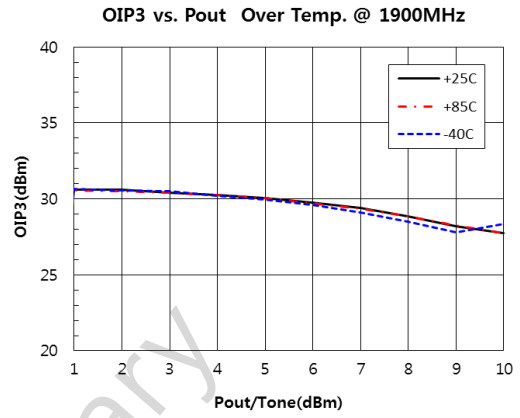
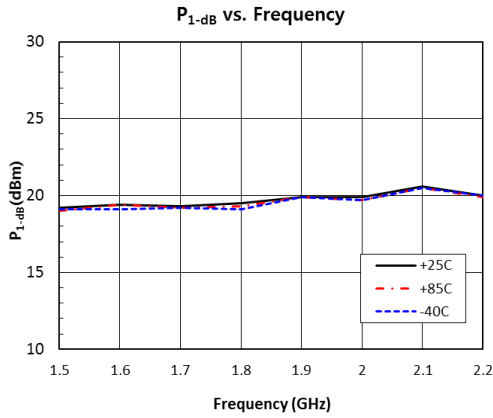
Parameter/Freq.(MHz)	1800	1900	2140	Unit
Small Signal Gain	14.4	14.2	13.5	dB
S11	-21.8	-22.1	-19.8	dB
S22	-16.3	-16.8	-17.0	dB
Output P1dB	19.5	20.0	20.6	dBm
Output OIP3*	29.9	30.0	30.3	dBm
Noise Figure	1.62	1.62	1.63	dB
Icq	27			mA
Vcc	3.3			V

* Pout=6dBm/tone

S-Parameter Over Temperature vs. Freq. at 1800~2200MHz

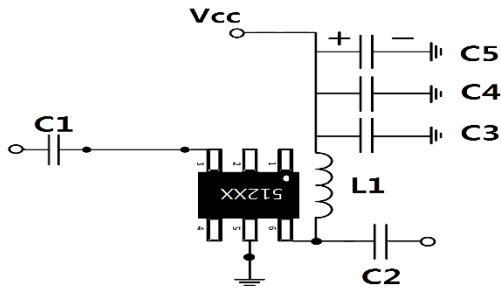


P1dB, OIP3 and Noise Figure Performance at 1800~2200MHz



RG512
500-4000MHz
High Linearity 3V Gain Block Amplifier

2300~2700MHz Reference Application Circuit



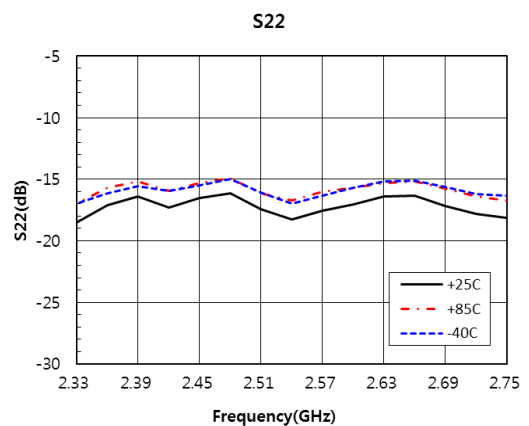
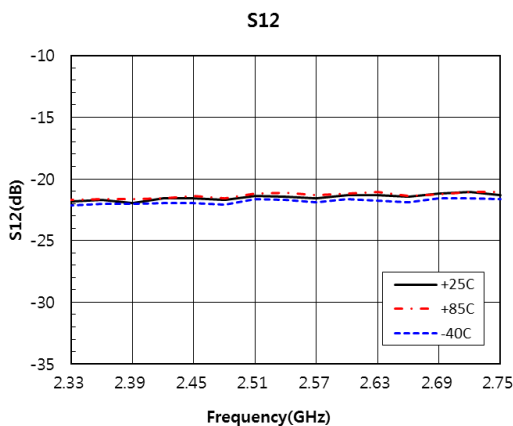
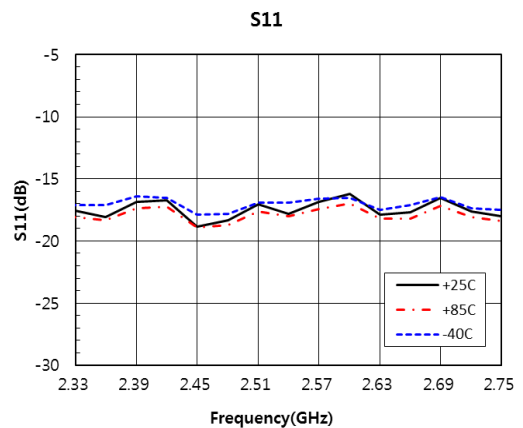
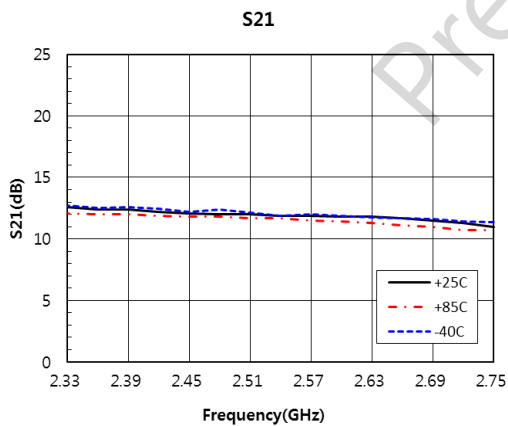
BOM	Value	BOM	Value	BOM	Value
C1	100pF	C4	1000pF	L1	10nH
C2	100pF	C5	10uF		
C3	100pF				

*Width and Length of Micro-strip line dimension in mm[mil]

Parameter/Freq.(MHz)	2300	2650	2750	Unit
Small Signal Gain	12.7	11.7	11.0	dB
S11	-18.4	-17.7	-18.0	dB
S22	-16.9	-16.3	-18.1	dB
Output P1dB	20.3	21.5	21.6	dBm
Output OIP3*	31.0	31.4	31.2	dBm
Noise Figure	1.64	1.65	1.66	dB
Icq	27			mA
Vcc	3.3			V

* Pout=6dBm/tone

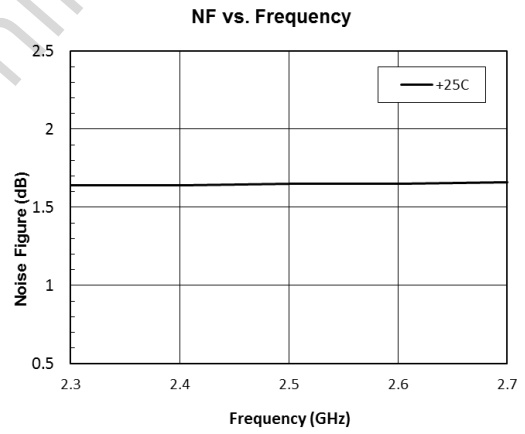
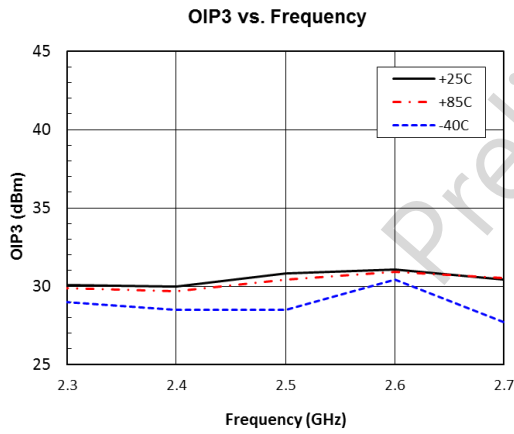
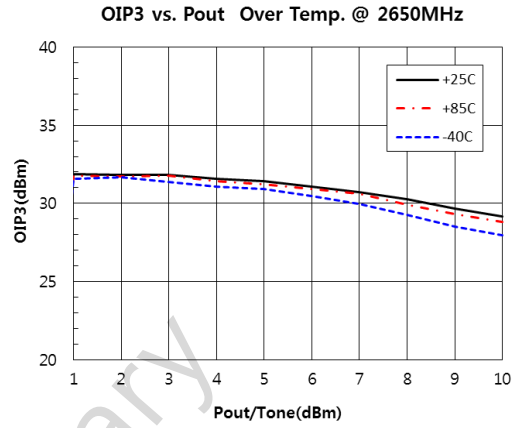
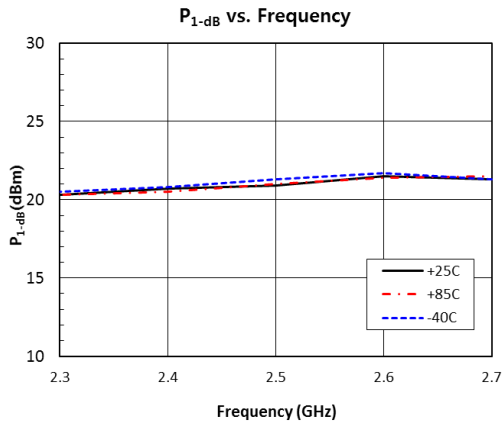
S-Parameter Over Temperature vs. Freq. at 2300~2700MHz



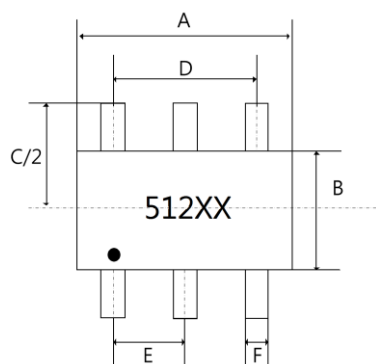
RG512
500-4000MHz
High Linearity 3V Gain Block Amplifier



P1dB, OIP3 and Noise Figure Performance at 2300~2700MHz

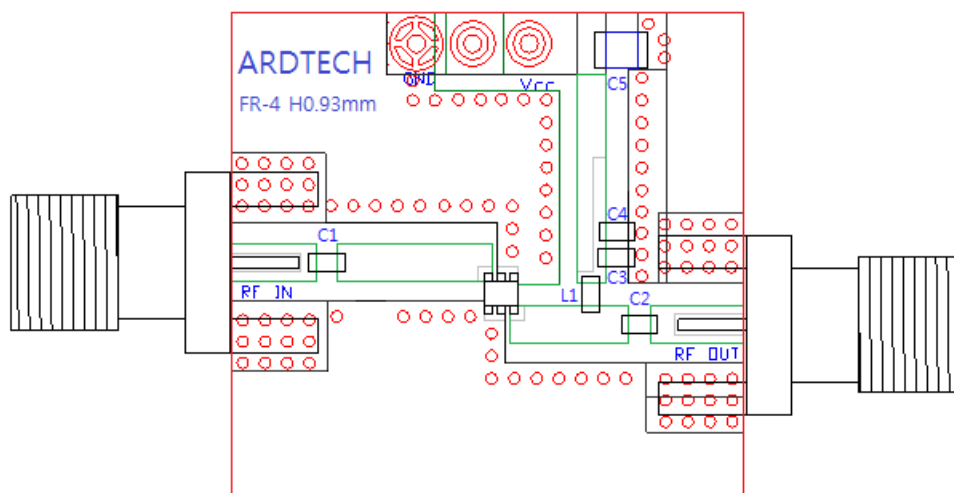


Package Mark and Dimensions



Symbol	DIMENSIONS MILLIMETER			DIMENSIONS INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.90	2.10	2.15	0.074	0.082	0.084
B	1.15	1.25	1.35	0.045	0.050	0.055
C	2.00	2.10	2.20	0.078	0.082	0.086
D	1.3			0.0512		
E	0.65			0.0255		
F	0.15	-	0.30	0.006	-	0.012

Evaluation PCB Layout



PCB Substrate Information[mm]	
Dielectric Constant	FR-4/4.6
Dielectric Height	0.037[0.93]
Copper Thickness	1 oz.

InGaP HBT IF Gain Block MMIC Amplifier

Product Description

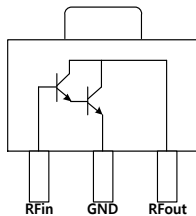
RG614 is a high performance InGaP HBT MMIC IF gain block amplifier utilizing a Darlington pair configuration with an active bias circuit and it can be used as a cascadable 50 ohm IF gain block applications that require high gain and excellent stable amplification. It's housed in a lead-free/green/RoHS-compliant SOT-89 industry-standard SMT package and internally matched to minimize number of external bias component

Features

- High Gain 27.1dB at 70MHz
- P1dB=21dBm at 140MHz
- Unconditionally stable
- Single fixed 5V supply
- Industry standard SOT-89 package
- Robust ESD, Class 1C
- Lead-free, RoHS compliant, Green



Component Diagram



Applications

- LO signal boosting Amplifier
- Receive IF Amplifier
- Cellular, PCS, GSM, WCDMA, LTE
- CATV, Cable Modem & DBS

Parameter	Specification			Condition	Units
	Min.	Typ.	Max.		
Small Signal Gain	25.6	27.1		70MHz	dB
	25.2	26.7		140MHz	dB
	25.1	26.6		240MHz	dB
Output power at 1-dB Compression	19.5	21.0		70MHz	dBm
	19.5	21.0		140MHz	dBm
Third Order Intercept Point	36.2	38.2		70MHz	dBm
	35.9	37.9		140MHz	dBm
Input Return Loss		-36.9		70MHz	dB
Output Return Loss		-11.9		70MHz	dB
Reverse Isolation		-32.8		70MHz	dB
Noise Figure		3.2		70MHz	dB
Device Voltage		5			V
Device current (Icq)	82	90	100		mA
Thermal Resistance		34		Junction to lead	°C/W

Test condition: Vcc=5V, I_b=90mA Typ., OIP₃ Tone Spacing=1MHz, P_{out} per tone=10dBm T_L=25°C, Z_s=Z_L=50

RG614
50-500MHz
InGaP HBT IF Gain Block MMIC Amplifier

Absolute Maximum Ratings

Parameter	Rating	Unit
Max Device Voltage(V_D)	5.5	V
Max Device Current(I_D)	136	mA
Max RF Input Power	18	dBm
Max Operating Dissipated Power	0.74	W
Junction Temperature(T_J)	+150	°C
Operating Temperature(T_L)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 1C	
Moisture Sensitivity Level	MSL1	

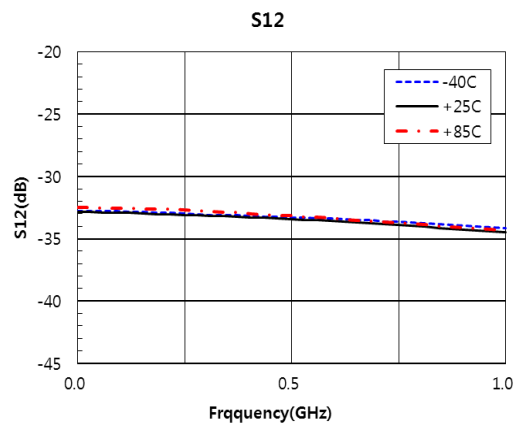
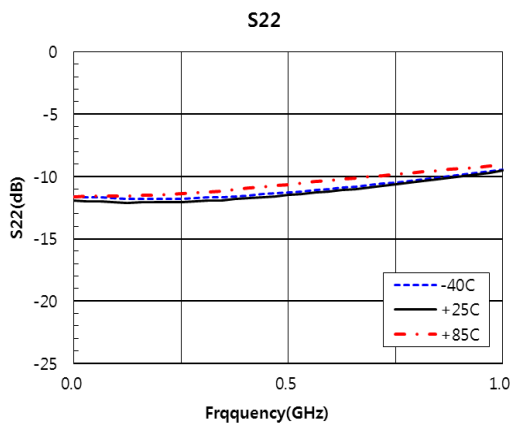
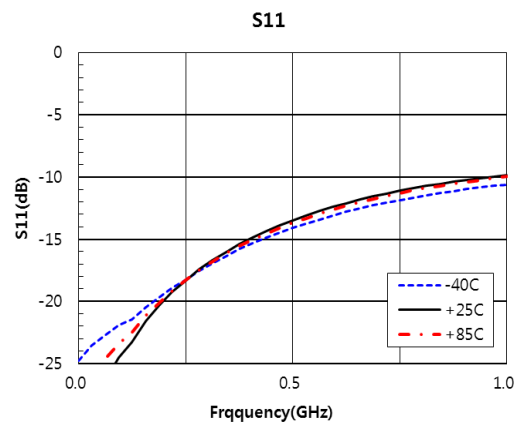
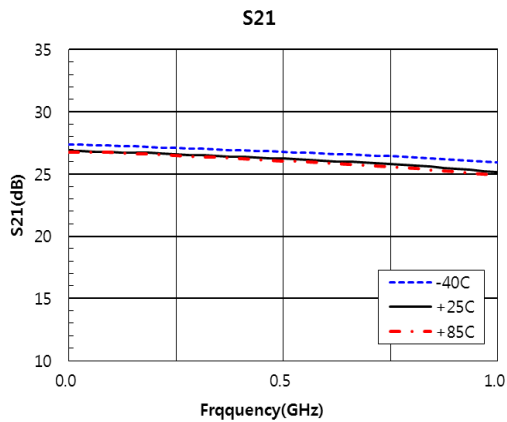


Typical Electrical Specification

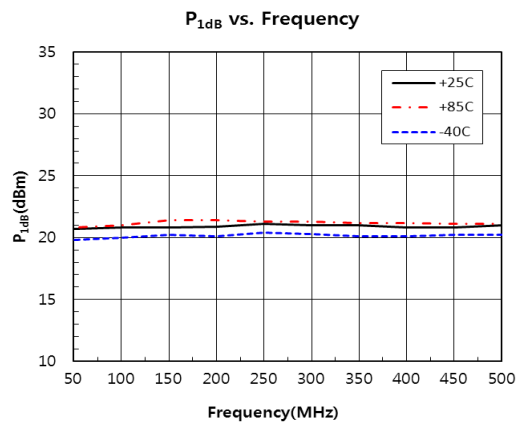
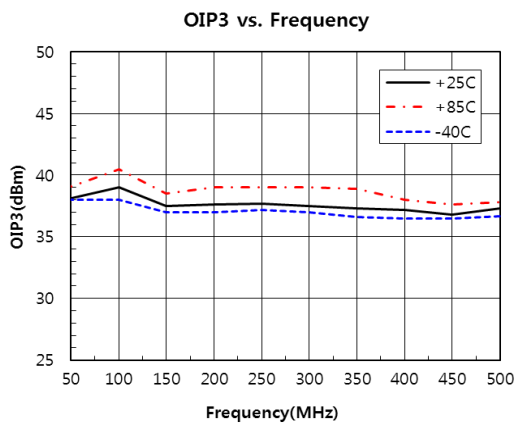
Parameter	70MHz	140MHz	240MHz	500MHz	Unit
S21	27.1	26.9	26.6	26.2	dB
OIP3	38.2	37.9	37.7	37.3	dBm
P1dB	21.0	21.0	21.0	21.0	dBm
S11	-36.9	-24.5	-20.3	-13.9	dB
S22	-11.9	-12.0	-12.0	-11.5	dB
S12	-32.8	-32.8	-33.0	-33.3	dB
NF	3.2	3.2	3.5	3.5	dB

Test condition: $V_{CC}=5V$, $I_D=90mA$ Typ., OIP_3 Tone Spacing=1MHz, P_{out} per tone=10dBm $T_L=25^\circ C$, $Z_S=Z_L=50$

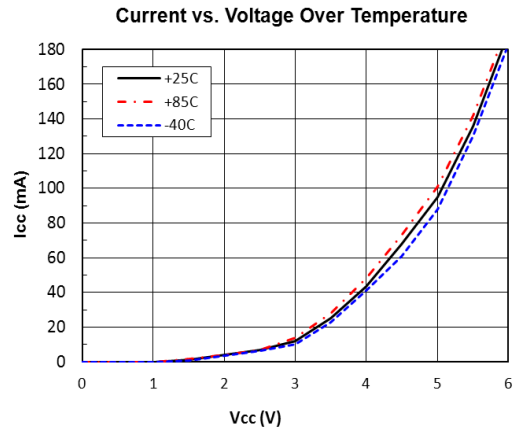
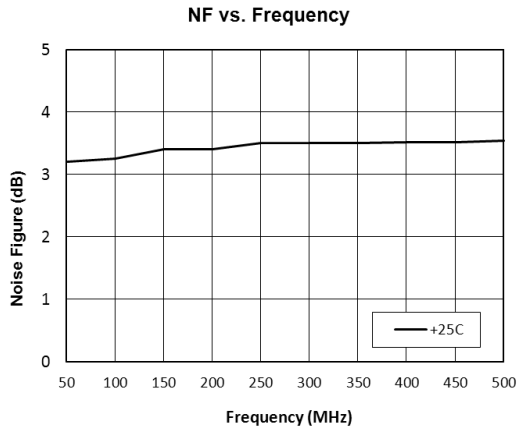
S-Parameter Over Temperature



P1dB and OIP3 vs. Frequency

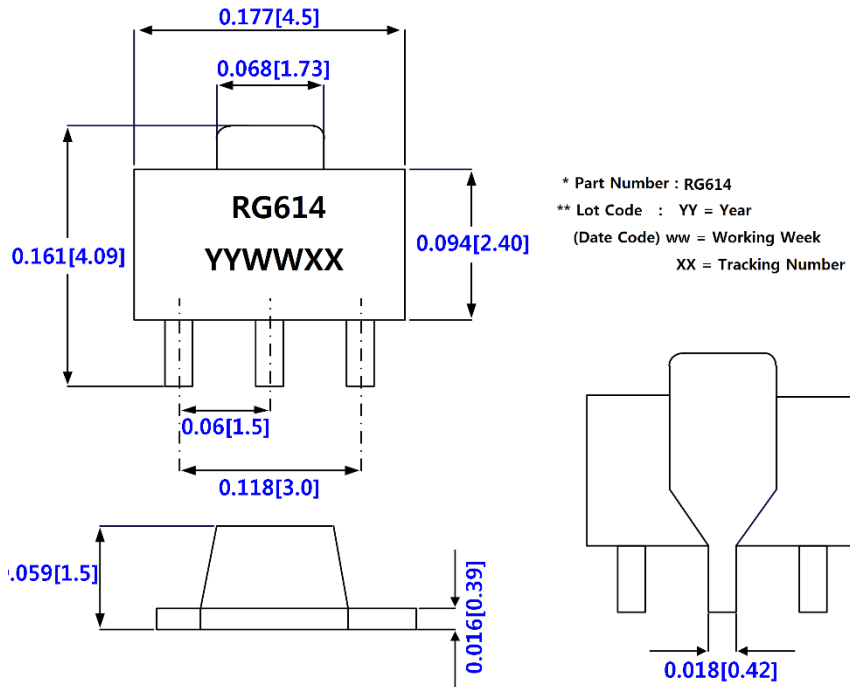


Icc vs. Vcc Over Temperature and Noise Figure



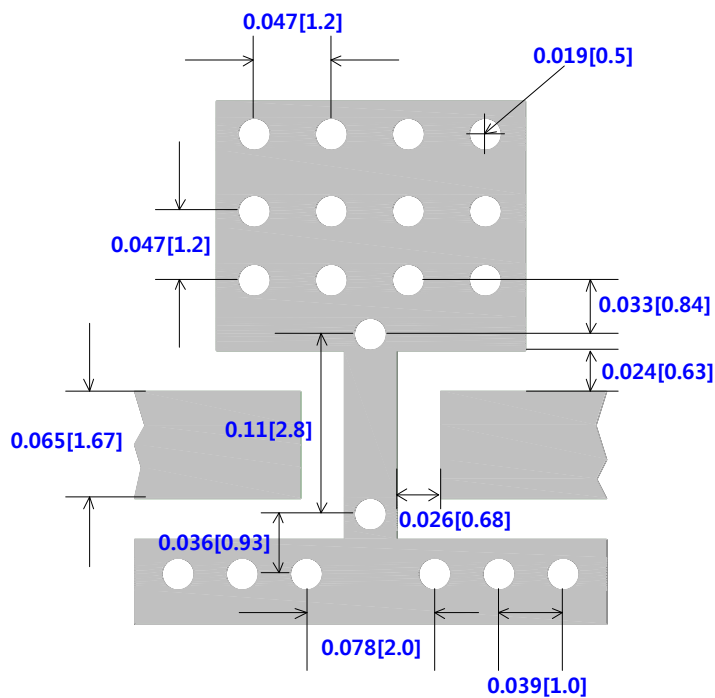
Package Mark and Dimensions

Dimension in inches[Millimeters]

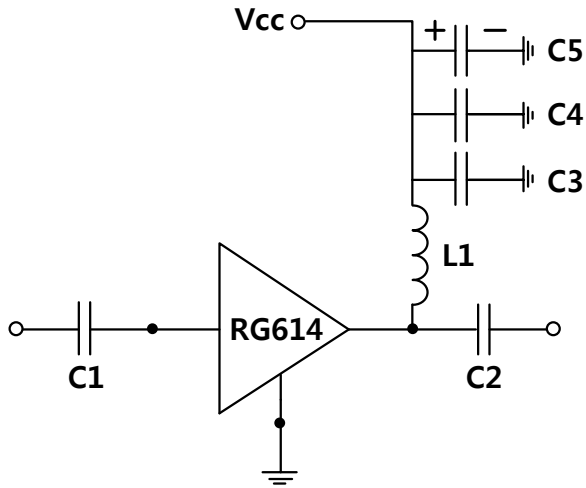


Recommended PCB Pad Pattern

Dimension in inches[Millimeters]

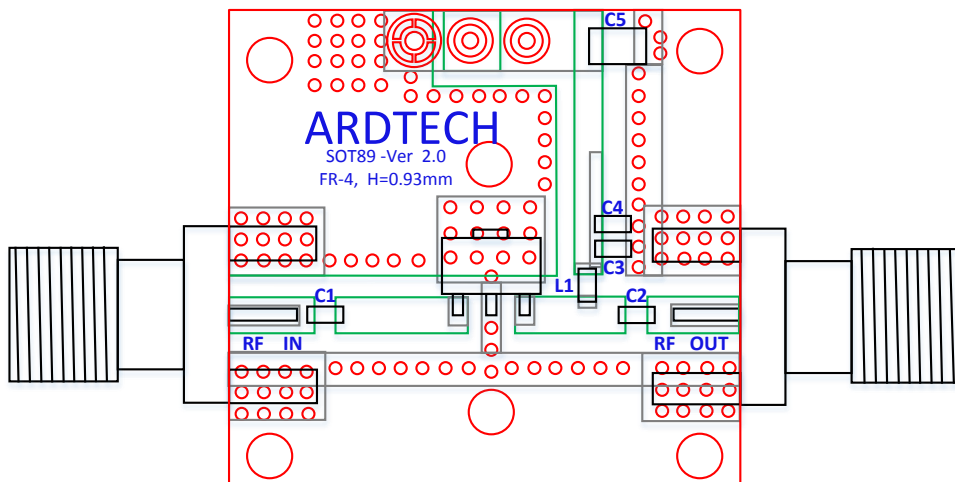


Application Schematic & BOM



Reference BOM	
C1	8200pF Capacitor, 0603 type
C2	8200pF Capacitor, 0603 type
C3	100pF Capacitor, 0603 type
C4	1000pF Capacitor, 0603 type
C5	10uF Capacitor, Tantalum
L1	1uH Chip inductor, 0805 type

Evaluation PCB Layout



PCB Substrate Information[mm]	
Dielectric Constant	FR-4/4.6
Dielectric Height	0.036[0.93]
Copper Thickness	1 oz.

InGaP HBT IF Gain Block MMIC Amplifier

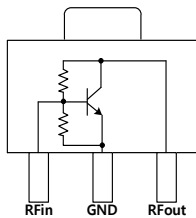
Product Description

RG625 is a high performance InGaP HBT MMIC IF gain block amplifier with an active bias circuit and it can be used as a cascadable 50 ohm IF gain block applications that require high OIP3 and P1dB performance. It's housed in a lead-free/green/RoHS-compliant SOT-89 industry-standard SMT package and internally matched to minimize number of external bias component

Features

- High OIP3= 44.0dBm at 70MHz
- P1dB=24.3dBm at 140MHz
- Unconditionally stable
- Single fixed 5V supply
- Industry standard SOT-89 package
- Robust ESD, Class 1C
- Lead-free, RoHS compliant, Green

Component Diagram



Applications

- LO signal boosting Amplifier
- Receive IF Amplifier
- Cellular, PCS, GSM, WCDMA, LTE
- CATV, Cable Modem & DBS



Parameter	Specification			Condition	Units
	Min.	Typ.	Max.		
Small Signal Gain	17.3	18.8		70MHz	dB
	17.1	18.6		140MHz	dB
	17.1	18.6		240MHz	dB
Output power at 1-dB Compression	22.5	24.0		70MHz	dBm
	22.8	24.3		140MHz	dBm
Third Order Intercept Point	43.5	45.5		70MHz	dBm
	40.0	42.0		140MHz	dBm
Input Return Loss		-17.1		70MHz	dB
Output Return Loss		-25.0		70MHz	dB
Reverse Isolation		-22.9		70MHz	dB
Noise Figure		4.6		70MHz	dB
Device Voltage		5			V
Device current (Icq)	76	84	94		mA
Thermal Resistance		45		Junction to lead	°C/W

Test condition: Vcc=5V, I_b=84mA Typ., OIP₃ Tone Spacing=1MHz, P_{out} per tone=8dBm T_L=25°C, Z_S=Z_L=50

RG625
50-500MHz
InGaP HBT IF Gain Block MMIC Amplifier

Absolute Maximum Ratings

Parameter	Rating	Unit
Max Device Voltage(V_D)	5.5	V
Max Device Current(I_D)	130	mA
Max RF Input Power	20	dBm
Max Operating Dissipated Power	0.71	W
Junction Temperature(T_J)	+150	°C
Operating Temperature(T_L)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 1C	
Moisture Sensitivity Level	MSL1	

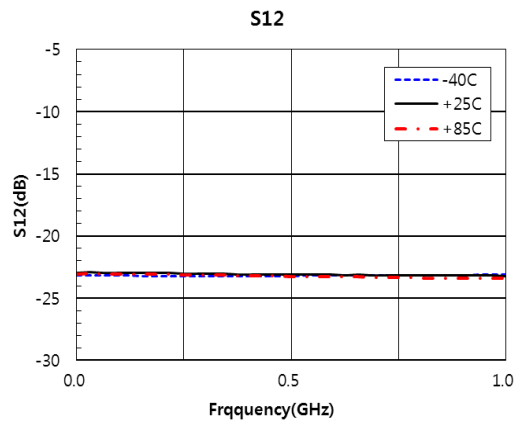
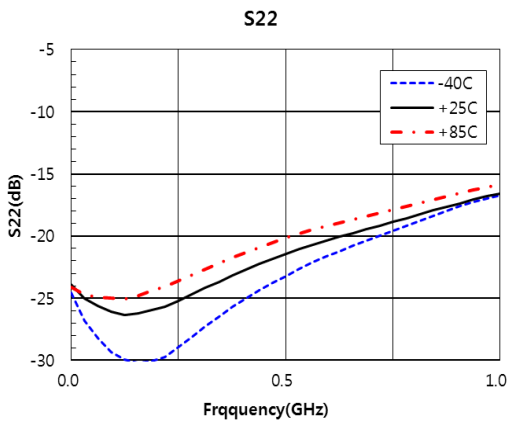
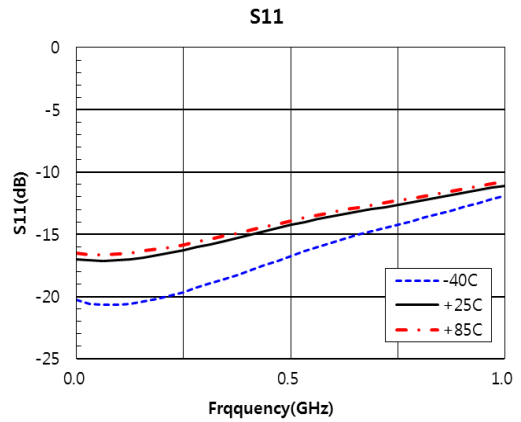
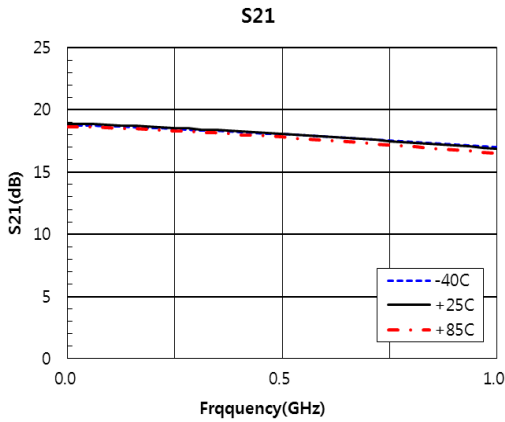


Typical Electrical Specification

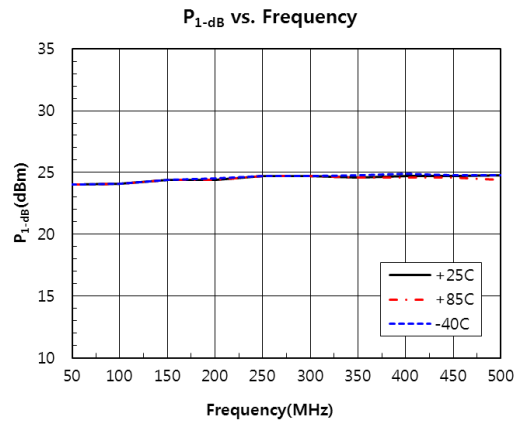
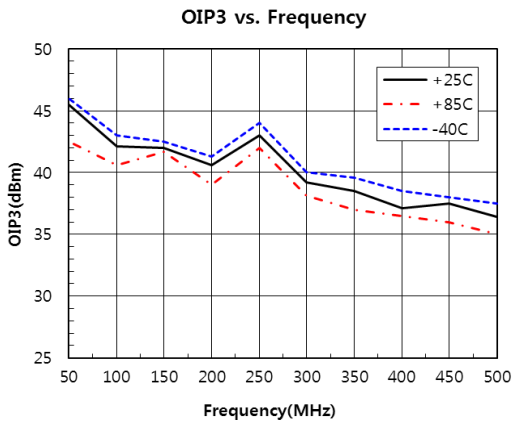
Parameter	70MHz	140MHz	240MHz	500MHz	Unit
S21	18.8	18.6	18.6	18.1	dB
OIP3	44.0	42.0	43.0	38.5	dBm
P1dB	24	24.3	24.7	24.2	dBm
S11	-17.1	-17.0	-16.6	-14.5	dB
S22	-25.0	-26.0	-25.9	-21.8	dB
S12	-22.9	-22.9	-22.9	-23.0	dB
NF	4.6	4.8	4.9	4.6	dB

Test condition: $V_{CC}=5V$, $I_D=84mA$ Typ., OIP_3 Tone Spacing=1MHz, P_{out} per tone=8dBm $T_L=25^\circ C$, $Z_S=Z_L=50$

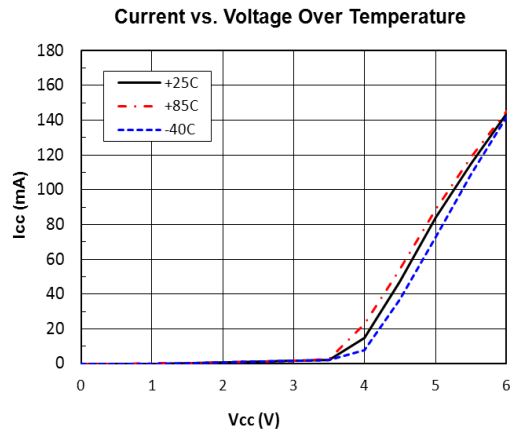
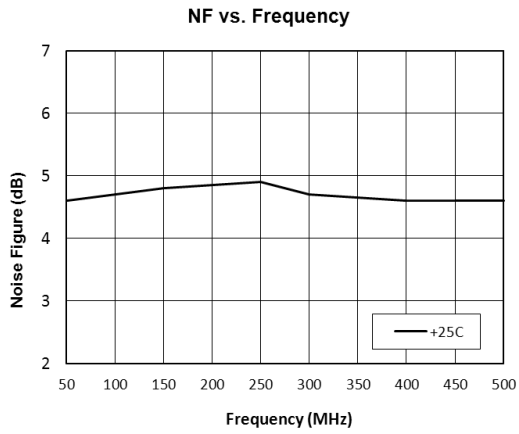
S-Parameter Over Temperature



P1dB and OIP3 vs. Frequency

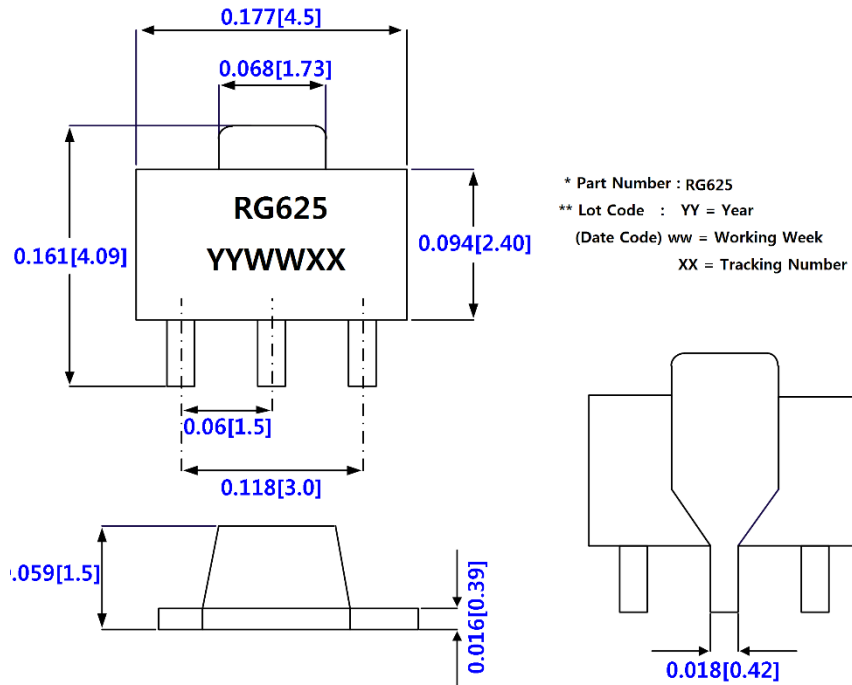


Icc vs. Vcc Over Temperature and Noise Figure



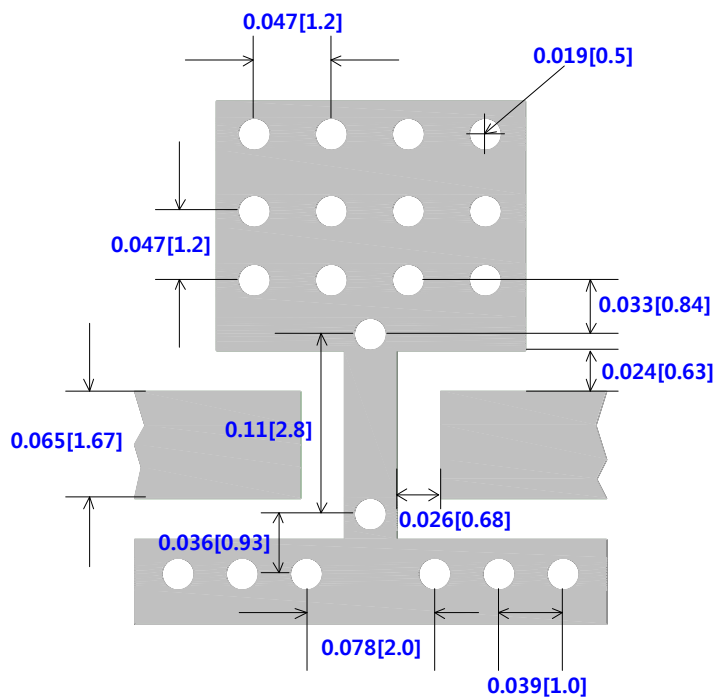
Package Mark and Dimensions

Dimension in inches[Millimeters]

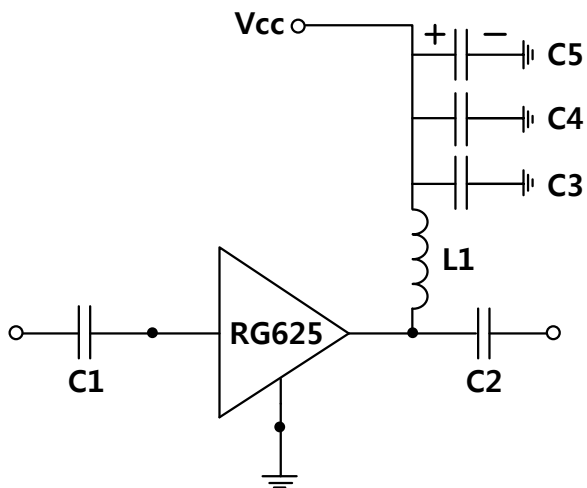


Recommended PCB Pad Pattern

Dimension in inches[Millimeters]

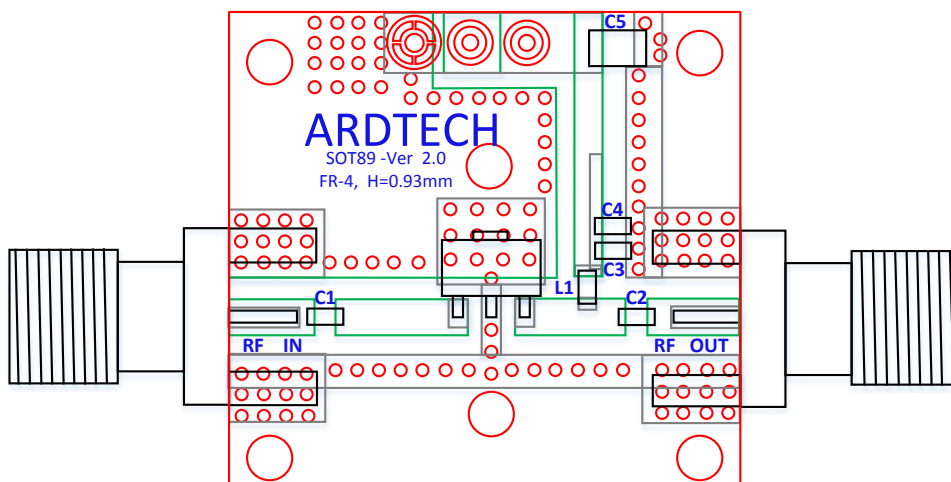


Application Schematic & BOM



Reference BOM	
C1	8200pF Capacitor, 0603 type
C2	8200pF Capacitor, 0603 type
C3	100pF Capacitor, 0603 type
C4	1000pF Capacitor, 0603 type
C5	10uF Capacitor, Tantalum
L1	680nH Chip inductor, 0805 type

Evaluation PCB Layout



PCB Substrate Information[mm]	
Dielectric Constant	FR-4/4.6
Dielectric Height	0.036[0.93]
Copper Thickness	1 oz.

0.25W High Linearity InGaP HBT Amplifier

Product Description

RA031 is a high linearity InGaP HBT 0.25W driver amplifier in a low-cost surface mount package. The InGaP/GaAs HBT is able to achieve high performance across a broad range and it is available in a lead-free / green / RoHS-compliant SOT-89 package. RA031 is targeted for use as a driver amplifier in wireless infrastructure where high linearity and medium power is required. Internal biasing allows RA031 to maintain high linearity over temperature and operate directly off a single +5V supply. All devices are 100% RF and DC tested.

Features

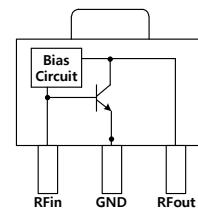
- High OIP3 44.1dBm @ 900MHz
- P1dB=24.1dBm @ 900MHz
- No output matching @ 1.8~2.4GHz application
- Unconditionally stable
- Single fixed 5V supply, 82mA current
- Industry standard SOT-89 package
- Lead-free, RoHS compliant, Green

Applications

- PA driver amplifier
- Wireless infrastructure
- Cellular, PCS, GSM, WCDMA,



Component Diagram



Parameter	Specification			Condition	Units
	Min.	Typ.	Max.		
Small Signal Gain	18.2	20.7		900MHz	dB
	15.1	16.6		1900MHz	dB
	13.7	15.2		2140MHz	dB
Output power at 1-dB Compression	22.6	24.1		900MHz	dBm
	22.5	24.0		1900MHz	dBm
Third Order Intercept Point	42.1	44.1		900MHz	dBm
	38.0	40.0		1900MHz	dBm
Input Return Loss		-15.0		1900MHz	dB
Output Return Loss		-16.8		1900MHz	dB
Reverse Isolation		-28.5		900MHz	dB
Noise Figure		4.4		900MHz	dB
Device Voltage		5			V
Device current (Icq)	75	82	95		mA
Thermal Resistance		23		Junction to lead	°C/W

Test condition: Vcc=5V, I_b=82mA Typ., OIP₃ Tone Spacing=1MHz, P_{out} per tone=14dBm T_l=25°C, Z_s=Z_l=50

RA031
50-3600MHz
0.25W High Linearity Amplifier

Absolute Maximum Ratings

Parameter	Rating	Unit
Max Device Voltage(V_D)	6.0	V
Max Device Current(I_D)	185	mA
Max RF Input Power	23	dBm
Max Operating Dissipated Power	1.11	W
Junction Temperature(T_J)	+150	°C
Operating Temperature(T_L)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 2	
Moisture Sensitivity Level	MSL1	



Typical Electrical Specification

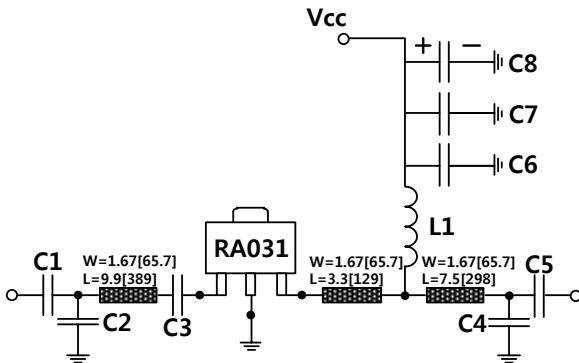
Parameter	900MHz	1900MHz	2140MHz	2350MHz	Unit
S21	20.7	16.6	15.2	14.4	dB
OIP3	44.1	40.0	39.0	39.1	dBm
P1dB	24.1	24.0	23.9	24.3	dBm
ACLR	-48.0	-48.3	-46.0	-46.2	dBc
S11	-11.0	-15.0	-15.9	-15.1	dB
S22	-15.2	-16.8	-11.9	-15.2	dB
S12	-28.5	-26.5	-26.0	-25.1	dB
NF	4.4	4.4	4.5	4.4	dB

Test condition: $V_{CC}=5V$, $I_D=65mA$ Typ., OIP_3 Tone Spacing=1MHz, P_{out} per tone=14dBm $T_L=25^\circ C$, $Z_S=Z_L=50$, ACLR=3GPP Test model 1+64 DPCH, PAR=10.3@0.01% Probability, 15.36MHz BW, 4FA

RA031

50-3600MHz
0.25W High Linearity Amplifier

800~900MHz Reference Application Circuit



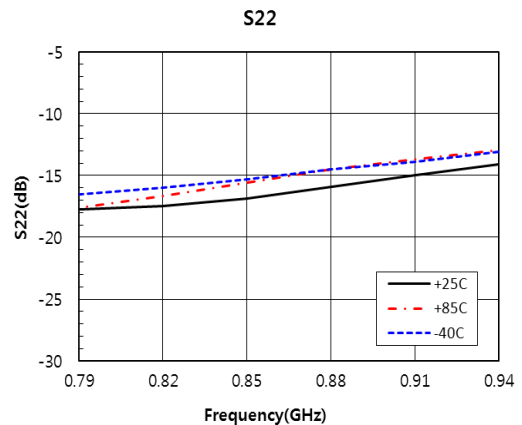
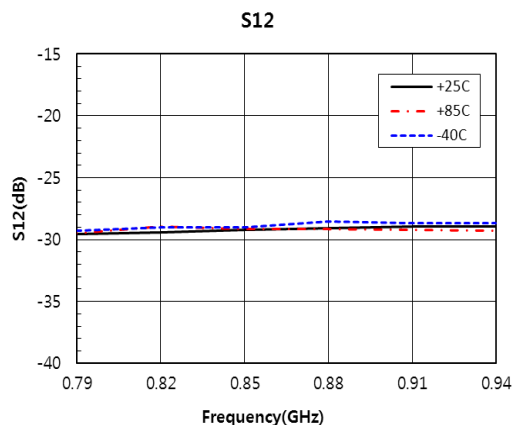
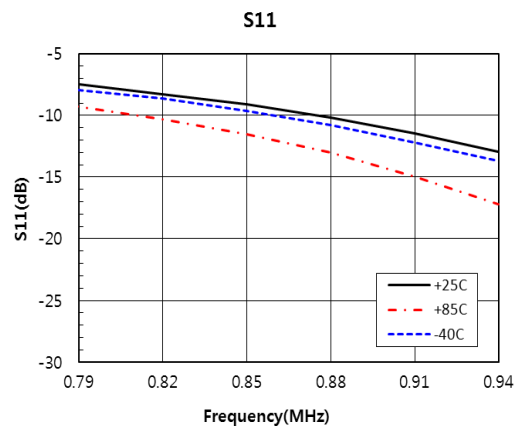
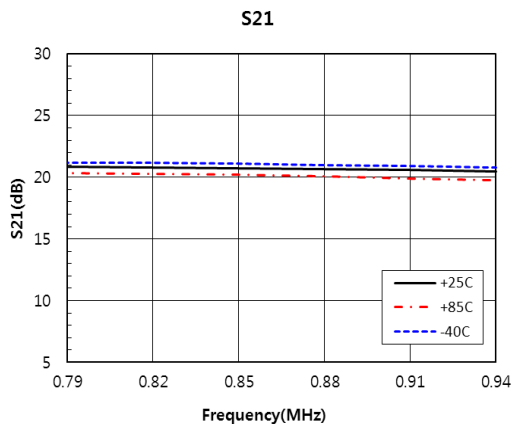
BOM	Value	BOM	Value	BOM	Value
C1	100pF	C4	1.8pF	C7	1000pF
C2	3.9pF	C5	100pF	C8	10uF
C3	NA	C6	100pF	L1	33nH

*Width and Length of Micro-strip line dimension in mm[mil]

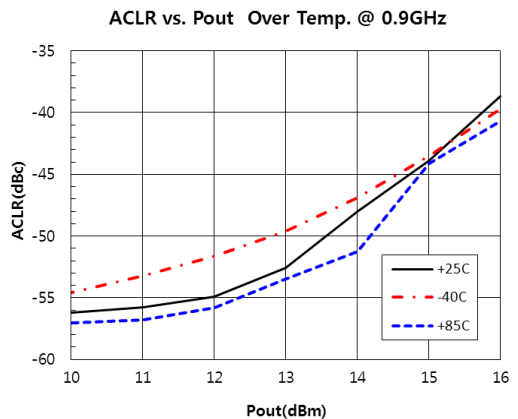
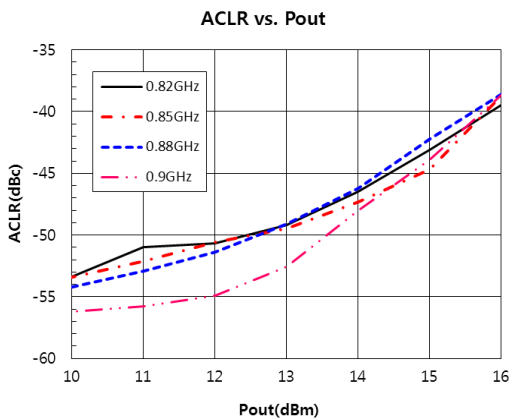
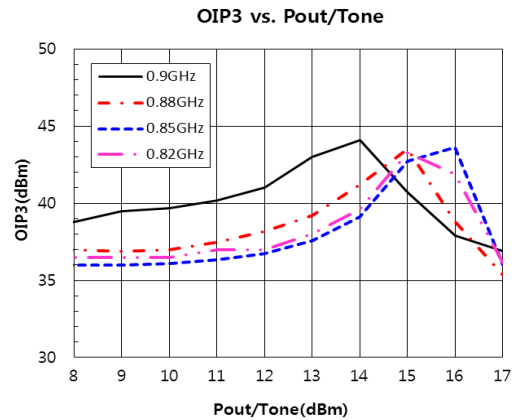
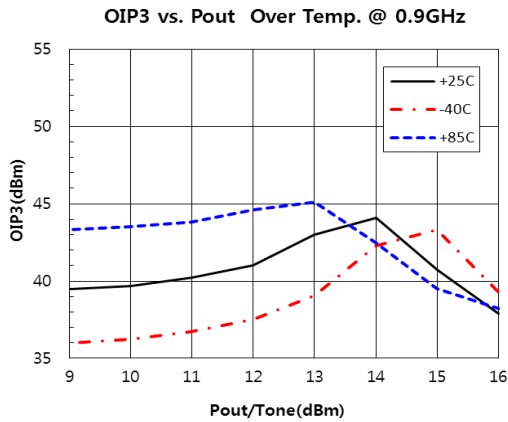
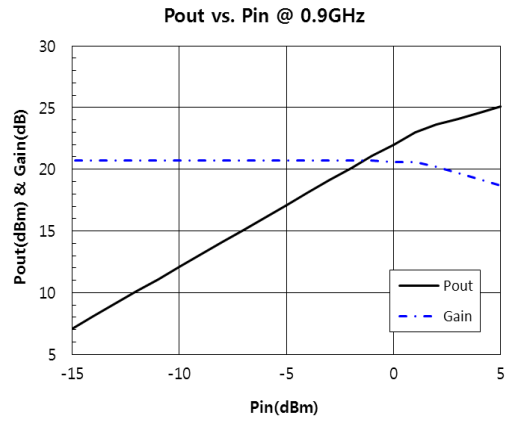
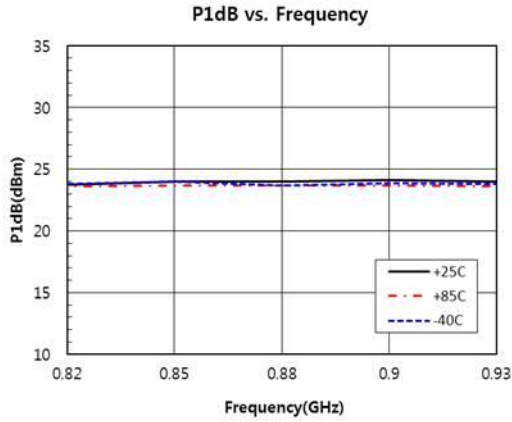
Parameter/Freq.(MHz)	820	850	900	Unit
Small Signal Gain	21.3	20.8	20.7	dB
S11	-8.2	-9.1	-11.0	dB
S22	-17.4	-16.8	-15.2	dB
ACLR@Pout=14dBm*	-46.5	-47.5	-48.0	dBc
Output P1dB	23.7	24.0	24.1	dBm
Output OIP3**	39.6	39.1	44.1	dBm
Noise Figure	4.3	4.4	4.4	dB
Icq	82			mA
Vcc	5			V

* 3GPP Test model 1+64 DPCH, PAR=10.3@0.01% Probability, 15.36MHz BW, 4FA / ** Pout=14dBm/tone

S-Parameter Over Temperature vs. Freq. at 800~900MHz



P1dB, OIP3, ACLR Performance at 800~900MHz



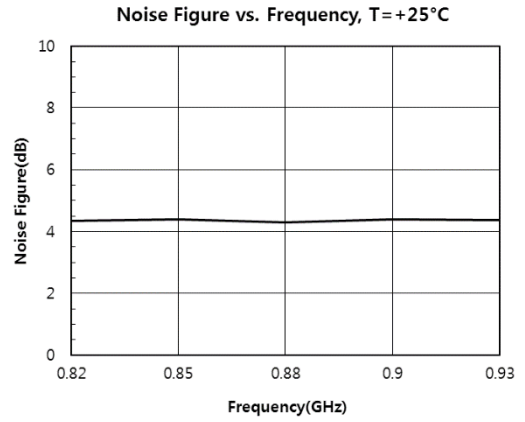
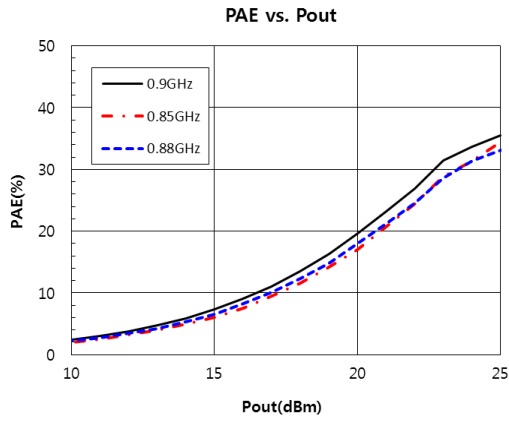
Test condition: 3GPP Test model 1+64 DPCH,
 PAR=10.3@0.01% Probability, 15.36MHz BW, 4FA

Test condition: 3GPP Test model 1+64 DPCH,
 PAR=10.3@0.01% Probability, 15.36MHz BW, 4FA

RA031
50-3600MHz
0.25W High Linearity Amplifier



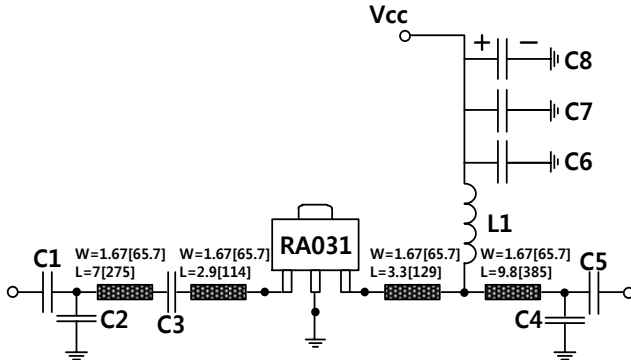
PAE, Noise Figure Performance at 800~900MHz



RA031

50-3600MHz
0.25W High Linearity Amplifier

1800~1900MHz Reference Application Circuit



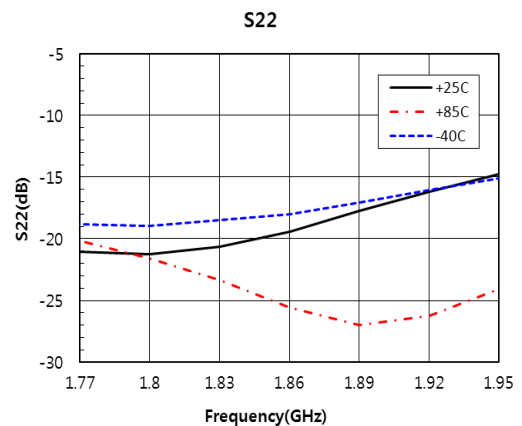
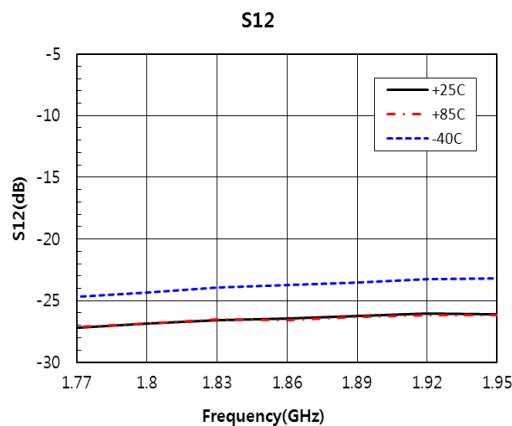
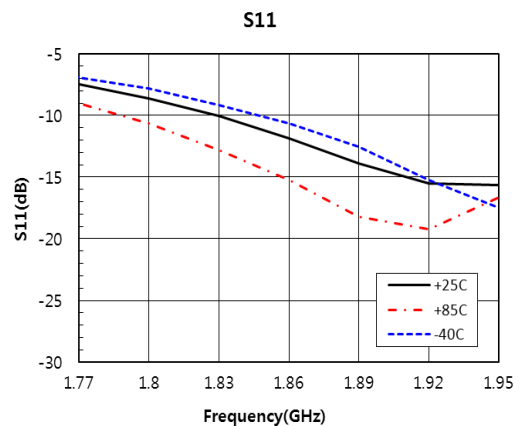
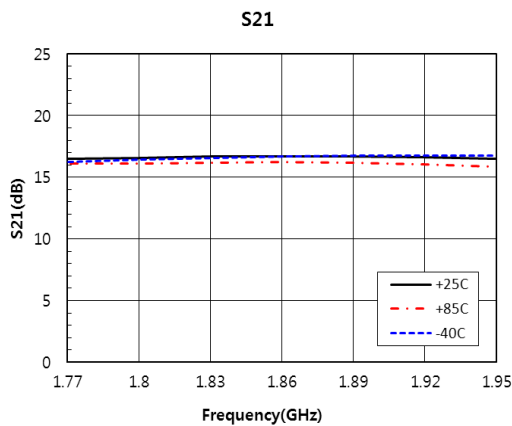
BOM	Value	BOM	Value	BOM	Value
C1	100pF	C4	NA	C7	1000pF
C2	2pF	C5	100pF	C8	10uF
C3	2.7pF	C6	100pF	L1	39nH

*Width and Length of Micro-strip line dimension in mm[mil]

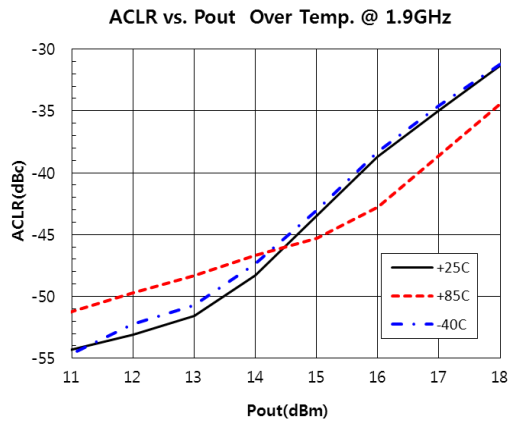
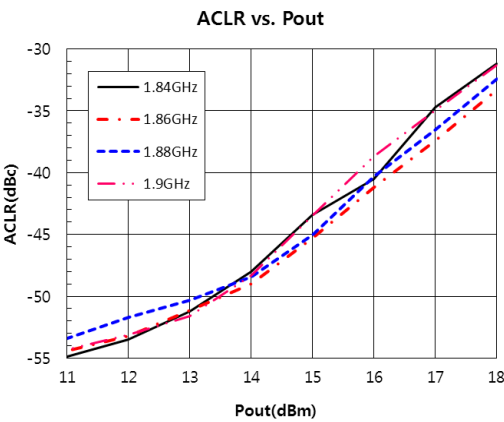
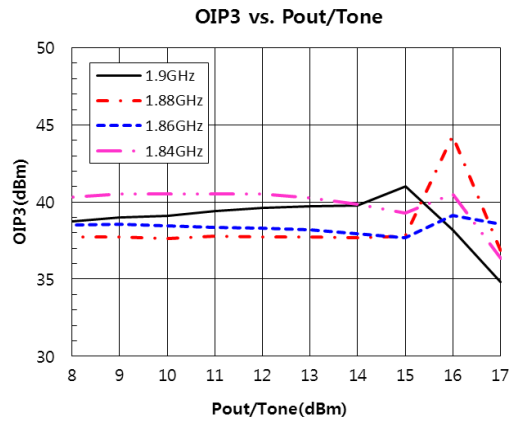
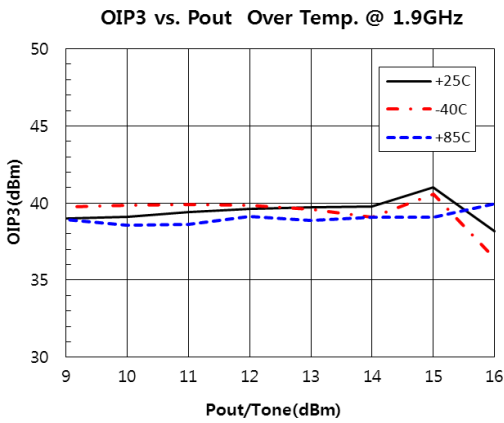
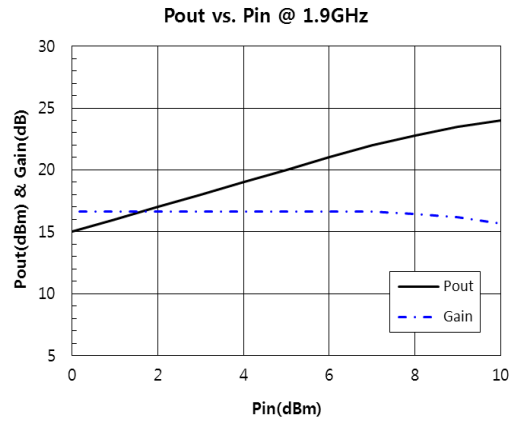
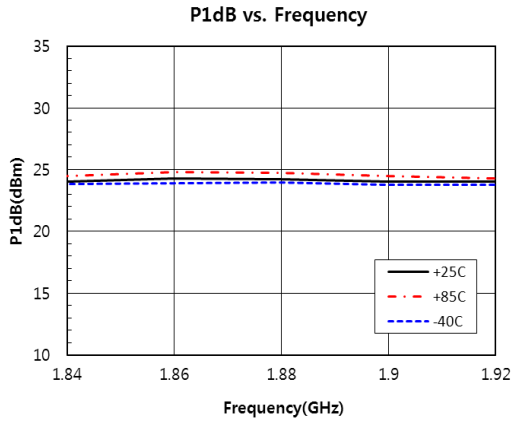
Parameter/Freq.(MHz)	1860	1880	1900	Unit
Small Signal Gain	16.7	16.7	16.6	dB
S11	-11.8	-13.9	-15.0	dB
S22	-19.4	-17.9	-16.8	dB
ACLR@Pout=14dBm*	-49.0	-48.4	-48.3	dBc
Output P1dB	24.3	24.2	24.0	dBm
Output OIP3**	38.0	37.9	40.0	dBm
Noise Figure	4.5	4.3	4.4	dB
Icq	82			mA
Vcc	5			V

* 3GPP Test model 1+64 DPCH, PAR=10.3@0.01% Probability, 15.36MHz BW, 4FA / ** Pout=14dBm/tone

S-Parameter Over Temperature vs. Freq. at 1800~1900MHz



P1dB, OIP3, ACLR Performance at 1800~1900MHz



Test condition: 3GPP Test model 1+64 DPCH, PAR=10.3@0.01% Probability, 15.36MHz BW, 4FA

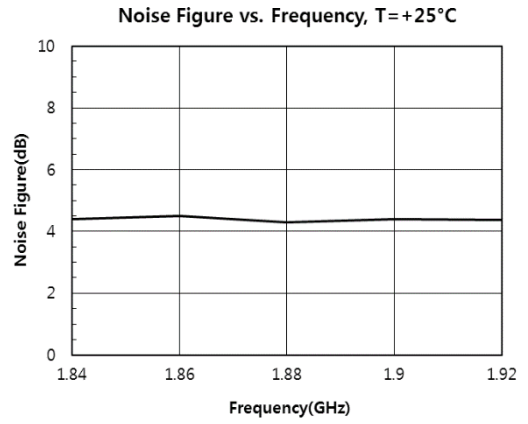
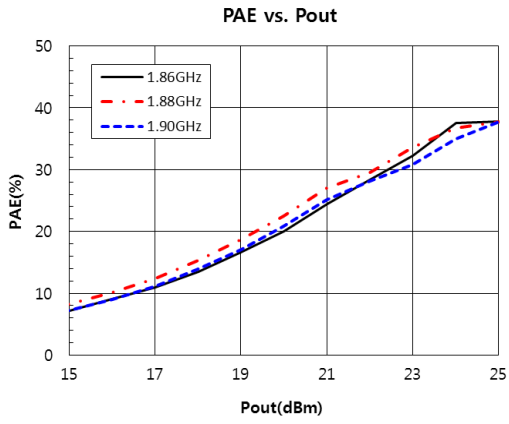
Test condition: 3GPP Test model 1+64 DPCH, PAR=10.3@0.01% Probability, 15.36MHz BW, 4FA

RA031

50-3600MHz
0.25W High Linearity Amplifier

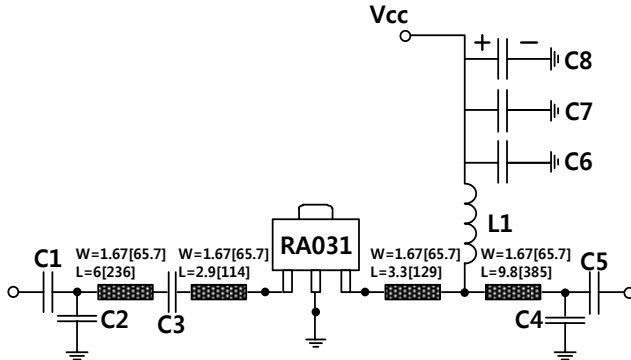


PAE, Noise Figure Performance at 1800~1900MHz



RA031
50-3600MHz
0.25W High Linearity Amplifier

2110~2170MHz Reference Application Circuit



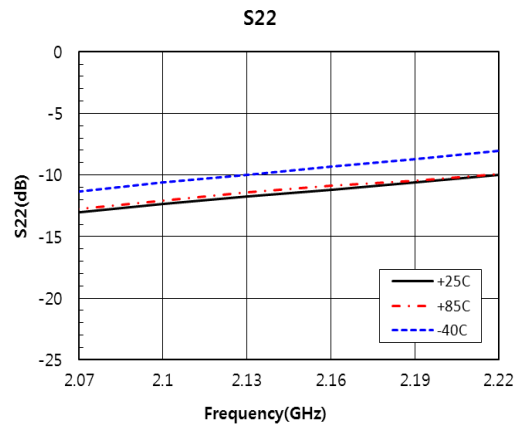
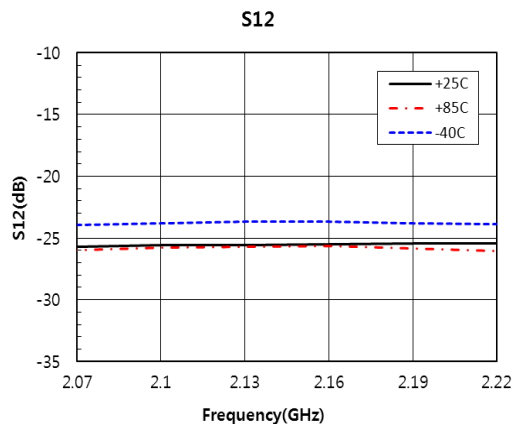
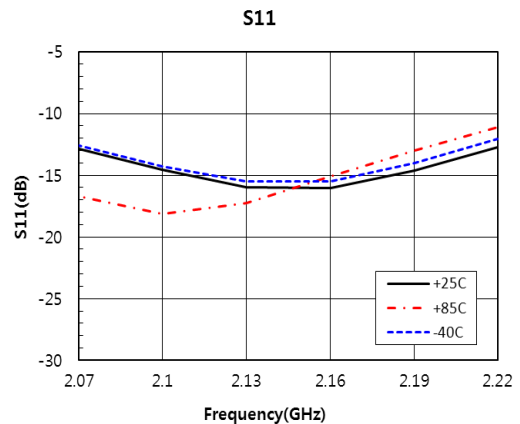
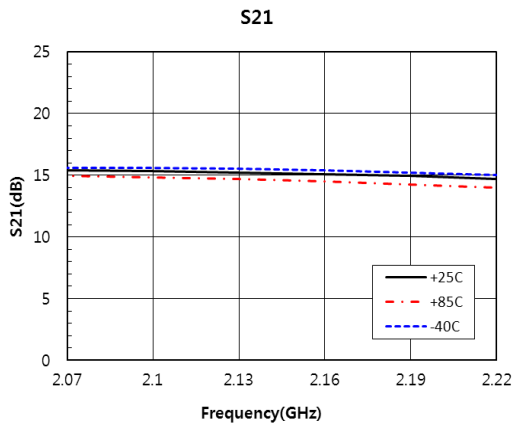
BOM	Value	BOM	Value	BOM	Value
C1	100pF	C4	NA	C7	1000pF
C2	1.5pF	C5	100pF	C8	10uF
C3	2pF	C6	100pF	L1	18nH

*Width and Length of Micro-strip line dimension in mm[mil]

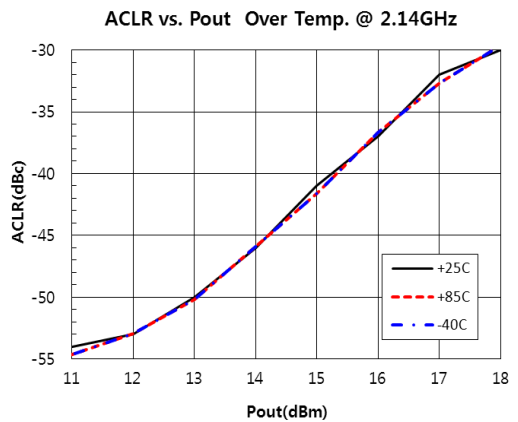
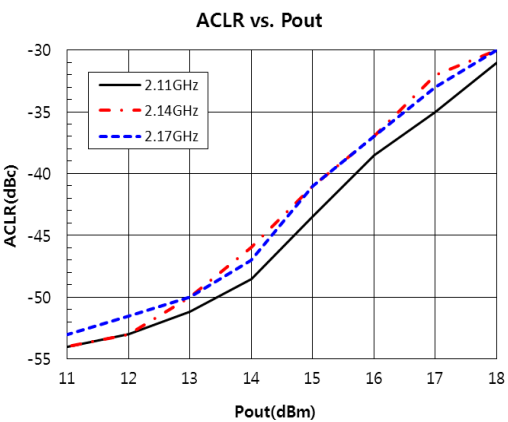
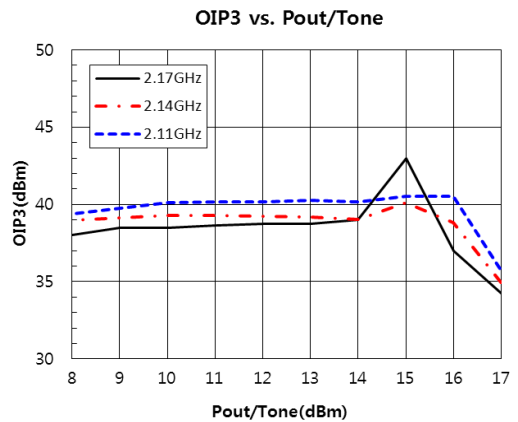
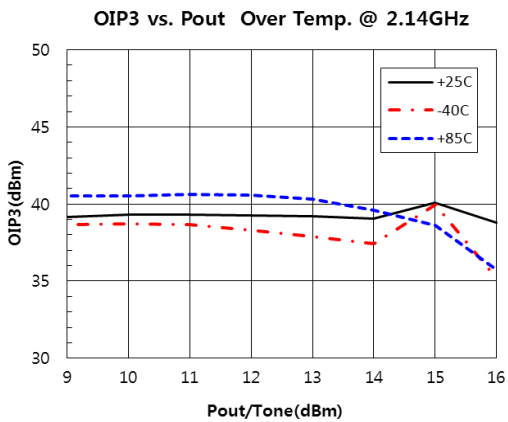
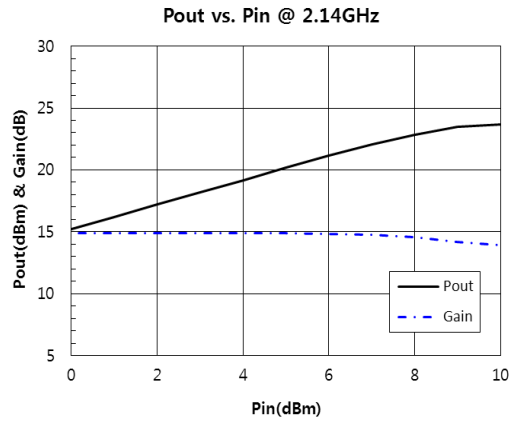
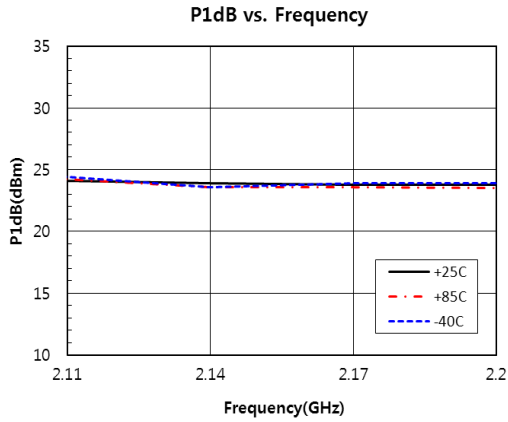
Parameter/Freq.(MHz)	2110	2140	2170	Unit
Small Signal Gain	15.3	15.2	15.1	dB
S11	-15.4	-15.9	-16.0	dB
S22	-12.3	-11.9	-11.2	dB
ACLR@Pout=14dBm*	-48.5	-46.0	-47.0	dBc
Output P1dB	24.3	23.9	23.6	dBm
Output OIP3**	40.1	39.0	39.0	dBm
Noise Figure	4.4	4.5	4.5	dB
Icq	84			mA
Vcc	5			V

* 3GPP Test model 1+64 DPCH, PAR=10.3@0.01% Probability, 15.36MHz BW, 4FA / ** Pout=14dBm/tone

S-Parameter Over Temperature vs. Freq. at 2110~2170MHz



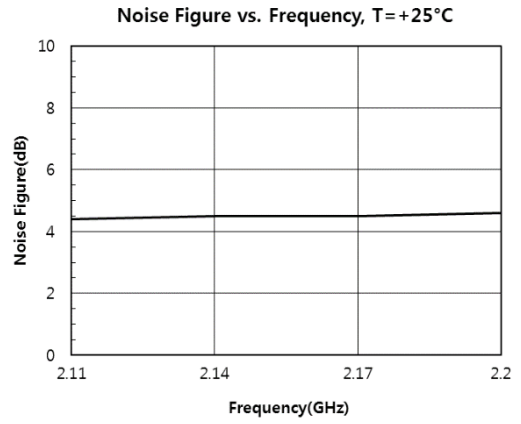
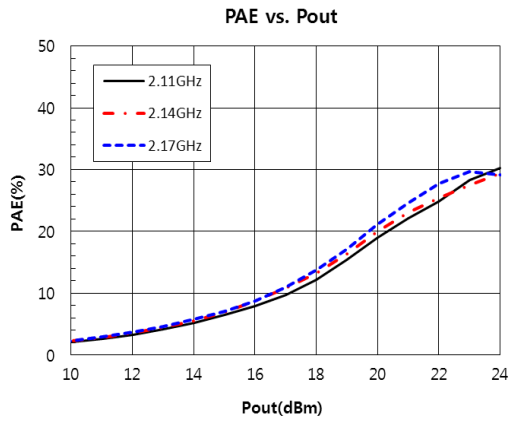
P1dB, OIP3, ACLR Performance at 2110~2170MHz



Test condition: 3GPP Test model 1+64 DPCH, PAR=10.3@0.01% Probability, 15.36MHz BW, 4FA

Test condition: 3GPP Test model 1+64 DPCH, PAR=10.3@0.01% Probability, 15.36MHz BW, 4FA

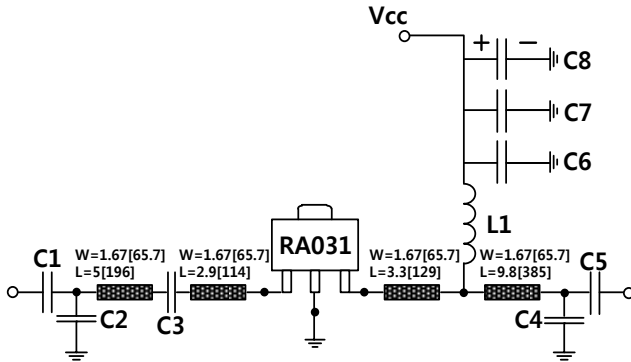
PAE, Noise Figure Performance at 2110~2170MHz



RA031

50-3600MHz
0.25W High Linearity Amplifier

2300~2400MHz Reference Application Circuit



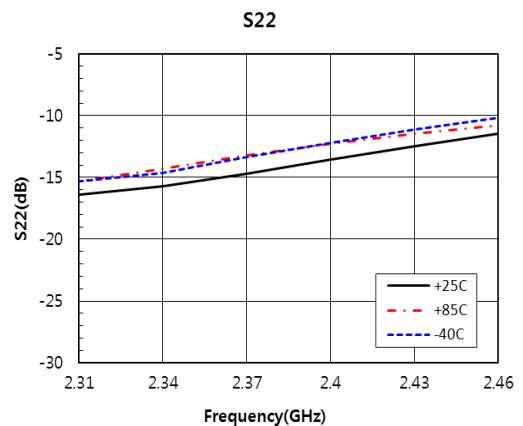
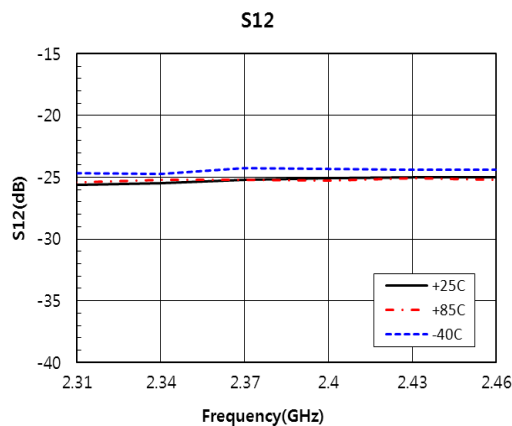
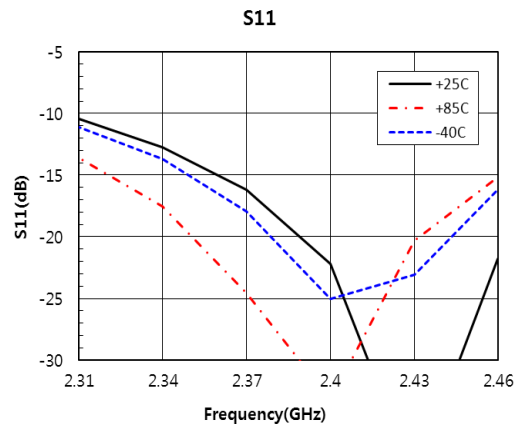
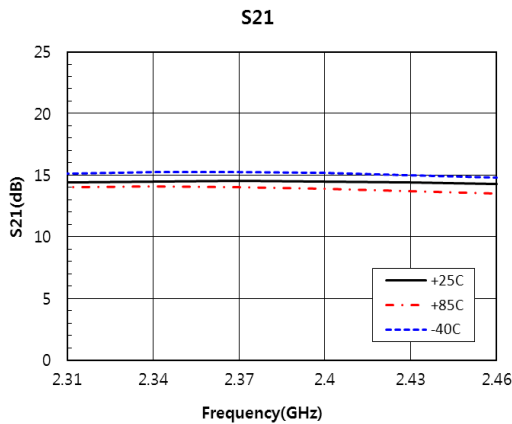
BOM	Value	BOM	Value	BOM	Value
C1	100pF	C4	NA	C7	1000pF
C2	1.5pF	C5	10pF	C8	10uF
C3	1.5pF	C6	100pF	L1	12nH

*Width and Length of Micro-strip line dimension in mm[mil]

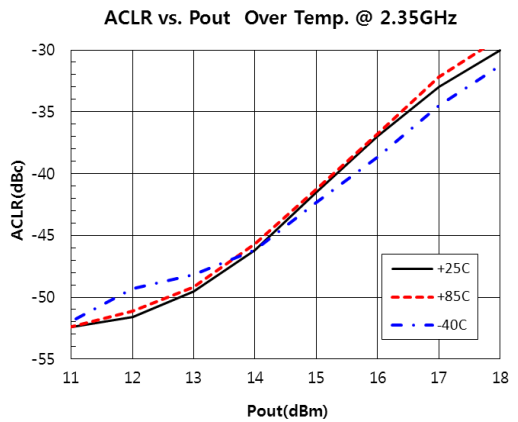
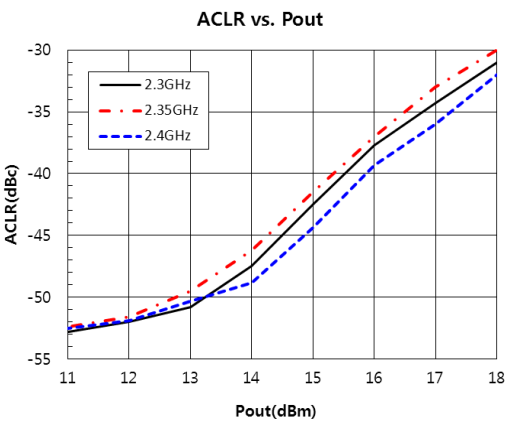
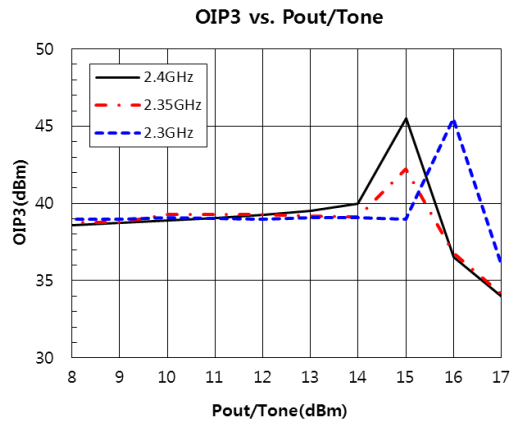
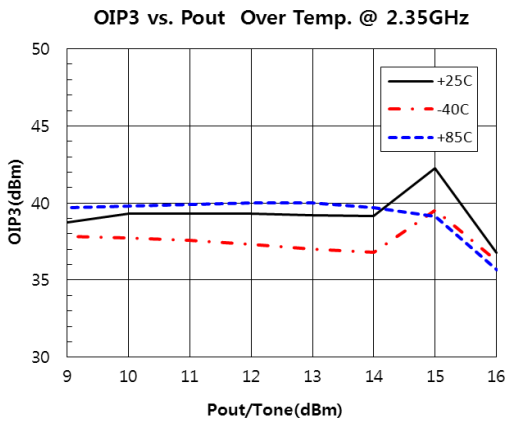
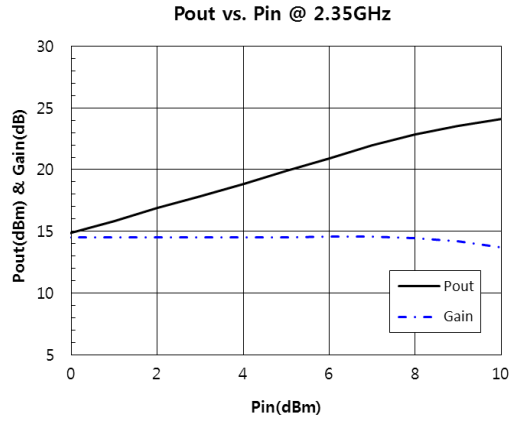
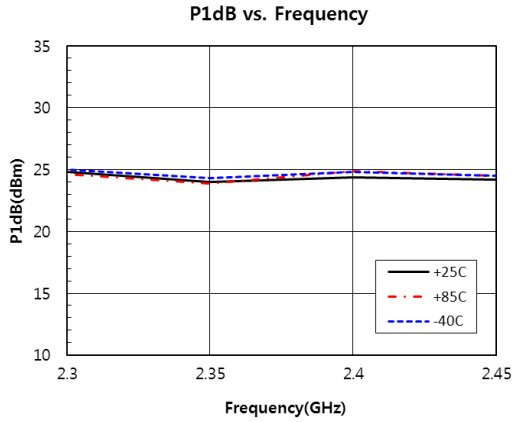
Parameter/Freq.(MHz)	2300	2350	2400	Unit
Small Signal Gain	14.5	14.4	14.4	dB
S11	-10.4	-15.1	-22.1	dB
S22	-16.5	-15.2	-13.5	dB
ACLR@Pout=14dBm*	-47.5	-46.2	-48.8	dBc
Output P1dB	25.0	24.3	24.4	dBm
Output OIP3**	39.1	39.1	40	dBm
Noise Figure	4.4	4.4	4.5	dB
Icq	81			mA
Vcc	5			V

* 3GPP Test model 1+64 DPCH, PAR=10.3@0.01% Probability, 15.36MHz BW, 4FA / ** Pout=14dBm/tone

S-Parameter Over Temperature vs. Freq. at 2300~2400MHz



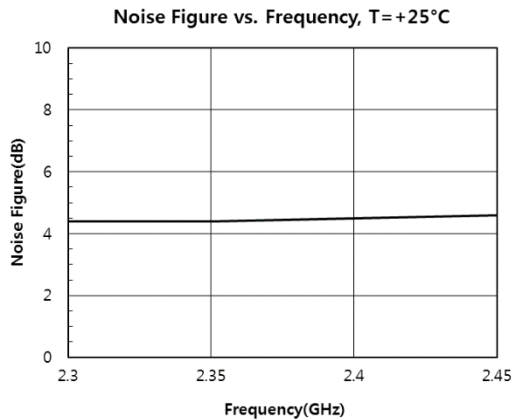
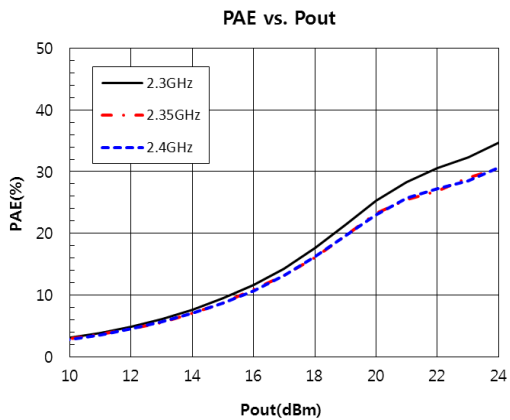
P1dB, OIP3, ACLR Performance at 2300~2400MHz



Test condition: 3GPP Test model 1+64 DPCH, PAR=10.3@0.01% Probability, 15.36MHz BW, 4FA

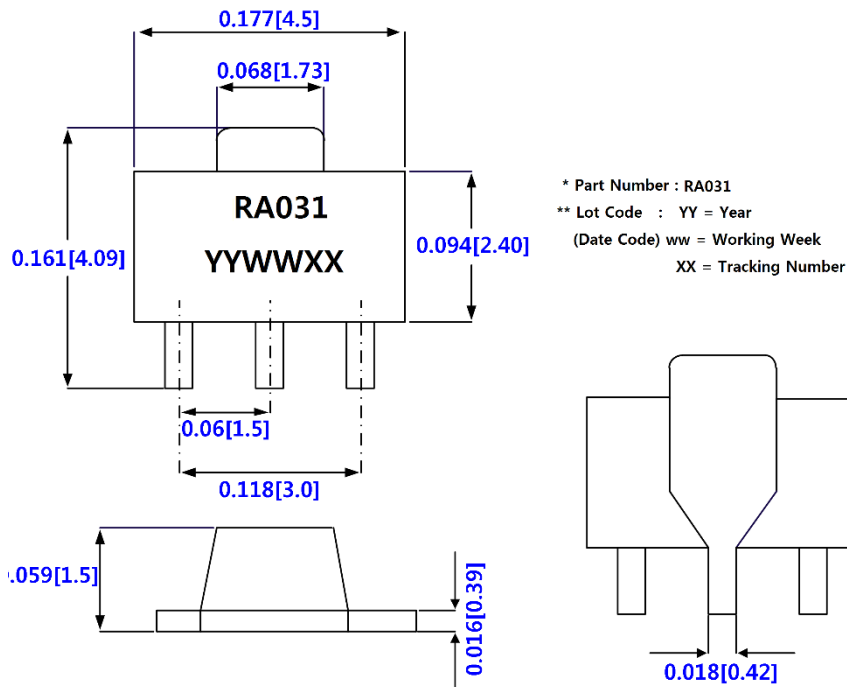
Test condition: 3GPP Test model 1+64 DPCH, PAR=10.3@0.01% Probability, 15.36MHz BW, 4FA

PAE, Noise Figure Performance at 2300~2400MHz



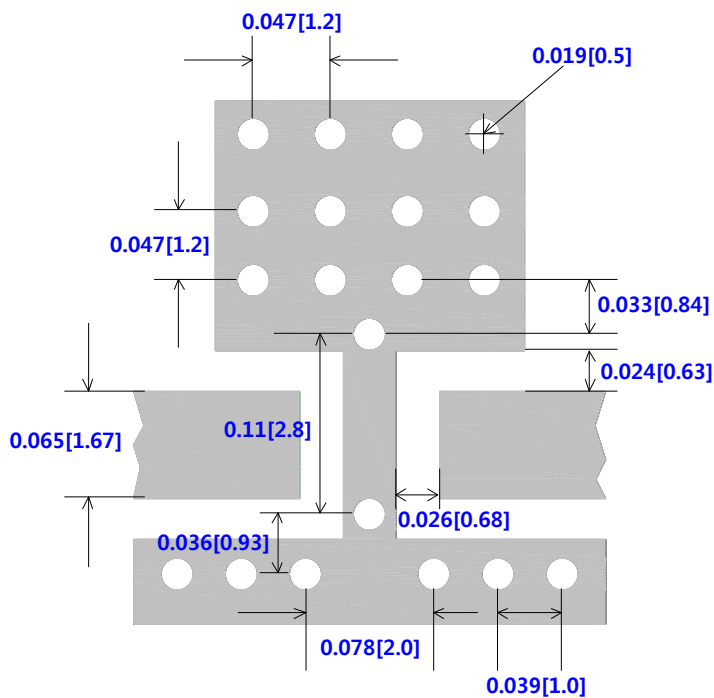
Package Mark and Dimensions

Dimension in inches[Millimeters]

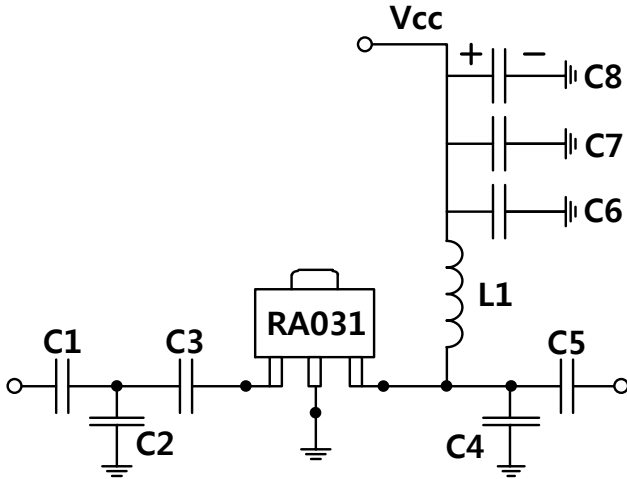


Recommended PCB Pad Pattern

Dimension in inches[Millimeters]

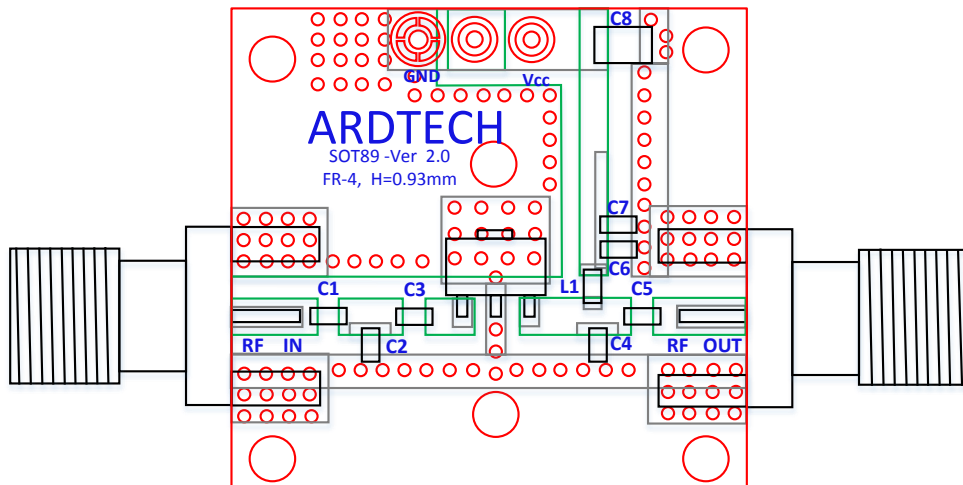


Application Schematic & BOM



Reference BOM Size	
C1	Chip Capacitor, 0603 type
C2	Chip Capacitor, 0603 type
C3	Chip Capacitor, 0603 type
C4	Chip Capacitor, 0603 type
C5	Chip Capacitor, 0603 type
C6	Chip Capacitor, 0603 type
C7	Chip Capacitor, 0603 type
C8	Tantalum Capacitor, 1206 type
L1	Wire-wound coil inductor, 0805 type

Evaluation PCB Layout



PCB Substrate Information[mm]	
Dielectric Constant	FR-4/4.6
Dielectric Height	0.036[0.93]
Copper Thickness	1 oz.

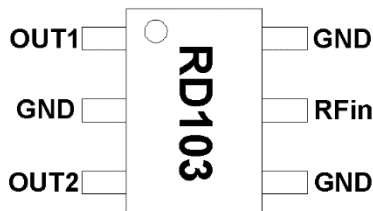
Product Description

RD103 is a monolithic two-way in-phase Wilkinson power splitter designed for applications require low loss, high isolation, good in/out matching and exceptional phase/amplitude balance. This product is built with Lead-Free and RoHS Compliant.

Features

- Isolation 23dB at 900MHz
- Insertion loss 3.65dB at 900MHz
- 50 Ω Characteristic Impedance
- Lead-free, RoHS compliant, Green

Component Diagram



Applications

- Base station Infrastructure
- Wireless Infrastructure



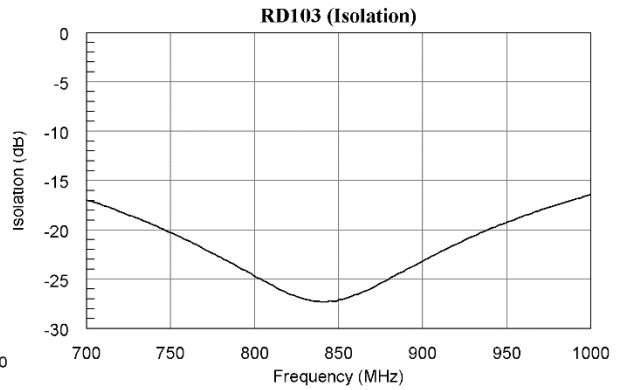
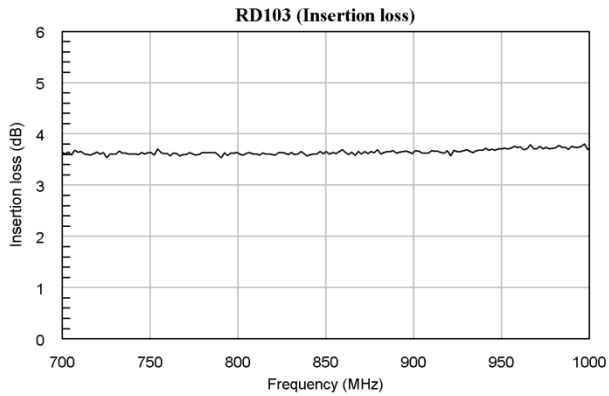
Parameter	Specification			Condition	Units
	Min.	Typ.	Max.		
Insertion Loss / Isolation		3.64 / -17.0		700MHz	dB
		3.62 / -24.6		800MHz	dB
		3.65 / -23.2		900MHz	dB
		3.72 / -16.5		1000MHz	dB
IRL / ORL		-22.3/ -21.9		700MHz	dB
		-38.7 / -23.3		800MHz	dB
		-22.2 / -24.5		900MHz	dB
		-15.8 / -25.8		1000MHz	dB
Amplitude Balance / Phase Balance		0.031 / 0.24		700MHz	dB / deg
		0.021 / 0.20		800MHz	dB / deg
		0.035 / 0.20		900MHz	dB / deg
		0.037 / 0.10		1000MHz	dB / deg

Absolute Maximum Ratings

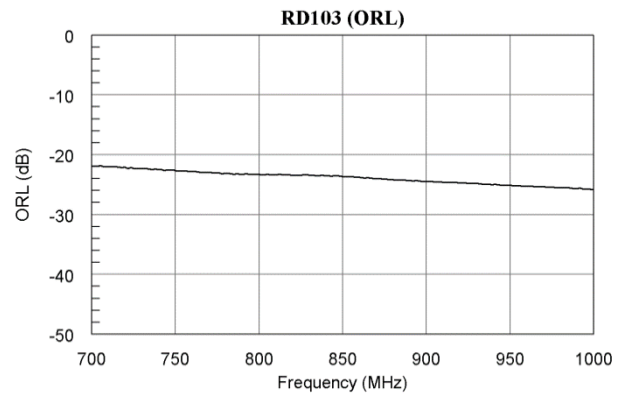
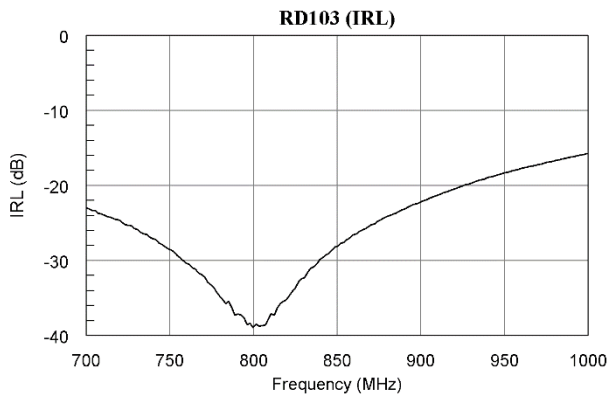
Parameter	Rating	Unit
Input power	30 (CW)	dBm
Operating Temperature(T _J)	-40 to +85	°C
Storage Temperature	-65 to +150	°C



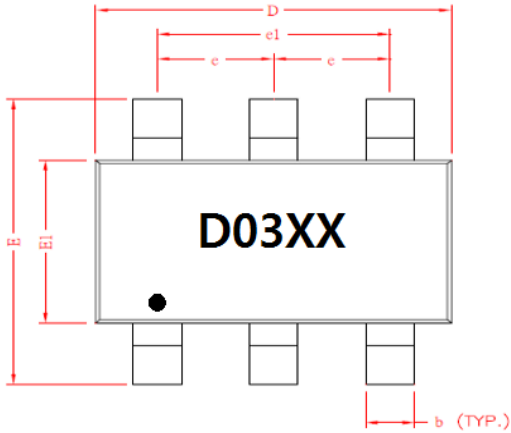
Insertion Loss, Isolation vs. Frequency



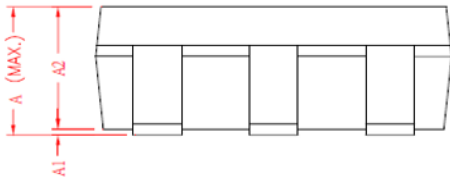
In/Out Return Loss vs. Frequency



Package Mark and Dimensions



* Part Number D03 = RD103 ** Tracking Number =XX

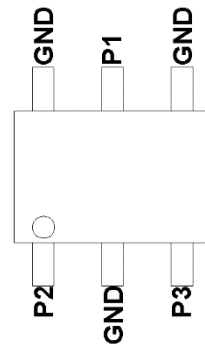
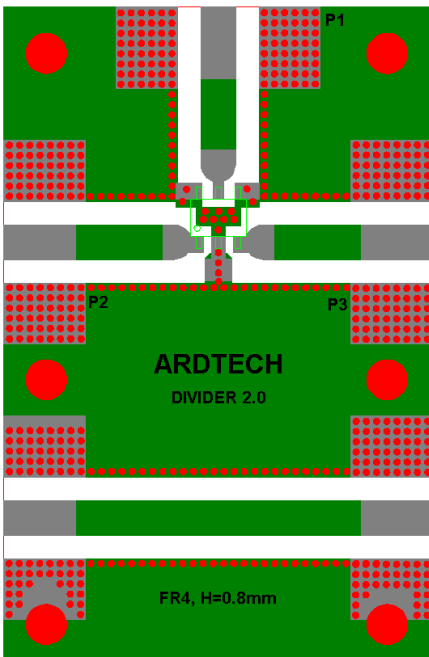


Package Dimension

REF	Millimeter	
	Min.	Max.
A		1.45
A1	0	0.1
A2	1.1	1.3
b	0.3	0.5
c	0.12 REF.	
D	2.7	3.1
E	2.6	3
E1	1.4	1.8
e	0.95 REF.	
e1	1.9 REF.	

Evaluation PCB Information

Evaluation PCB Layout



PCB Substrate Information[mm]

Dielectric Constant	FR-4/4.6
Dielectric Height	0.037[0.93]
Copper Thickness	1 oz.

NOTE

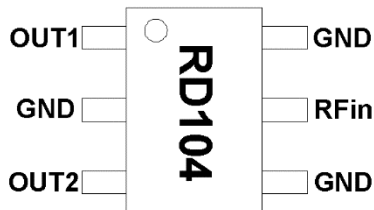
Product Description

RD104 is a monolithic two-way in-phase Wilkinson power splitter designed for applications require low loss, high isolation, good in/out matching and exceptional phase/amplitude balance. This product is built with Lead-Free and RoHS Compliant.

Features

- Isolation 28dB at 2100MHz
- Insertion loss 3.64dB at 2100MHz
- 50 Ω Characteristic Impedance
- Lead-free, RoHS compliant, Green

Component Diagram



Applications

- Base station Infrastructure
- Wireless Infrastructure



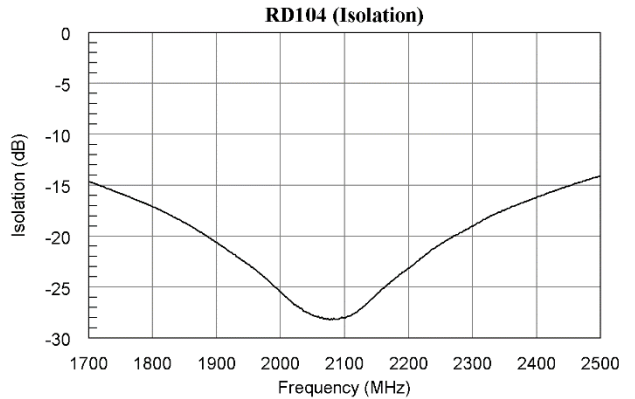
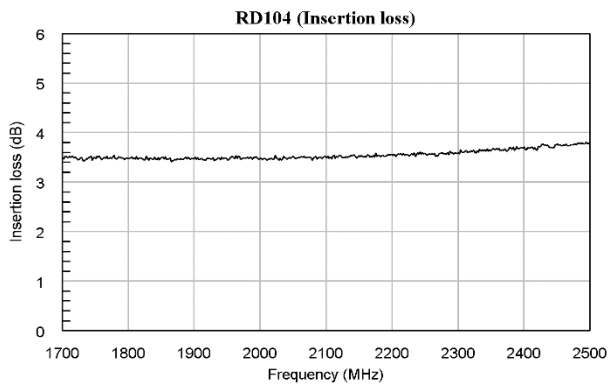
Parameter	Specification			Condition	Units
	Min.	Typ.	Max.		
Insertion Loss / Isolation		3.59 / -15.0		1700MHz	dB
		3.59 / -20.6		1900MHz	dB
		3.64 / -28.0		2100MHz	dB
		3.86 / -16.2		2400MHz	dB
IRL / ORL		-17.7 / -22.1		1700MHz	dB
		-17.1 / -29.7		1900MHz	dB
		-14.8 / -34.9		2100MHz	dB
		-10.9 / -20.4		2400MHz	dB
Amplitude Balance / Phase Balance		0.035 / 0.20		1700MHz	dB / deg
		0.028 / 0.10		1900MHz	dB / deg
		0.014 / 0.10		2100MHz	dB / deg
		0.065 / 0.12		2400MHz	dB / deg

Absolute Maximum Ratings

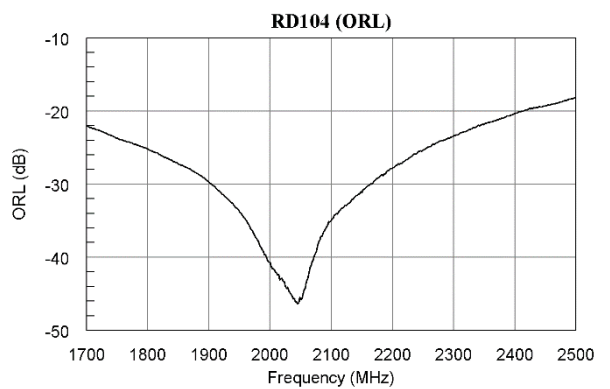
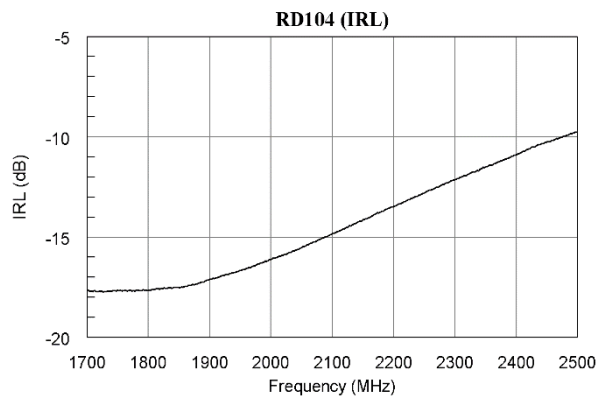
Parameter	Rating	Unit
Input power	30 (CW)	dBm
Operating Temperature(T _J)	-40 to +85	°C
Storage Temperature	-65 to +150	°C



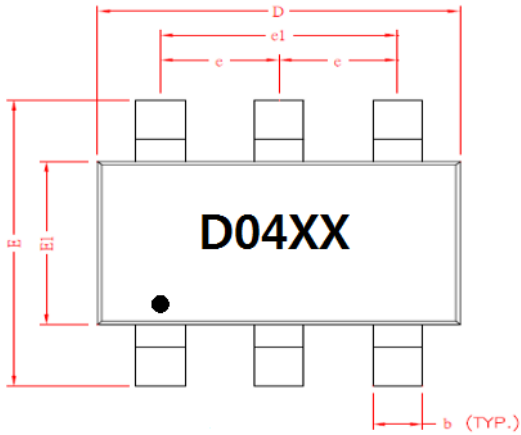
Insertion Loss, Isolation vs. Frequency



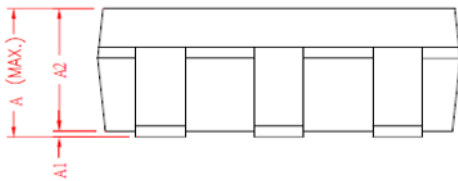
In/Out Return Loss vs. Frequency



Package Mark and Dimensions



* Part Number D04 =RD104 ** Tracking Number =XX

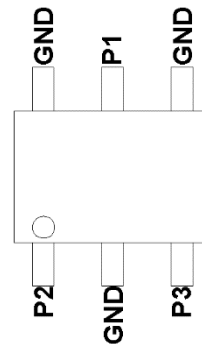
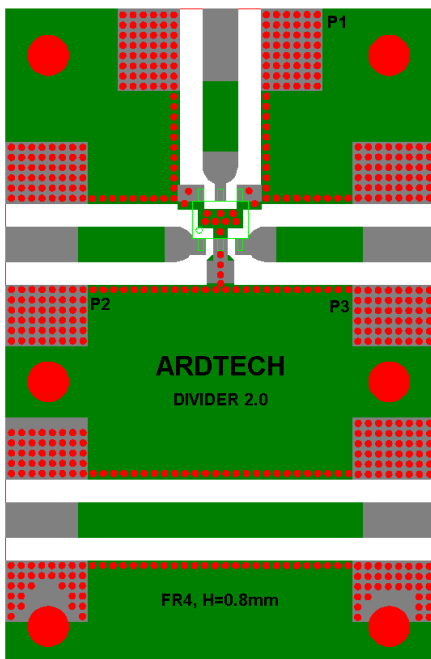


Package Dimension

REF	Millimeter	
	Min.	Max.
A		1.45
A1	0	0.1
A2	1.1	1.3
b	0.3	0.5
c	0.12 REF.	
D	2.7	3.1
E	2.6	3
E1	1.4	1.8
e	0.95 REF.	
e1	1.9 REF.	

Evaluation PCB Information

Evaluation PCB Layout



PCB Substrate Information[mm]

Dielectric Constant	FR-4/4.6
Dielectric Height	0.037[0.93]
Copper Thickness	1 oz.

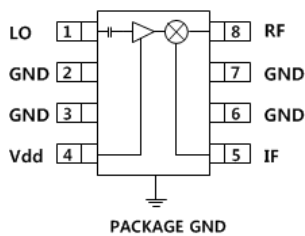
NOTE

HIGH IIP3 GaAs MMIC MIXER With INTEGRATED LO AMPLIFIER, 700 – 1500MHz

Product Description

RM101 can use at 3.3V to 5V. It is a high dynamic range passive MMIC mixer with an integrated LO amplifier in a plastic surface mount 8 lead Mini Small Outline Package (MSOP) covering 700MHz to 1500MHz. It has excellent input IP3 performance of +32.3dBm at 3.3V. RM101 is pin to pin compatible with RM102 which is 1700-2400MHz Mixers with LO amplifiers.

Component Diagram



Features

- + 32.35 dBm input IP3 at 3.3V
- Conversion Loss : 9.1 dB
- Single Positive Supply : 22mA @ 3.3V
- Low LO drive level: -2 to +4dBm
- Available 3.0 to 5 V single voltage
- High ESD level: Class 1B
- Lead-free, RoHS compliant, Green



Applications

- High Dynamic Range Infrastructure system
- GSM GPRS & EDGE
- CDMA & WCDMA
- Cable Modem Termination Systems

Parameter	3.3V		5.0V		Units
Frequency Range. RF	0.8 – 1.1	0.7 – 1.5	0.8 – 1.1	0.7 – 1.5	GHz
Frequency Range. LO	0.8 – 1.1	0.7 – 1.5	0.8 – 1.1	0.7 – 1.5	GHz
Frequency Range. IF	DC-350				MHz
Conversion Loss	TYP 9.2 MAX 10.5				dB
Noise Figure(SSB)	TYP 9.2 MAX 10.5				dB
LO to RF Isolation	-14	-12.8	-14.6	-15.6	dB
LO to IF Isolation	-22	-23	-24	-27.2	dB
RF to IF Isolation	-11.6	-17.5	-13.7	-16	dB
IP3(Input)	32.1	32.35	30	31	dBm
Pin1dB	24	22	24.4	23.6	dBm
LO Input Drive Level (Typical)	0				dBm
Supply Current	22		34		

Test condition: LO = 0dBm, IF = 70MHz, T_L=25°C, Z_s=Z_L=50

RM101

HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 700 – 1500MHz

Absolute Maximum Ratings

Parameter	Rating	Unit
Max RF/IF Input Power	27	dBm
Max LO Drive Input Power	10	dBm
Max Device Voltage(V_D)	6.5	V
Max Operating Dissipated Power	0.5	W
Junction Temperature(T_J)	150	°C
Operating Temperature(T_L)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 1B	
Moisture Sensitivity Level	MSL1	



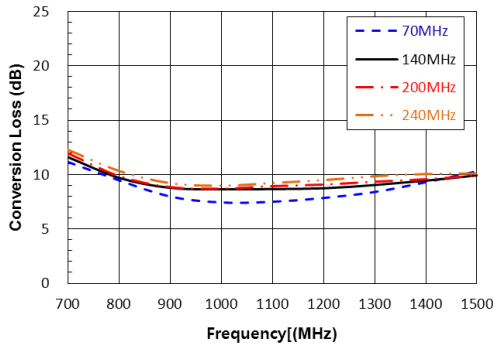
RM101

HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 700 – 1500MHz

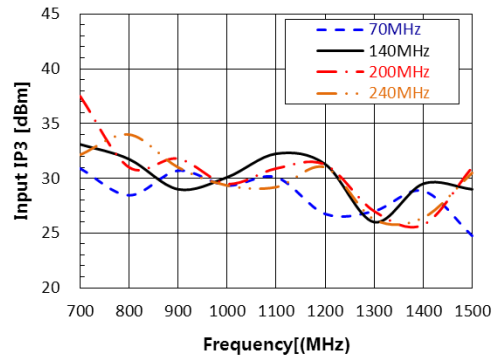


Performances at 3.3V

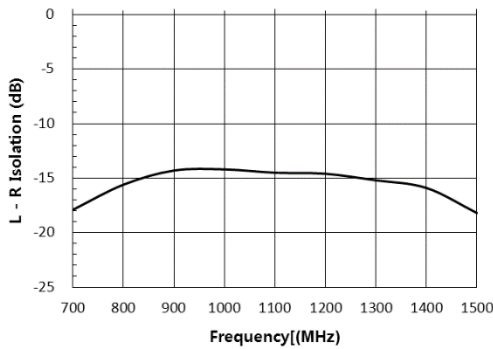
Conversion Loss vs. RF Freq vs. IF Freq
+25°C LO = 0dBm, low-side LO



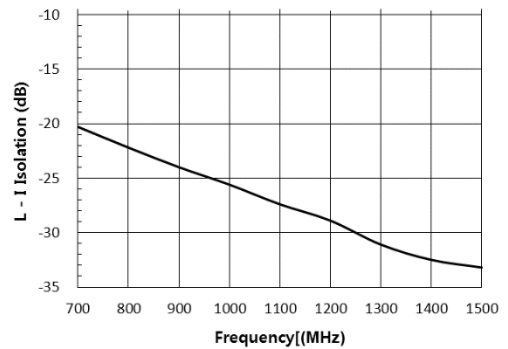
Input IP3 vs. RF Freq vs. IF Freq
+25°C LO = 0dBm, low-side LO



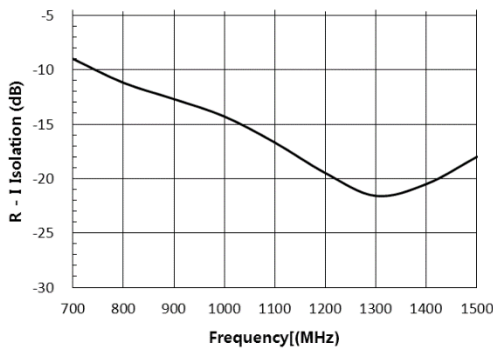
L - R Isolation vs. LO Freq
Referenced with LO = 0dBm



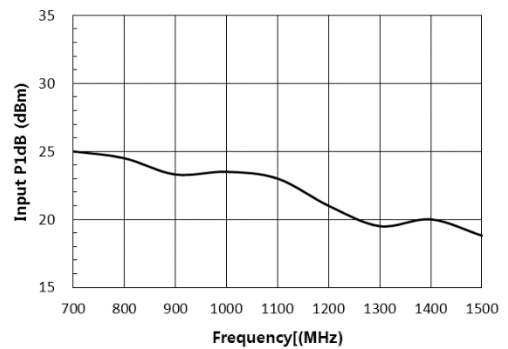
L - I Isolation vs. LO Freq
Referenced with LO = 0dBm



R - I Isolation vs. LO Freq
Referenced with LO = 0dBm



Input P1dB vs. RF Frequency
+25°C LO = 0dBm, IF = 70MHz, low-side LO



RM101

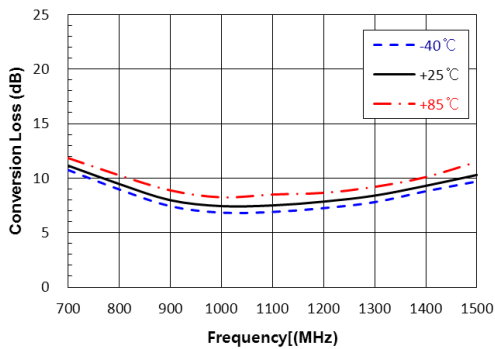
HIGH IIP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 700 – 1500MHz



Performances at 3.3V

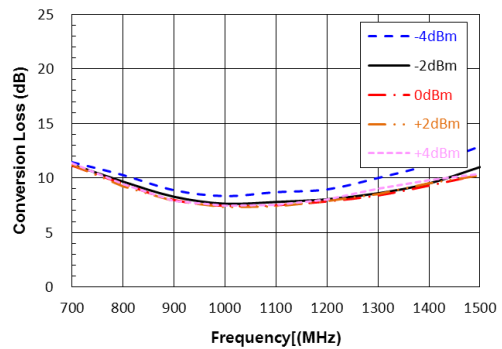
Conversion Loss vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 70MHz, low-side LO



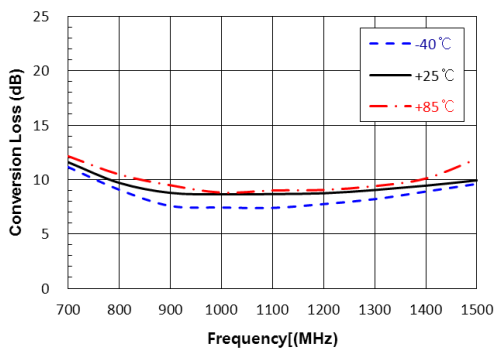
Conversion Loss vs. RF Freq vs. IF Freq

+25°C, IF = 70MHz, low-side LO



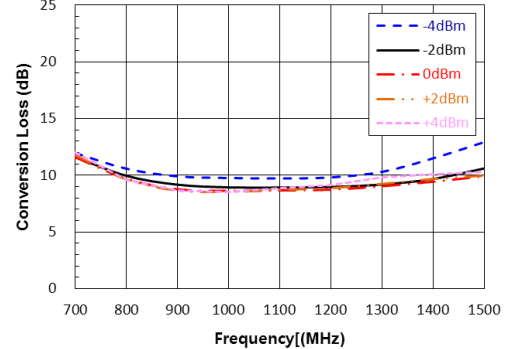
Conversion Loss vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 140MHz, low-side LO



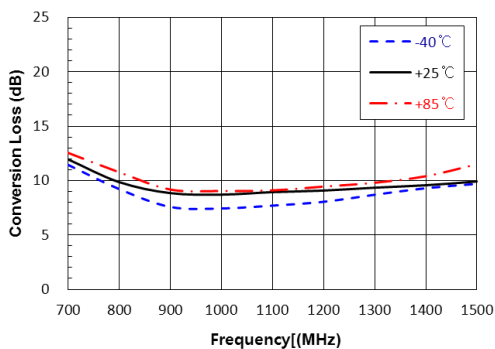
Conversion Loss vs. RF Freq vs. IF Freq

+25°C, IF = 140MHz, low-side LO



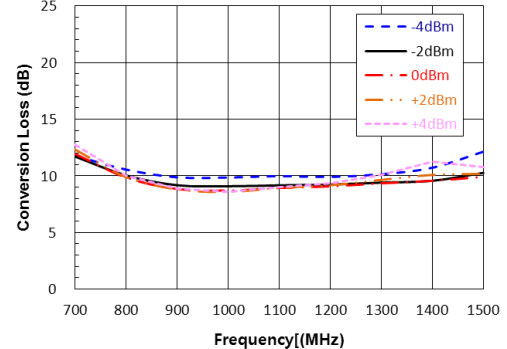
Conversion Loss vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 200MHz, low-side LO



Conversion Loss vs. RF Freq vs. IF Freq

+25°C, IF = 200MHz, low-side LO



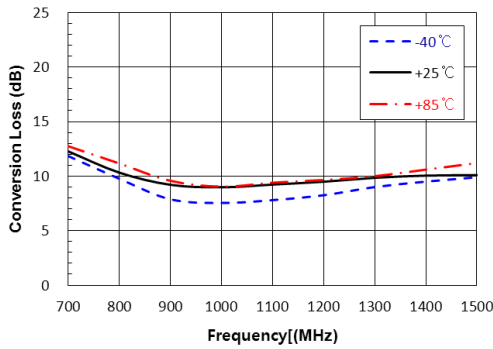
RM101

HIGH IP3 GaAs MMIC MIXER With INTEGRATED LO AMPLIFIER, 700 – 1500MHz

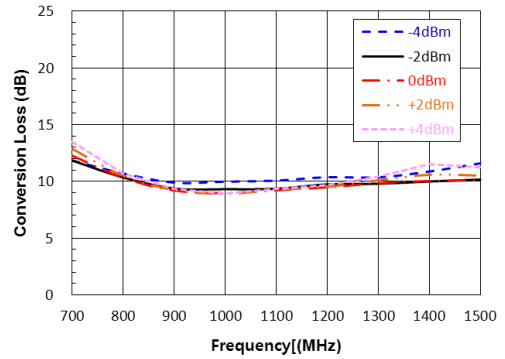


Performances at 3.3V

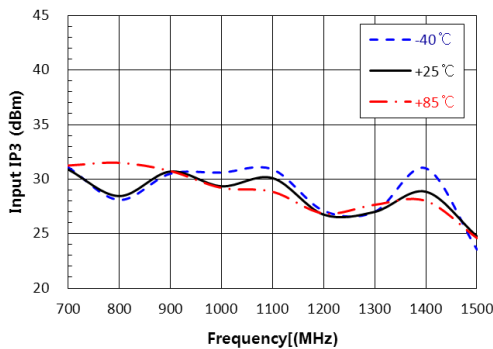
Conversion Loss vs. RF Freq vs. IF Freq
LO = 0dBm, IF = 240MHz, low-side LO



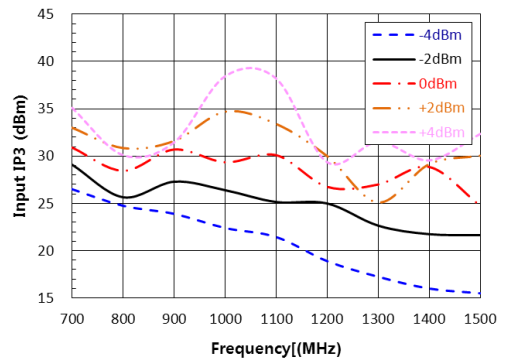
Conversion Loss vs. RF Freq vs. IF Freq
+25°C, IF = 240MHz, low-side LO



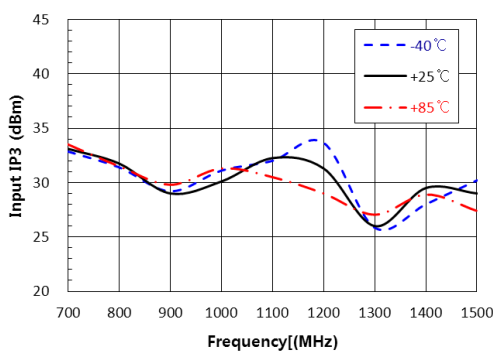
Input IP3 vs. RF Freq vs. IF Freq
LO = 0dBm, IF = 70MHz, low-side LO



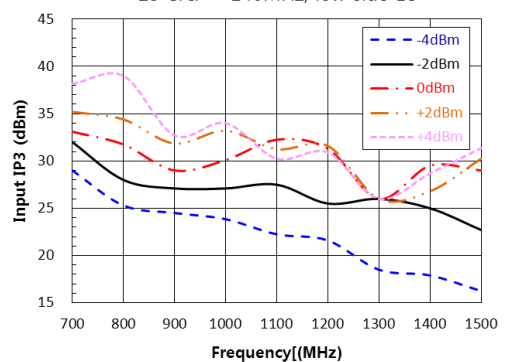
Input IP3 vs. RF Freq vs. LO Power
+25°C, IF = 70MHz, low-side LO



Input IP3 vs. RF Freq vs. IF Freq
LO = 0dBm, IF = 140MHz, low-side LO



Input IP3 vs. RF Freq vs. LO Power
+25°C, IF = 140MHz, low-side LO



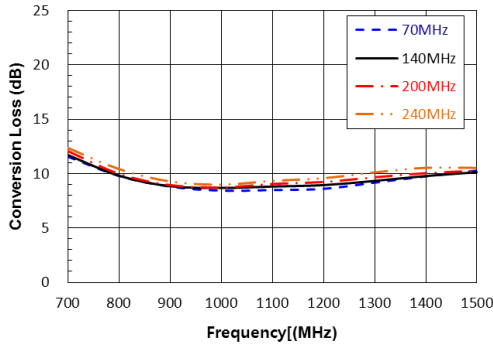
RM101

HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 700 – 1500MHz

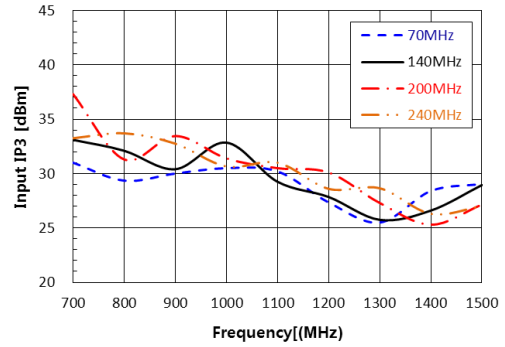


Performances at 5.0V

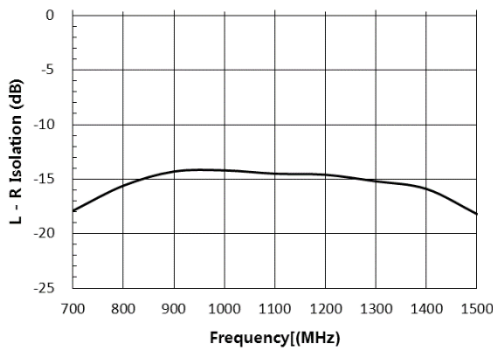
Conversion Loss vs. RF Freq vs. IF Freq
+25°C. LO = 0dBm, low-side LO



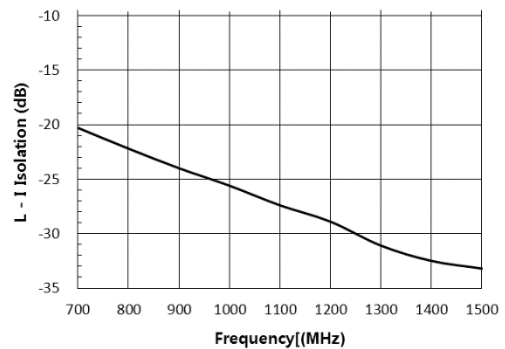
Input IP3 vs. RF Freq vs. IF Freq
+25°C LO = 0dBm, low-side LO



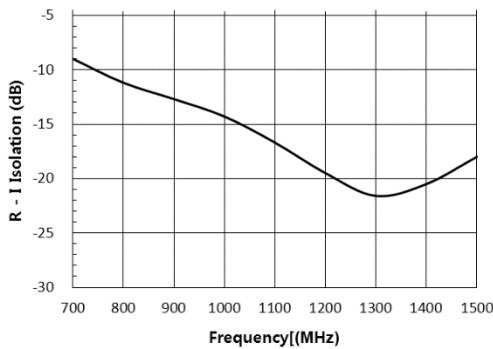
L - R Isolation vs. LO Freq
Referenced with LO = 0dBm



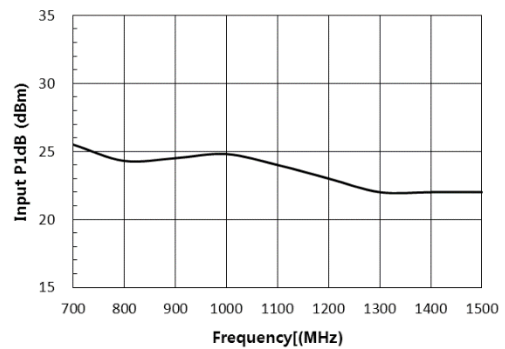
L - I Isolation vs. LO Freq
Referenced with LO = 0dBm



R - I Isolation vs. LO Freq
Referenced with LO = 0dBm



Input P1dB vs. RF Frequency
+25°C LO = 0dBm, IF = 70MHz, low-side LO



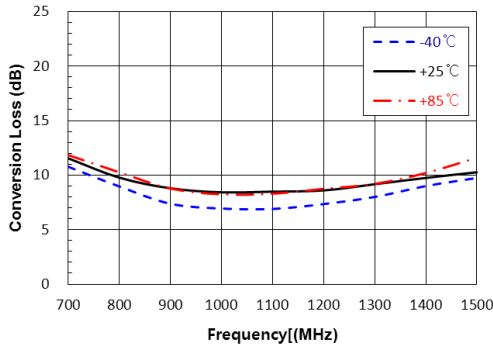
RM101

HIGH IIP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 700 – 1500MHz

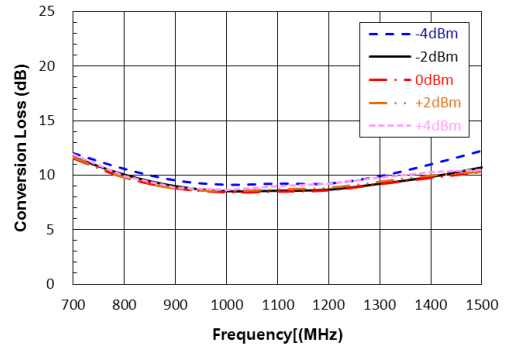


Performances at 5.0V

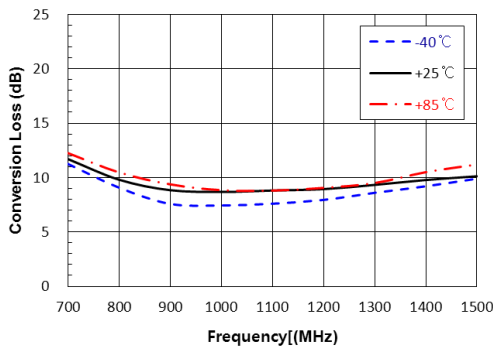
Conversion Loss vs. RF Freq vs. IF Freq
LO = 0dBm, IF = 70MHz, low-side LO



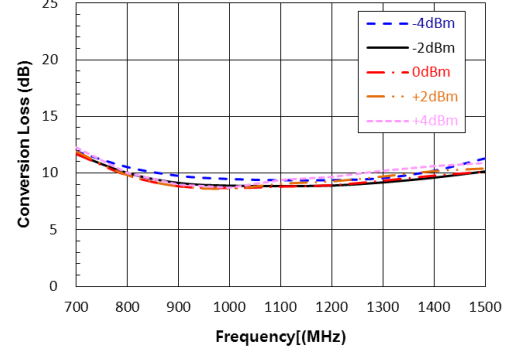
Conversion Loss vs. RF Freq vs. IF Freq
+25°C, IF = 70MHz, low-side LO



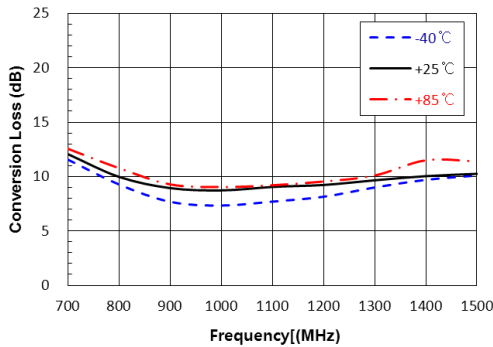
Conversion Loss vs. RF Freq vs. IF Freq
LO = 0dBm, IF = 140MHz, low-side LO



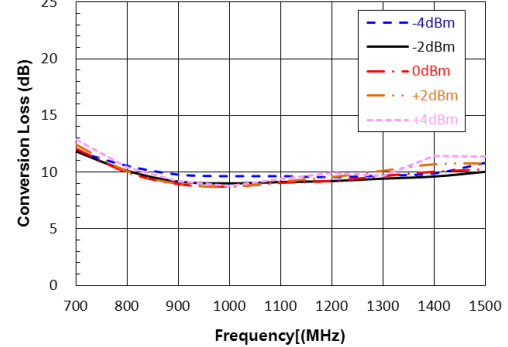
Conversion Loss vs. RF Freq vs. IF Freq
+25°C, IF = 140MHz, low-side LO



Conversion Loss vs. RF Freq vs. IF Freq
LO = 0dBm, IF = 200MHz, low-side LO



Conversion Loss vs. RF Freq vs. IF Freq
+25°C, IF = 200MHz, low-side LO



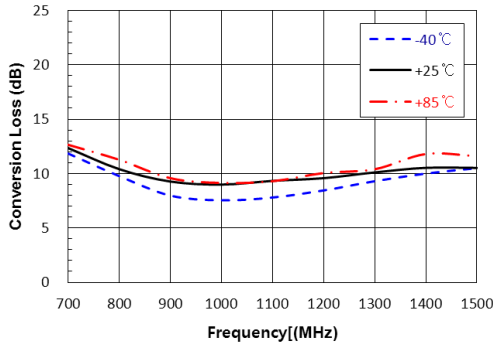
RM101

HIGH IP3 GaAs MMIC MIXER With INTEGRATED LO AMPLIFIER, 700 – 1500MHz

Performances at 5.0V

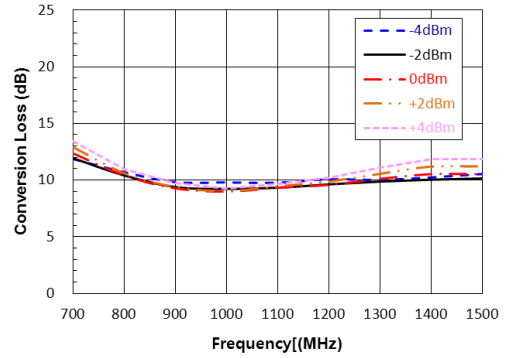
Conversion Loss vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 240MHz, low-side LO



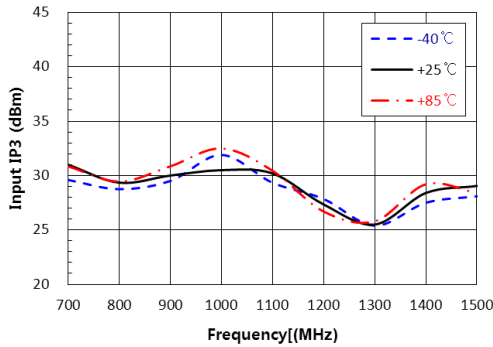
Conversion Loss vs. RF Freq vs. IF Freq

+25°C, IF = 240MHz, low-side LO



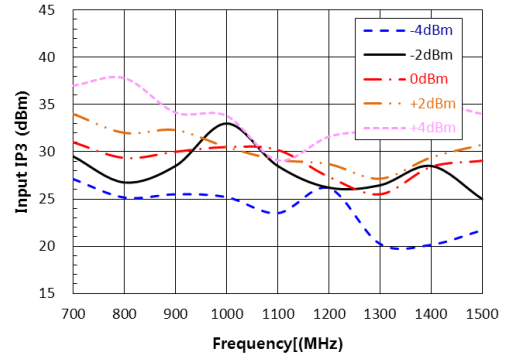
Input IP3 vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 70MHz, low-side LO



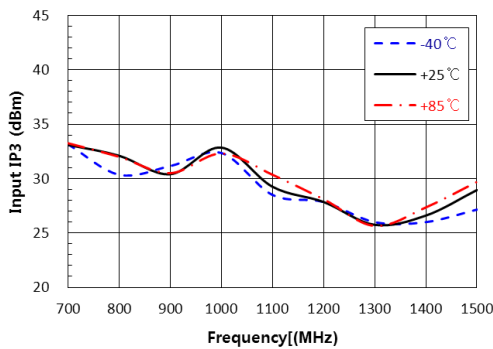
Input IP3 vs. RF Freq vs. LO Power

+25°C, IF = 70MHz, low-side LO



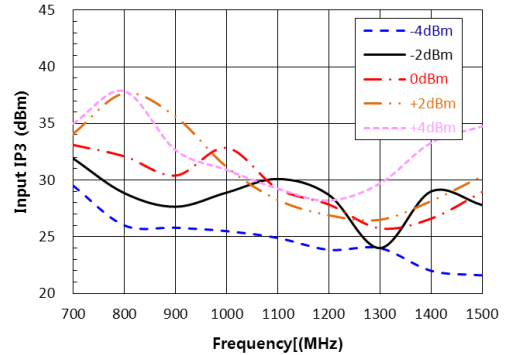
Input IP3 vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 140MHz, low-side LO



Input IP3 vs. RF Freq vs. LO Power

+25°C, IF = 140MHz, low-side LO

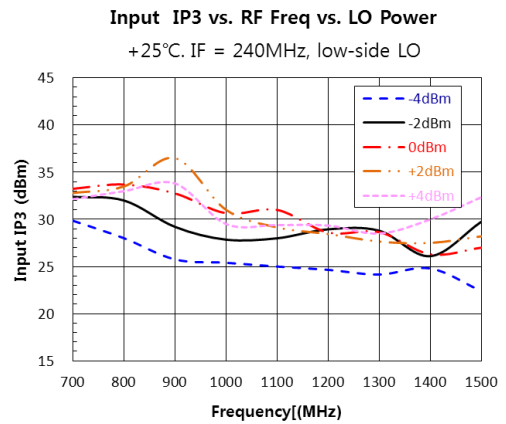
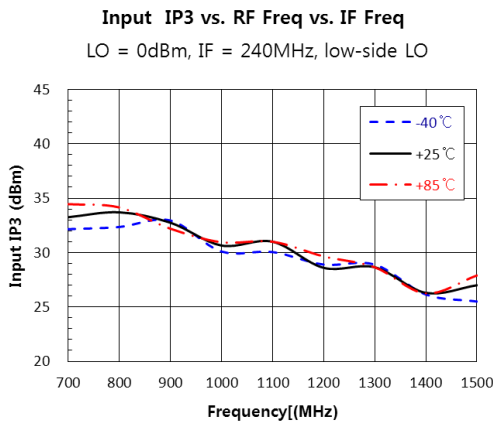
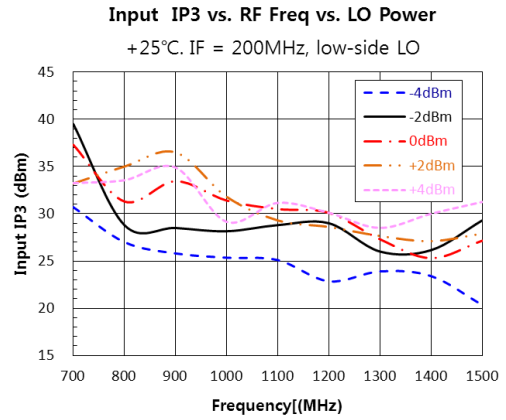
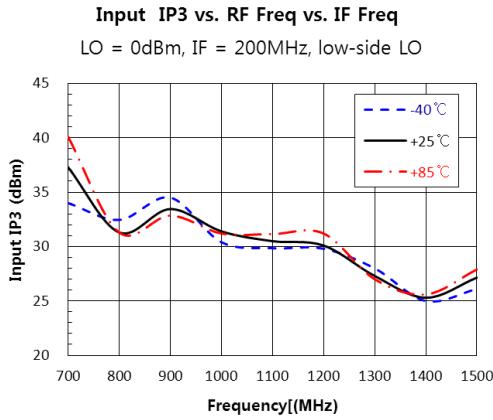


RM101

HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 700 – 1500MHz



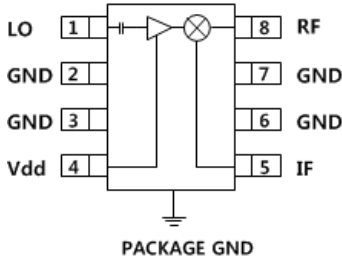
Performances at 5.0V



RM101

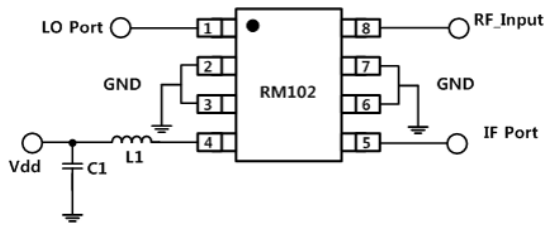
**HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 700 – 1500MHz**

Pin Configuration and Description



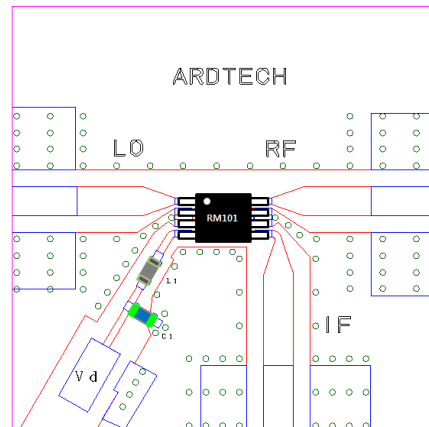
Pin No.	Symbol	Description
1	LO	Local Oscillator Input, Internally DC Block
2,3,6,7	GND	RF/DC Ground
4	Vdd	Supply Voltage,
5	IF	Intermediate Frequency
8	RF	Radio Frequency
Backside Plate	GND	RF/DC Ground. Follow recommended via pattern and ensure good solder attach for best thermal and electrical performance.

Application Circuit



Test condition : L1=33nH, C1=100pF

Evaluation PCB Layout



Harmonics of LO

LO Freq GHz	3.3V			
	1	2	3	4
0.5	30.6	26.1	42.9	30.3
0.6	25.1	21.0	33.7	26.9
0.7	23.5	19.5	34.3	25.2
0.8	17.6	18.3	24.8	28.3
0.9	15.7	18.6	26.2	25.1
1.0	14.6	19.6	24.2	27.1

LO power = 0 dBm
All values in dBc below input LO level measured at RF port

LO Freq GHz	5V			
	1	2	3	4
0.5	28.6	26.3	43.2	30
0.6	23.3	21.5	61.3	26
0.7	20.1	19.1	44.5	24.8
0.8	16.7	17.5	38.4	24.8
0.9	14.9	16.6	34.3	22.4
1.0	14.1	16.6	27.6	23.7

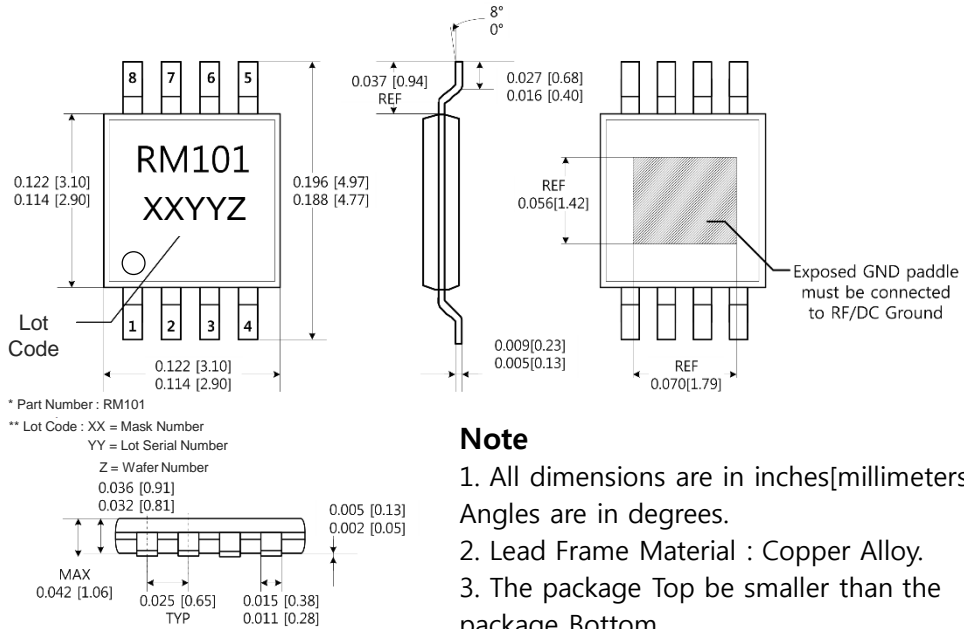
LO power = 0 dBm
All values in dBc below input LO level measured at RF port

RM101

**HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 700 – 1500MHz**

Package Mark and Dimensions

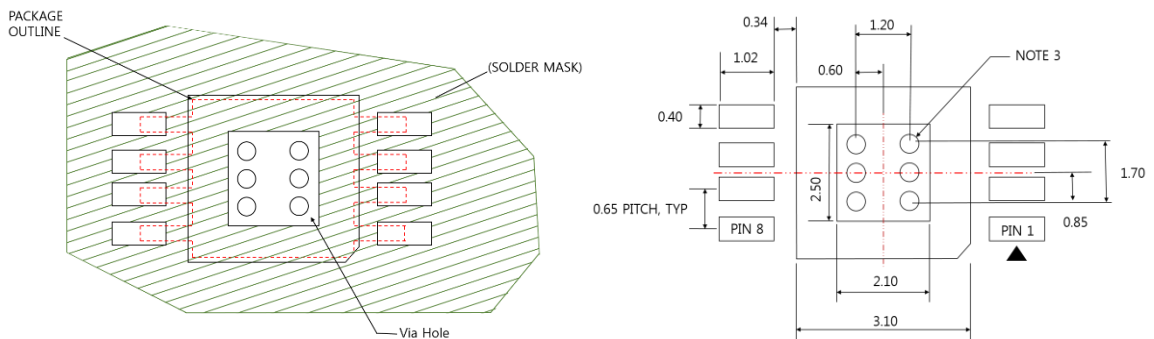
Dimension in inches[Millimeters]



Note

1. All dimensions are in inches[millimeters]. Angles are in degrees.
2. Lead Frame Material : Copper Alloy.
3. The package Top be smaller than the package Bottom

PCB Mounting Pattern



Note

1. All dimensions are in millimeters. Angles are in degrees.
2. Use 1 oz. copper minimum for top and bottom layer metal.
3. We recommend a 0.35mm diameter bit for drilling via holes and a final plated thru diameter of 0.25mm.
4. If possible, the recommended thickness of metal mask is 0.15mm

RM101

HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 700 – 1500MHz



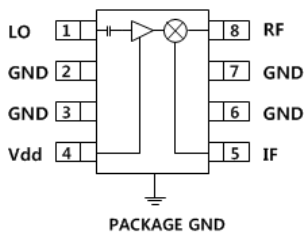
NOTE

HIGH IIP3 GaAs MMIC MIXER With INTEGRATED LO AMPLIFIER, 1700 – 2400MHz

Product Description

RM102 can use at 3.3V to 5V. It is a high dynamic range passive MMIC mixer with an integrated LO amplifier in a plastic surface mount 8 lead Mini Small Outline Package (MSOP) covering 1700 to 2400MHz. It has excellent input IP3 performance of +30.5dBm at 3.3V. Conversion Loss is 9dBm Typical. RM102 is pin to pin compatible with RM101 which is 700-1500MHz Mixers with LO amplifiers.

Component Diagram



Features

- + 30.5 dBm input IP3
- Conversion Loss : 9.0 dB
- Single Positive Supply : 23mA @ 3.3V
- Low LO drive level: -2 to +4dBm
- Available 3.0 to 5 V single voltage
- High ESD level: Class 1B
- Lead-free, RoHS compliant, Green



Applications

- High Dynamic Range Infrastructure system
- GSM GPRS & EDGE
- CDMA & WCDMA
- Cable Modem Termination Systems

Parameter	3.3 V			5 V			Units
Frequency Range. RF	1.7 – 1.9	1.9 – 2.1	2.1 – 2.4	1.7 - 2.9	1.9 - 2.1	2.1 – 2.4	GHz
Frequency Range. LO	1.7 – 1.8	1.8 – 2.0	2.0 – 2.2	1.7 – 1.8	1.8 - 2.0	2.0 – 2.2	GHz
Frequency Range. IF	50 - 300						MHz
Conversion Loss	TYP 9.3 MAX 10.5						dB
Noise Figure(SSB)	TYP 9.3 MAX 10.5						dB
LO to RF Isolation	-7.8	-6.8	-7	-8	-8	-8.6	dB
LO to IF Isolation	-16	-13.4	-13.5	-16	-13.4	-13.5	dB
RF to IF Isolation	-12.8	-17	-15	-15	-17.2	-15.3	dB
IP3(Input)	28.5	30.5	30	27.6	29.5	29.5	dBm
Pin1dB	20.5	20	18	22	20	18	dBm
LO Input Drive Level(Typical)	0						dBm

Test condition: Vcc = 3.3 V, I_D=23mA, Vcc=5V, I_D=35mA, Typ., LO = 0dBm, IF = 200MHz, T_L=25°C, Z_s=Z_L=50

RM102

HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 1700 – 2400MHz

Absolute Maximum Ratings

Parameter	Rating	Unit
Max RF/IF Input Power	27	dBm
Max LO Drive Input Power	10	dBm
Max Device Voltage(V_D)	6.5	V
Max Operating Dissipated Power	0.5	W
Junction Temperature(T_J)	150	°C
Operating Temperature(T_L)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 1B	
Moisture Sensitivity Level	MSL1	



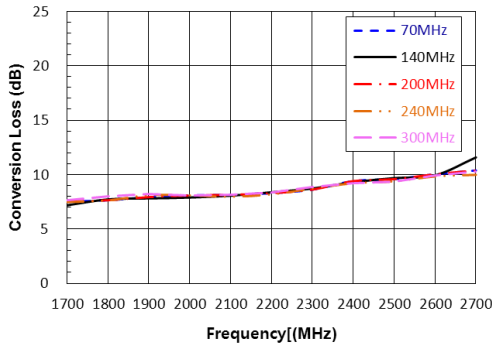
RM102

HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 1700 – 2400MHz

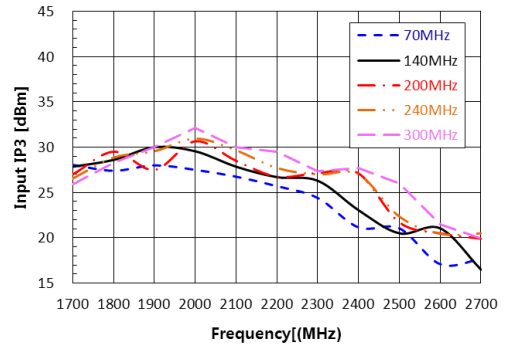


Performances at 3.3V

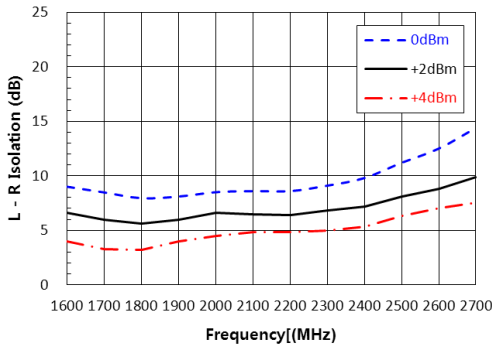
Conversion Loss vs. RF Freq vs. IF Freq
+25°C LO = 0dBm, low-side LO



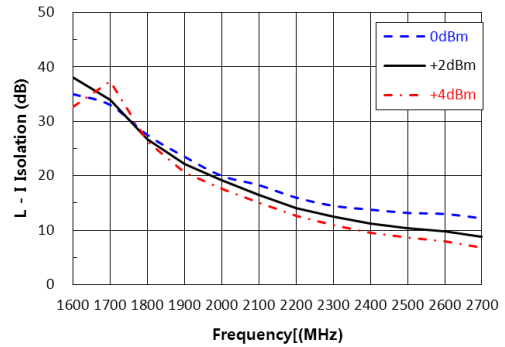
Input IP3 vs. RF Freq vs. IF Freq
+25°C LO = 0dBm, low-side LO



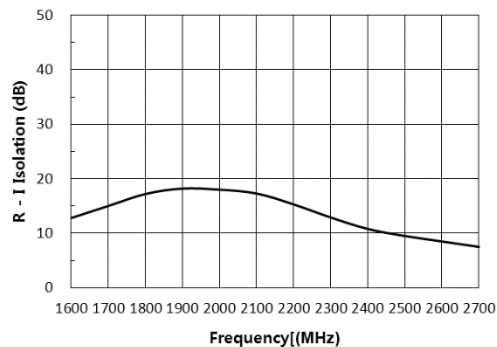
L - R Isolation vs. LO Freq
+25°C Referenced with



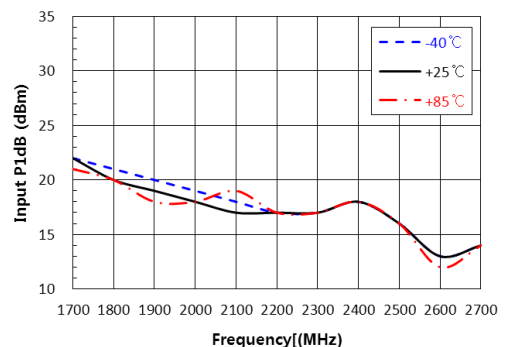
L - I Isolation vs. LO Freq
+25°C Referenced with



R - I Isolation vs. LO Freq
+25°C LO at 0 dBm Referenced with



Input P1dB vs. RF Frequency
LO at 0 dBm, IF = 200MHz, Low-side LO



RM102

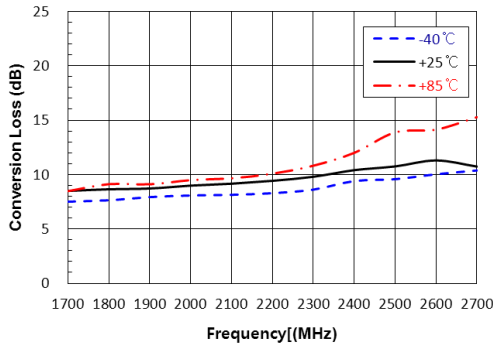
HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 1700 – 2400MHz



Performances at 3.3V

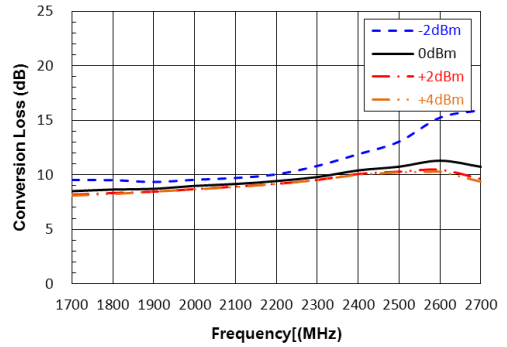
Conversion Loss vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 70MHz, low-side LO



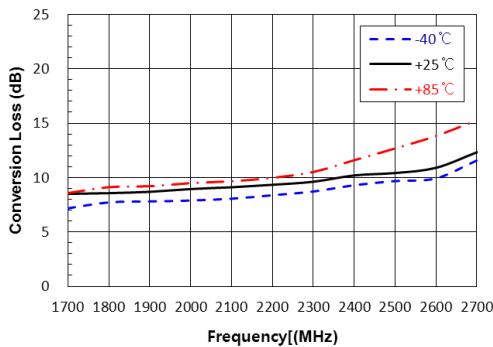
Conversion Loss vs. RF Freq vs. IF Freq

+25°C. IF = 70MHz, low-side LO



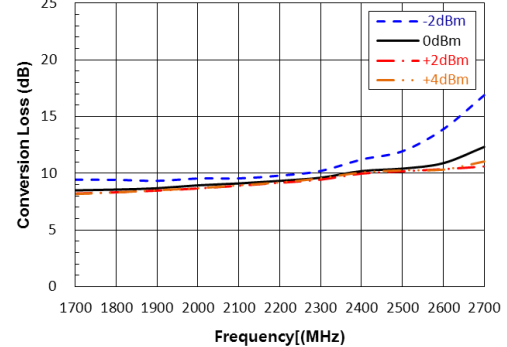
Conversion Loss vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 140MHz, low-side LO



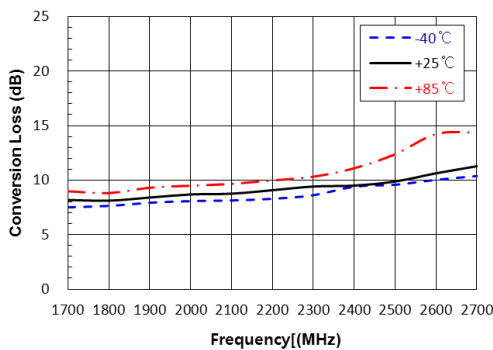
Conversion Loss vs. RF Freq vs. IF Freq

+25°C. IF = 140MHz, low-side LO



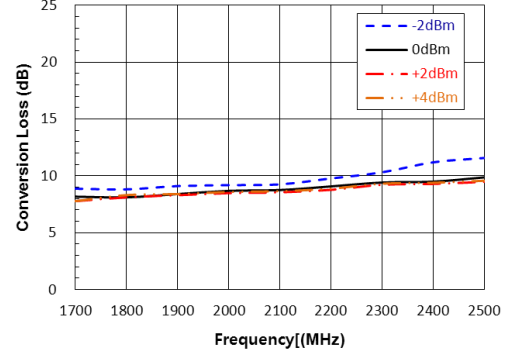
Conversion Loss vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 200MHz, low-side LO



Conversion Loss vs. RF Freq vs. IF Freq

+25°C. IF = 200MHz, low-side LO



RM102

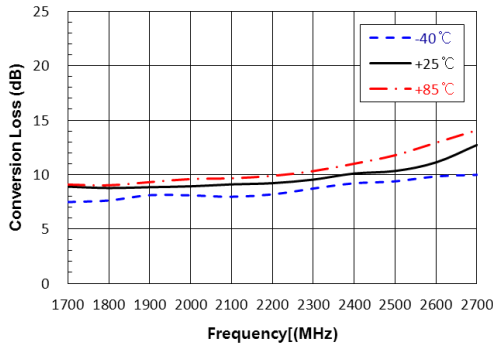
HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 1700 – 2400MHz



Performances at 3.3V

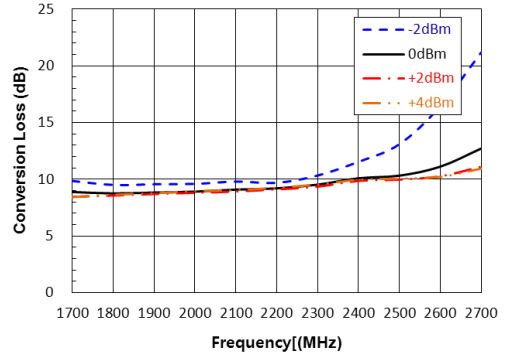
Conversion Loss vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 240MHz, low-side LO



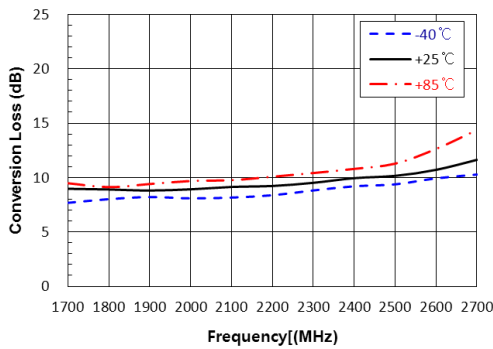
Conversion Loss vs. RF Freq vs. IF Freq

+25°C. IF = 240MHz, low-side LO



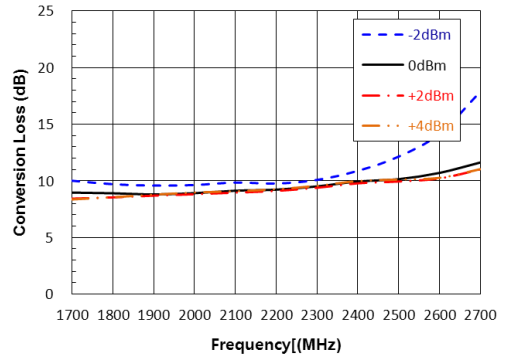
Conversion Loss vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 300MHz, low-side LO



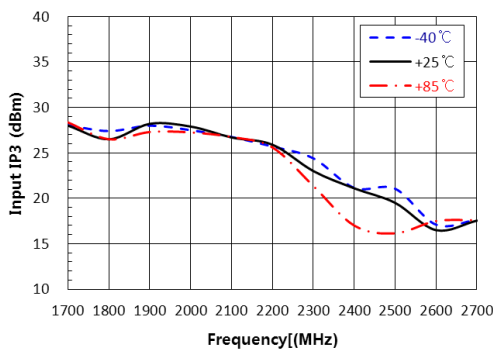
Conversion Loss vs. RF Freq vs. IF Freq

+25°C. IF = 300MHz, low-side LO



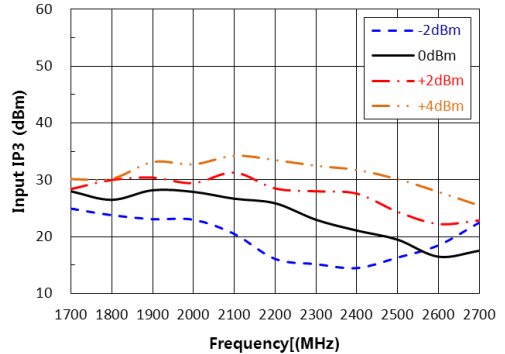
Input IP3 vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 70MHz, low-side LO



Input IP3 vs. RF Freq vs. LO Power

+25°C. IF = 70MHz, low-side LO



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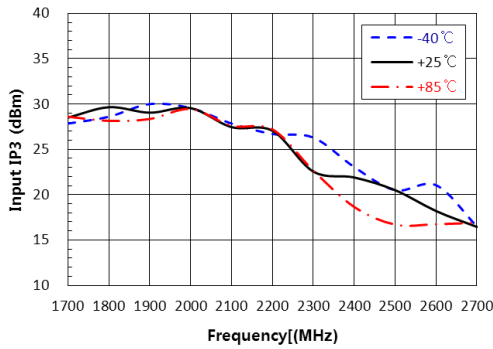
HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 1700 – 2400MHz



Performances at 3.3V

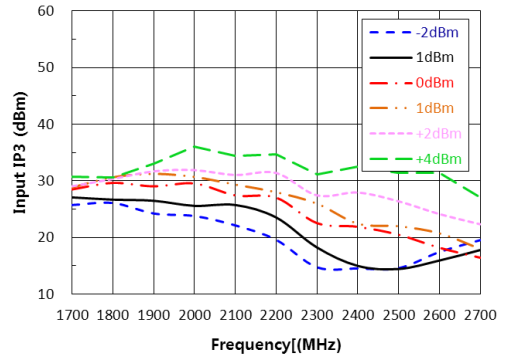
Input IP3 vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 140MHz, low-side LO



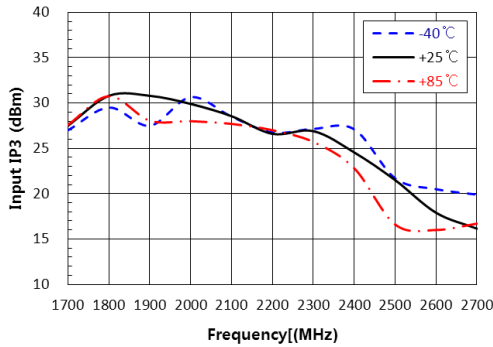
Input IP3 vs. RF Freq vs. LO Power

+25°C, IF = 140MHz, low-side LO



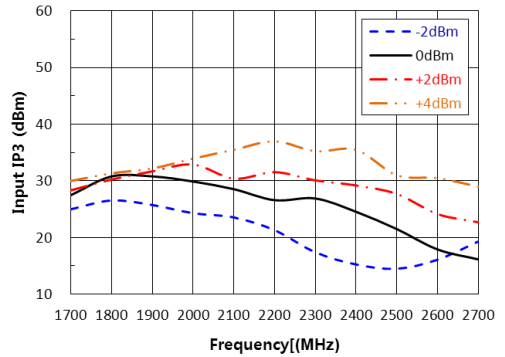
Input IP3 vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 200MHz, low-side LO



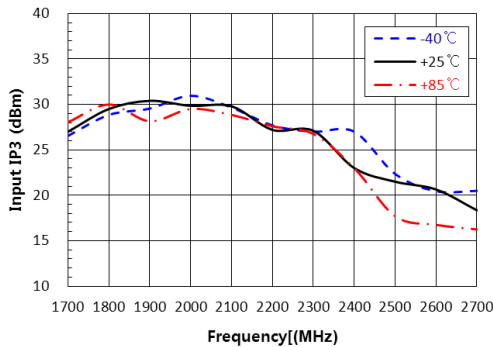
Input IP3 vs. RF Freq vs. LO Power

+25°C, IF = 200MHz, low-side LO



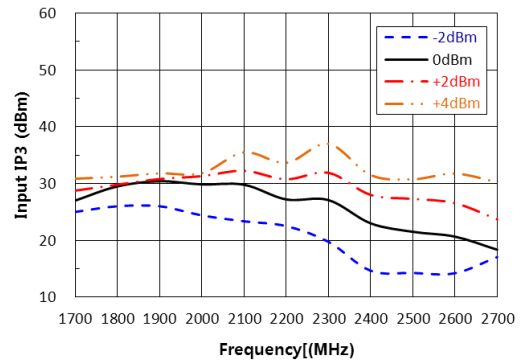
Input IP3 vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 240MHz, low-side LO



Input IP3 vs. RF Freq vs. LO Power

+25°C, IF = 240MHz, low-side LO

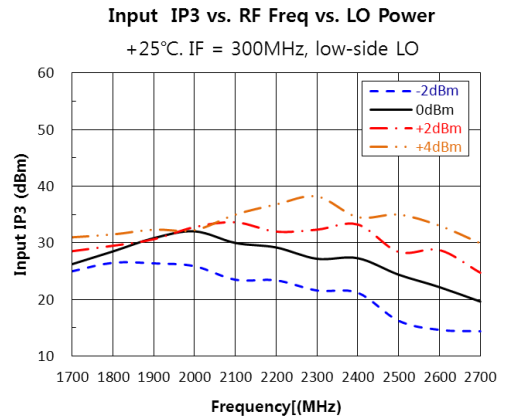
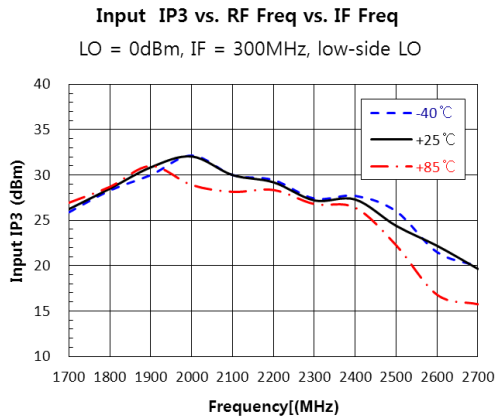


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HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 1700 – 2400MHz



Performances at 3.3V



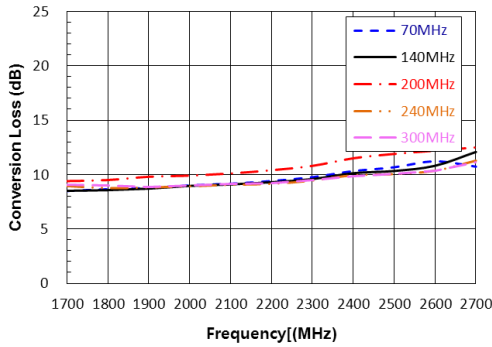
RM102

HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 1700 – 2400MHz

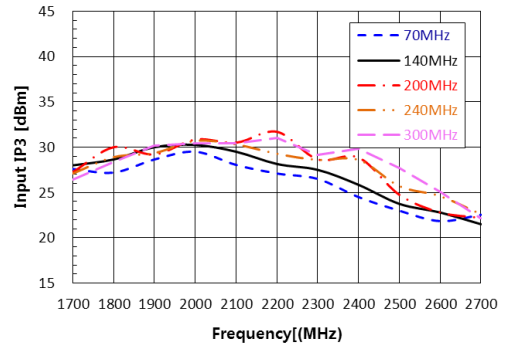


Performances at 5.0V

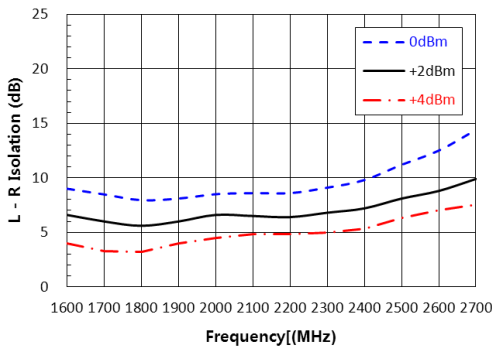
Conversion Loss vs. RF Freq vs. IF Freq
+25°C LO = 0dBm, low-side LO



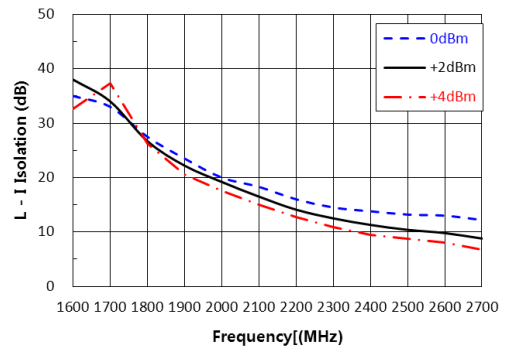
Input IP3 vs. RF Freq vs. IF Freq
+25°C LO = 0dBm, low-side LO



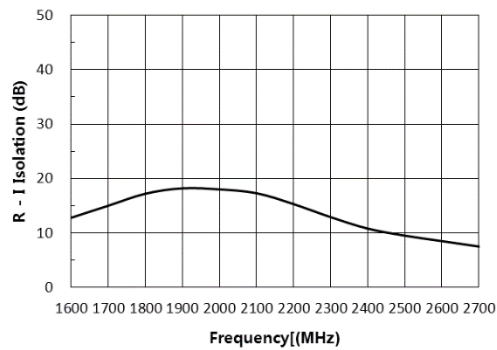
L - R Isolation vs. LO Freq
+25°C Referenced with



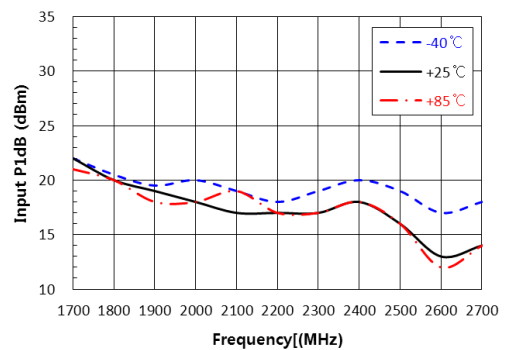
L - I Isolation vs. LO Freq
+25°C Referenced with



R - I Isolation vs. LO Freq
+25°C LO at 0 dBm Referenced with



Input P1dB vs. RF Frequency
LO at 0 dBm, IF = 200MHz, Low-side LO



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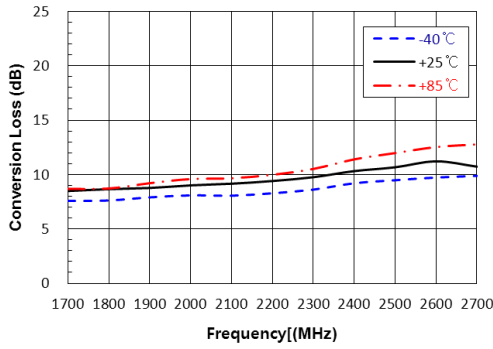
HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 1700 – 2400MHz



Performances at 5.0V

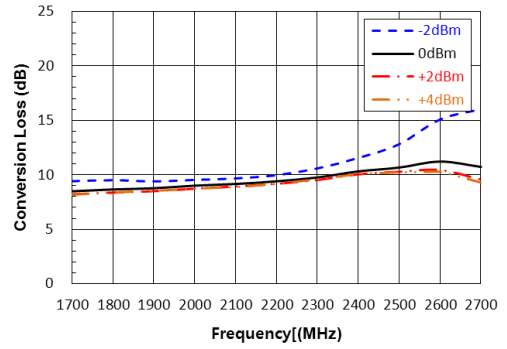
Conversion Loss vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 70MHz, low-side LO



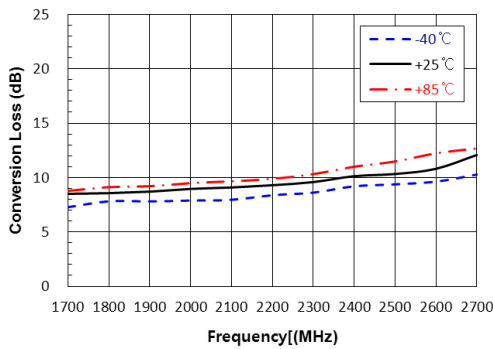
Conversion Loss vs. RF Freq vs. IF Freq

+25°C. IF = 70MHz, low-side LO



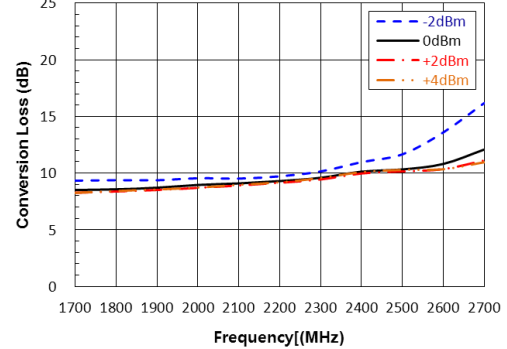
Conversion Loss vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 140MHz, low-side LO



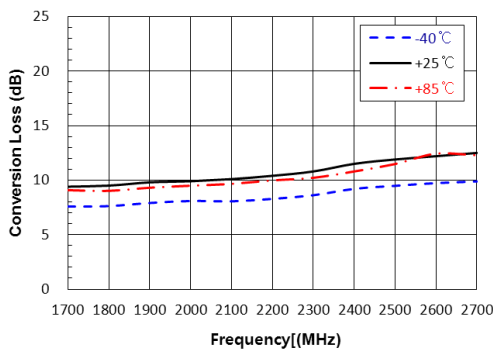
Conversion Loss vs. RF Freq vs. IF Freq

+25°C. IF = 140MHz, low-side LO



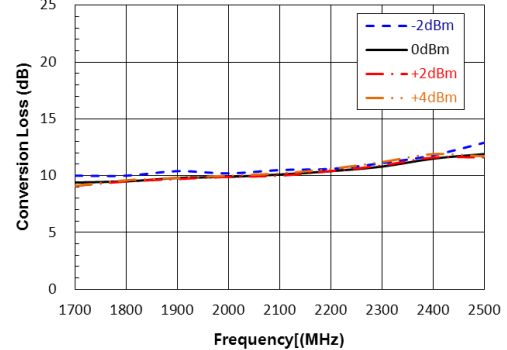
Conversion Loss vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 200MHz, low-side LO



Conversion Loss vs. RF Freq vs. IF Freq

+25°C. IF = 200MHz, low-side LO



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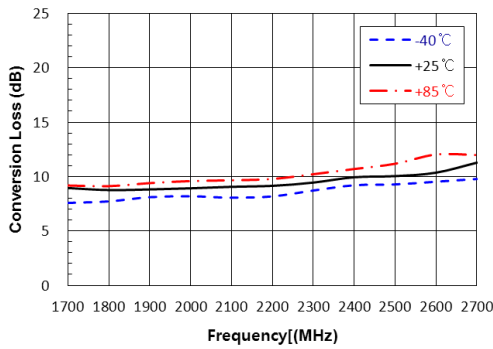
HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 1700 – 2400MHz



Performances at 5.0V

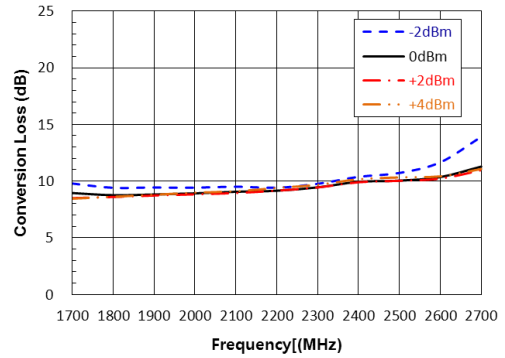
Conversion Loss vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 240MHz, low-side LO



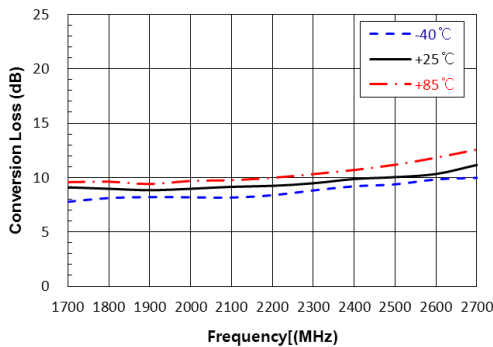
Conversion Loss vs. RF Freq vs. IF Freq

+25°C. IF = 240MHz, low-side LO



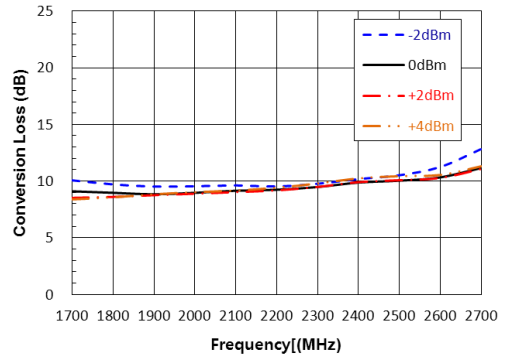
Conversion Loss vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 300MHz, low-side LO



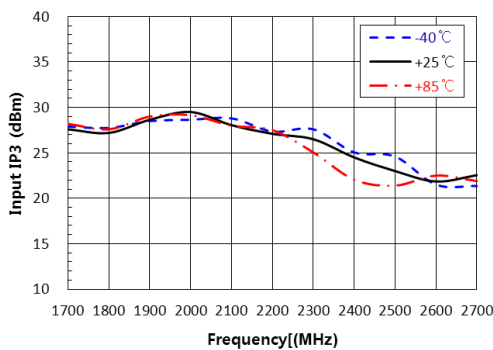
Conversion Loss vs. RF Freq vs. IF Freq

+25°C. IF = 300MHz, low-side LO



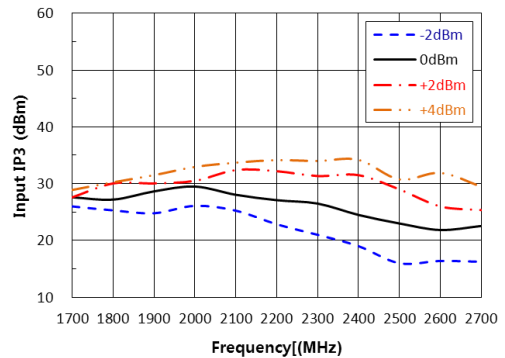
Input IP3 vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 70MHz, low-side LO



Input IP3 vs. RF Freq vs. LO Power

+25°C. IF = 70MHz, low-side LO



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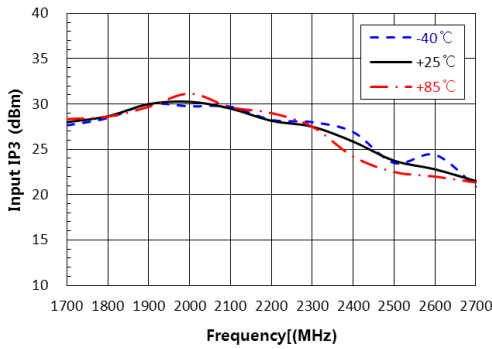
HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 1700 – 2400MHz



Performances at 5.0V

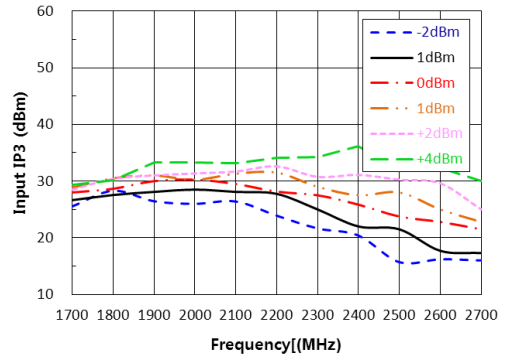
Input IP3 vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 140MHz, low-side LO



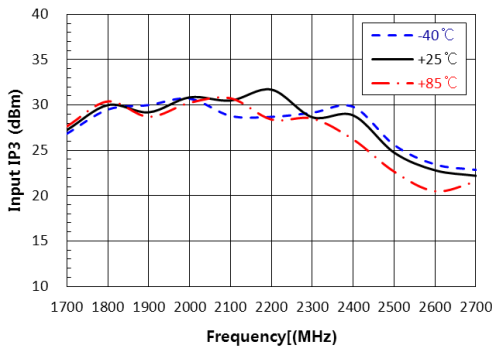
Input IP3 vs. RF Freq vs. LO Power

+25°C, IF = 140MHz, low-side LO



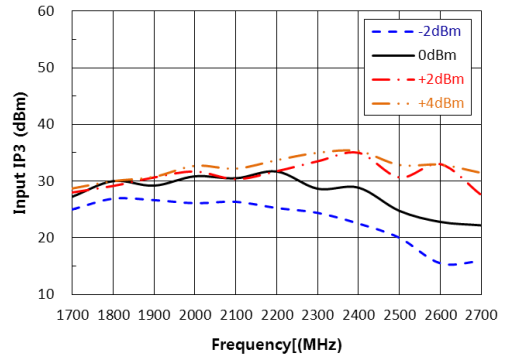
Input IP3 vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 200MHz, low-side LO



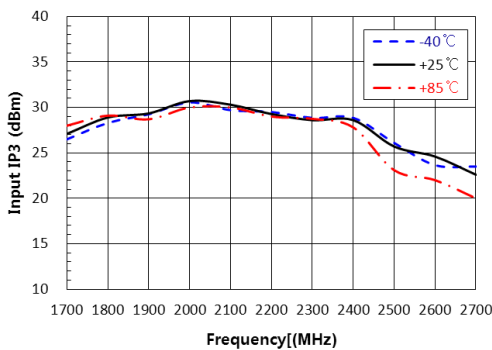
Input IP3 vs. RF Freq vs. LO Power

+25°C, IF = 200MHz, low-side LO



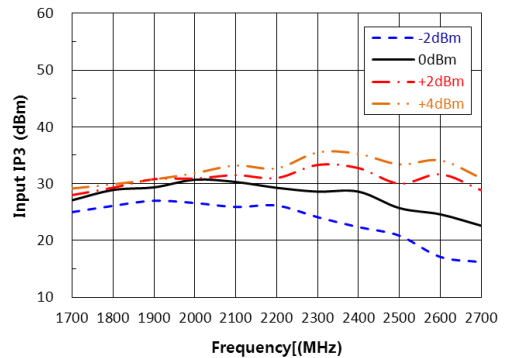
Input IP3 vs. RF Freq vs. IF Freq

LO = 0dBm, IF = 240MHz, low-side LO



Input IP3 vs. RF Freq vs. LO Power

+25°C, IF = 240MHz, low-side LO

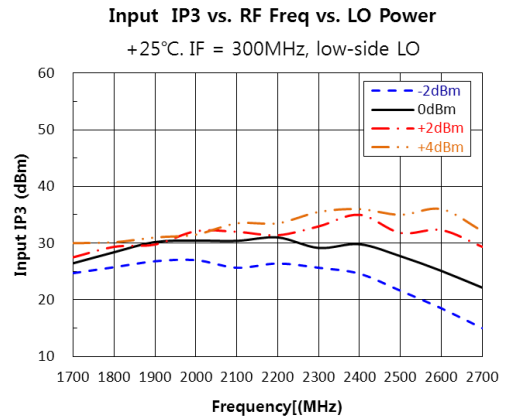
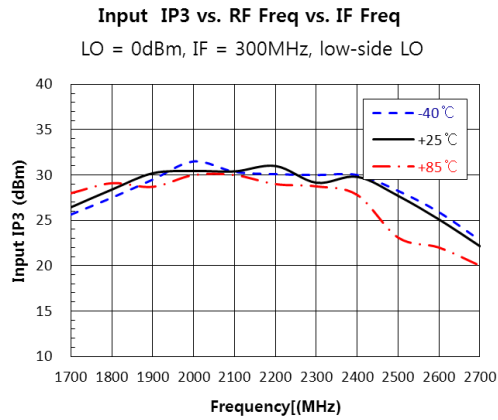


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HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 1700 – 2400MHz



Performances at 5.0V

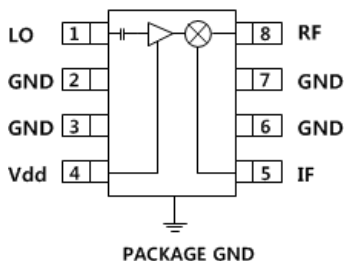


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**HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 1700 – 2400MHz**

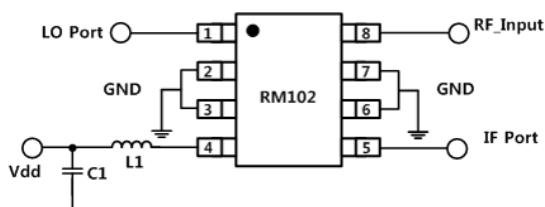


Pin Configuration and Description



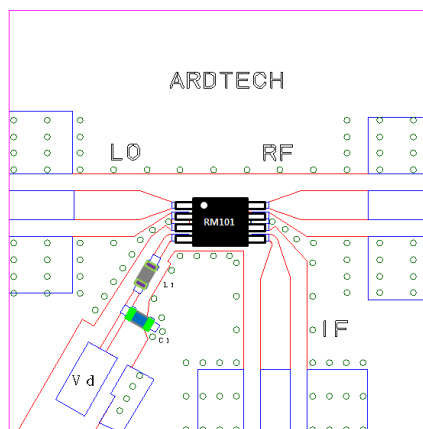
Pin No.	Symbol	Description
1	LO	Local Oscillator Input, Internally DC Block
2,3,6,7	GND	RF/DC Ground
4	Vdd	Supply Voltage,
5	IF	Intermediate Frequency
8	RF	Radio Frequency
Backside Plate	GND	RF/DC Ground. Follow recommended via pattern and ensure good solder attach for best thermal and electrical performance.

Application Circuit



Frequency(MHz)	L1(nH)	C1(pF)
1800	3.3	100
2100	3.3	
2400	1.2	

Evaluation PCB Layout



Harmonics of LO

LO Freq GHz	3.3V			
	1	2	3	4
1.5	18.9	15.5	17.7	32.7
1.6	16.1	14.4	17.7	30.9
1.7	13.9	15.8	16.9	30.9
1.8	14.8	16.9	19.3	27.1
1.9	13.3	19	20.7	25.6
2.0	14	23.6	25.3	28.2

LO power = 0 dBm
All values in dBc below input LO level measured at RF port

LO Freq GHz	5V			
	1	2	3	4
1.5	17.5	15.5	17.2	32.3
1.6	14.4	14.3	16.9	30.9
1.7	12.6	14.8	16.3	28.6
1.8	13.3	15.5	19.4	25.1
1.9	12	16.4	21.4	22.4
2.0	12.8	19.2	27.1	23.1

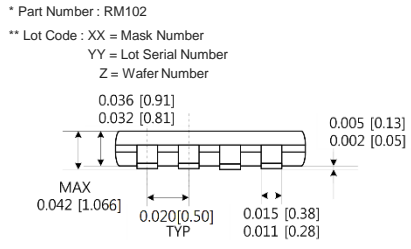
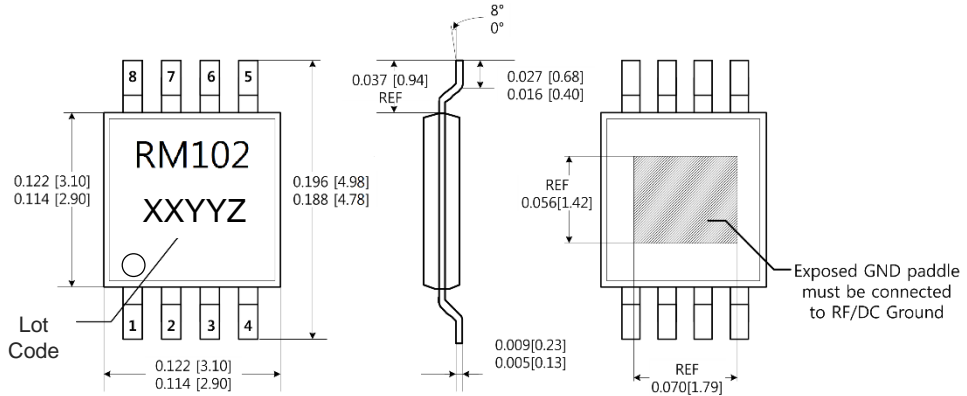
LO power = 0 dBm
All values in dBc below input LO level measured at RF port

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HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 1700 – 2400MHz

Package Mark and Dimensions

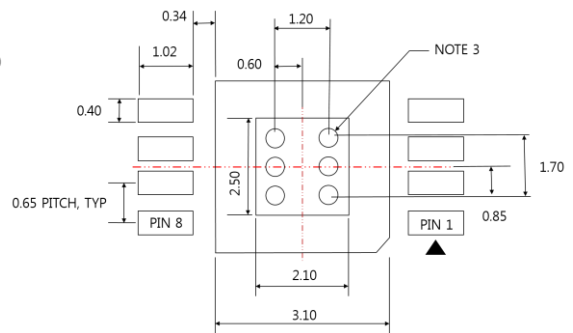
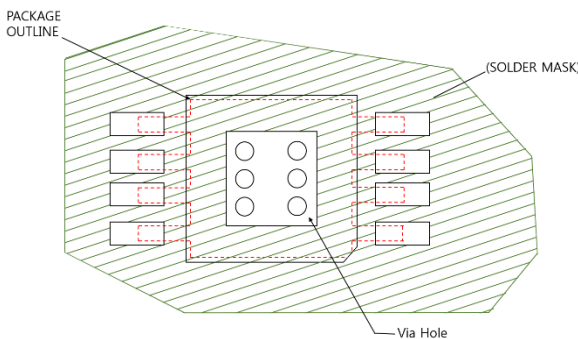
Dimension in inches[Millimeters]



Note

1. All dimensions are in inches[millimeters]. Angles are in degrees.
2. Lead Frame Material : Copper Alloy.
3. The package Top be smaller than the package Bottom

PCB Mounting Pattern



Note

1. All dimensions are in millimeters. Angles are in degrees.
2. Use 1 oz. copper minimum for top and bottom layer metal.
3. We recommend a 0.35mm diameter bit for drilling via holes and a final plated thru diameter of 0.25mm.
4. If possible, the recommended thickness of metal mask is 0.15mm

HIGH IIP3 GaAs MMIC MIXER With INTEGRATED LO AMPLIFIER, 300 – 2700MHz

Product Description

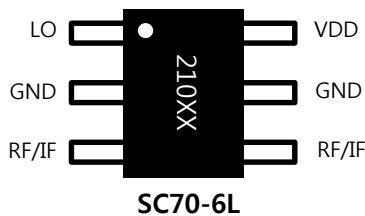
RM210 can use at 3V to 5.5V. It is a high dynamic range passive MMIC mixer with an integrated LO amplifier covering 300 to 2700MHz. It combines low conversion losses and excellent input IP3 characteristics with a low demand of LO power and DC power.

Features

- + 24 dBm input IP3 @ 850MHz
- Conversion Loss : 6.7 dB @ 850MHz
- Single Positive Supply : 5mA @ 3.3V
- LO drive level: -8 to +8dBm
- Available 3.0 to 5.5 V single voltage



Component Diagram



Applications

- High Dynamic Range Infrastructure system
- GSM GPRS & EDGE
- CDMA & WCDMA
- Cable Modem Termination Systems

Parameter	3.3 V				Units
	850	1800	2100	2600	
TEST Frequency (RF)	850	1800	2100	2600	MHz
TEST Frequency (LO)	710	1660	1960	2460	MHz
TEST Frequency (IF)	140				MHz
Conversion Loss	6.7	5.4	4.7	5.2	dB
Noise Figure(SSB)	6.7	5.4	4.7	5.2	dB
LO to RF Isolation	10	6.6	4.8	5.5	dB
LO to IF Isolation	20	13	24.5	11.7	dB
RF to IF Isolation	24	20	33	13	dB
IP3(Input)	24	26.5	29.5	25	dBm
Pin ₁ dB	19	17.5	18	17.5	dBm
Ids	6	7	11	10	mA
LO Input Drive Level	0				dBm

Test condition: Vcc = 3.3 V, Typ., LO = 0dBm, IF = 140MHz, T_L=25°C, Z_s=Z_L=50

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HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 300 – 2700MHz

Absolute Maximum Ratings

Parameter	Rating	Unit
Max RF/IF Input Power	17	dBm
Max LO Drive Input Power	10	dBm
Max Device Voltage(V_D)	6	V
Junction Temperature(T_J)	150	°C
Operating Temperature(T_L)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 1A	
Moisture Sensitivity Level	MSL1	



RM210

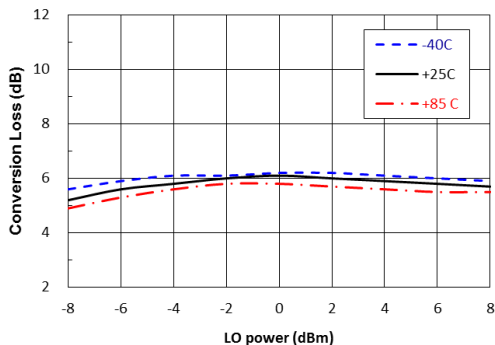
HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 300 – 2700MHz



Performances at 850MHz

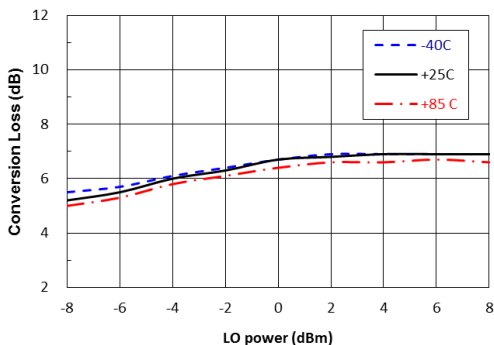
Conversion Loss vs. RF 850MHz

IF = 70MHz



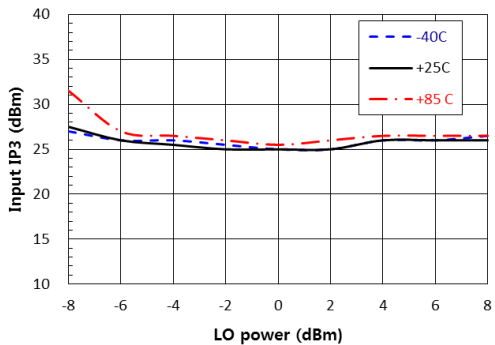
Conversion Loss vs. RF 850MHz

IF = 140MHz



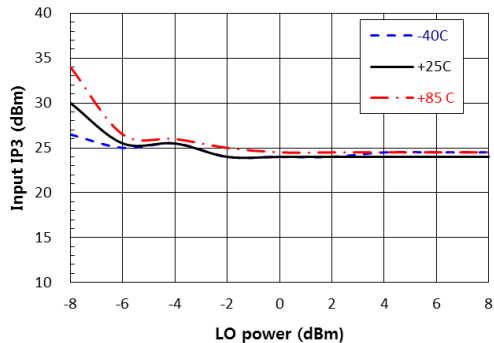
Input IP3 vs. RF 850MHz

IF = 70MHz



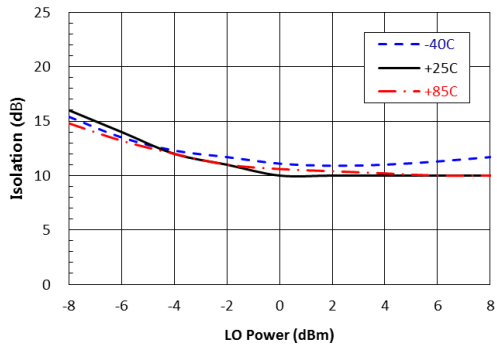
Input IP3 vs. RF 850MHz

IF = 140MHz



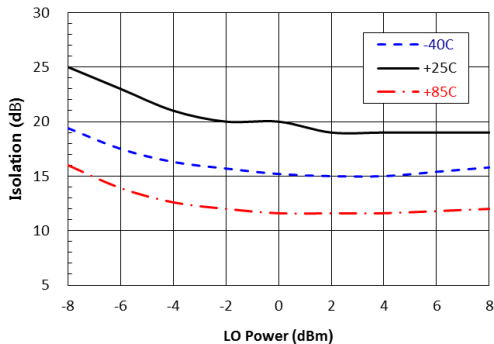
LO leakage at RF port (850M)

IF = 70/140MHz



LO leakage at IF port (850M)

IF = 70/140MHz



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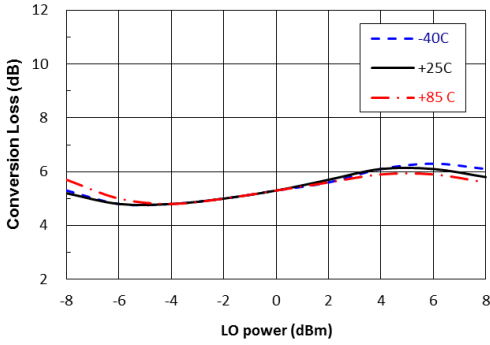
HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 300 – 2700MHz



Performances at 1800MHz

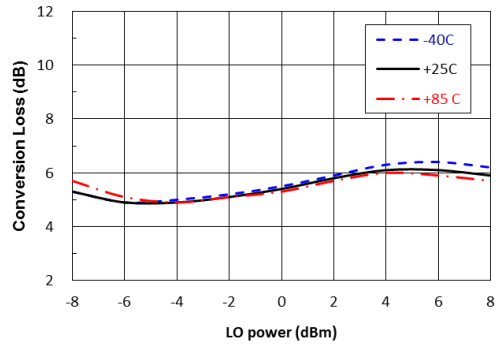
Conversion Loss vs. RF 1800MHz

IF = 70MHz



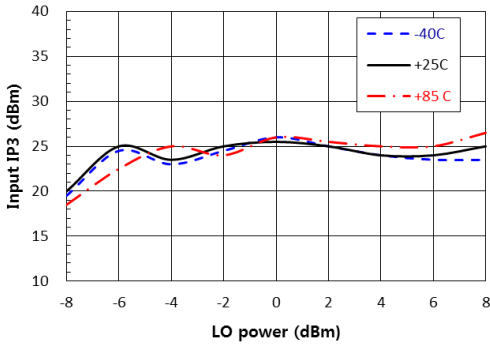
Conversion Loss vs. RF 1800MHz

IF = 140MHz



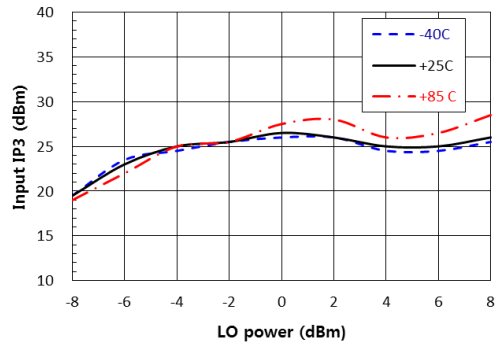
Input IP3 vs. RF 1800MHz

IF = 70MHz



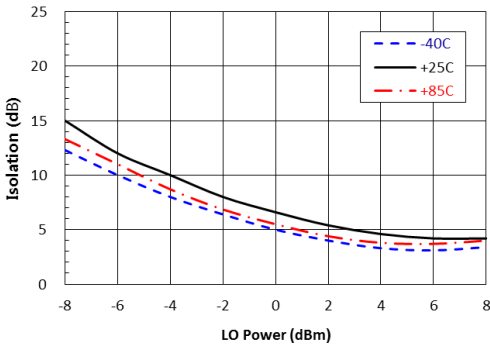
Input IP3 vs. RF 1800MHz

IF = 140MHz



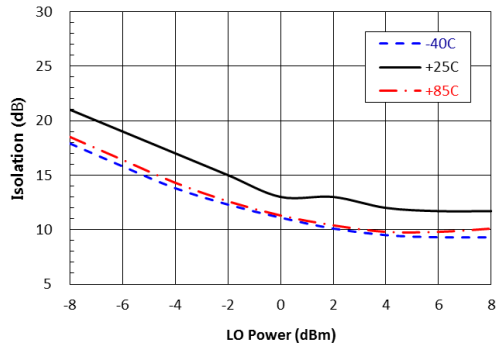
LO leakage at RF port (1800M)

IF = 70/140MHz



LO leakage at IF port (1800M)

IF = 70/140MHz



RM210

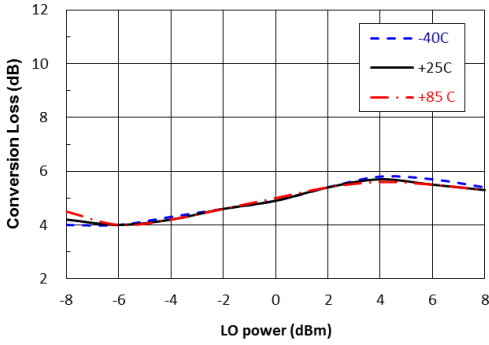
HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 300 – 2700MHz



Performances at 2100MHz

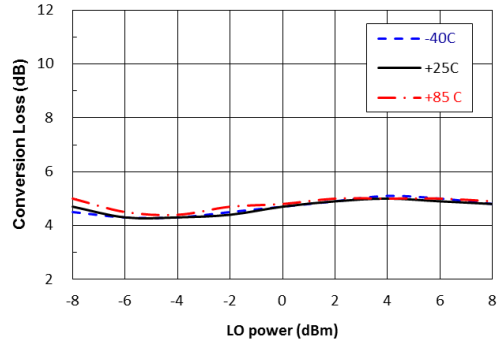
Conversion Loss vs. RF 2100MHz

IF = 70MHz



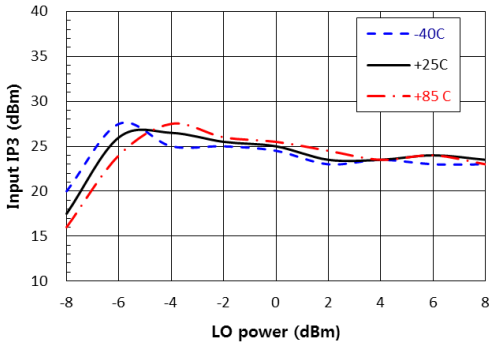
Conversion Loss vs. RF 2100MHz

IF = 140MHz



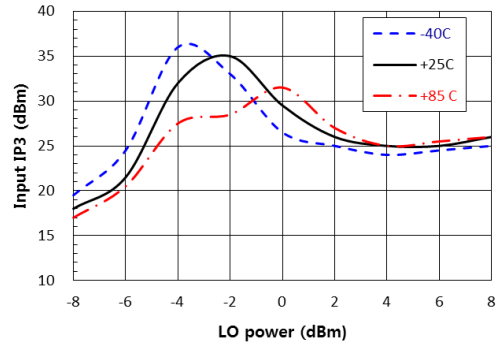
Input IP3 vs. RF 2100MHz

IF = 70MHz



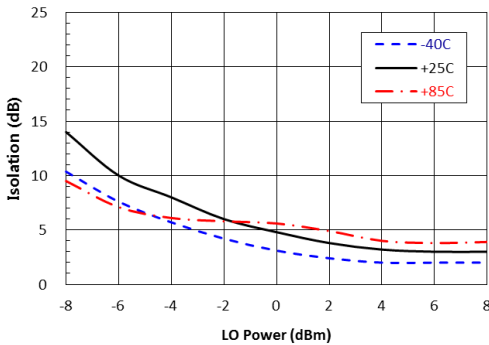
Input IP3 vs. RF 2100MHz

IF = 140MHz



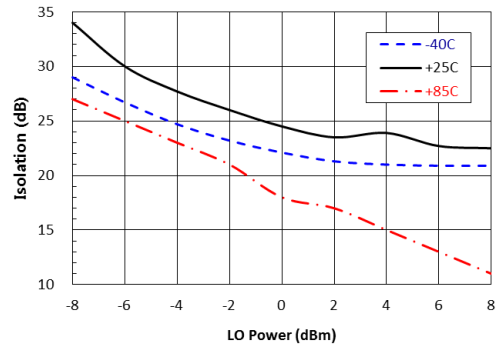
LO leakage at RF port (2100M)

IF = 70/140MHz



LO leakage at IF port (2100M)

IF = 70/140MHz



RM210

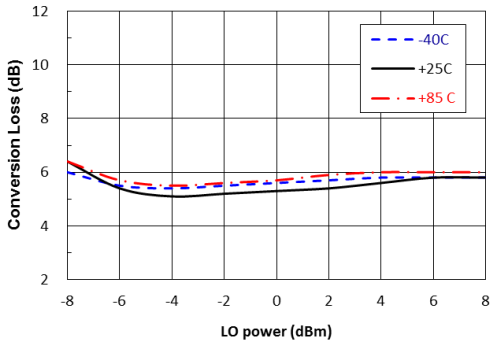
HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 300 – 2700MHz



Performances at 2600MHz

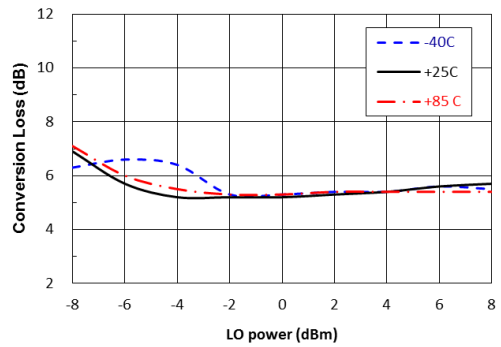
Conversion Loss vs. RF 2600MHz

IF = 70MHz



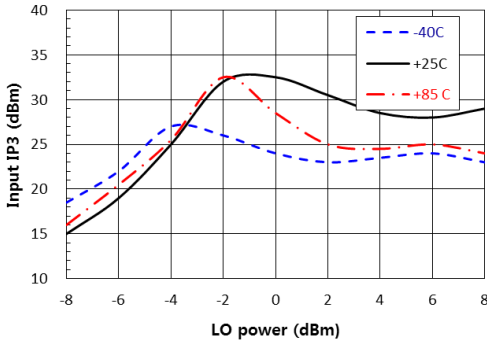
Conversion Loss vs. RF 2600MHz

IF = 140MHz



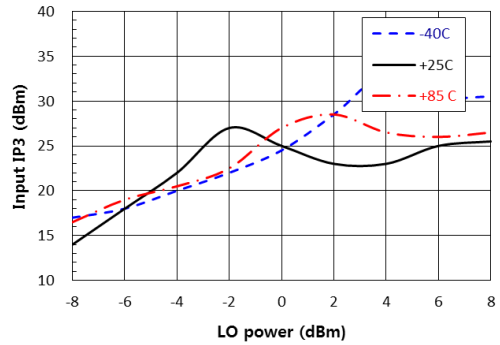
Input IP3 vs. RF 2600MHz

IF = 70MHz



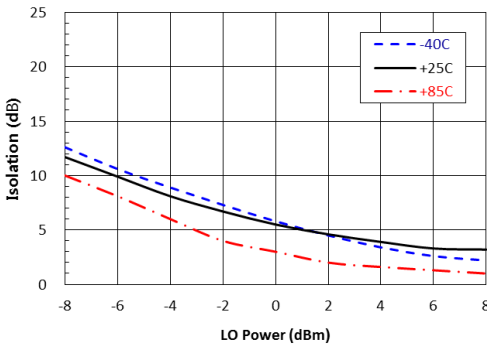
Input IP3 vs. RF 2600MHz

IF = 140MHz



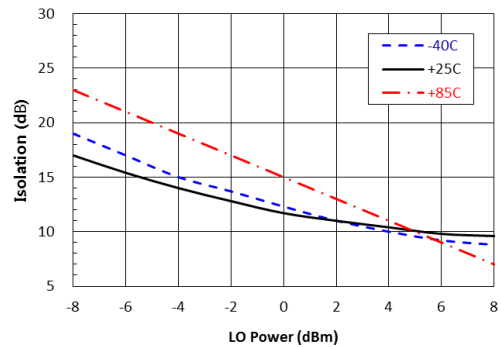
LO leakage at RF port (2600M)

IF = 70/140MHz



LO leakage at IF port (2600M)

IF = 70/140MHz

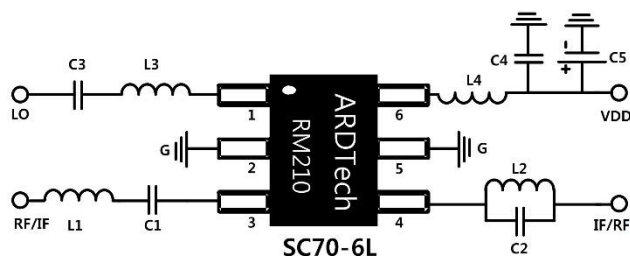


RM210

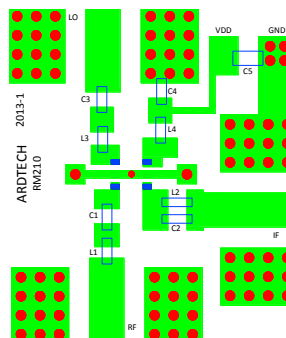
HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 300 – 2700MHz



Down Conversion Application Circuit



TEST Circuit



Evaluation PCB Layout

Typical lumped element values for different RF frequencies :

RF[MHz]	IF[MHz]	L1(nH)	C1(pF)	L2(nH)	C2(pF)	L3(nH)	C3(pF)	L4(nH)	C4(pF)	C5(uF)
850	70/140	5.6	3.9	6.8	3.9	6.8	3.9	22	100	10
1800	70/140	3.3	1.8	3.9	1.8	5.6	3.3	3.9	100	10
2100	70/140	3.9	1.8	3.3	1.8	4.7	1.8	3.3	100	10
2600	70/140	1	1.8	1.8	1.8	2.7	1.8	1.5	82	10

Pin Configuration and Description

Pin No.	Symbol	Description
1	LO	Local Oscillator Input
2,5	GND	RF/DC Ground
6	Vdd	Supply Voltage
3	IF/RF	Intermediate Frequency or Radio Frequency
4	IF/RF	Radio Frequency or Intermediate Frequency

Harmonics of LO

LO Freq GHz	3.3V			
	1	2	3	4
780	29.7	17.7	40	40
710	29.3	18.8	32	31
1780	18.1	13	45.3	25.4
1710	15.4	10.7	41.9	20.7
2030	11.9	10.3	27.6	30.4
1960	11.3	15.5	33.5	25.7
2530	19.5	20.2	30.2	32.1

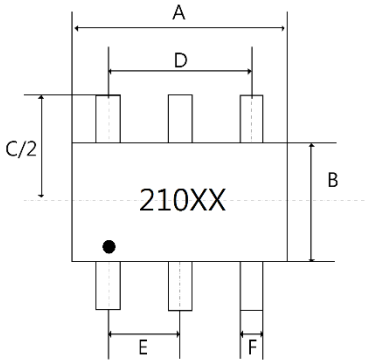
LO power = 0 dBm
All values in dBc below input LO level measured at RF port

RM210

HIGH IP3 GaAs MMIC MIXER With
INTEGRATED LO AMPLIFIER, 300 – 2700MHz



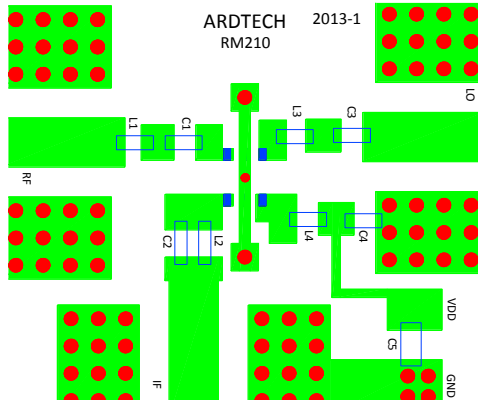
Package Mark and Dimensions



Symbol	DIMENSIONS MILLIMETER			DIMENSIONS INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.90	2.10	2.15	0.074	0.082	0.084
B	1.15	1.25	1.35	0.045	0.050	0.055
C	2.00	2.10	2.20	0.078	0.082	0.086
D	1.3			0.0512		
E	0.65			0.0255		
F	0.15	-	0.30	0.006	-	0.012

* Part Number : 210 =RM210
** Tracking Number : XX

Evaluation PCB Information



PCB Substrate Information[mm]	
Dielectric Constant	FR-4/4.6
Dielectric Height	0.037[0.93]
Copper Thickness	1 oz.

RL101 50-4000MHz High Linearity Low Noise Amplifier

Product Description

RL101 is a high linearity wide-band low noise amplifier in a low-cost surface mount package and provides 39dBm high OIP3 and 0.85dB Noise Figure at 1.85GHz. RL101 using enhancement pHEMT process is able to achieve high performance across a broad range and is available in a lead-free / green / RoHS-compliant SOT-89 package. RL101 is targeted for use as a receiver and transmitter in wireless infrastructure where high linearity and medium power is required. Internal active bias circuitry allows RL101 to maintain high linearity and gain performance over temperature and operate directly off a single +5V supply. All devices are 100% RF and DC tested.

Features

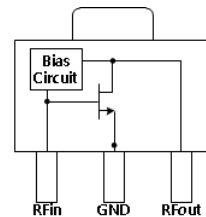
- High OIP3 39dBm @ 1.85GHz
- P1dB=23.0dBm @ 850MHz
- No output matching component @ 0.7~2.6GHz
- Unconditionally stable
- Single fixed 5V supply, 79mA current
- Industry standard SOT-89 package
- Lead-free, RoHS compliant, Green

Applications

- Low noise amplifier for wireless repeaters
- Wireless infrastructure
- Cellular, PCS, GSM, WCDMA, LTE



Component Diagram



Parameter	Specification			Condition	Units
	Min.	Typ.	Max.		
Small Signal Gain	18.3	19.8		850MHz	dB
	13.0	14.5		1850MHz	dB
	12.0	13.5		2140MHz	dB
Output power at 1-dB Compression	21.0	23.0		850MHz	dBm
	20.5	22.5		1850MHz	dBm
Third Order Intercept Point	34.0	36.0		850MHz	dBm
	37.0	39.0		1850MHz	dBm
Input Return Loss		-27.4		2140MHz	dB
Output Return Loss		-19.5		2140MHz	dB
Reverse Isolation		-26.7		850MHz	dB
Noise Figure		0.85	1.1	1850MHz	dB
Device Voltage		5			V
Device current (Icq)	60	79	95		mA
Thermal Resistance		41.6		Junction to lead	°C/W

Test condition: Vcc=5V, I_b=79mA Typ., OIP₃ Tone Spacing=1MHz, P_{out} per tone=6dBm T_L=25°C, Z_s=Z_L=50

RL101

50-4000MHz High Linearity Low Noise Amplifier

Absolute Maximum Ratings

Parameter	Rating	Unit
Max Device Voltage(V_D)	6.0	V
Max Device Current(I_D)	120	mA
Max RF Input Power	18	dBm
Max Operating Dissipated Power	0.72	W
Junction Temperature(T_J)	+150	°C
Operating Temperature(T_L)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 0B	
Moisture Sensitivity Level	MSL1	



Typical Electrical Specification

Parameter	850MHz	1850MHz	2140MHz	2600MHz	Unit
S21	19.8	14.5	13.5	11.8	dB
OIP3	37.0	39.0	39.2	39.5	dBm
P1dB	23.0	22.5	22.5	22.5	dBm
S11	-16.0	-15.0	-24.7	-17.3	dB
S22	-13.6	-13.7	-19.5	-19.2	dB
S12	-26.7	-21.0	-19.7	-18.3	dB
NF	0.85	0.82	0.91	0.96	dB

Test condition: $V_{CC}=5V$, $I_D=79mA$ Typ., OIP_3 Tone Spacing=1MHz, P_{out} per tone=6dBm $T_L=25^\circ C$, $Z_S=Z_L=50$

Typical 3.3V Performance

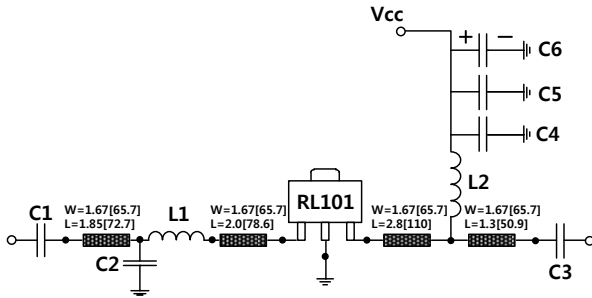
Parameter	850MHz	1850MHz	2140MHz	2600MHz	Unit
S21	19.5	14.3	13.2	11.5	dB
OIP3	34.0	33.1	33.3	31.5	dBm
P1dB	21.5	19.0	19.0	18.0	dBm
S11	-14.5	-13.7	-25.3	-15.8	dB
S22	-16.0	-17.3	-23.2	-19.6	dB
S12	-25.5	-20.1	-18.8	-17.7	dB
NF	0.85	0.82	0.91	0.96	dB

Test condition: $V_{CC}=3.3V$, $I_D=55mA$ Typ., OIP_3 Tone Spacing=1MHz, P_{out} per tone=6dBm $T_L=25^\circ C$, $Z_S=Z_L=50$

RL101

50-4000MHz High Linearity Low Noise Amplifier

700~1000MHz Reference Application Circuit



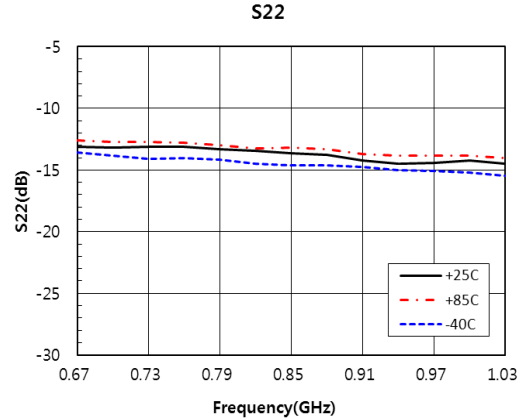
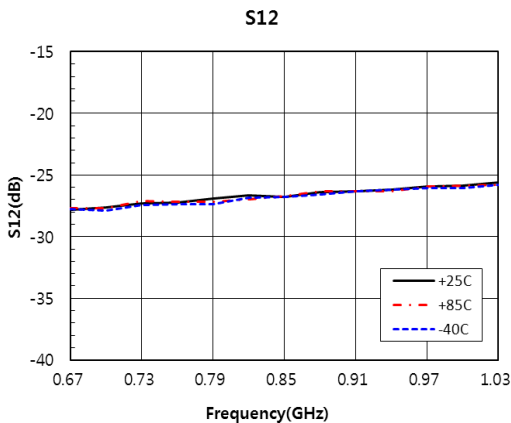
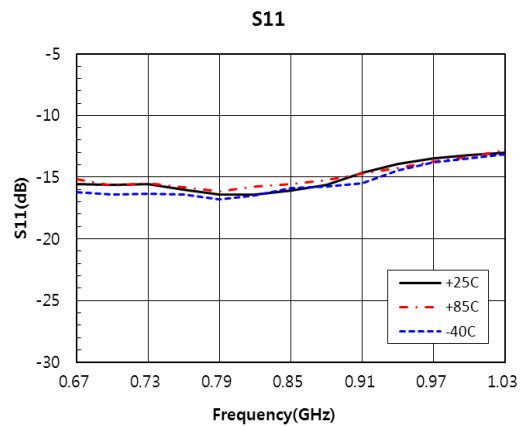
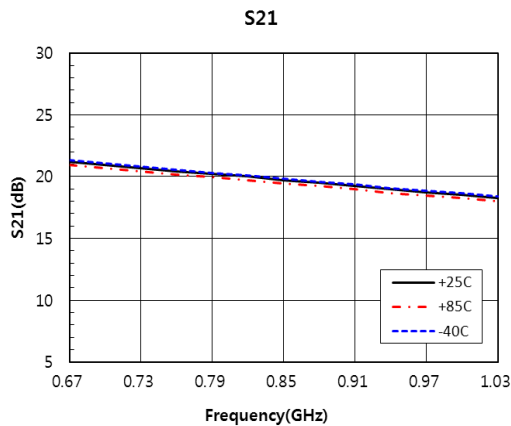
BOM	Value	BOM	Value	BOM	Value
C1	100pF	C4	100pF	L1	6.8nH
C2	1.0pF	C5	1000pF	L2	33nH
C3	100pF	C6	10uF		

*Width and Length of Micro-strip line dimension in mm[mil]

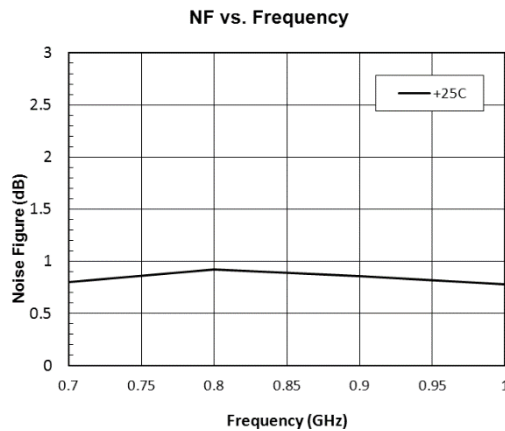
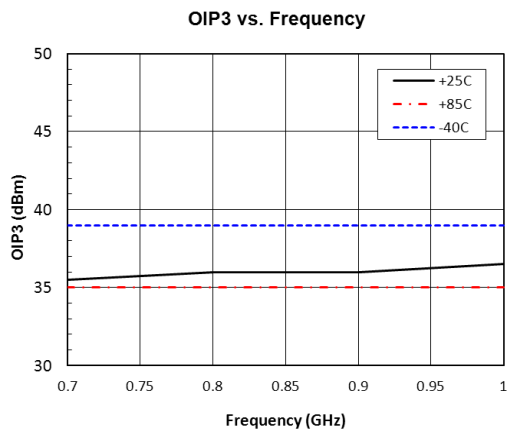
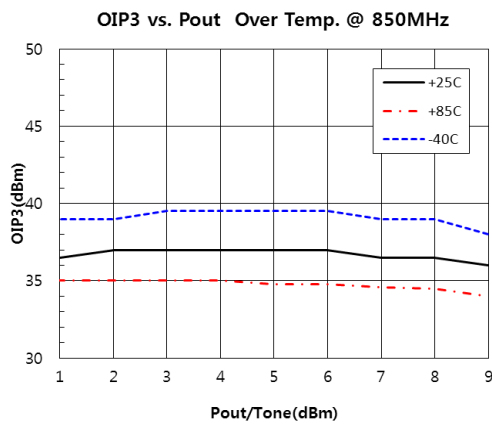
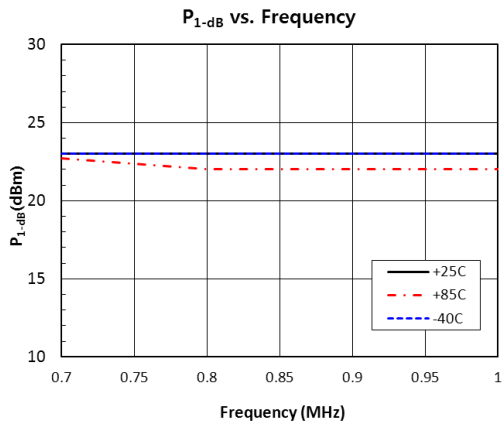
Parameter/Freq.(MHz)	750	800	850	Unit
Small Signal Gain	20.5	20.1	19.7	dB
S11	-15.7	-16.4	-16.0	dB
S22	-13.2	-13.3	-13.6	dB
Output P1dB	23.0	23.0	23.0	dBm
Output OIP3*	35.5	36.0	36.0	dBm
Noise Figure	0.83	0.89	0.85	dB
Ic _q	79			mA
Vcc	5			V

* P_{out}=6dBm/tone

S-Parameter Over Temperature vs. Freq. at 700~1000MHz



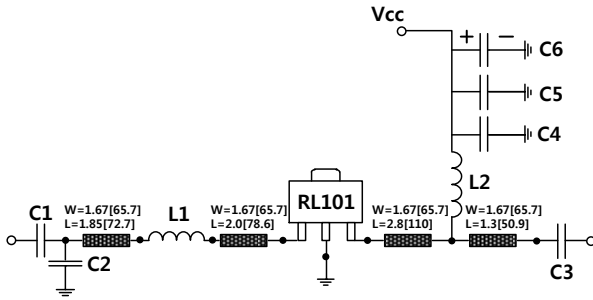
P1dB, OIP3 and Noise Figure Performance at 700~1000MHz



RL101

50-4000MHz High Linearity Low Noise Amplifier

1800~2200MHz Reference Application Circuit



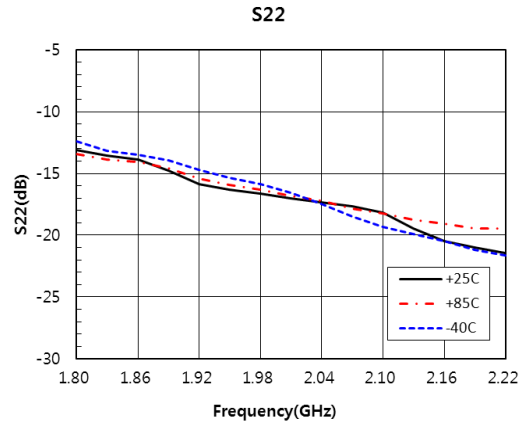
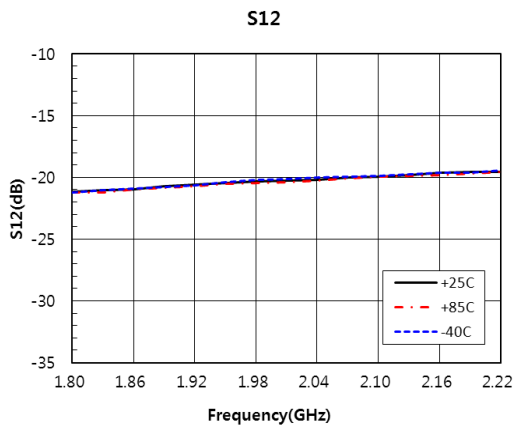
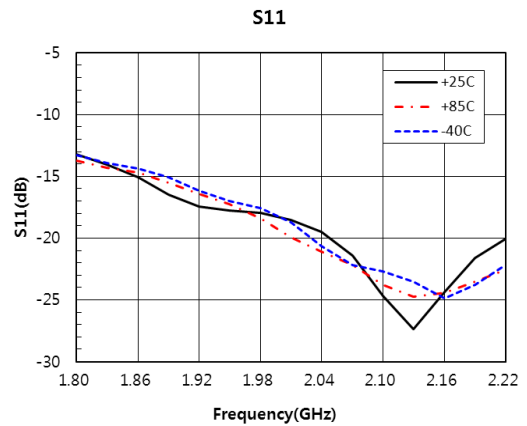
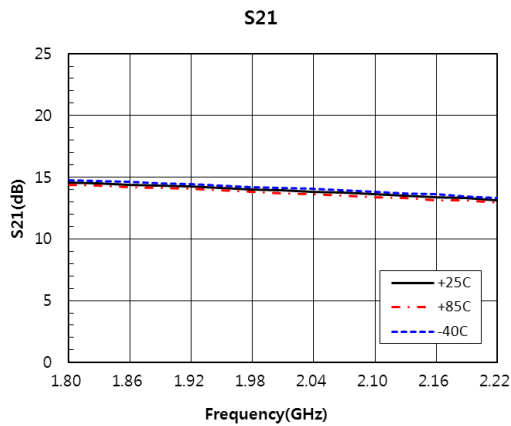
BOM	Value	BOM	Value	BOM	Value
C1	100pF	C4	100pF	L1	NA
C2	1pF	C5	1000pF	L2	8.2nH
C3	100pF	C6	10uF		

*Width and Length of Micro-strip line dimension in mm[mil]

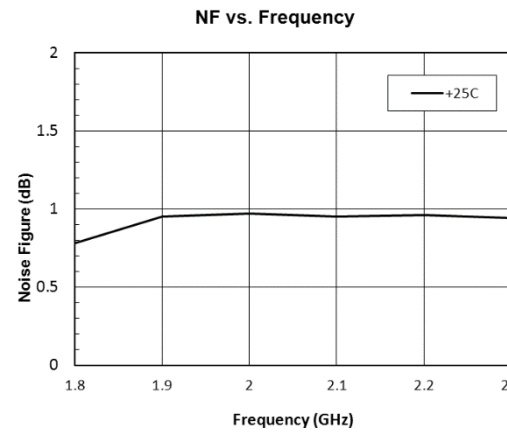
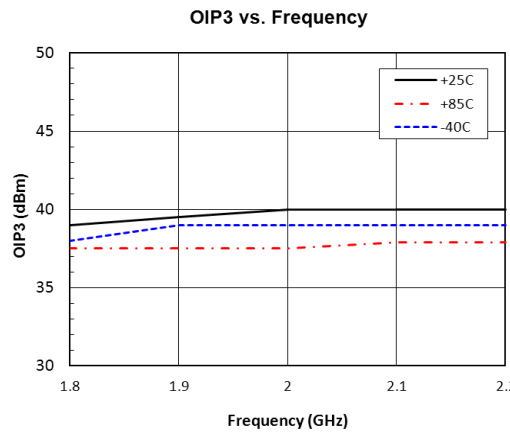
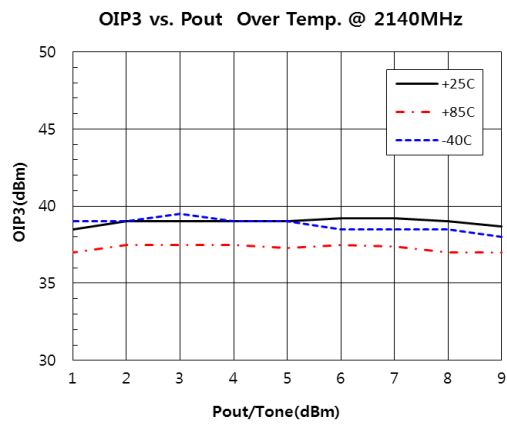
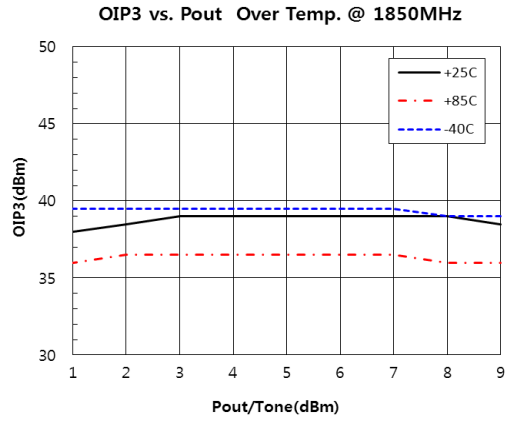
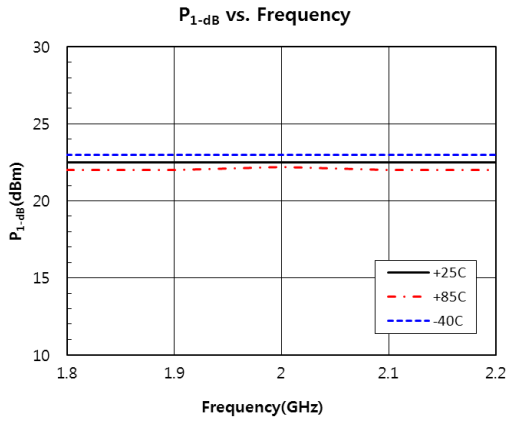
Parameter/Freq.(MHz)	1800	1900	2140	Unit
Small Signal Gain	14.6	14.3	13.4	dB
S11	-13.2	-17.2	-28.0	dB
S22	-13.1	-15.2	-20.0	dB
Output P1dB	22.5	22.5	22.5	dBm
Output OIP3*	39.0	39.5	40.0	dBm
Noise Figure	0.82	0.90	0.95	dB
Ic _q	79			mA
Vcc	5			V

* Pout=6dBm/tone

S-Parameter Over Temperature vs. Freq. at 1800~2200MHz



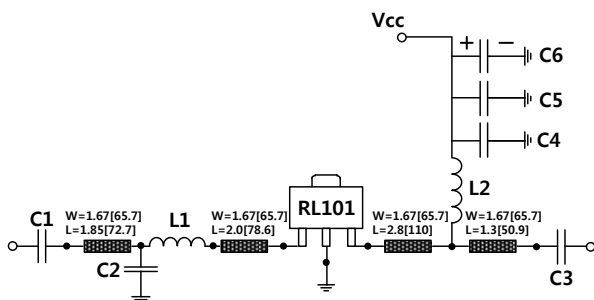
P1dB, OIP3 and Noise Figure Performance at 1800~2200MHz



RL101

50-4000MHz High Linearity Low Noise Amplifier

2300~2700MHz Reference Application Circuit



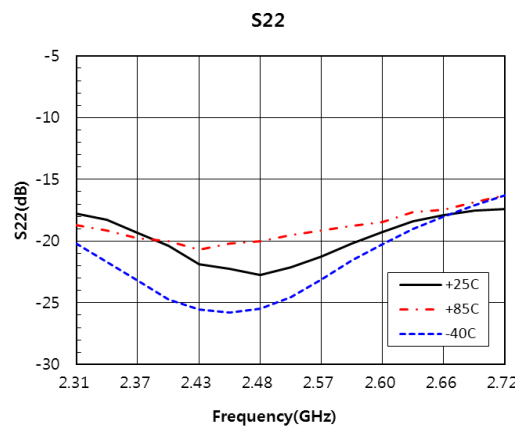
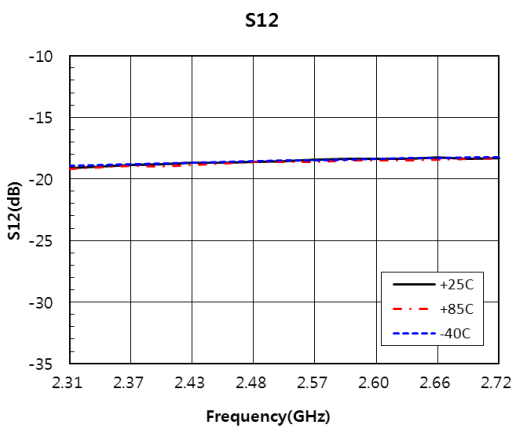
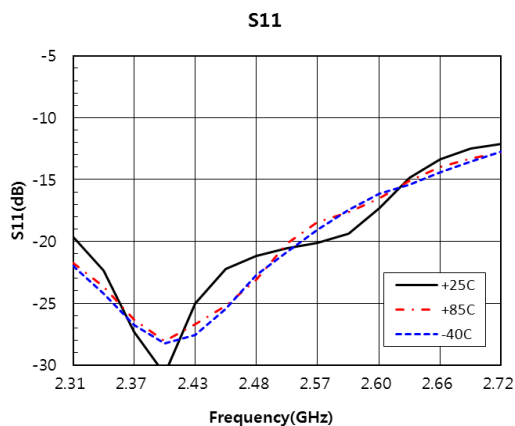
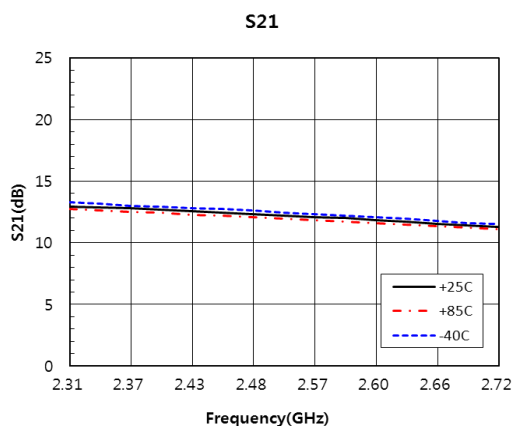
BOM	Value	BOM	Value	BOM	Value
C1	100pF	C4	100pF	L1	NA
C2	1.0pF	C5	1000pF	L2	5.6nH
C3	100pF	C6	10uF		

*Width and Length of Micro-strip line dimension in mm[mil]

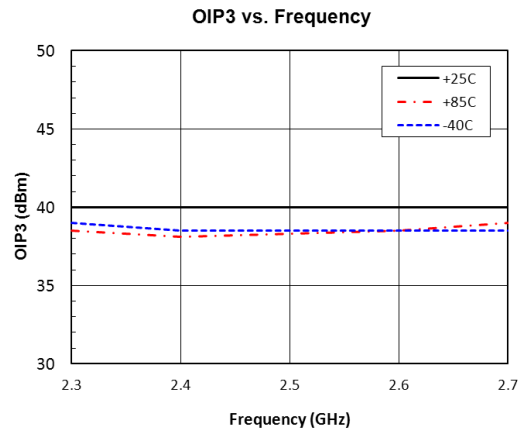
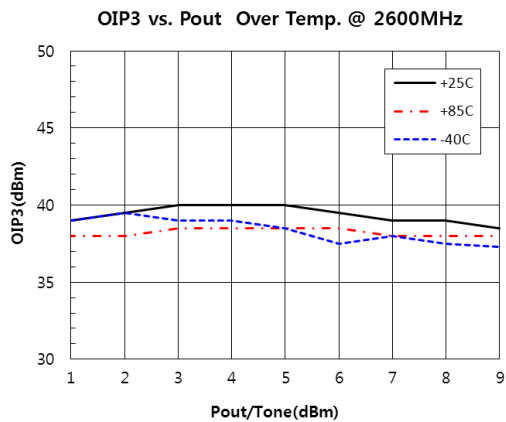
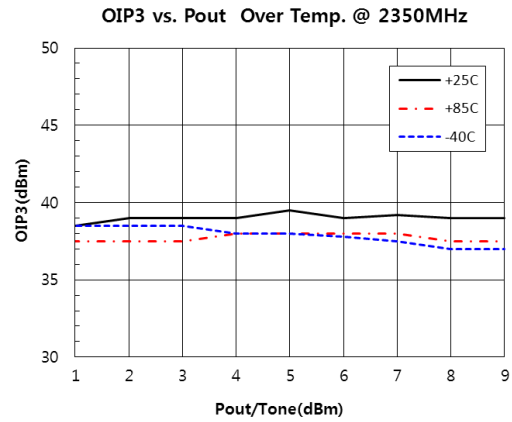
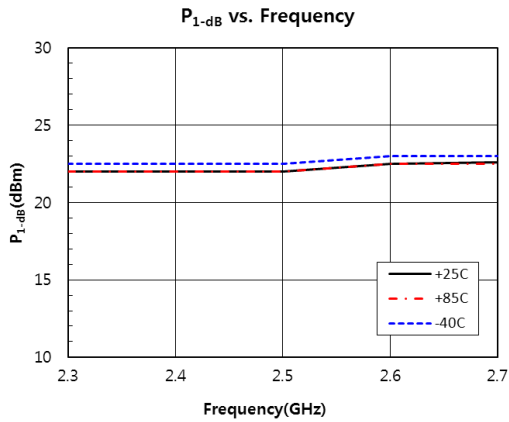
Parameter/Freq.(MHz)	2300	2500	2600	Unit
Small Signal Gain	13.0	12.3	11.8	dB
S11	-19.6	-21.0	-17.3	dB
S22	-17.7	-22.5	-19.2	dB
Output P1dB	22.0	22.0	22.5	dBm
Output OIP3*	40.0	40.0	40.0	dBm
Noise Figure	0.92	0.91	0.95	dB
Icq	79			mA
Vcc	5			V

* Pout=6dBm/tone

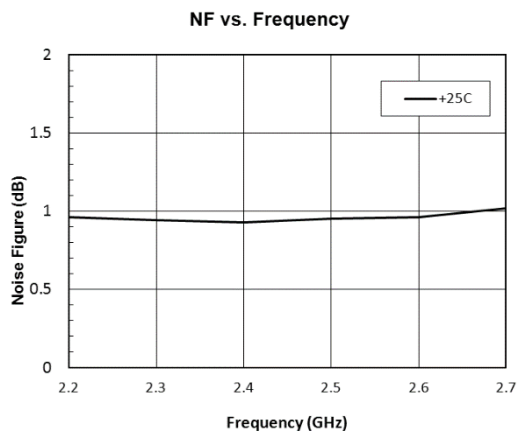
S-Parameter Over Temperature vs. Freq. at 2300~2700MHz



P1dB, OIP3 and Noise Figure Performance at 2300~2700MHz

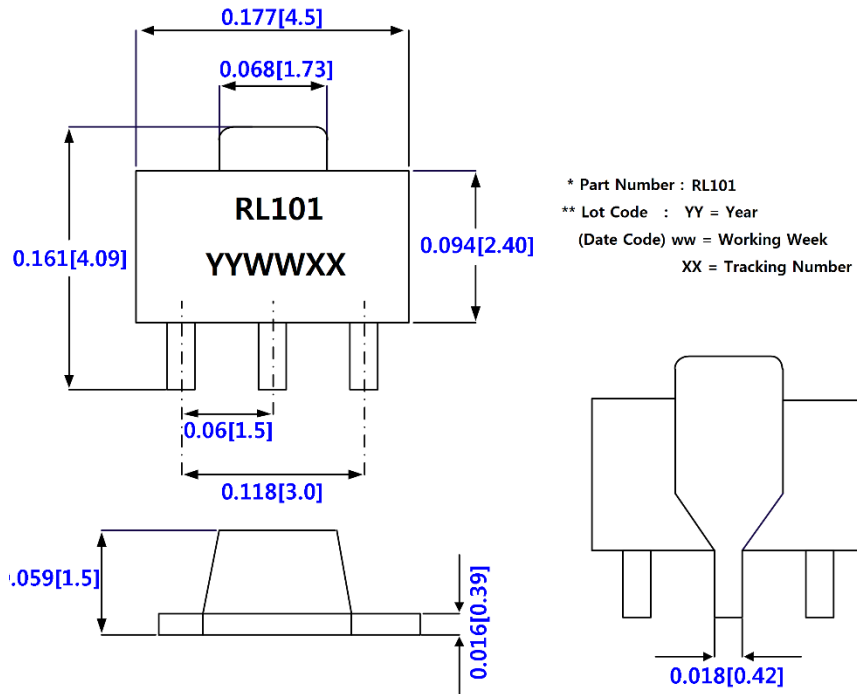


Test condition: Pout 7dBm per tone



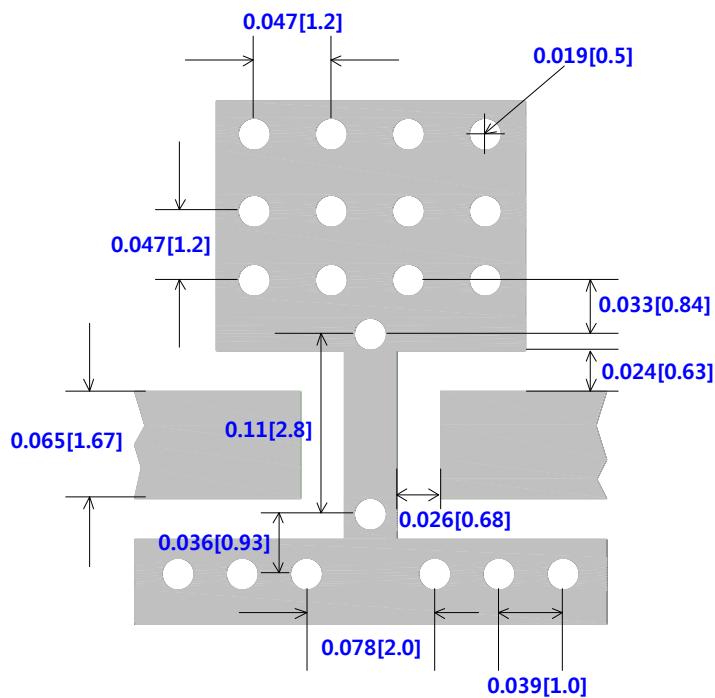
Package Mark and Dimensions

Dimension in inches[Millimeters]

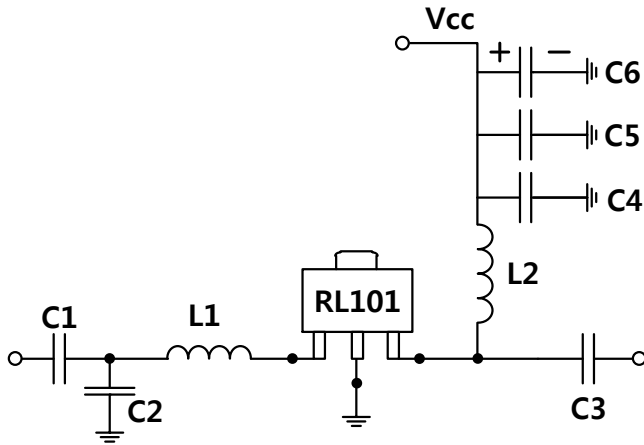


Recommended PCB Pad Pattern

Dimension in inches[Millimeters]

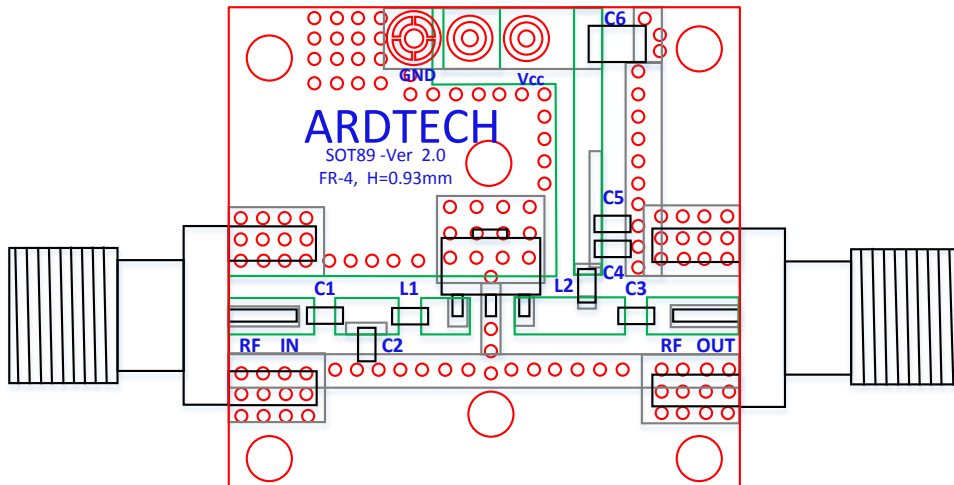


Application Schematic & BOM



Reference BOM Size	
C1	Chip Capacitor, 0603 type
C2	Chip Capacitor, 0603 type
C3	Chip Capacitor, 0603 type
C4	Chip Capacitor, 0603 type
C5	Chip Capacitor, 0603 type
C6	Tantalum Capacitor, 1206 type
L1	Chip Inductor, 0603 type
L2	Chip Inductor, 0603 type

Evaluation PCB Layout



PCB Substrate Information[mm]	
Dielectric Constant	FR-4/4.6
Dielectric Height	0.036[0.93]
Copper Thickness	1 oz.

Product Description

RL102 is a high linearity wide-band low noise amplifier in a low-cost surface mount package and internally matched. RL102 provides 35dBm high OIP3 and 0.95dB Noise Figure at 1.85GHz. RL102 using enhancement pHEMT process is able to achieve high performance across a broad range with low current consumption and is available in a lead-free/green/RoHS-compliant SOT-89 package. RL102 is targeted for use as a receiver and transmitter in wireless infrastructure. Internal active bias circuitry allows RL102 to maintain high linearity and gain performance over temperature and operate directly off a single +5V supply. All devices are 100% RF and DC tested.

Features

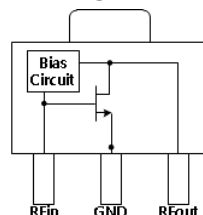
- Full internal matched @ 0.7~3.0GHz
- High OIP3 35dBm @ 1.85GHz
- P1dB=24.0dBm @ 2.14GHz
- Unconditionally stable
- Single fixed 5V supply, 46mA current
- Industry standard SOT-89 package
- Lead-free, RoHS compliant, Green

Applications

- Low noise amplifier for wireless repeaters
- Wireless infrastructure
- Cellular, PCS, GSM, WCDMA, LTE



Component Diagram



Parameter	Specification			Condition	Units
	Min.	Typ.	Max.		
Small Signal Gain	18.9	20.4		850MHz	dB
	14.0	15.5		1850MHz	dB
	13.0	14.5		2140MHz	dB
Output power at 1-dB Compression	19.0	21.0		850MHz	dBm
	21.5	23.5		1850MHz	dBm
Third Order Intercept Point	29.0	31.0		850MHz	dBm
	33.0	35.0		1850MHz	dBm
Input Return Loss		-16.0		2140MHz	dB
Output Return Loss		-18.0		2140MHz	dB
Reverse Isolation		-27.3		850MHz	dB
Noise Figure		0.95		1850MHz	dB
Device Voltage		5			V
Device current (Icq)		46			mA
Thermal Resistance		46.2		Junction to lead	°C/W

Test condition: Vcc=5V, I_p=46mA Typ., OIP₃ Tone Spacing=1MHz, P_{out} per tone=6dBm T_L=25°C, Z_s=Z_L=50

RL102
50-4000MHz
High Linearity Low Noise Amplifier

Absolute Maximum Ratings

Parameter	Rating	Unit
Max Device Voltage(V_D)	6.0	V
Max Device Current(I_D)	65	mA
Max RF Input Power	18	dBm
Max Operating Dissipated Power	0.39	W
Junction Temperature(T_J)	+150	°C
Operating Temperature(T_L)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 0B	
Moisture Sensitivity Level	MSL1	



Typical Electrical Specification

Parameter	850MHz	1850MHz	2140MHz	2600MHz	Unit
S21	20.4	15.5	14.5	12.7	dB
OIP3	31.0	35.0	35.0	36.0	dBm
P1dB	21.0	23.5	24.0	24.6	dBm
S11	-15.0	-16.0	-16.0	-17.7	dB
S22	-11.0	-18.1	-18.0	-15.4	dB
S12	-27.3	-23.4	-22.6	-21.6	dB
NF	1.15	0.95	1.13	1.14	dB

Test condition: $V_{CC}=5V$, $I_D=46mA$ Typ., OIP_3 Tone Spacing=1MHz, P_{out} per tone=6dBm $T_L=25^\circ C$, $Z_S=Z_L=50$

Typical 3.3V Performance

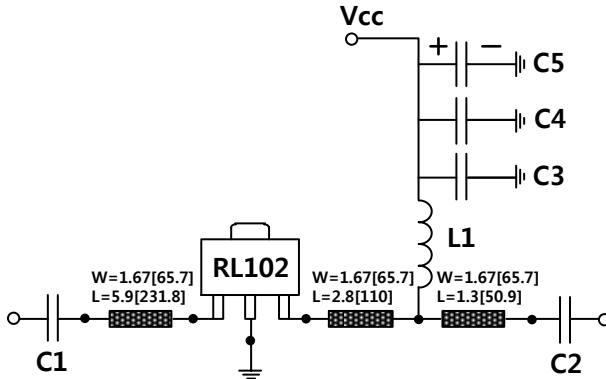
Parameter	850MHz	1850MHz	2140MHz	2600MHz	Unit
S21	19.8	15.2	14.1	12.5	dB
OIP3	25.5	28.4	28.1	29.3	dBm
P1dB	16.0	19.0	19.5	20.0	dBm
S11	-12.3	-14.6	-15.0	-16.8	dB
S22	-10.5	-23.0	-21.7	-18.2	dB
S12	-25.9	-22.0	-21.5	-20.4	dB
NF	1.15	0.95	1.13	1.14	dB

Test condition: $V_{CC}=3.3V$, $I_D=28mA$ Typ., OIP_3 Tone Spacing=1MHz, P_{out} per tone=6dBm $T_L=25^\circ C$, $Z_S=Z_L=50$

RL102

50-4000MHz
High Linearity Low Noise Amplifier

700~1000MHz Reference Application Circuit



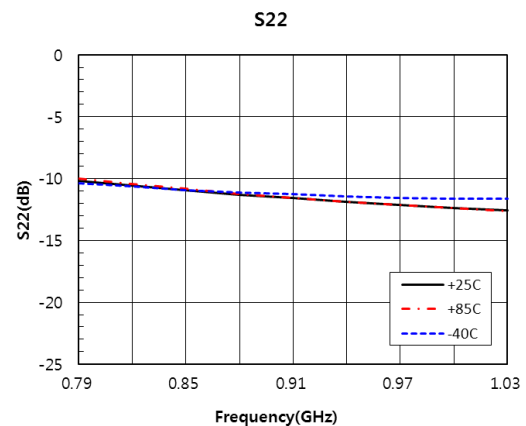
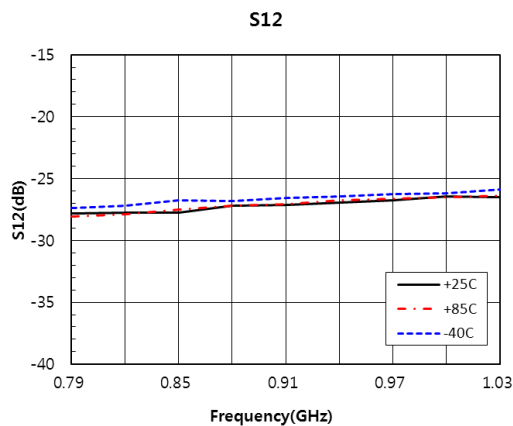
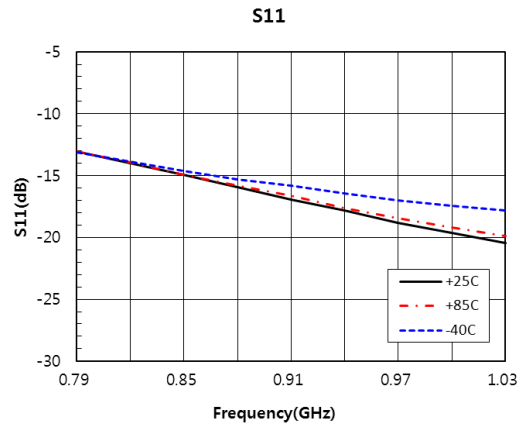
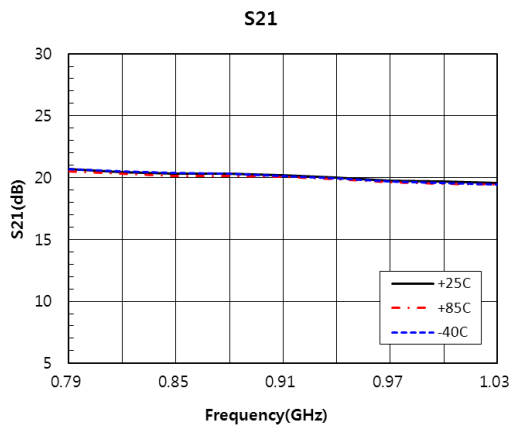
BOM	Value	BOM	Value
C1	100pF	C4	1000pF
C2	100pF	C5	10uF
C3	100pF	L1	22nH

*Width and Length of Micro-strip line dimension in mm[mil]

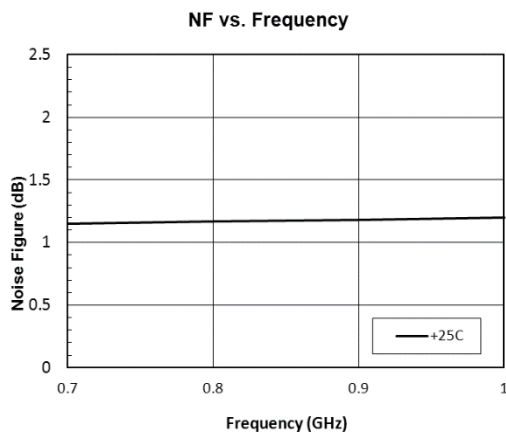
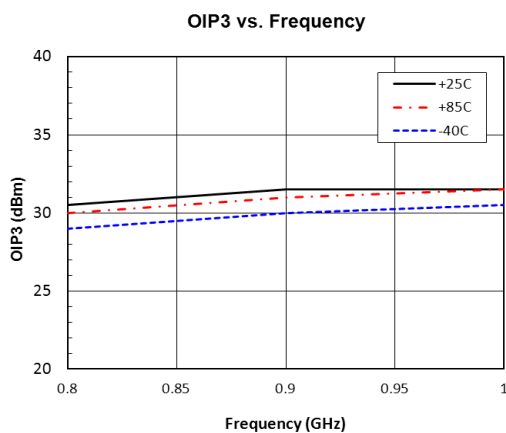
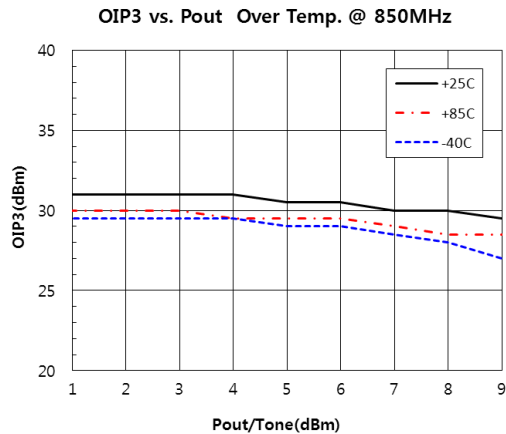
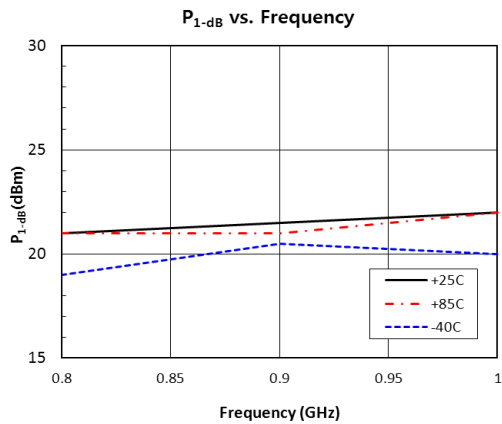
Parameter/Freq.(MHz)	800	850	900	Unit
Small Signal Gain	20.5	20.4	20.2	dB
S11	-13.8	-15.0	-16.9	dB
S22	-10.5	-11.0	-11.5	dB
Output P1dB	21.0	21.5	21.5	dBm
Output OIP3*	31.0	31.0	31.0	dBm
Noise Figure	1.27	1.28	1.24	dB
Ic _q	46			mA
Vcc	5			V

* P_{out}=6dBm/tone

S-Parameter Over Temperature vs. Freq. at 800~1000MHz



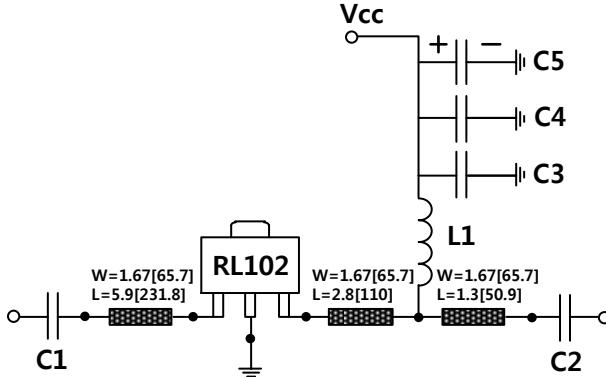
P1dB, OIP3 and Noise Figure Performance at 800~1000MHz



RL102

50-4000MHz High Linearity Low Noise Amplifier

1800~2200MHz Reference Application Circuit



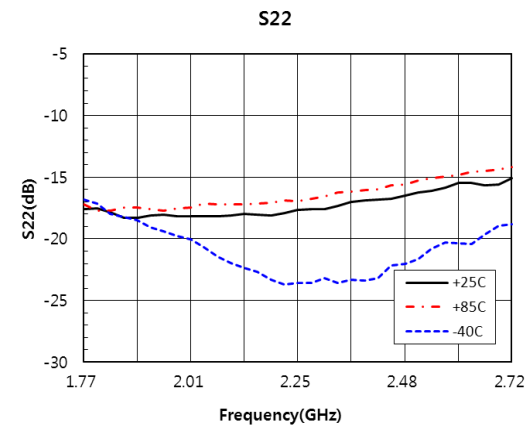
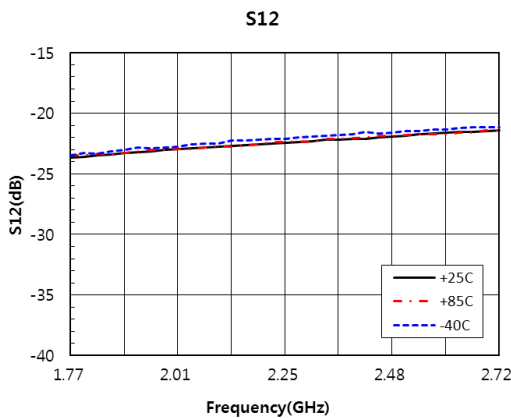
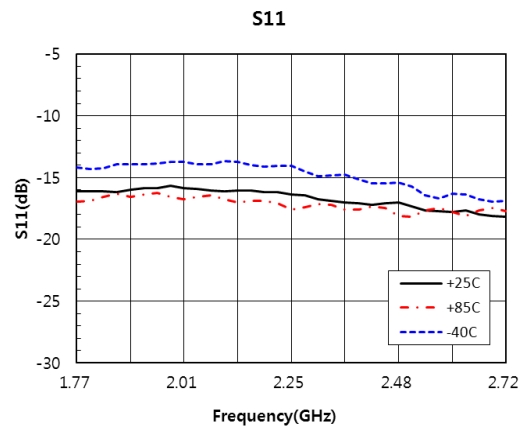
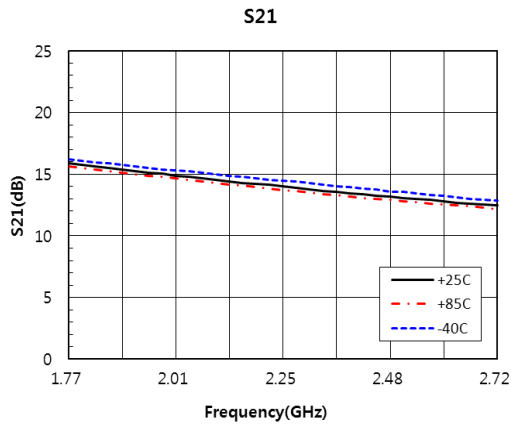
BOM	Value	BOM	Value
C1	100pF	C4	1000pF
C2	100pF	C5	10uF
C3	100pF	L1	12nH

*Width and Length of Micro-strip line dimension in mm[mil]

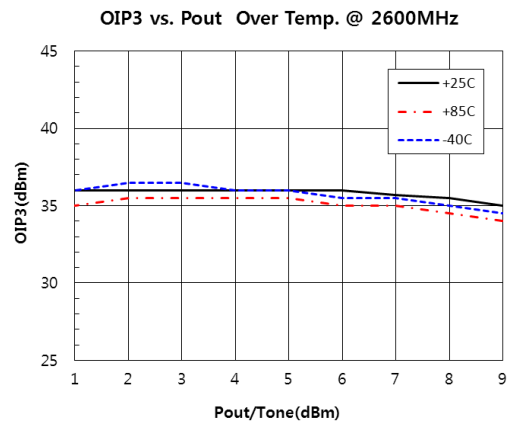
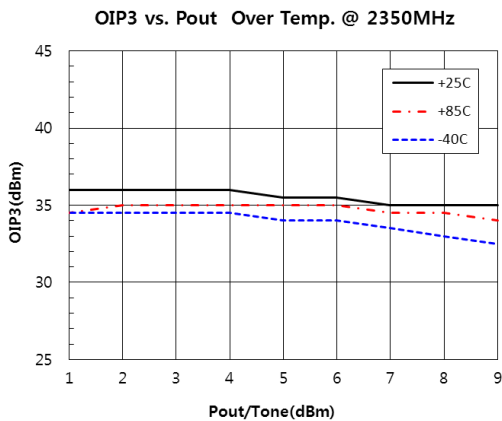
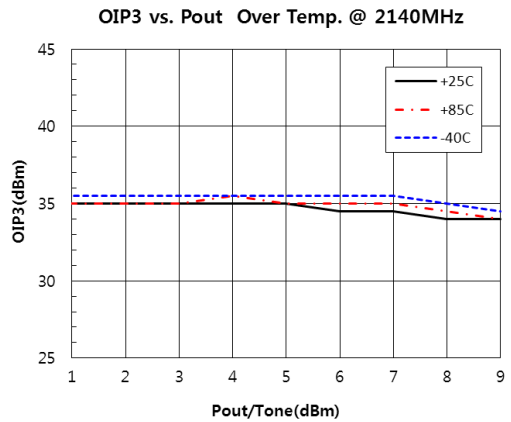
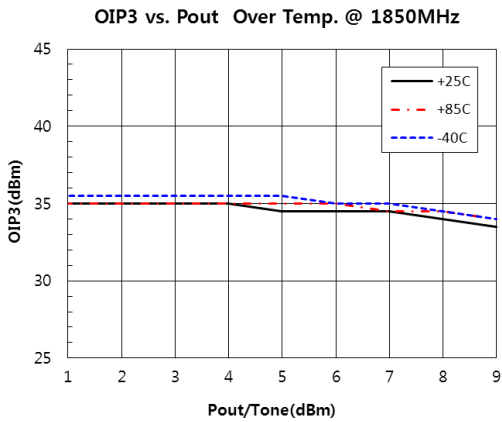
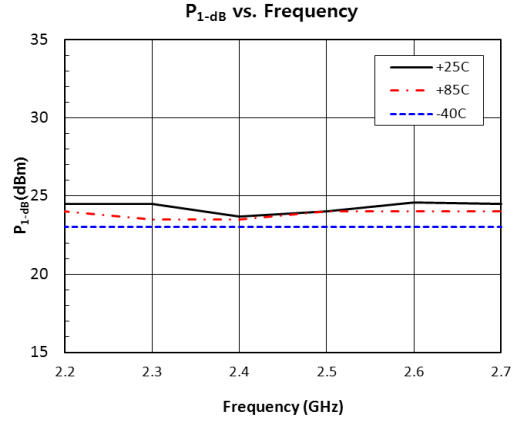
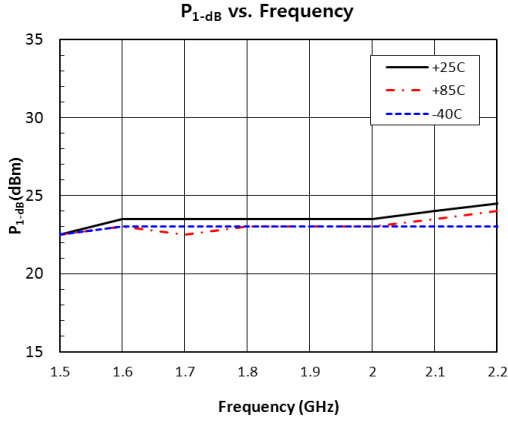
Parameter/Freq.(MHz)	1850	2140	2600	Unit
Small Signal Gain	15.5	14.5	12.7	dB
S11	-16.0	-16.0	-17.7	dB
S22	-18.0	-18.0	-15.4	dB
Output P1dB	23.5	24.0	24.6	dBm
Output OIP3*	35.0	35.0	36.0	dBm
Noise Figure	0.95	1.13	1.14	dB
Ic _q	46			mA
Vcc	5			V

* Pout=6dBm/tone

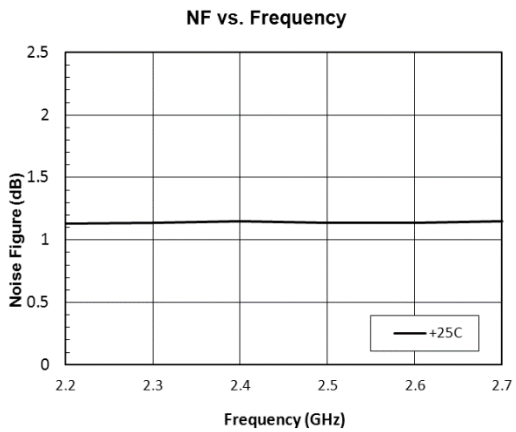
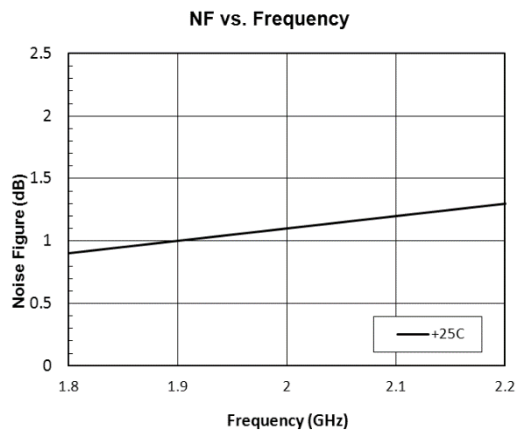
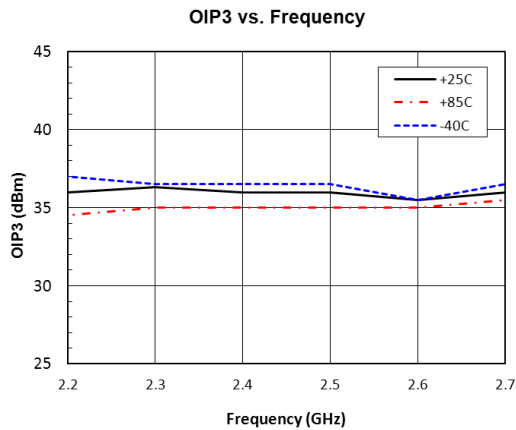
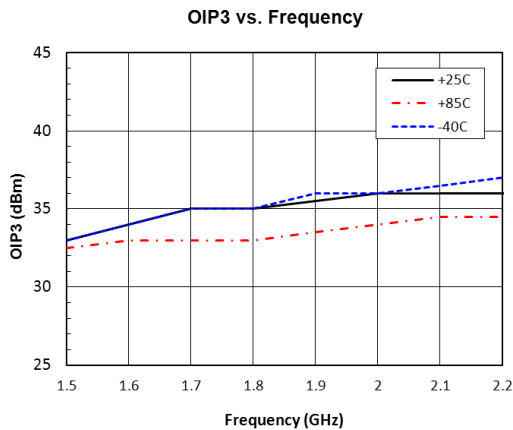
S-Parameter Over Temperature vs. Freq. at 1800~2600MHz



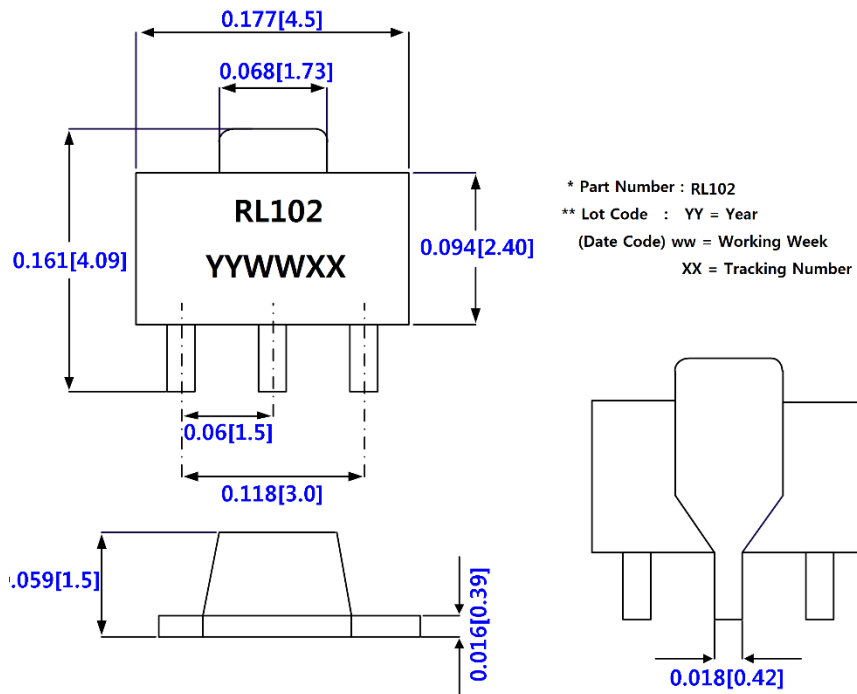
P1dB, OIP3 and Noise Figure Performance at 1800~2600MHz



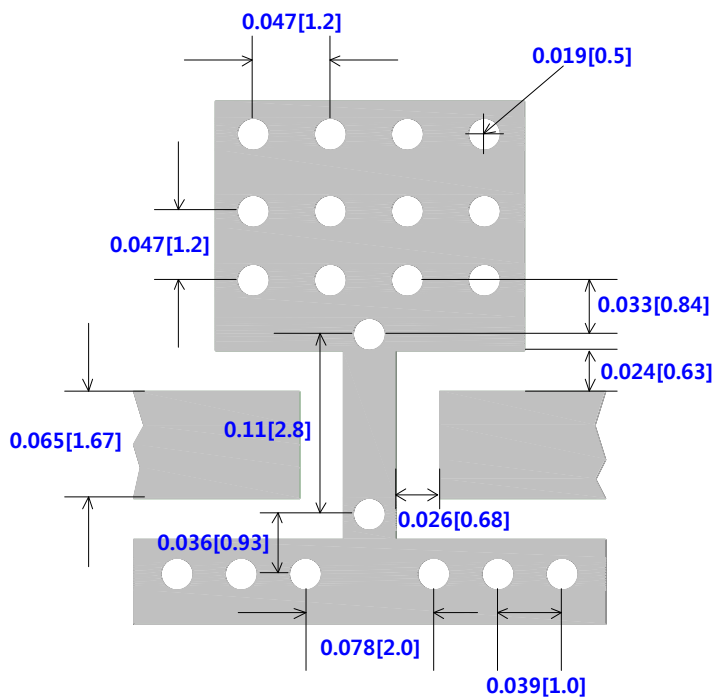
P1dB, OIP3 and Noise Figure Performance at 1800~2600MHz



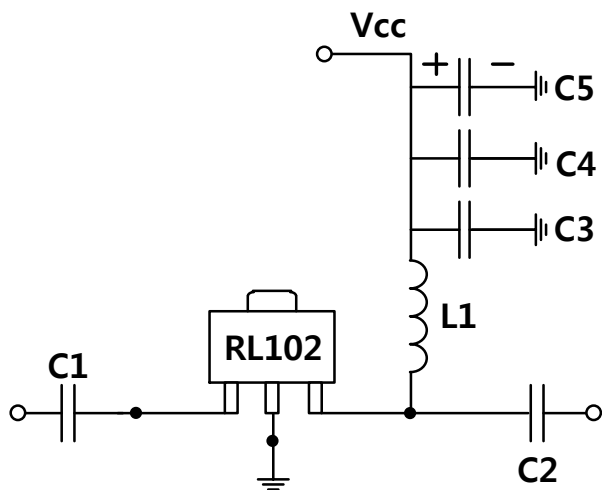
Package Mark and Dimensions
 Dimension in inches[Millimeters]



Recommended PCB Pad Pattern
 Dimension in inches[Millimeters]

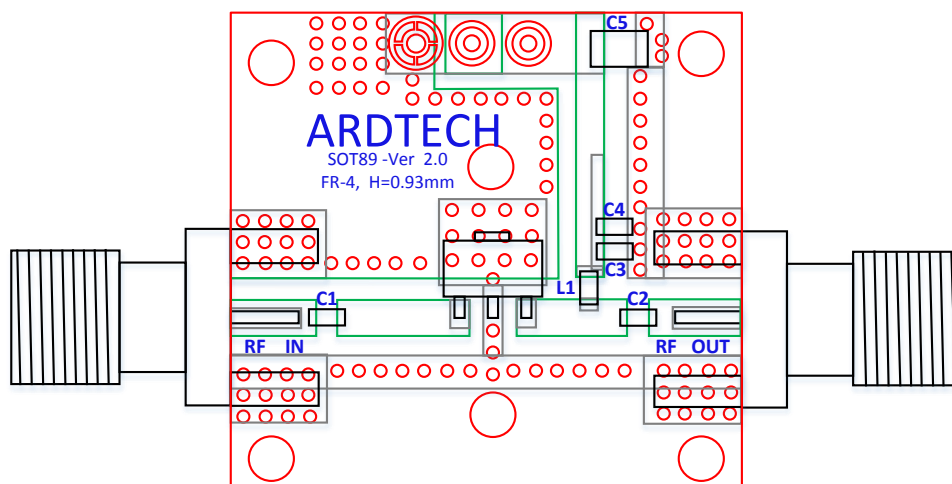


Application Schematic & BOM



Reference BOM Size	
C1	Chip Capacitor, 0603 type
C2	Chip Capacitor, 0603 type
C3	Chip Capacitor, 0603 type
C4	Chip Capacitor, 0603 type
C5	Tantalum Capacitor, 1206 type
L1	Chip Inductor, 0603 type

Evaluation PCB Layout



PCB Substrate Information[mm]	
Dielectric Constant	FR-4/4.6
Dielectric Height	0.036[0.93]
Copper Thickness	1 oz.

RL102
50-4000MHz
High Linearity Low Noise Amplifier



NOTE

HIGH IIP3 UP-CONVERTOR With INTEGRATED RF & IF AMPLIFIER, 700 – 1200MHz

Product Description

RUC093 is a highly integrated up-converter IC that operates from 0.7 to 1.2 GHz. It incorporates a high dynamic ranged and single-balanced mixer core with integrated RF Amplifier, Local Amplifier and IF amplifiers. This integration makes RUC093 ideal for compact transceiver applications such as PCS, GSM, WCDMA, TD-SCDMA, WiMAX and LTE Repeaters and Base Stations.

This product provides high dynamic range performance in a low profile lead-free / RoHS-compliant Quad Flat No-Lead (QFN) 4x4 mm package. RUC093 is implemented with reliable and mature GaAs pHEMT and InGaP HBT technology.

Features

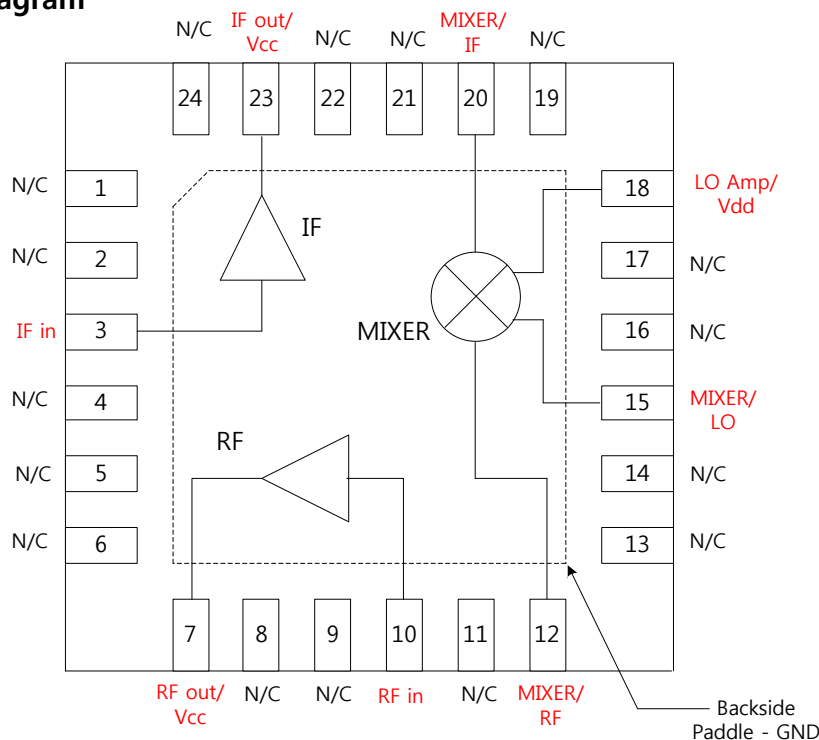
- High dynamic range up-converter with integrated LO , IF, & RF amps
- RF: 700 – 1200 MHz
- IF: DC – 350 MHz
- + 33.4 dBm Output IP3 @0.8GHz of RF Amplifier
- + 20.5 dBm Output P1dB @ RF Amplifier
- Pb- free 4mm 24-pin QFN package
- Low- side LO configuration



Applications

- High Dynamic Range Infrastructure
- CDMA, GSM & TDMA
- CDMA2000, WCDMA
- EDGA 2.5G&3G mobile base transceiver stations
- Cable Modem Termination Systems

Component Diagram



RUC093

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 700 – 1200MHz



Typical Electrical Specification

Parameter	IF Amplifier	Mixer	RF Amplifier	Units
Frequency Range. RF	-	0.7 – 1.2	-	GHz
Frequency Range. LO	-	0.7 – 1.2	-	GHz
Frequency Range. IF	DC – 350			MHz
Conversion Loss	-	10.0	-	dB
Noise Figure(SSB)	-	10.0	-	dB
LO to RF Isolation	-	-13.2	-	dB
LO to IF Isolation	-	-22.0	-	dB
RF to IF Isolation	-	-12.6	-	dB
IP3(Input)	-	27.8	-	dBm
Pin1dB	-	24.0	-	dBm
LO Input Drive Level(Typical)	0			dBm
Small Signal Gain@140MHz/0.8GHz	18.6	-	23.5	dB
Input Return Loss@140MHz/0.8GHz	-17.1	-	-18.0	dB
Output Return Loss@140MHz/0.8GHz	-25.0	-	-18.4	dB
Third Order Intercept Point @70MHz/0.8GHz	45.5	-	33.4	dBm
Output power at 1-dB Compression	24.3	-	20.5	dBm
Noise Figure	4.6	-	2.9	dB
Device Voltage	5			V
Device current (Icq)	184			mA

Test condition: Vcc=5V, I_b=184mA, Typ., LO = 0dBm, IF = 140MHz, T_L=25°C, Z_s=Z_L=50

RUC093

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 700 – 1200MHz

Absolute Maximum Ratings

Parameter	Rating	Unit
Max RF/IF Input Power	27	dBm
Max LO Drive Input Power	10	dBm
Max Device Voltage(V_D)	6.5	V
Max Operating Dissipated Power	0.5	W
Junction Temperature(T_J)	150	°C
Operating Temperature(T_L)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 0B	
Moisture Sensitivity Level	MSL1	

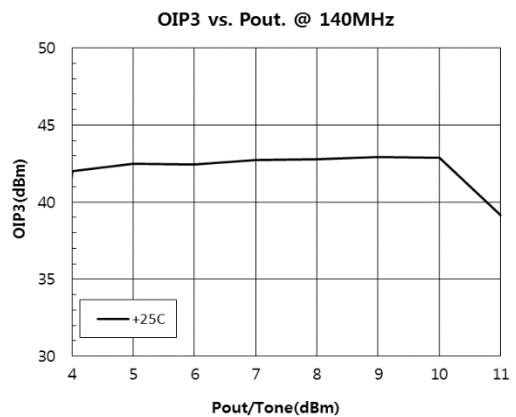
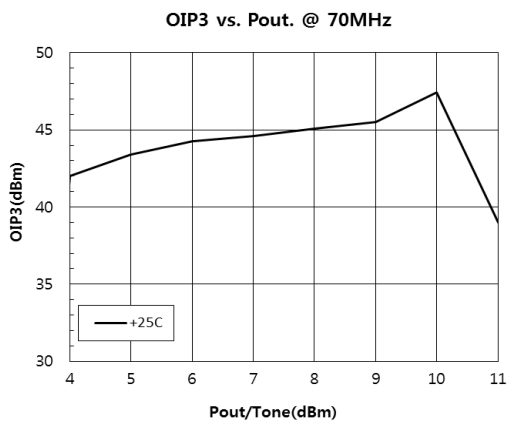
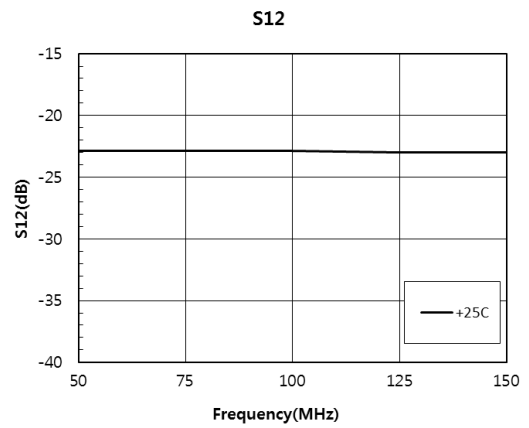
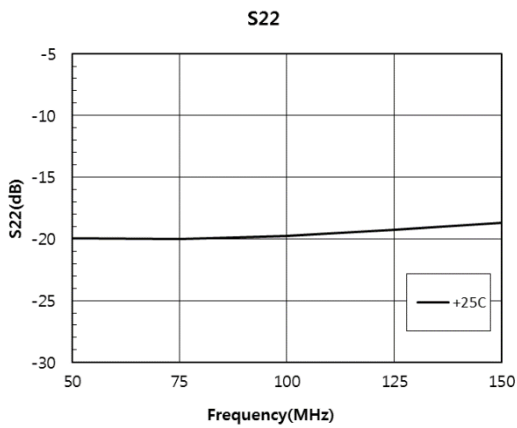
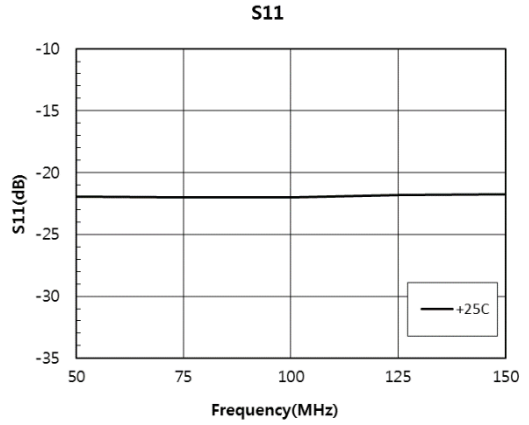
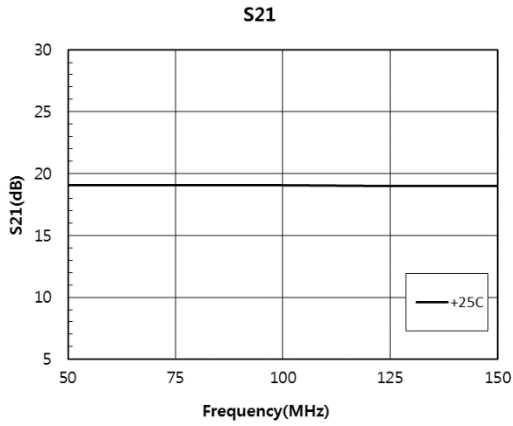


RUC093

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 700 – 1200MHz



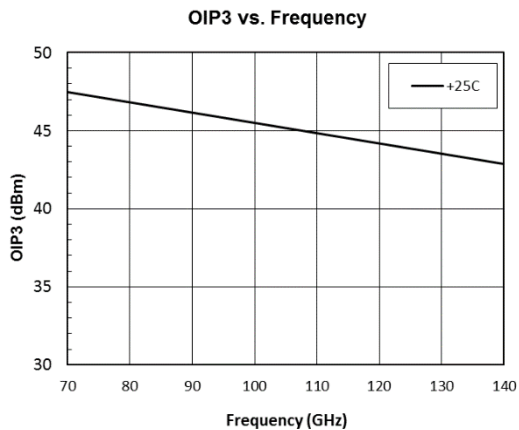
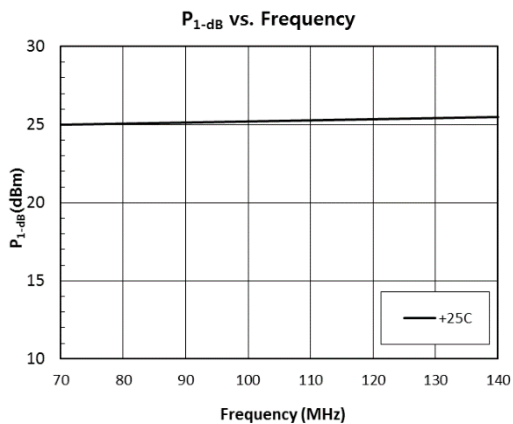
IF Amplifier Performance



RUC093

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 700 – 1200MHz

IF Amplifier Performance

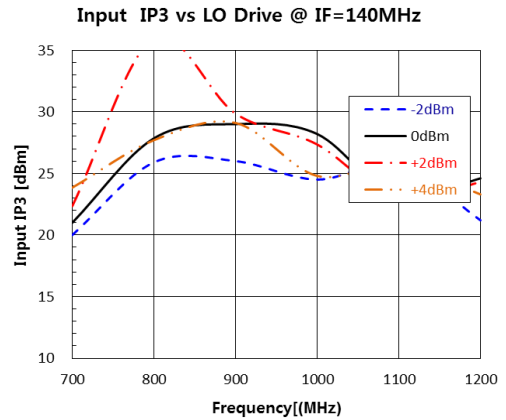
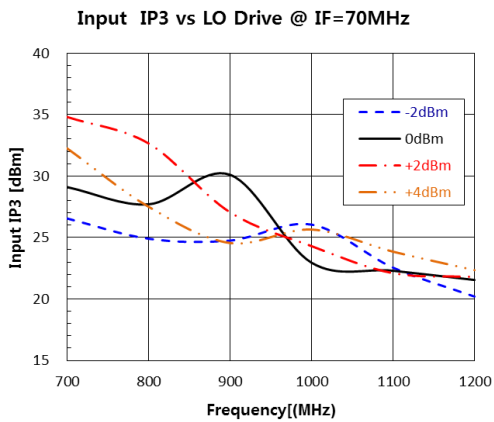
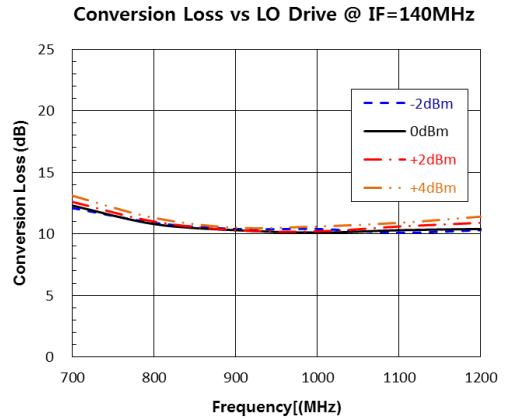
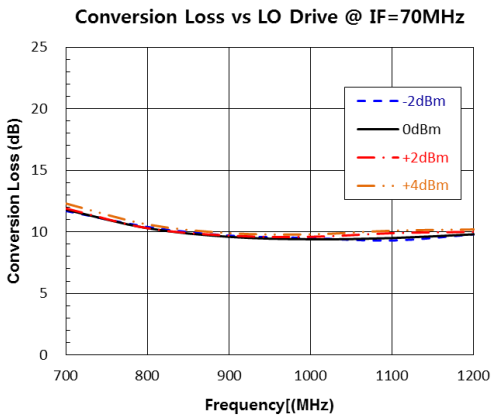
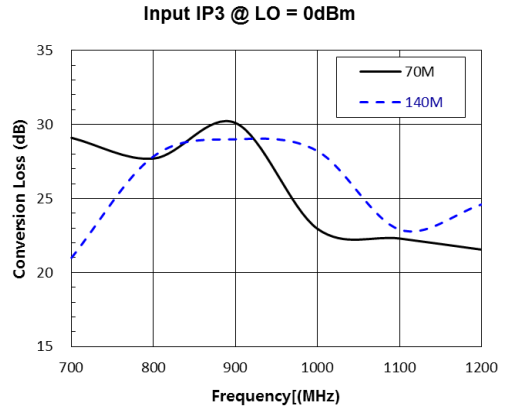
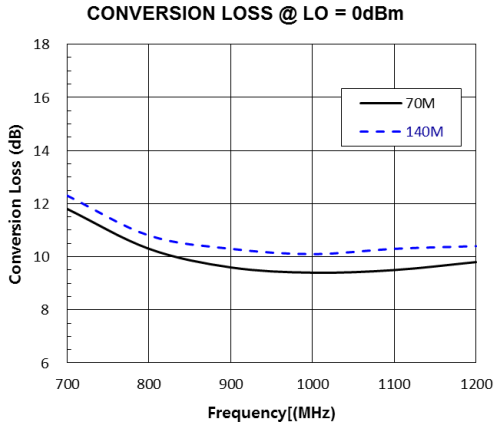


RUC093

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 700 – 1200MHz



Mixer MMIC Performances



RUC093

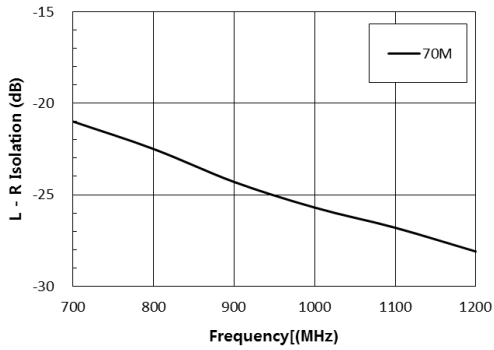
HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 700 – 1200MHz



Mixer MMIC Performance

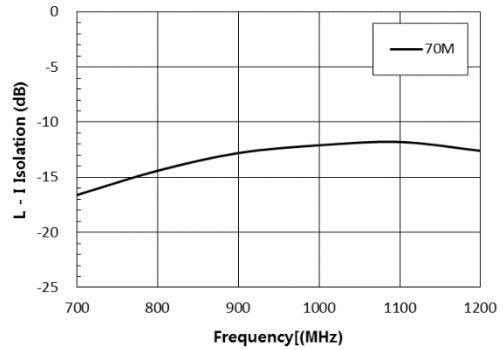
LO to RF Isolation vs. LO Freq

Referenced with LO = 0dBm



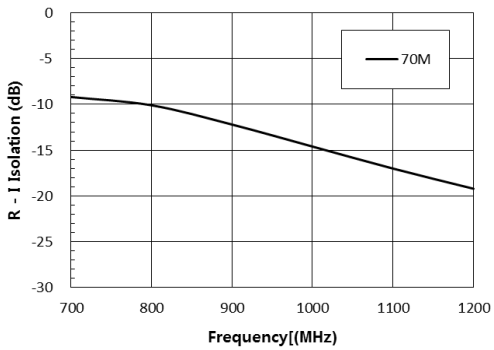
LO to IF Isolation vs. LO Freq

Referenced with LO = 0dBm



RF to IF Isolation vs. LO Freq

Referenced with LO = 0dBm

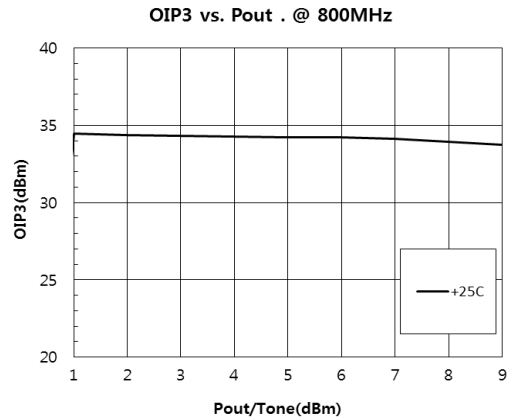
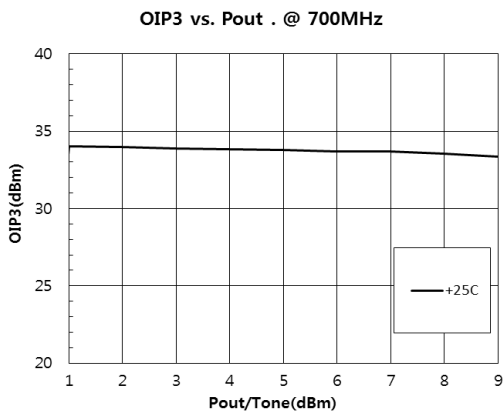
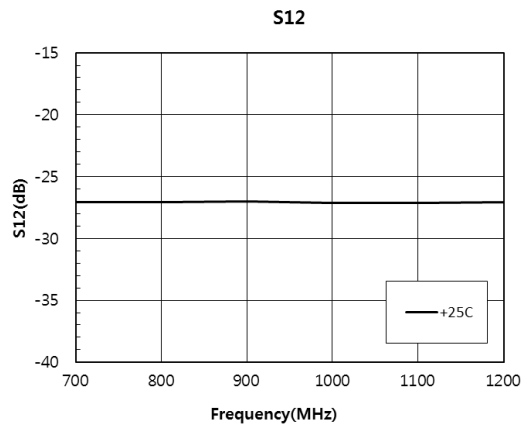
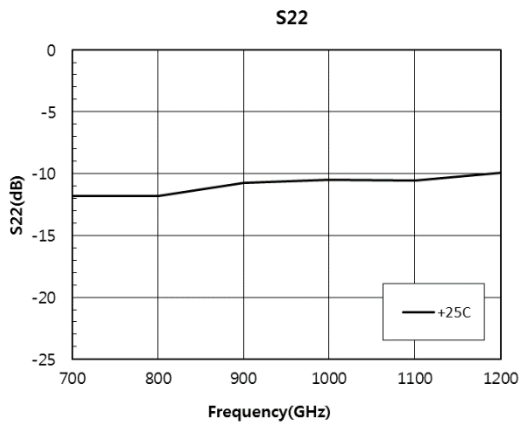
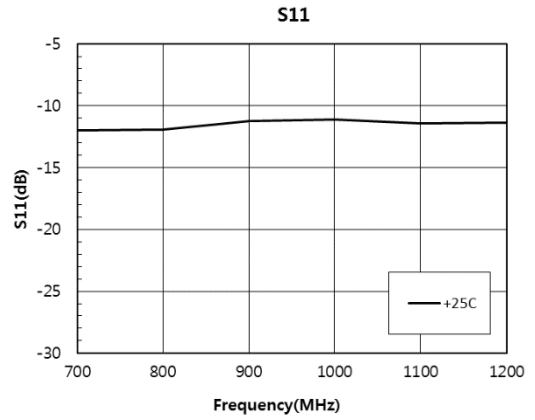
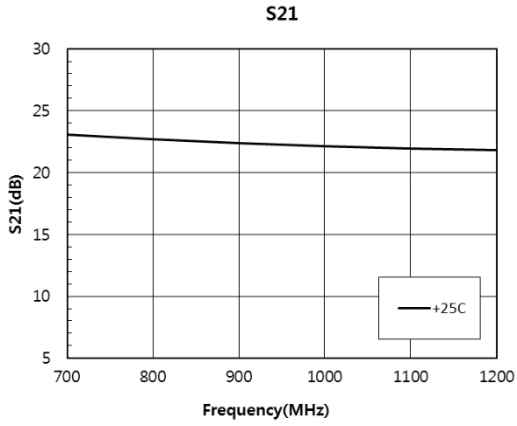


RUC093

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 700 – 1200MHz



RF MMIC Amplifier Performance

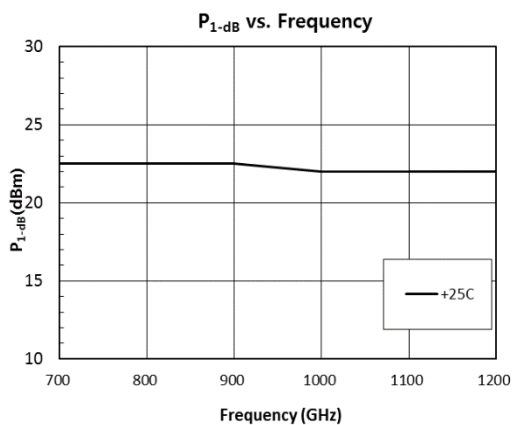
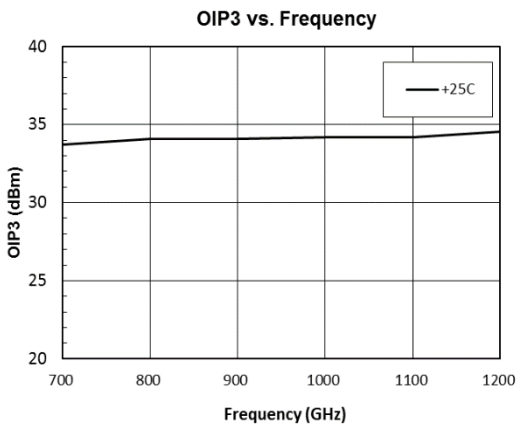
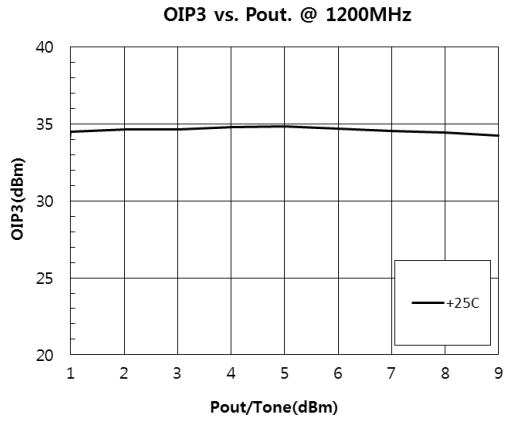
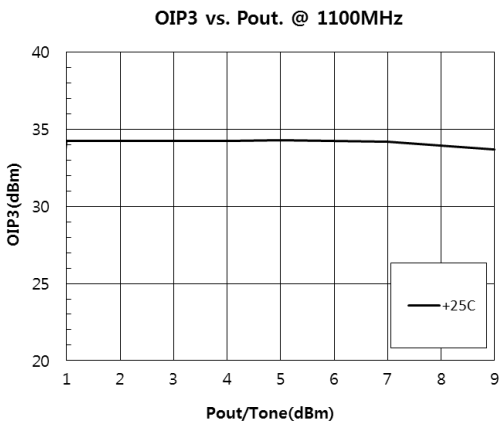
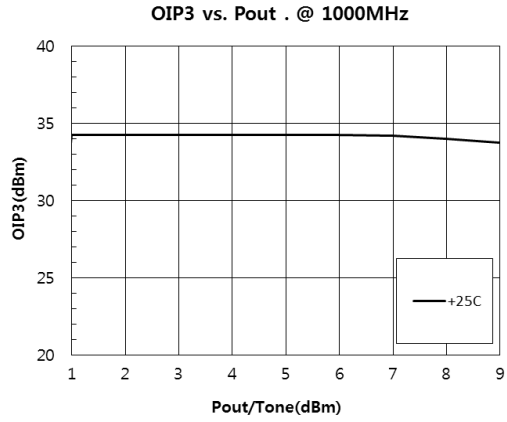
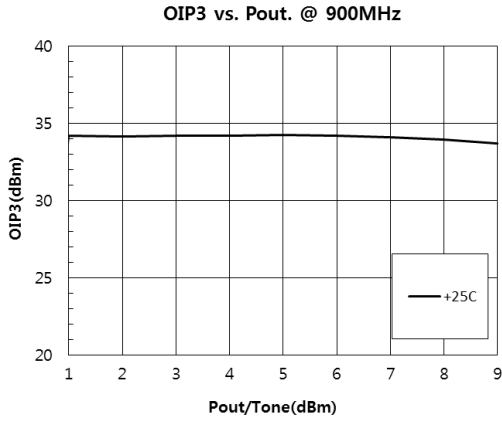


RUC093

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 700 – 1200MHz



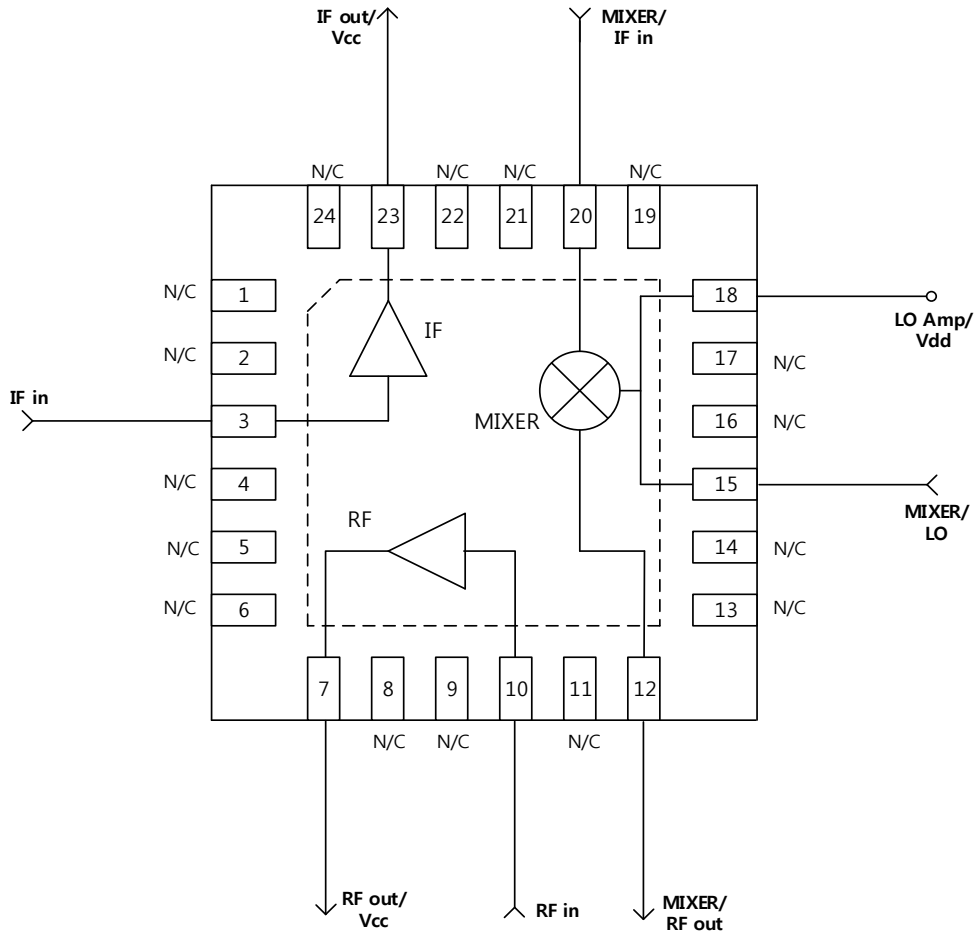
RF MMIC Amplifier Performance



RUC093

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 700 – 1200MHz

Pin Configuration and Description



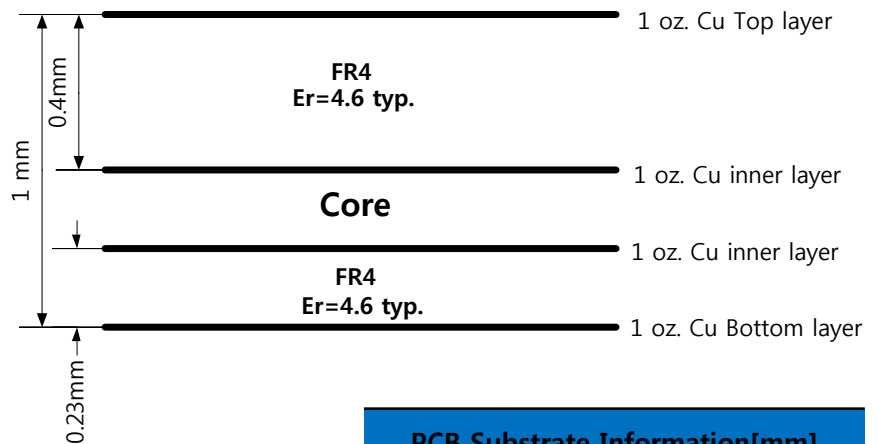
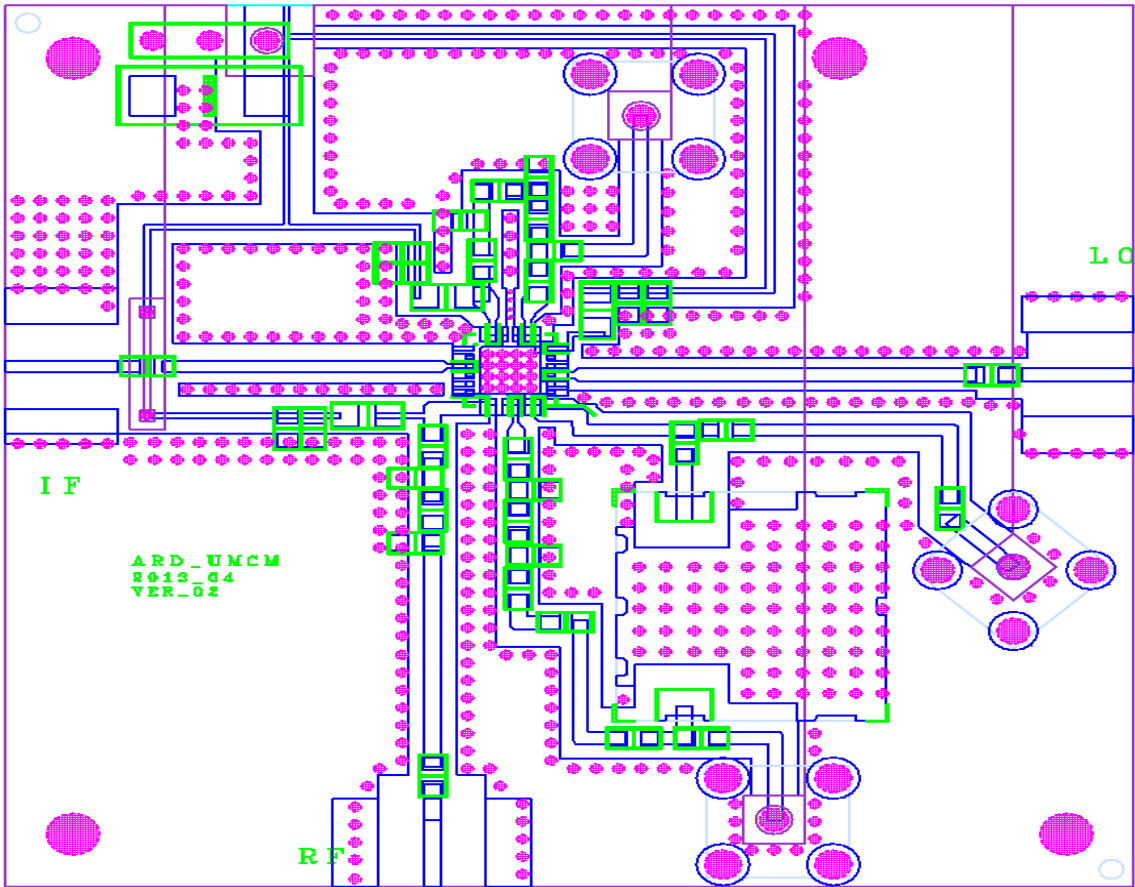
Pin No.	Description
3	IF amplifier signal input
7	RF amplifier RF out/DC bias
10	RF amplifier RF input
12	Mixer RF signal output
15	Mixer Local oscillator signal input
18	Mixer integrated LO amplifier DC bias
20	Mixer IF signal input
23	IF amplifier signal out/DC bias

RUC093

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 700 – 1200MHz



Evaluation PCB

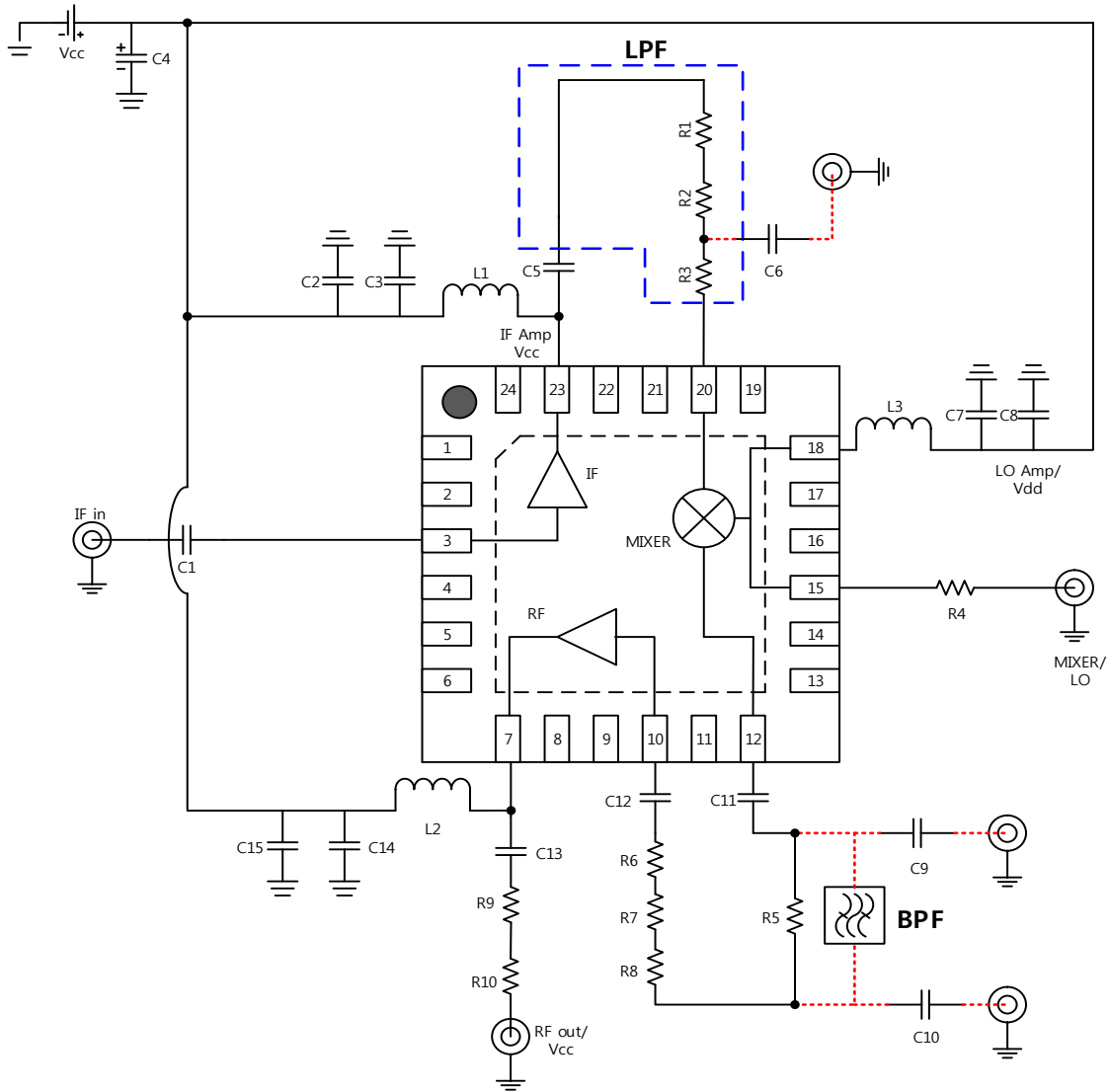


PCB Substrate Information[mm]	
Dielectric Constant	FR-4/4.6
Dielectric Height	0.015[0.4]
Copper Thickness	1 oz.

RUC093

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 700 – 1200MHz

Evaluation PCB



Item	Value	Description
C1, C5,	8200pF	DC-block capacitor/Chip capacitor, 0603 type
C3, C6, C7, C9, C10, C11, C12, C13, C14	100pF	DC-block or By-pass capacitor/Chip capacitor, 0603 type
C4	10uF	Tantalum capacitor, 1206 type
C2, C8, C15	0.1uF	By-pass capacitor/Chip capacitor, 0603 type
L1	680nH	IF Choke inductor/Chip inductor, 0603 type
L2	33nH	RF Choke inductor/Chip inductor, 0603 type
L3	33nH	Mixer Choke inductor/Chip inductor, 0603 type
R1 ~ R10	0 ohm	0 ohm resistor/Chip resistor, 0603 type

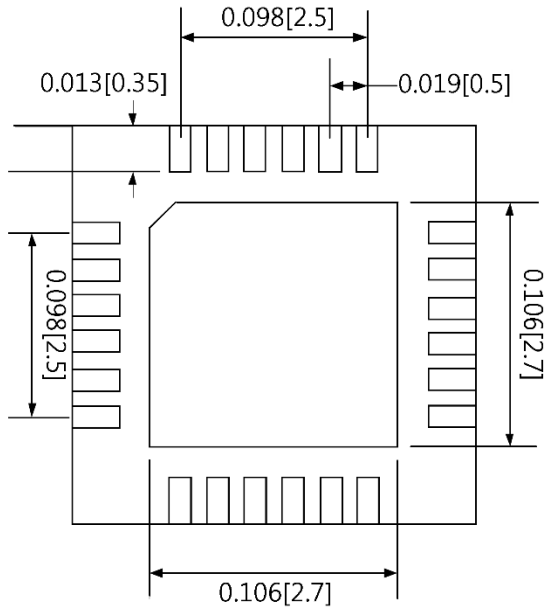
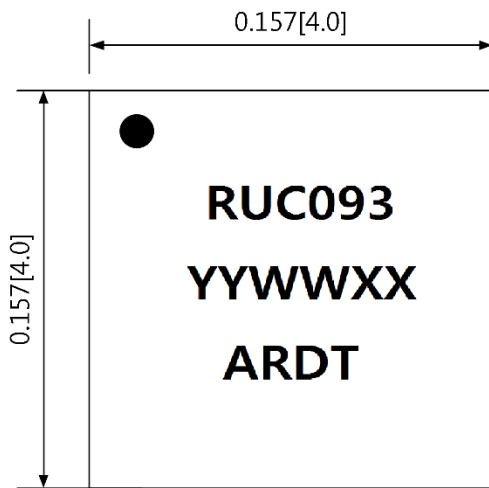
RUC093

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 700 – 1200MHz



Package Mark and Dimensions

Dimension in inches[Millimeters]

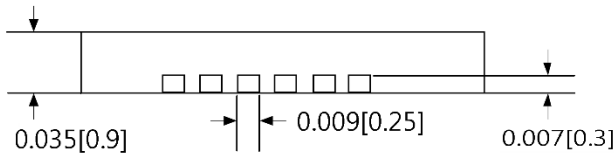


* Part Number : RUC093

**Lot Code : YY = Year

ww = Working Week

XX = Tracking Number



Note

1. All dimensions are in inches[millimeters]. Angles are in degrees.
2. Lead Frame Material : Copper Alloy.
3. The package Top be smaller than the package Bottom

RUC093

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 700 – 1200MHz



NOTE

**HIGH IIP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 700 – 1200MHz**

Product Description

RDC095 is a highly integrated down-converter IC that operates from 0.7 to 1.2 GHz. It incorporates a high dynamic ranged and single-balanced mixer core with integrated Low Noise Amplifier, Local Amplifier and IF amplifiers. This integration makes RDC095 ideal for compact receiver applications such as PCS, GSM, WCDMA, TD-SCDMA, WiMAX and LTE Repeaters and Base Stations.

This product provides high dynamic range performance in a low profile lead-free / RoHS-compliant Quad Flat No-Lead (QFN) 4x4 mm package. The RDC095 is implemented with reliable and mature GaAs pHEMT and InGaP HBT technology.

Features

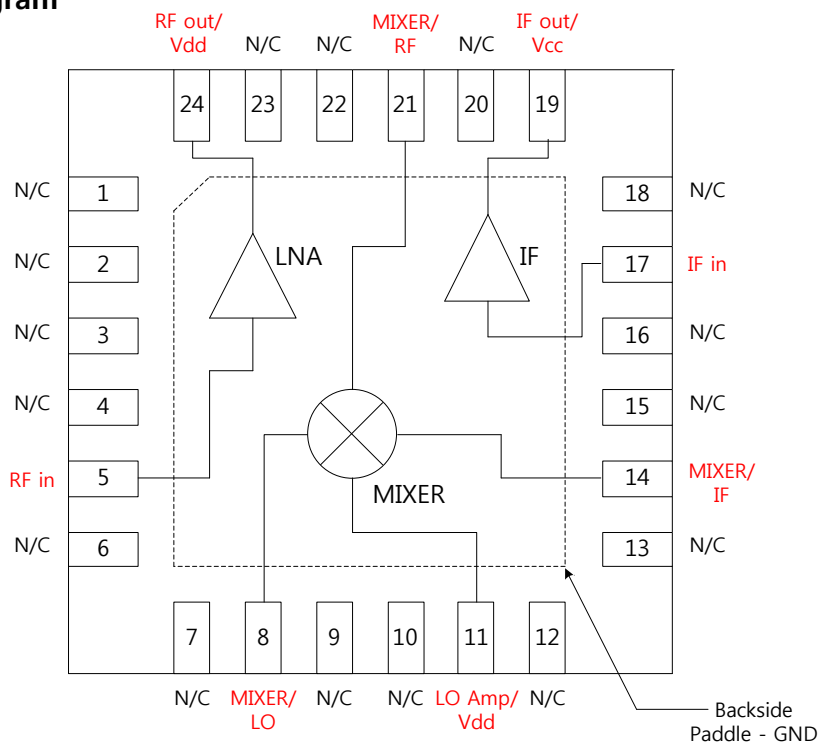
- High dynamic range down-converter with integrated LO , IF, & RF amplifiers
- RF:700 – 1200 MHz
- IF: DC – 350 MHz
- + 45.5 dBm Output IP3 at IF Amplifier
- + 24.0 dBm Output P1dB at IF Amplifier
- Pb- free 4mm 24-pin QFN package
- Low- side LO configuration

Applications

- High Dynamic Range Infrastructure
- CDMA, GSM & TDMA
- CDMA2000, WCDMA
- EDGA 2.5G&3G mobile base transceiver stations
- Cable Modem Termination Systems



Component Diagram



RDC095

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 700 – 1200MHz



Typical Electrical Specification

Parameter	Low Noise Amplifier	Mixer	IF Amplifier	Units
Frequency Range. RF	-	0.7 – 1.2	-	GHz
Frequency Range. LO	-	0.7 – 1.2	-	GHz
Frequency Range. IF	DC – 350			MHz
Conversion Loss	-	10.0	-	dB
Noise Figure(SSB)	-	10.0	-	dB
LO to RF Isolation	-	-13.2	-	dB
LO to IF Isolation	-	-22.0	-	dB
RF to IF Isolation	-	-12.6	-	dB
IP3(Input)	-	27.8	-	dBm
Pin1dB	-	24.0	-	dBm
LO Input Drive Level(Typical)	0			dBm
Small Signal Gain@0.85GHz/70MHz	20.4	-	18.8	dB
Input Return Loss@0.85GHz/70MHz	-16.0	-	-17.1	dB
Output Return Loss@0.85GHz/70MHz	-18.0	-	-25.0	dB
Third Order Intercept Point @0.85GHz/70MHz	31.0	-	45.5	dBm
Output power at 1-dB Compression	21.0	-	24.0	dBm
Noise Figure	0.95	-	4.6	dB
Device Voltage	5			V
Device current (Icq)	164			mA

Test condition: Vcc = 5V, I_b=164mA, Typ., LO = 0dBm, IF = 70MHz, T_L=25°C, Z_s=Z_L=50

RDC095

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 700 – 1200MHz

Absolute Maximum Ratings

Parameter	Rating	Unit
Max RF/IF Input Power	27	dBm
Max LO Drive Input Power	10	dBm
Max Device Voltage(V_D)	6.5	V
Max Operating Dissipated Power	0.5	W
Junction Temperature(T_J)	150	°C
Operating Temperature(T_L)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 0B	
Moisture Sensitivity Level	MSL1	

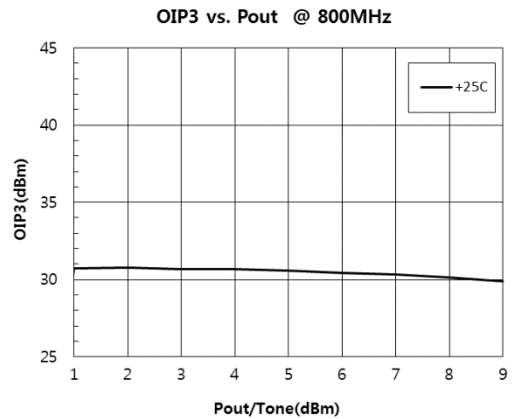
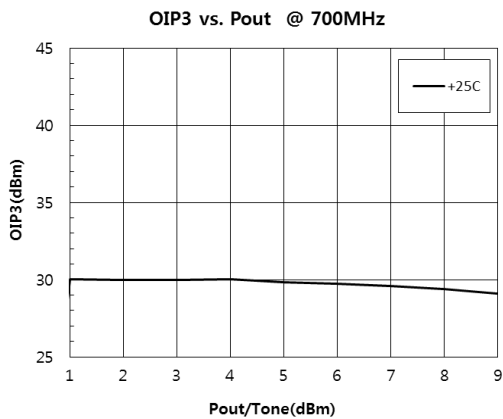
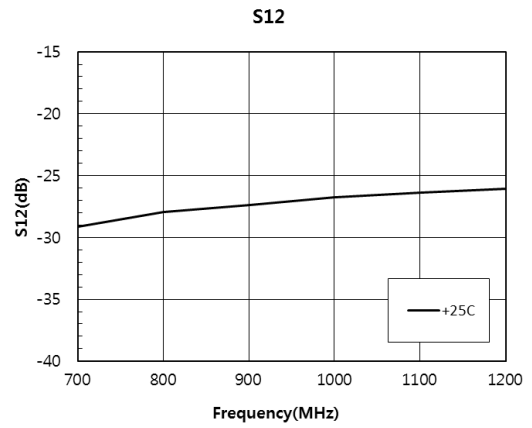
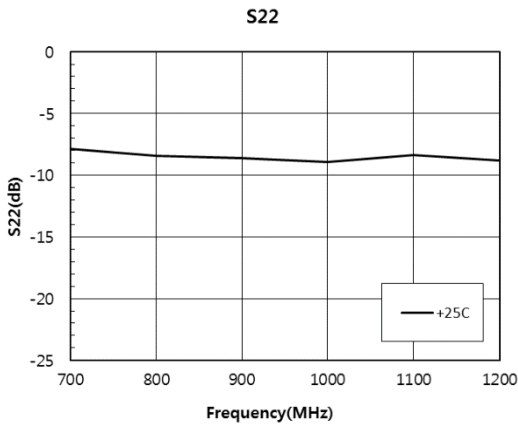
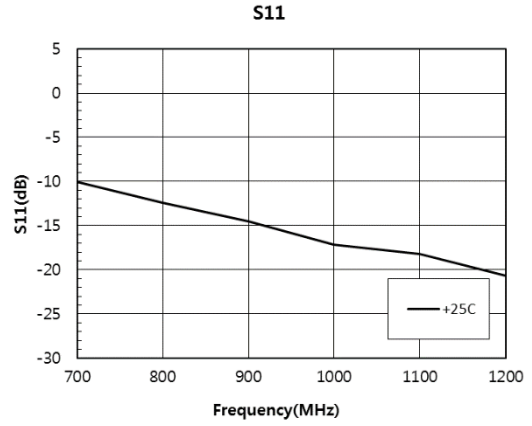
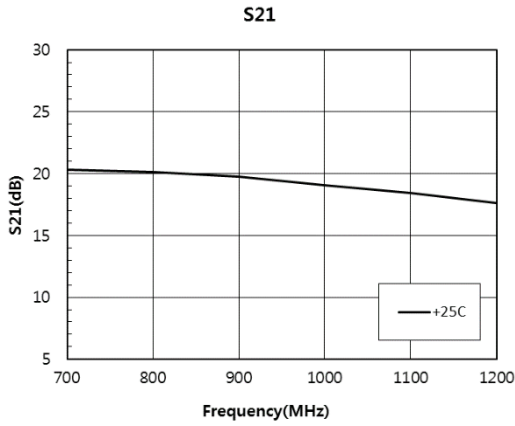


RDC095

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 700 – 1200MHz



Low Noise Amplifier Performances

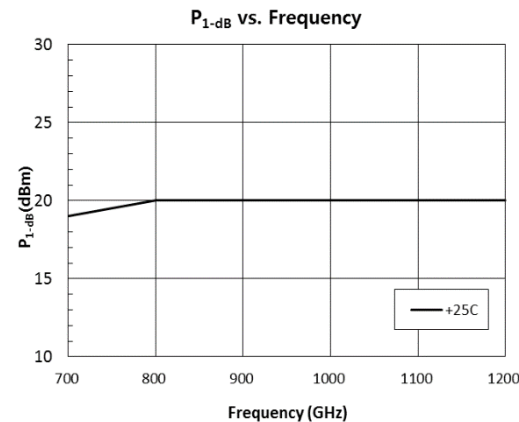
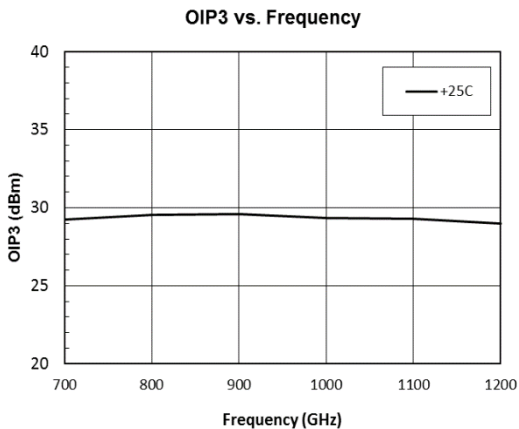
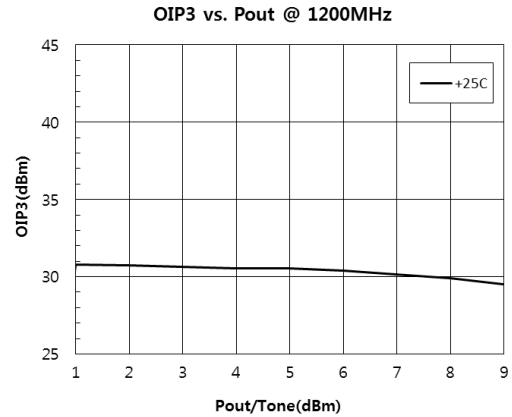
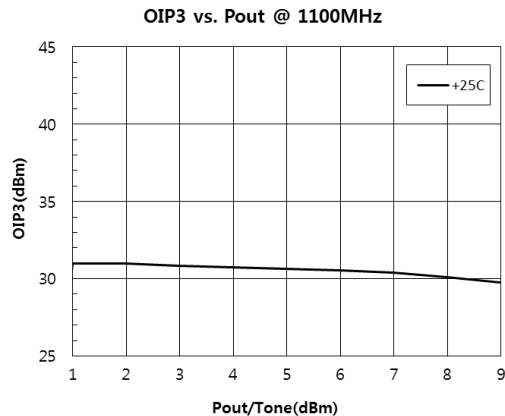
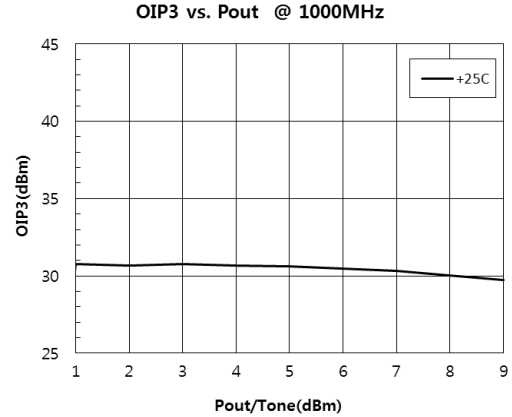
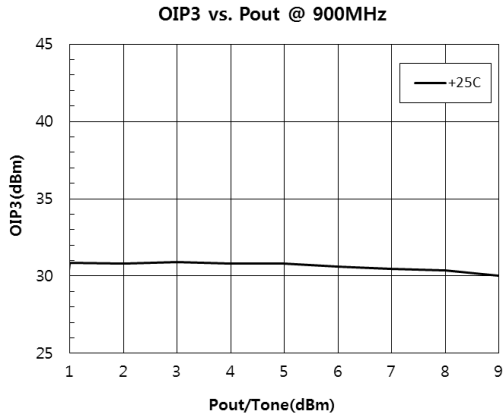


RDC095

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 700 – 1200MHz



Low Noise Amplifier Performances

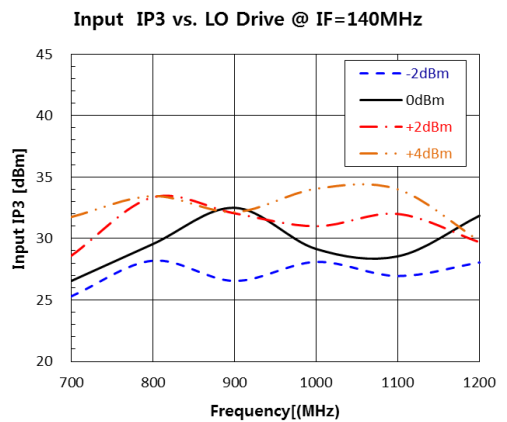
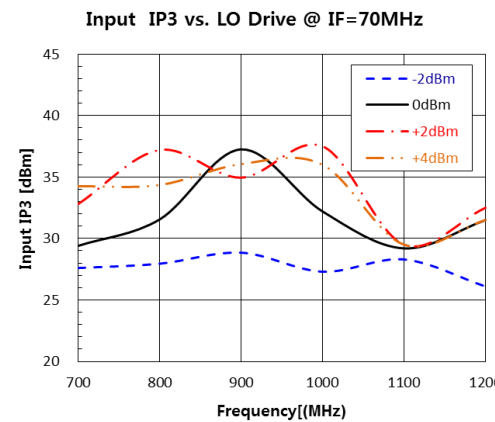
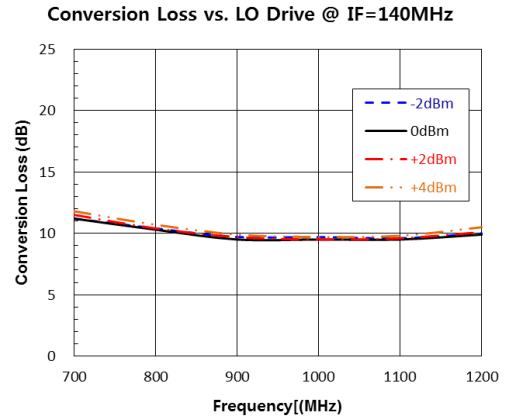
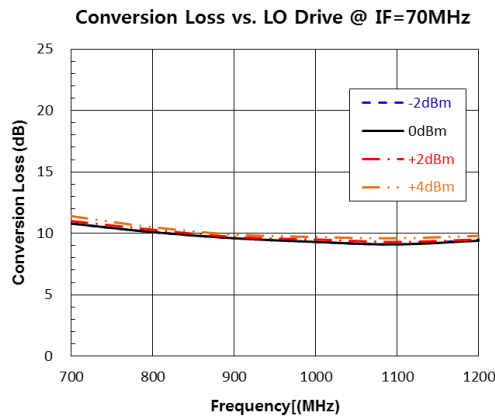
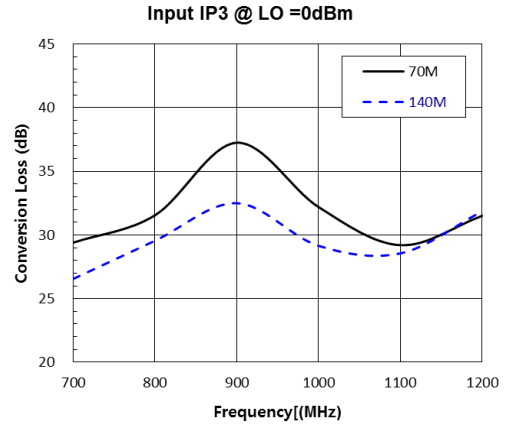
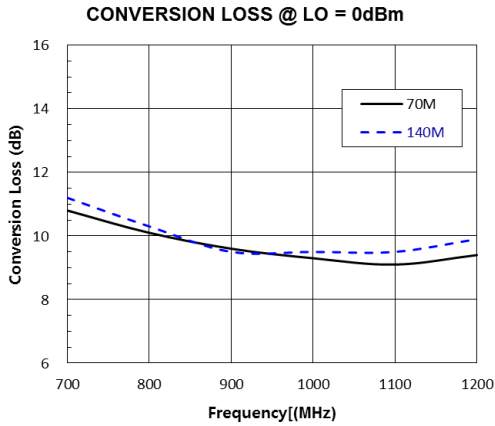


RDC095

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 700 – 1200MHz



Mixer MMIC Performances



RDC095

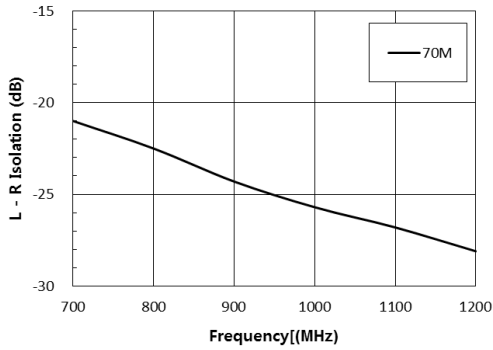
HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 700 – 1200MHz



Mixer MMIC Performances

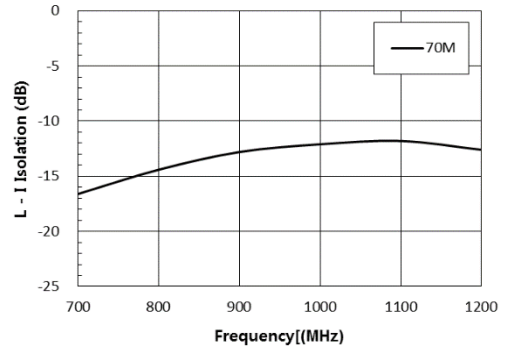
LO to RF Isolation vs. LO Freq

Referenced with LO = 0dBm



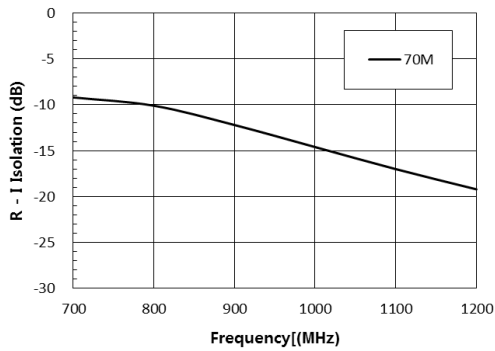
LO to IF Isolation vs. LO Freq

Referenced with LO = 0dBm



RF to IF Isolation vs. LO Freq

Referenced with LO = 0dBm

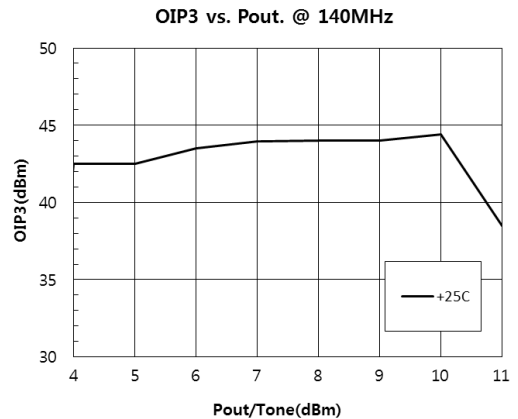
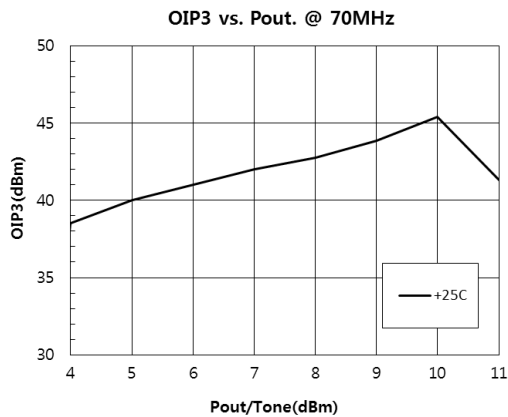
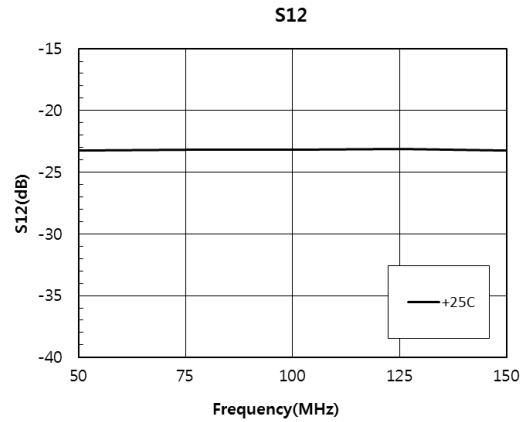
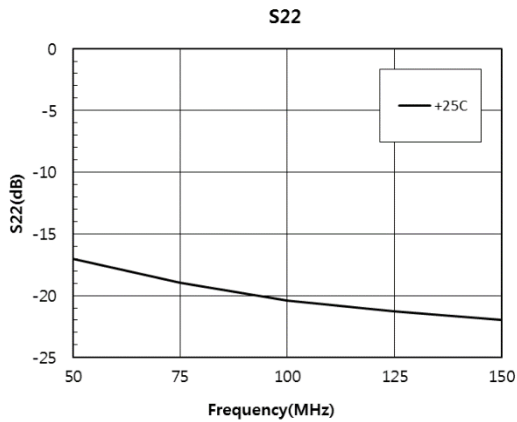
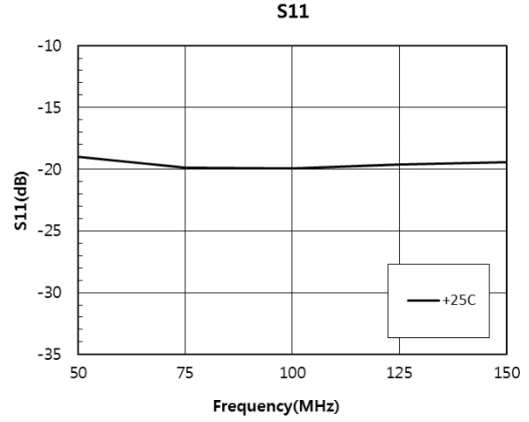
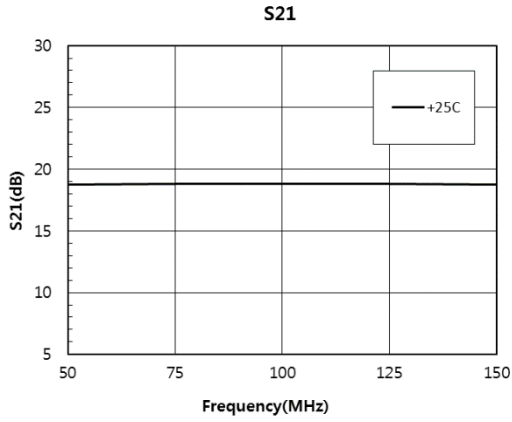


RDC095

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 700 – 1200MHz



IF Amplifier MMIC Performances



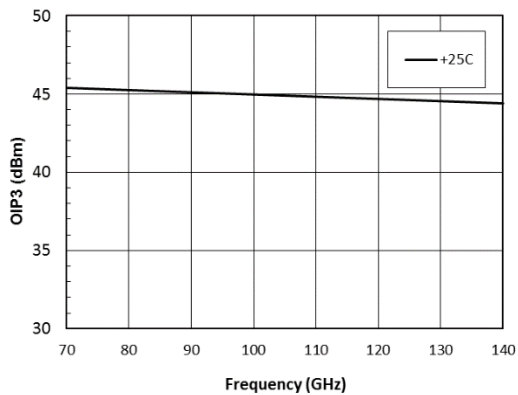
RDC095

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 700 – 1200MHz

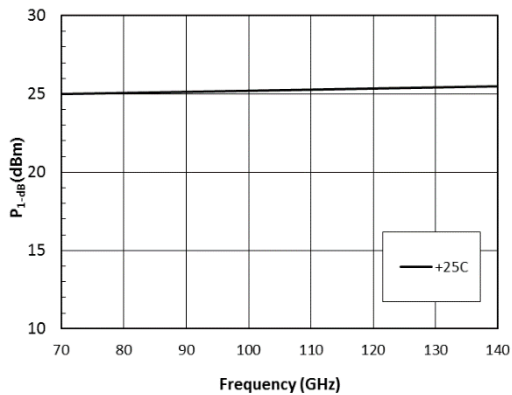


IF Amplifier MMIC Performances

OIP3 vs. Frequency



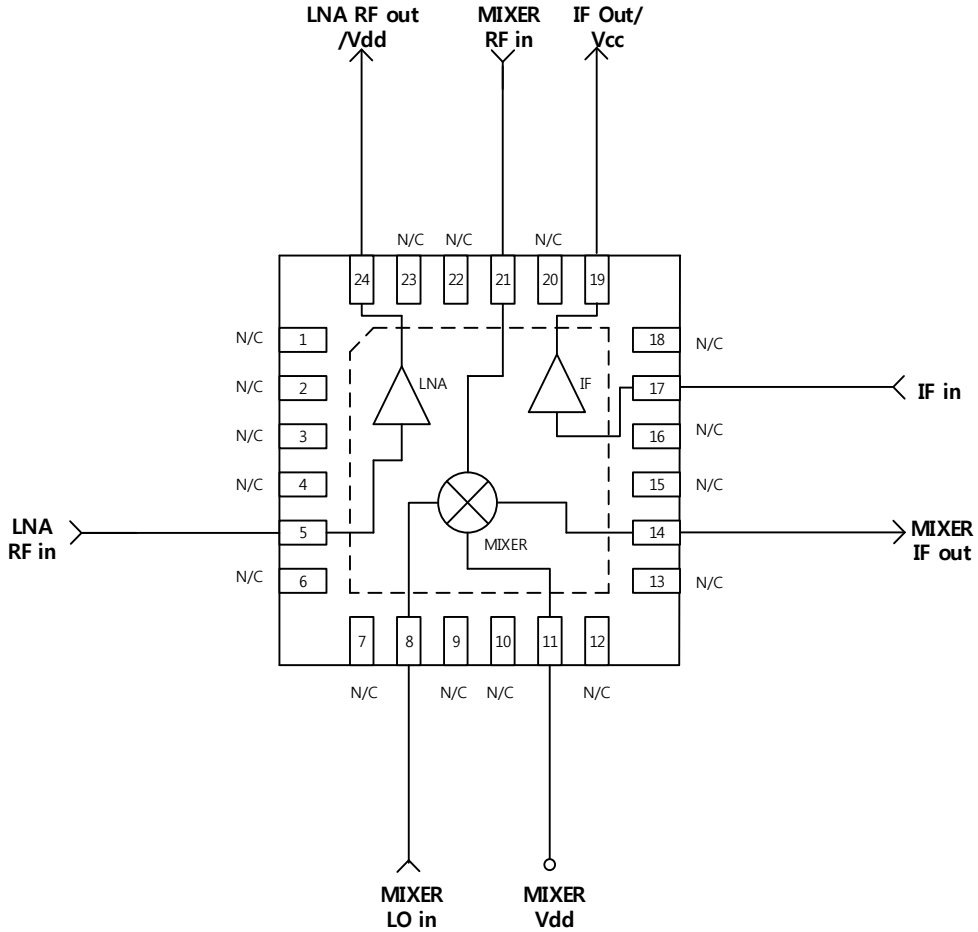
P_{1-dB} vs. Frequency



RDC095

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 700 – 1200MHz

Pin Configuration and Description



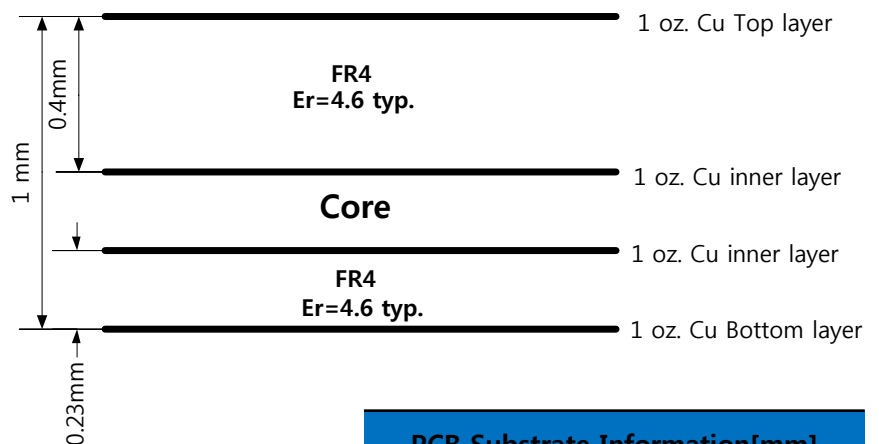
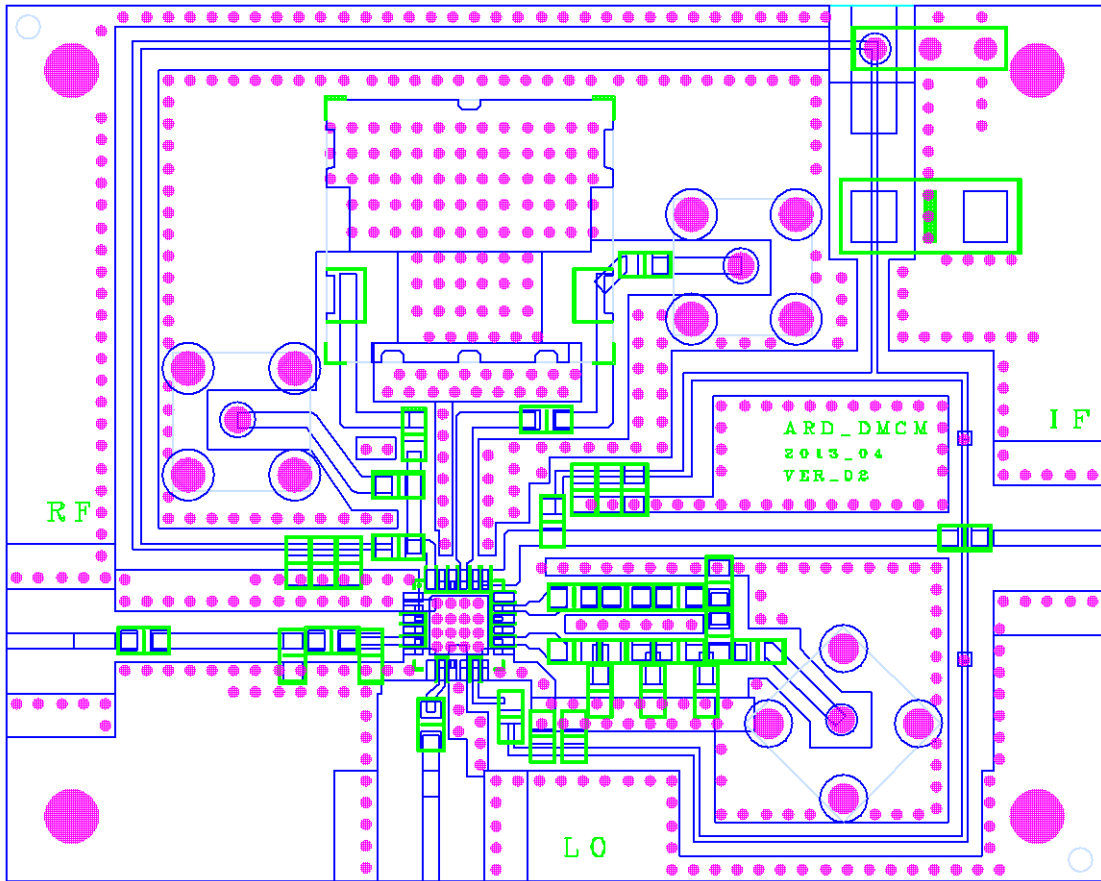
Pin No.	Description
5	LNA RF In
8	Mixer Local oscillator signal In
11	Mixer integrated LO amplifier DC bias
14	Mixer IF signal output
17	IF amplifier Input
19	IF amplifier output/IF amplifier DC bias
21	Mixer RF signal Input
24	LNA RF out/LNA DC bias

RDC095

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 700 – 1200MHz



Evaluation PCB

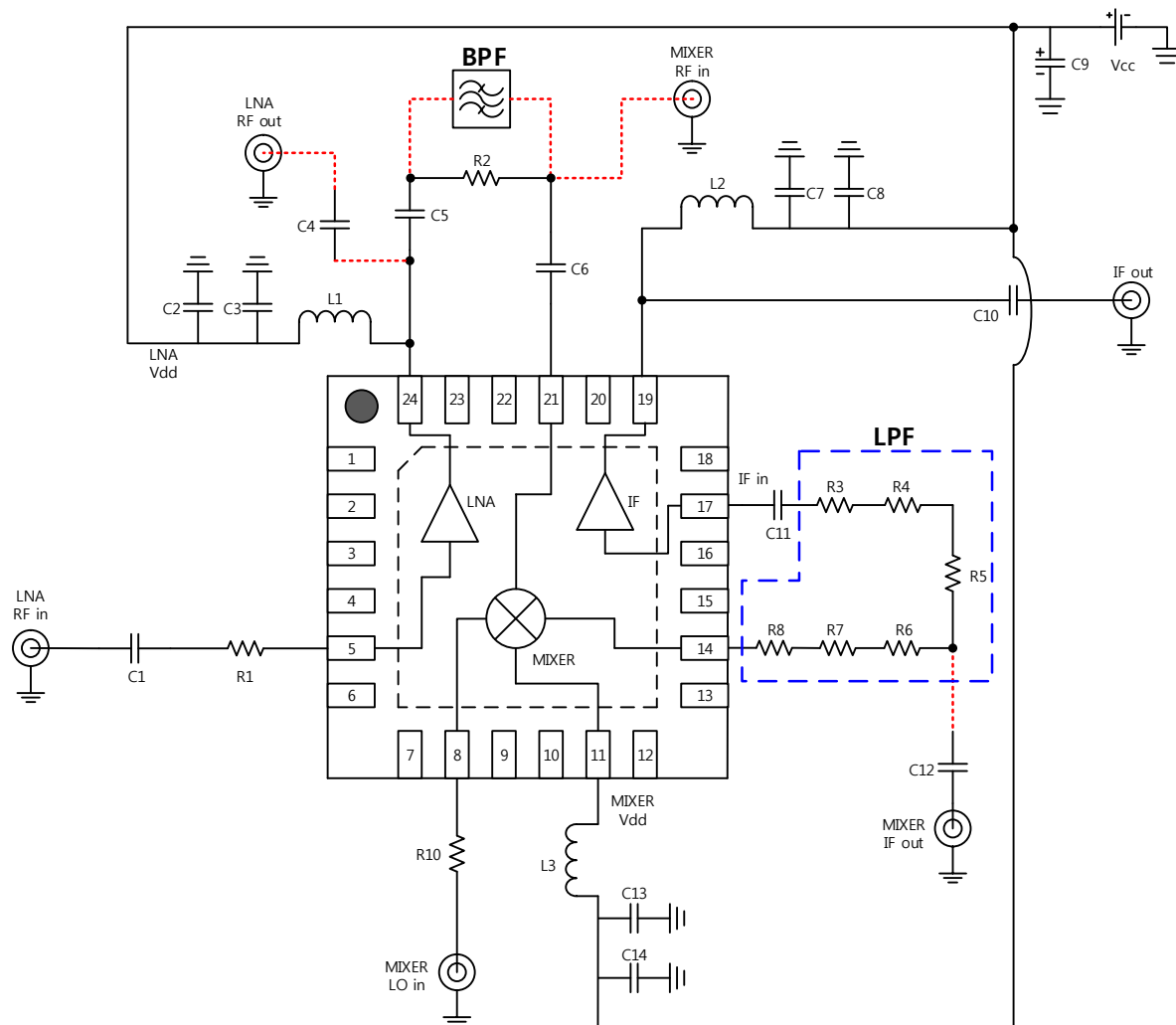


PCB Substrate Information[mm]	
Dielectric Constant	FR-4/4.6
Dielectric Height	0.015[0.4]
Copper Thickness	1 oz.

RDC095

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 700 – 1200MHz

Evaluation PCB



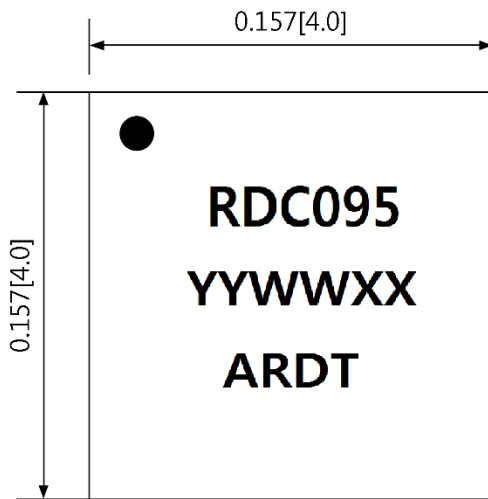
Item	Value	Description
C1, C3, C4, C5, C6, C7, C13	100pF	DC-block or By-pass capacitor/Chip capacitor, 0603 type
C2, C8, C14	0.1uF	By-pass capacitor/Chip capacitor, 0603 type
C9	10uF	Tantalum capacitor, 1206 type
C10, C11, C12	8200pF	DC-block capacitor/Chip capacitor, 0603 type
L1	8.2nH	RF Choke inductor/Chip inductor, 0603 type
L2	1uH	IF Choke inductor/Chip inductor, 0603 type
L3	33nH	Mixer Choke inductor/Chip inductor, 0603 type
R1 ~ R9	0 ohm	0 ohm resistor/Chip resistor, 0603 type

RDC095

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 700 – 1200MHz

Package Mark and Dimensions

Dimension in inches[Millimeters]

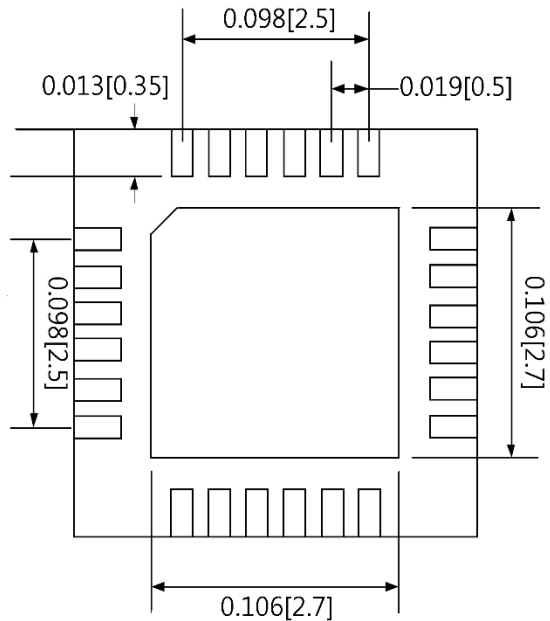
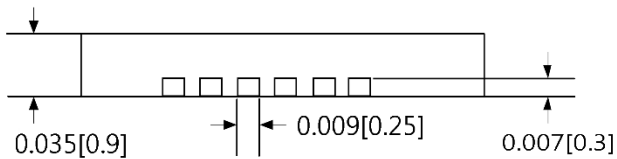


* Part Number : RDC095

**Lot Code : YY = Year

ww = Working Week

XX = Tracking Number



Note

1. All dimensions are in inches[millimeters]. Angles are in degrees.
2. Lead Frame Material : Copper Alloy.
3. The package Top be smaller than the package Bottom

RDC095

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 700 – 1200MHz



NOTE

**HIGH IIP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz**

Product Description

RDC105 is a highly integrated down-converter IC that operates from 1.7 to 2.4 GHz. It incorporates a high dynamic ranged and single-balanced mixer core with integrated Low Noise Amplifier, Local Amplifier and IF amplifiers, This integration makes RDC105 ideal for compact receiver applications such as PCS, GSM, WCDMA, TD-SCDMA, WiMAX and LTE Repeaters and Base Stations. This product provides high dynamic range performance in a low profile lead-free/RoHS-compliant Quad Flat No-Lead (QFN) 4x4 mm package. The RDC105 is implemented with reliable and mature GaAs pHEMT and InGaP HBT technology.

Features

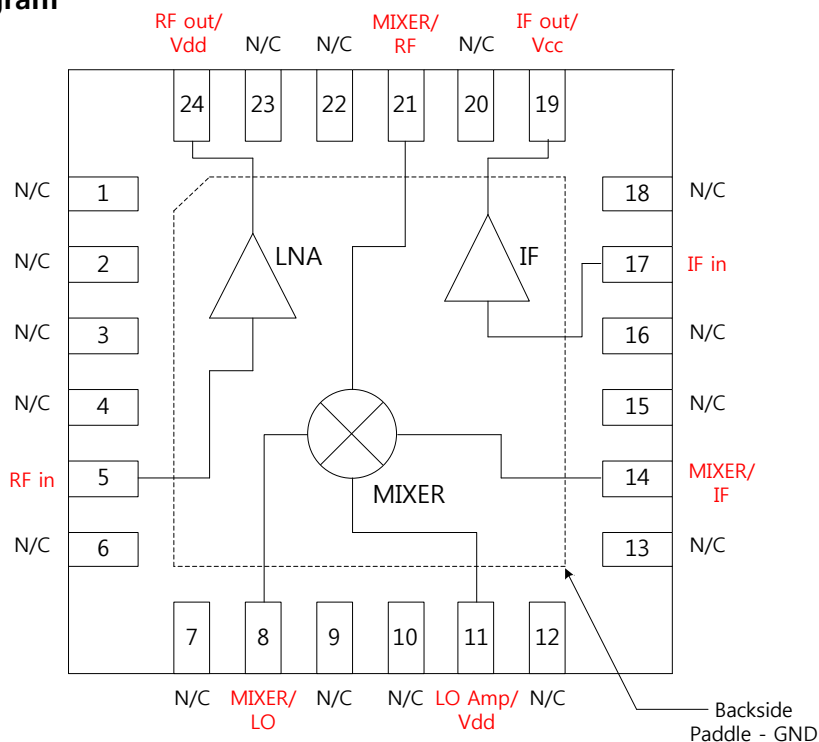
- High dynamic range down-converter with integrated LO , IF, & RF amplifiers
- RF: 1700 – 2400 MHz
- IF: 50 – 300 MHz
- + 38.5 dBm Output IP3 at IF Amplifier
- + 22.0 dBm Output P1dB at IF Amplifier
- Pb- free 4mm 24-pin QFN package
- **Low- side LO configuration**



Applications

- High Dynamic Range Infrastructure system
- GSM GPRS & EDGE
- CDMA & WCDMA
- Cable Modem Termination Systems

Component Diagram



RDC105

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz



Typical Electrical Specification

Parameter	Low Noise Amplifier	Mixer	IF Amplifier	Units
Frequency Range. RF	-	1.7 - 2.4	-	GHz
Frequency Range. LO	-	1.7 - 2.4	-	GHz
Frequency Range. IF	50 – 300			MHz
Conversion Loss	-	10.0	-	dB
Noise Figure(SSB)	-	10.1	-	dB
LO to RF Isolation	-	-6.8	-	dB
LO to IF Isolation	-	-27.7	-	dB
RF to IF Isolation	-	-16.8	-	dB
IP3(Input)	-	29.5	-	dBm
Pin1dB	-	20	-	dBm
LO Input Drive Level(Typical)	0			dBm
Small Signal Gain@1.8/2.1GHz/70MHz	15.6/14.0	-	27.1	dB
Input Return Loss@1.8/2.1GHz/70MHz	-30.1/-17.6	-	-28.1	dB
Output Return Loss@1.8/2.1GHz/70MHz	-10/-10.4	-	-10.1	dB
Third Order Intercept Point @1.8GHz/70MHz	34.2	-	38.5	dBm
Output power at 1-dB Compression	24	-	22.0	dBm
Noise Figure	1.07	-	2.8	dB
Device Voltage	5			V
Device current (Icq)	170			mA

Test condition: Vcc = 5V, I_D=170mA, Typ., LO = 0dBm, IF = 140MHz, T_L=25°C, Z_S=Z_L=50

RDC105

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz

Absolute Maximum Ratings

Parameter	Rating	Unit
Max RF/IF Input Power	18	dBm
Max LO Drive Input Power	10	dBm
Max Device Voltage(V_D)	6.5	V
Max Operating Dissipated Power	0.5	W
Junction Temperature(T_J)	150	°C
Operating Temperature(T_L)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 0B	
Moisture Sensitivity Level	MSL1	

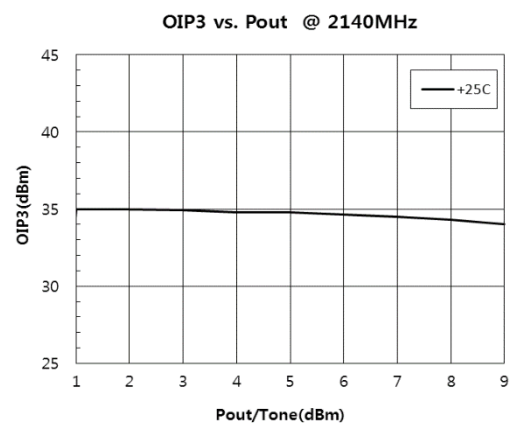
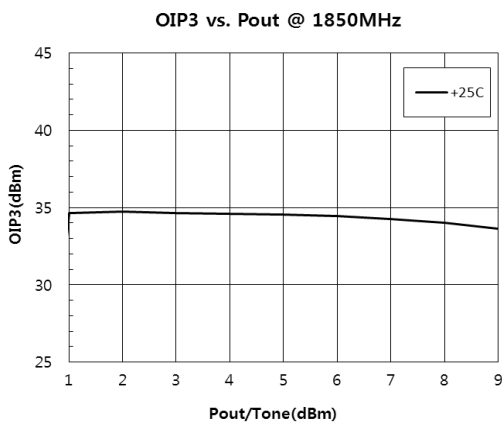
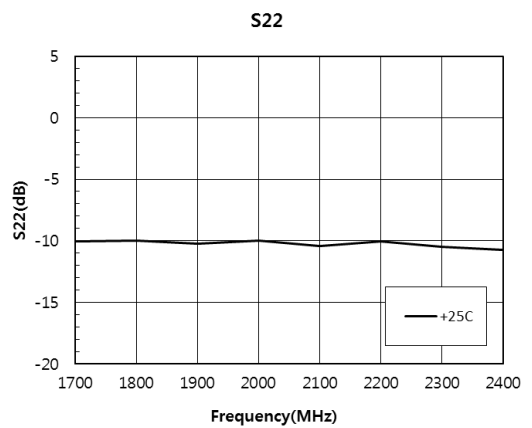
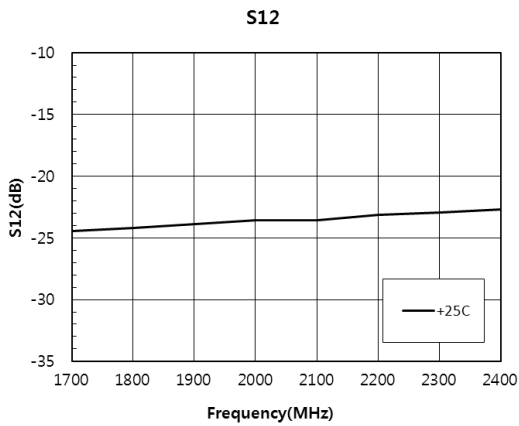
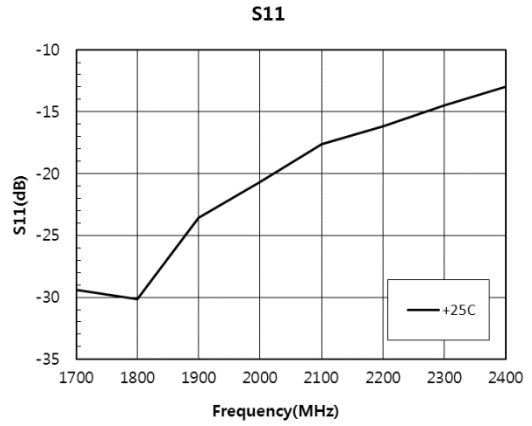
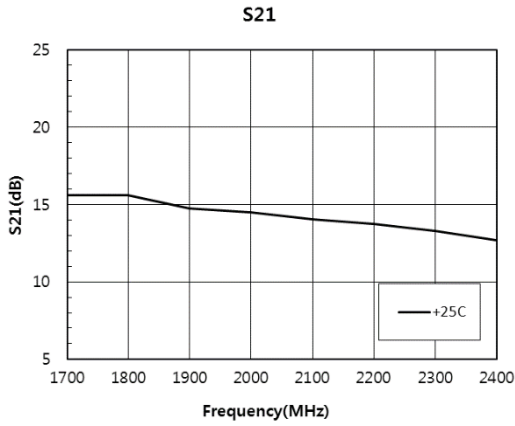


RDC105

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz



Low Noise Amplifier Performances

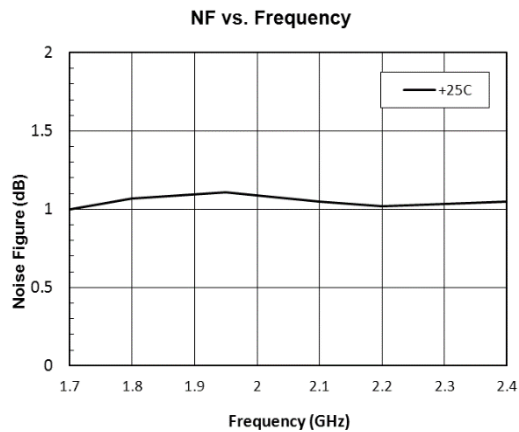
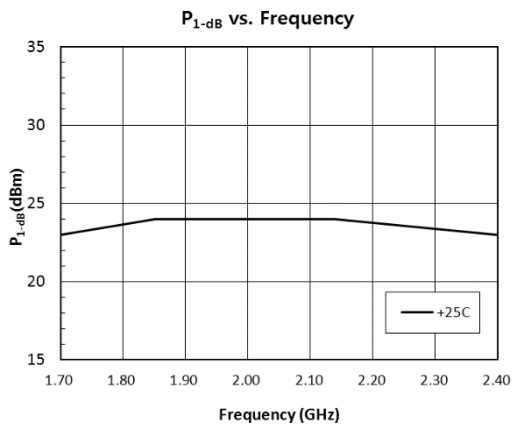


RDC105

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz



Low Noise Amplifier Performances

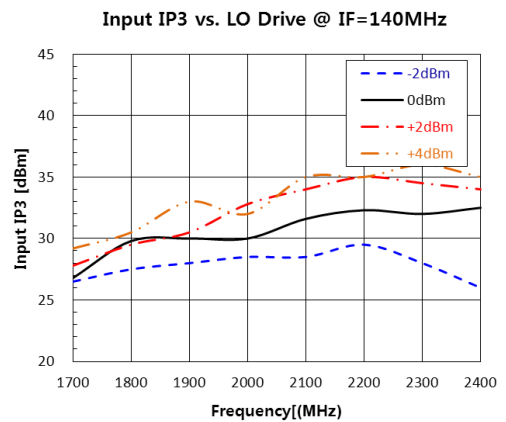
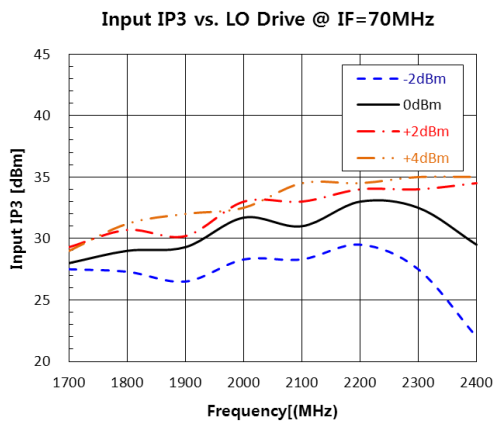
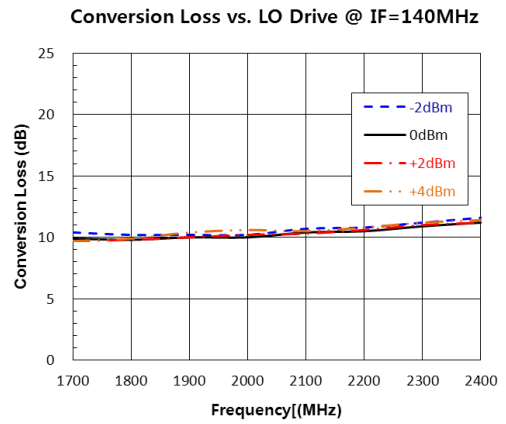
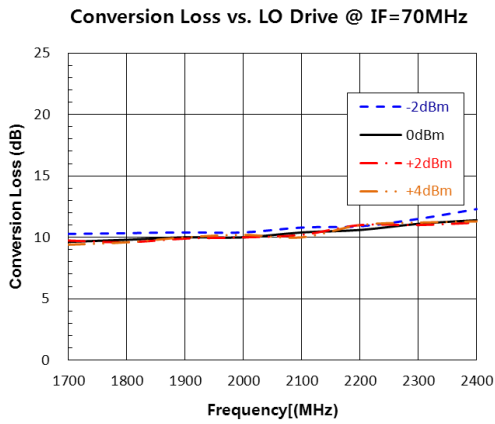
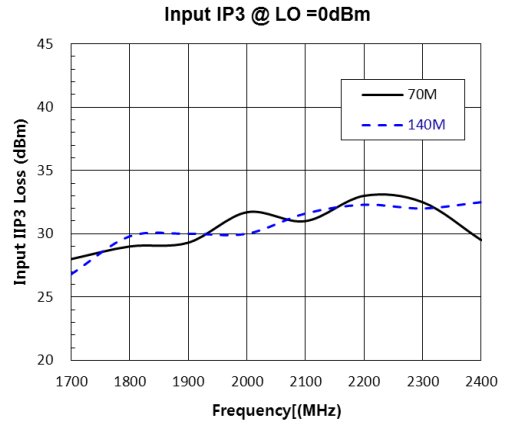
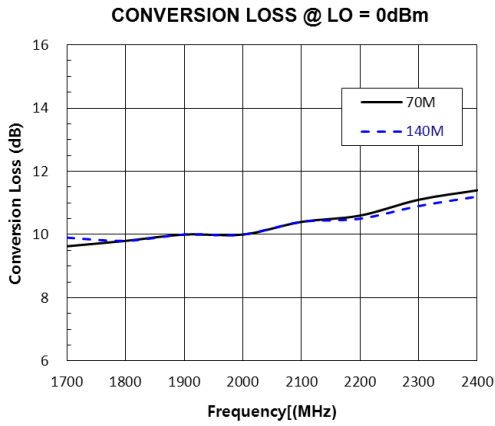


RDC105

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz



Mixer MMIC Performances



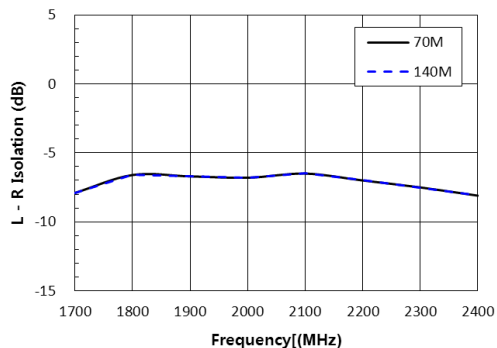
RDC105

HIGH IP3 DOWN-CONVERTOR With INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz

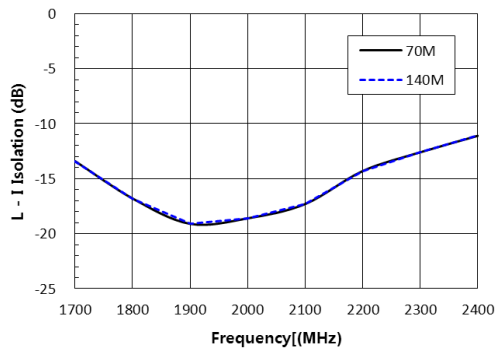
Mixer MMIC Performances



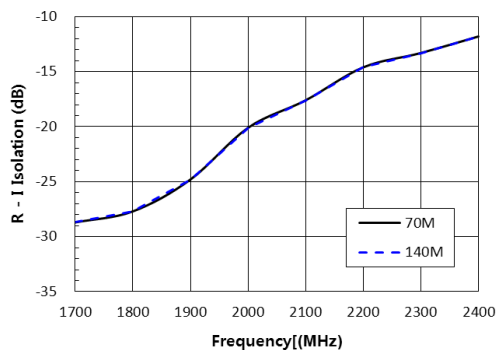
LO - RF Isolation vs. LO Freq
Referenced with LO = 0dBm



LO - IF Isolation vs. LO Freq
Referenced with LO = 0dBm



RF - IF Isolation vs. LO Freq
Referenced with LO = 0dBm

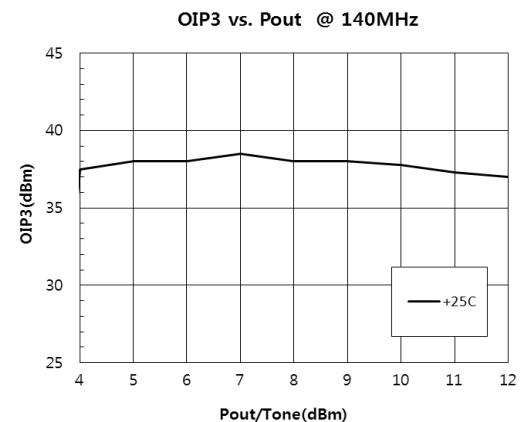
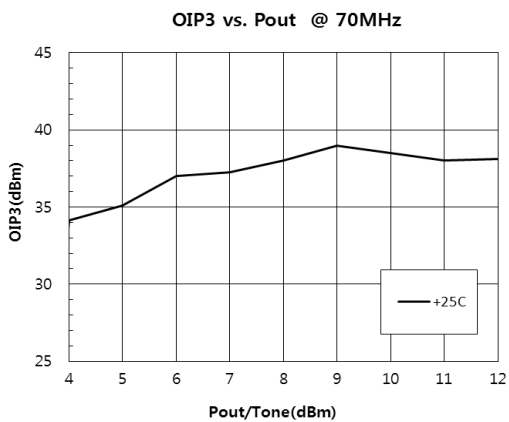
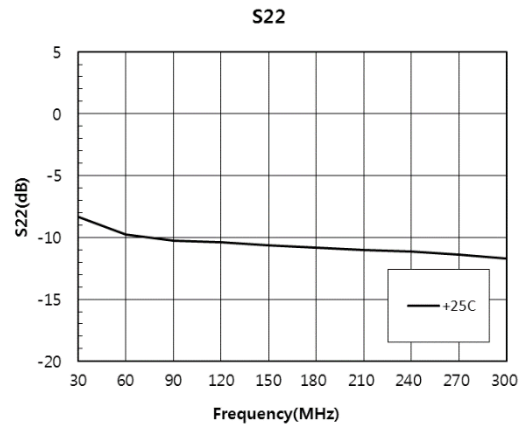
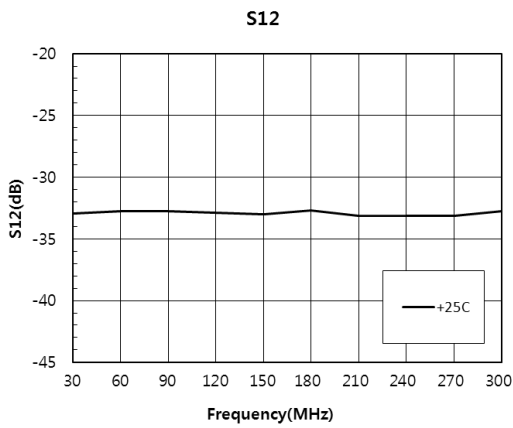
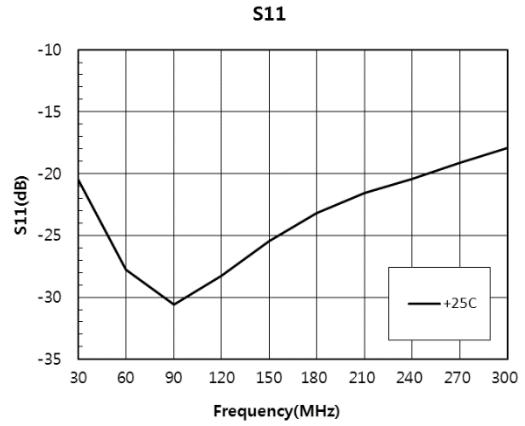
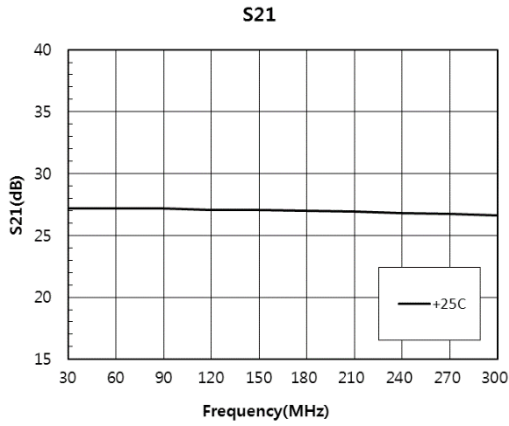


RDC105

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz



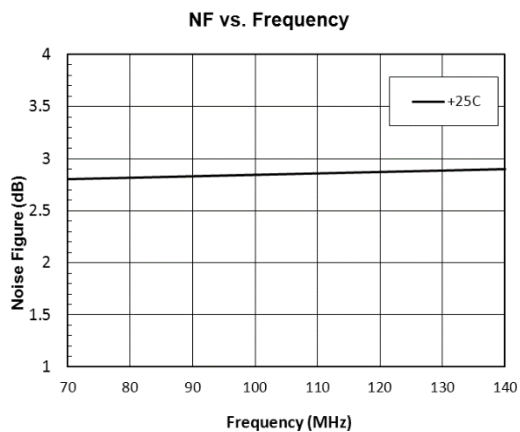
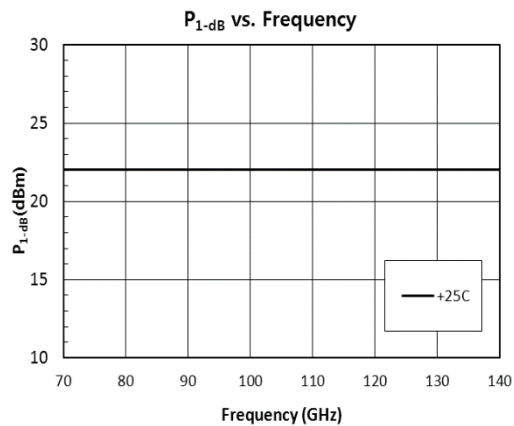
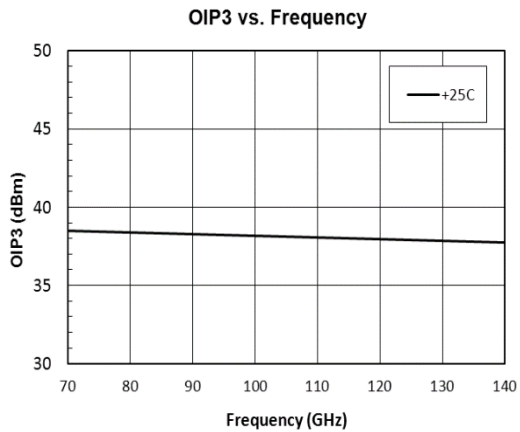
IF Amplifier MMIC Performances



RDC105

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz

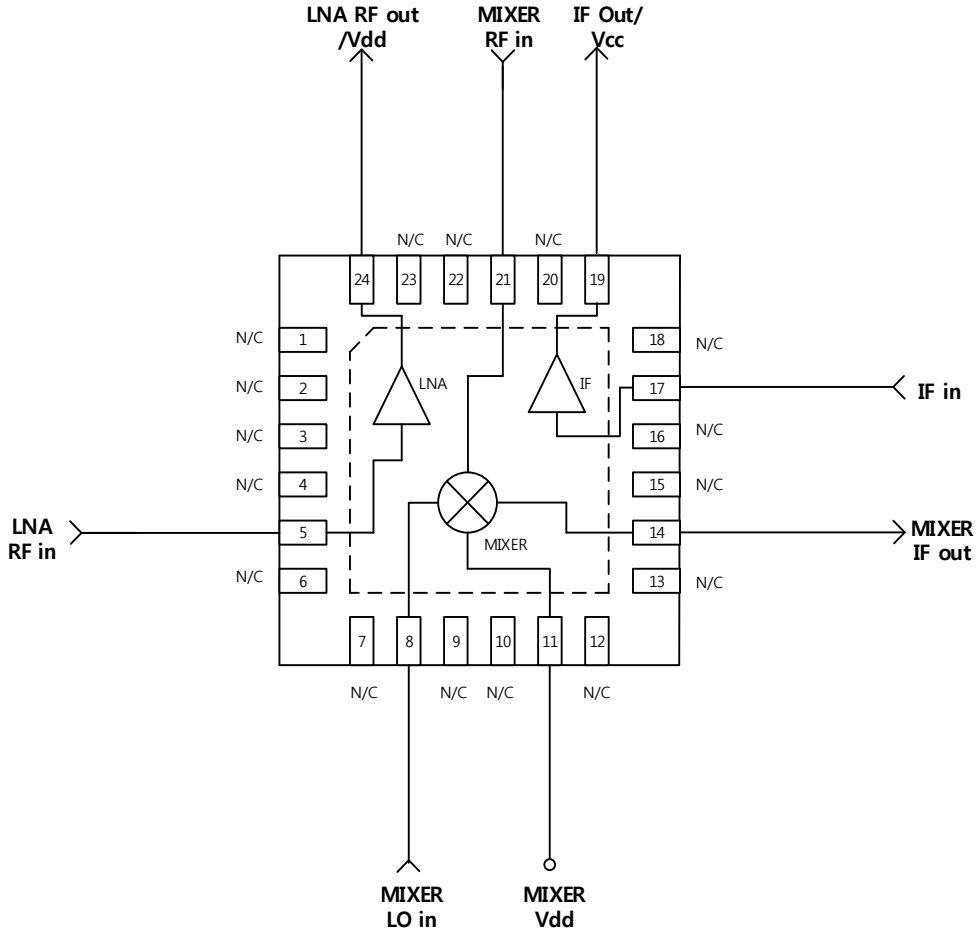
IF Amplifier MMIC Performances



RDC105

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz

Pin Configuration and Description



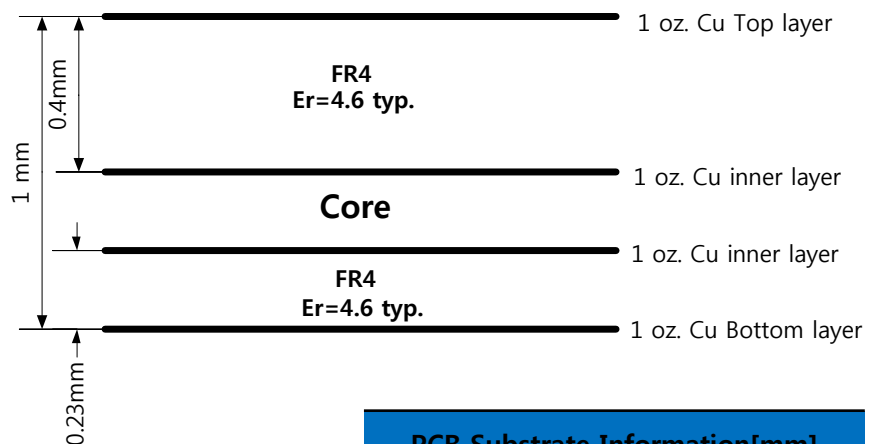
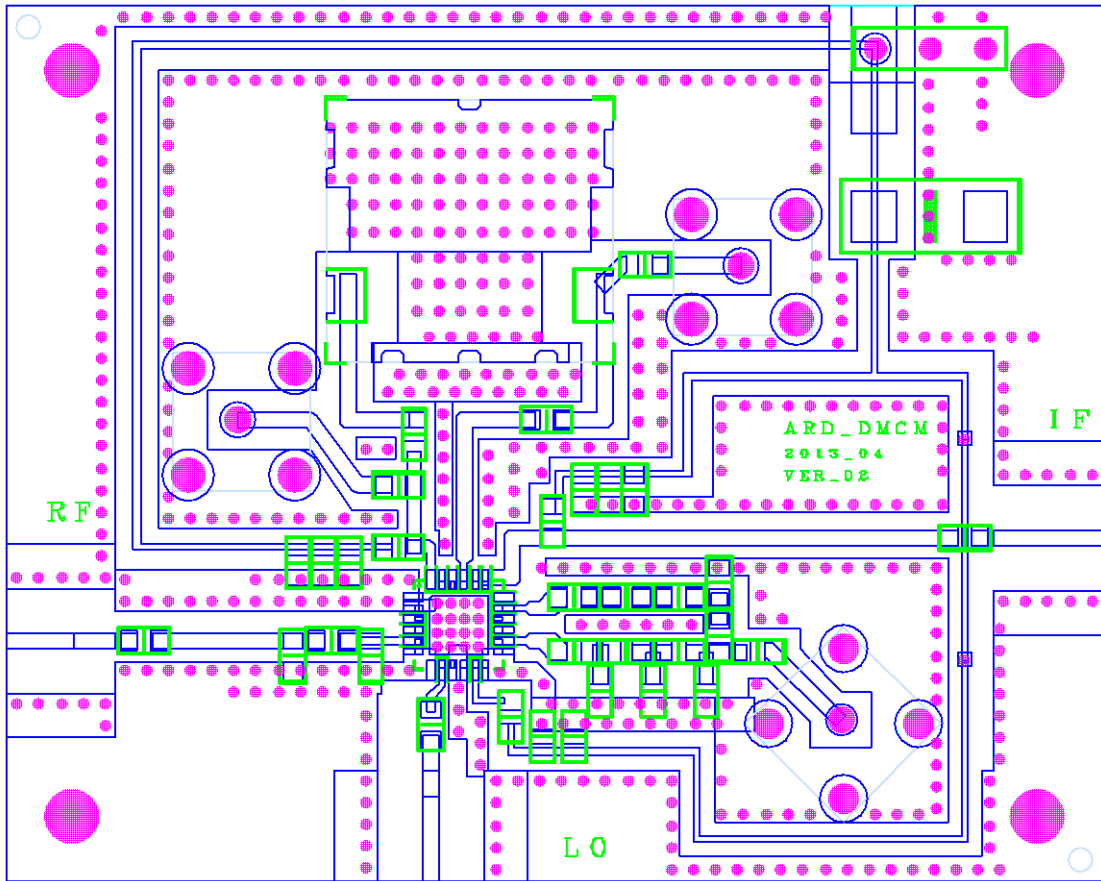
Pin No.	Description
5	LNA RF In
8	Mixer Local oscillator signal In
11	Mixer integrated LO amplifier DC bias
14	Mixer IF signal output
17	IF amplifier Input
19	IF amplifier output/IF amplifier DC bias
21	Mixer RF signal Input
24	LNA RF out/LNA DC bias

RDC105

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz



Evaluation PCB

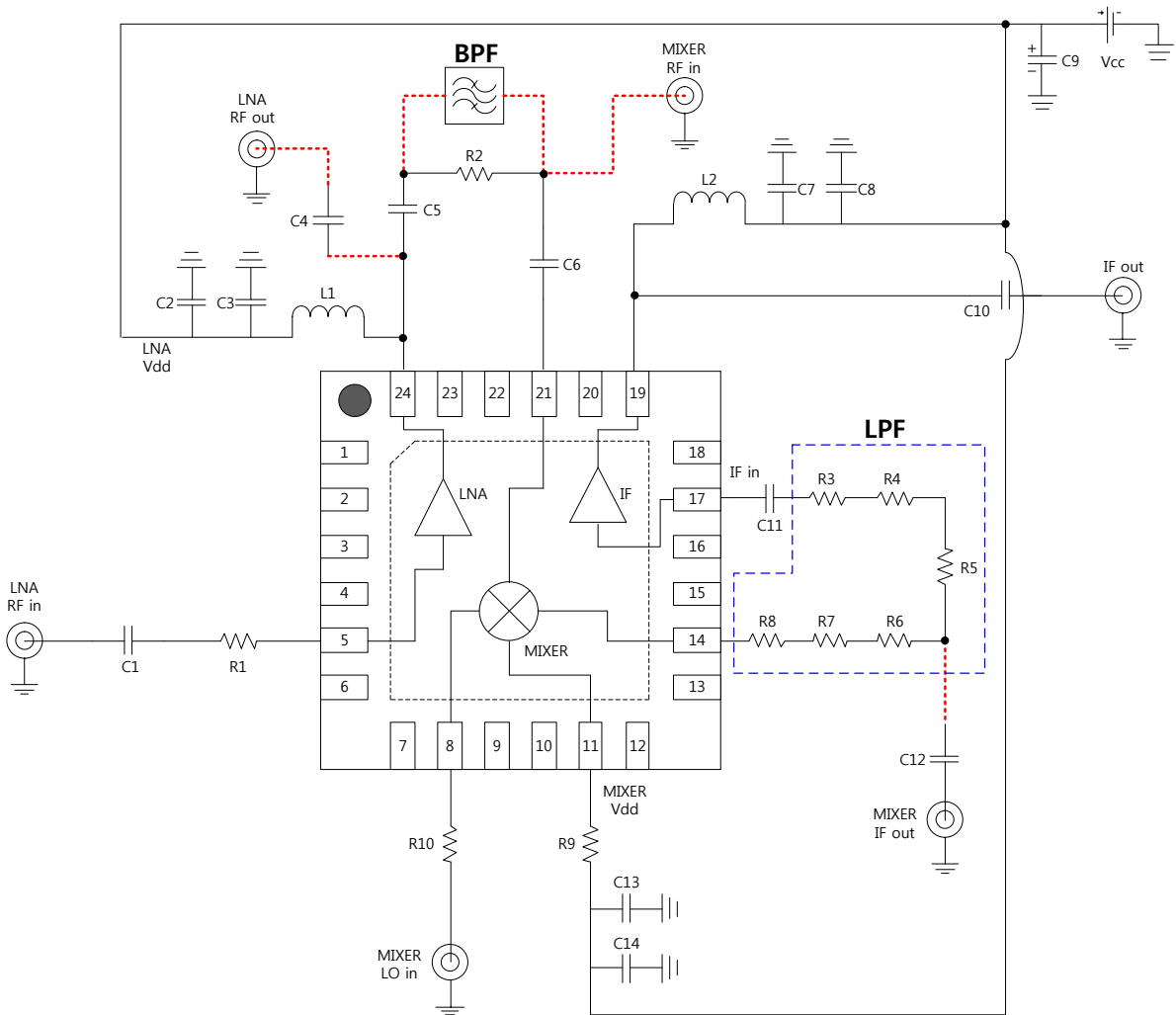


PCB Substrate Information[mm]	
Dielectric Constant	FR-4/4.6
Dielectric Height	0.015[0.4]
Copper Thickness	1 oz.

RDC105

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz

Evaluation PCB



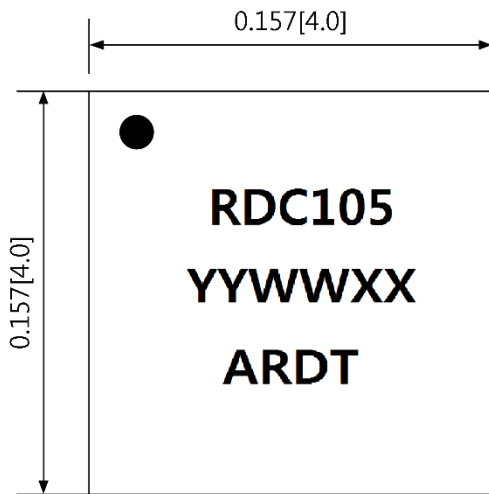
Item	Value	Description
C1, C3, C4, C5, C6, C7, C13	100pF	DC-block or By-pass capacitor/Chip capacitor, 0603 type
C2, C8, C14	0.1uF	By-pass capacitor/Chip capacitor, 0603 type
C9	10uF	Tantalum capacitor, 1206 type
C10, C11, C12	8200pF	DC-block capacitor/Chip capacitor, 0603 type
L1	8.2nH	RF Choke inductor/Chip inductor, 0603 type
L2	1uH	IF Choke inductor/Chip inductor, 0603 type
R1 ~ R10	0 ohm	0 ohm resistor/Chip resistor, 0603 type

RDC105

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz

Package Mark and Dimensions

Dimension in inches[Millimeters]

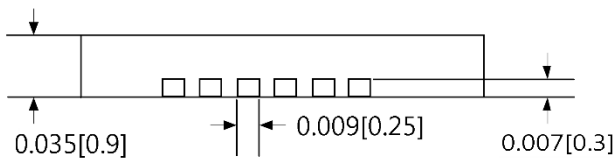
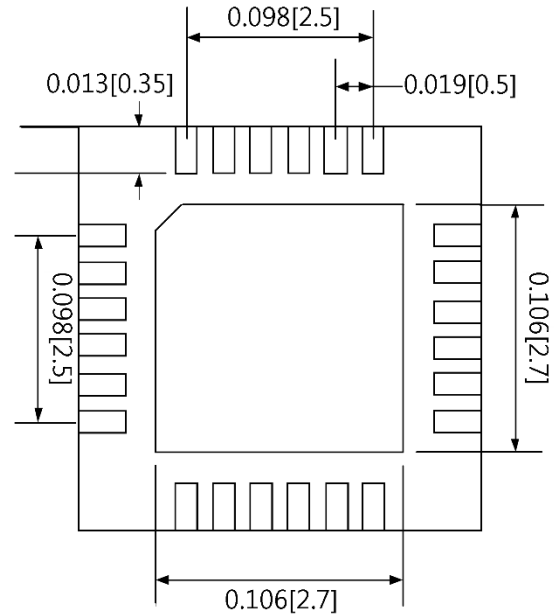


* Part Number : RDC105

**Lot Code : YY = Year

ww = Working Week

XX = Tracking Number



Note

1. All dimensions are in inches[millimeters]. Angles are in degrees.
2. Lead Frame Material : Copper Alloy.
3. The package Top be smaller than the package Bottom

RDC105

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz



NOTE

HIGH IIP3 DOWN-CONVERTOR With INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz

Product Description

RDC106 is a highly integrated down-converter IC that operates from 1.7 to 2.4 GHz. It incorporates a high dynamic ranged and single-balanced mixer core with integrated Low Noise Amplifier, Local Amplifier and IF amplifiers, This integration makes RDC106 ideal for compact receiver applications such as PCS, GSM, WCDMA, TD-SCDMA, WiMAX and LTE Repeaters and Base Stations. This product provides high dynamic range performance in a low profile lead-free/RoHS-compliant Quad Flat No-Lead (QFN) 4x4 mm package. The RDC106 is implemented with reliable and mature GaAs pHEMT and InGaP HBT technology.

Features

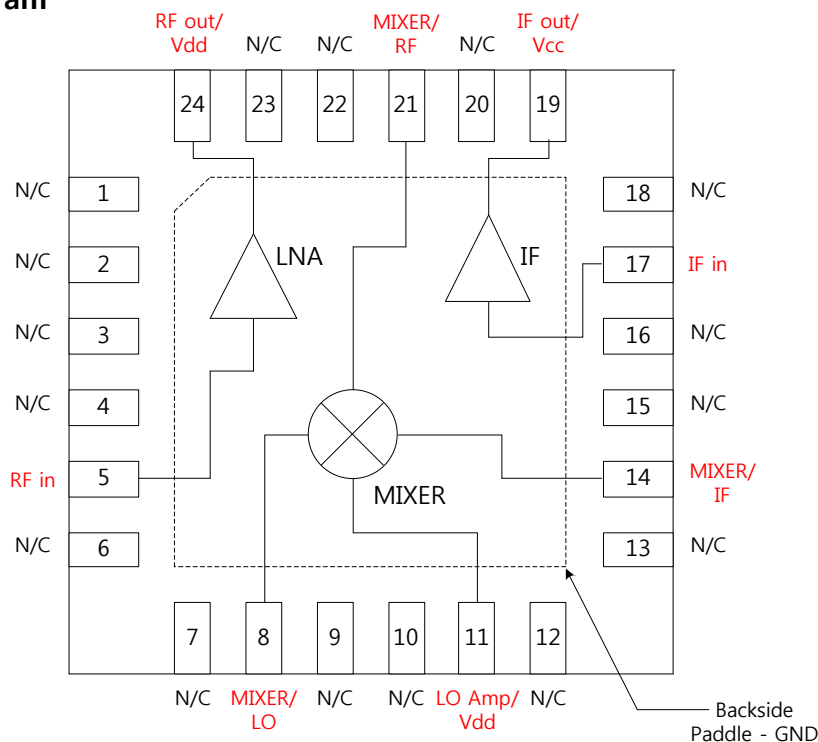
- High dynamic range up-converter with integrated LO , IF, & RF amplifiers
- RF: 1700 – 2400 MHz
- IF: 50 – 300 MHz
- + 45.0 dBm Output IP3
- + 25.0 dBm Output P1dB
- Pb- free 4mm 24-pin QFN package
- Low- side LO configuration

Applications

- High Dynamic Range Infrastructure system
- GSM GPRS & EDGE
- CDMA & WCDMA
- Cable Modem Termination Systems



Component Diagram



RDC106

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz



Typical Electrical Specification

Parameter	Low Noise Amplifier	Mixer	IF Amplifier	Units
Frequency Range. RF	-	1.7 - 2.4	-	GHz
Frequency Range. LO	-	1.7 - 2.4	-	GHz
Frequency Range. IF	50 – 300			MHz
Conversion Loss	-	10.0	-	dB
Noise Figure(SSB)	-	10.1	-	dB
LO to RF Isolation	-	-6.8	-	dB
LO to IF Isolation	-	-27.7	-	dB
RF to IF Isolation	-	-16.8	-	dB
IP3(Input)	-	29.5	-	dBm
Pin1dB	-	20	-	dBm
LO Input Drive Level(Typical)	0			dBm
Small Signal Gain@1.8/2.1GHz/70MHz	15.6/14.0	-	19.1	dB
Input Return Loss@1.8/2.1GHz/70MHz	-30.1/-17.6	-	-19.4	dB
Output Return Loss@1.8/2.1GHz/70MHz	-10/-10.4	-	-17.6	dB
Third Order Intercept Point @1.8GHz/70MHz	34.2	-	45	dBm
Output power at 1-dB Compression	24	-	25.0	dBm
Noise Figure	1.07	-	4.2	dB
Device Voltage	5			V
Device current (Icq)	164			mA

Test condition: Vcc = 5V, I_b=164mA, Typ., LO = 0dBm, IF = 140MHz, T_L=25°C, Z_s=Z_L=50

RDC106

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz

Absolute Maximum Ratings

Parameter	Rating	Unit
Max RF/IF Input Power	27	dBm
Max LO Drive Input Power	10	dBm
Max Device Voltage(V_D)	6.5	V
Max Operating Dissipated Power	0.5	W
Junction Temperature(T_J)	150	°C
Operating Temperature(T_L)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 0B	
Moisture Sensitivity Level	MSL1	

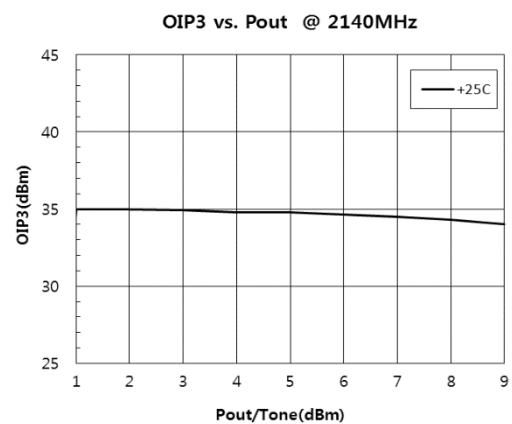
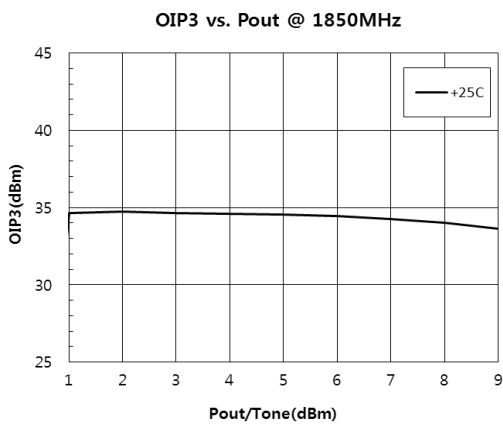
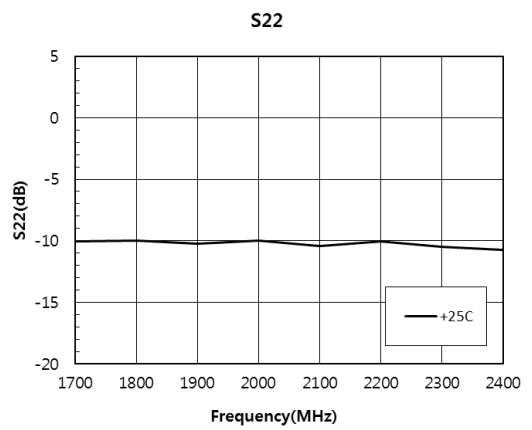
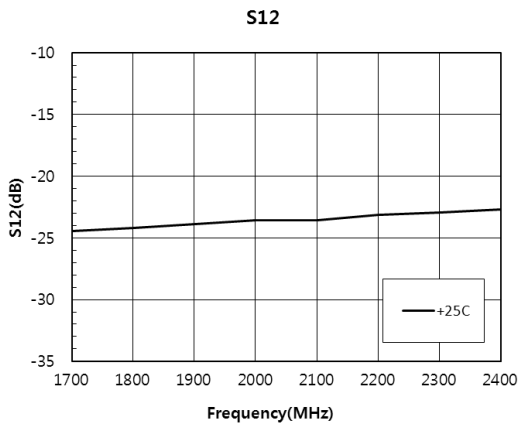
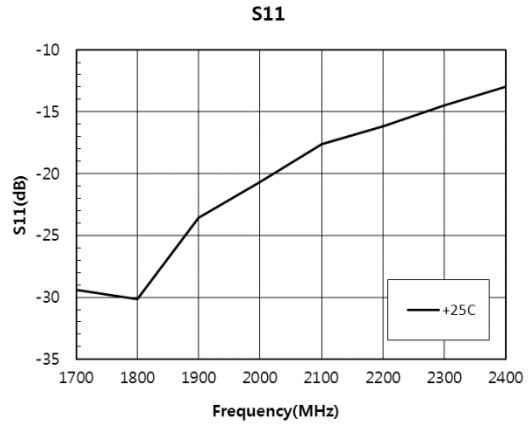
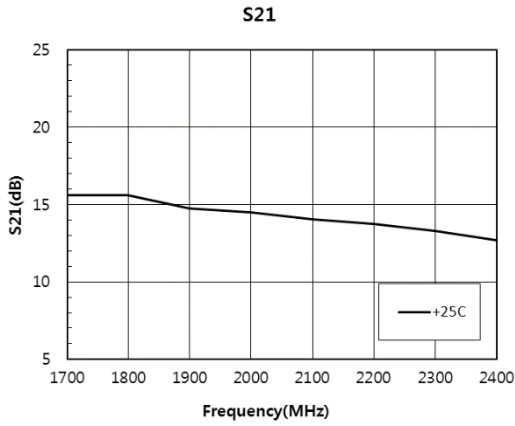


RDC106

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz



Low Noise Amplifier Performances

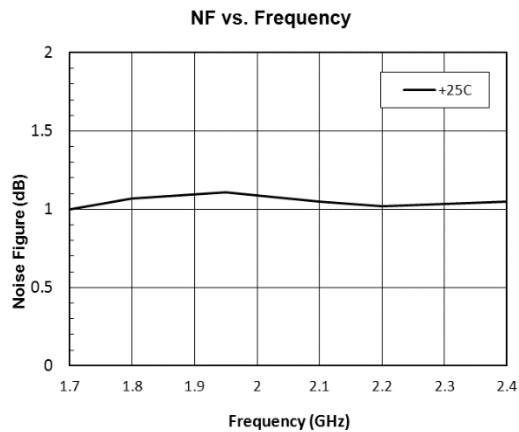
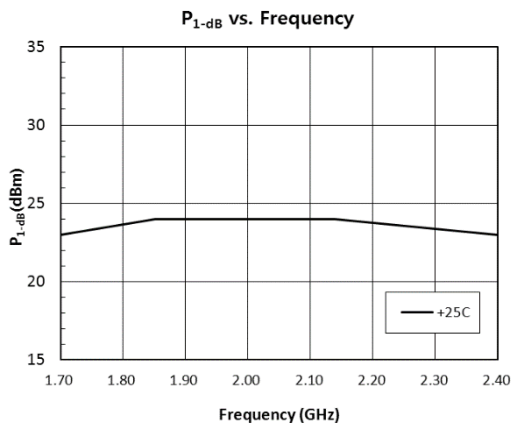


RDC106

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz



Low Noise Amplifier Performances

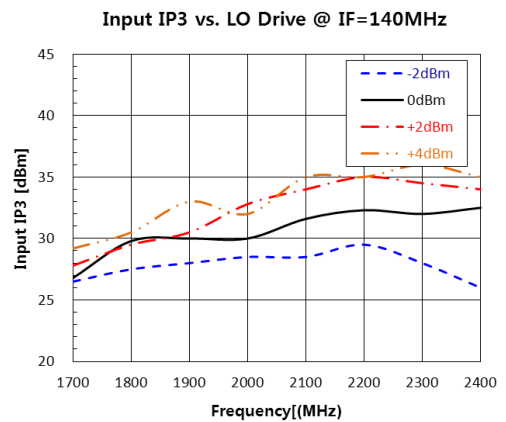
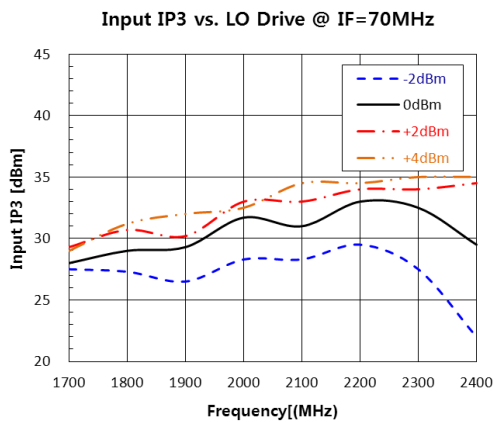
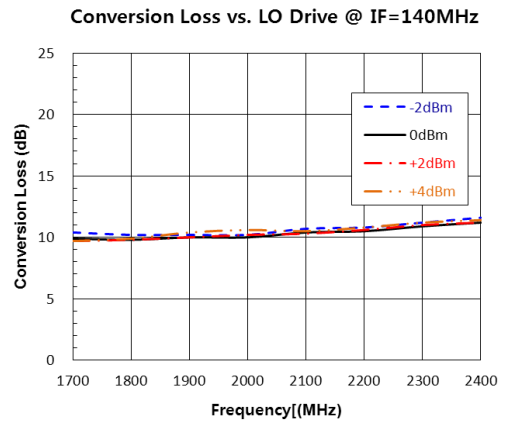
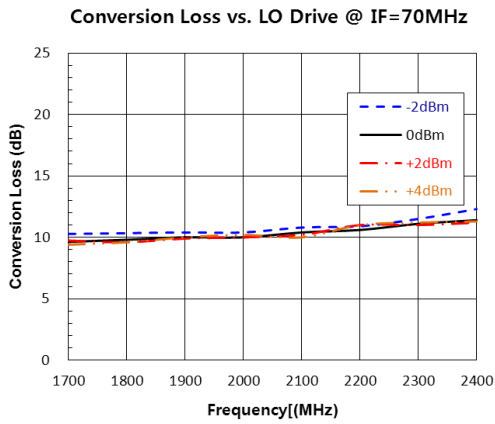
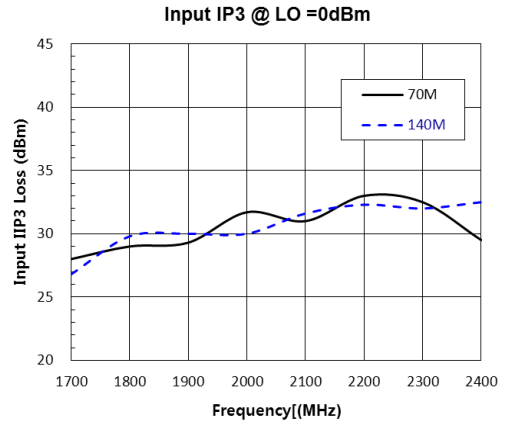
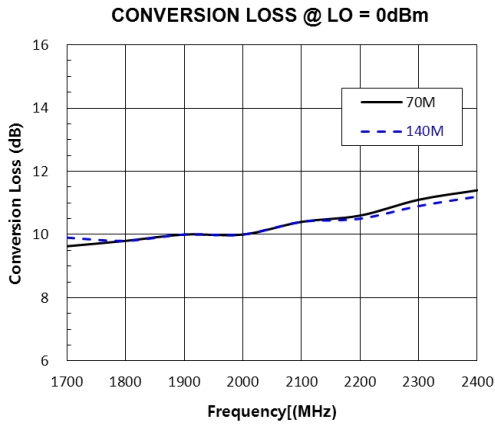


RDC106

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz



Mixer MMIC Performances



RDC106

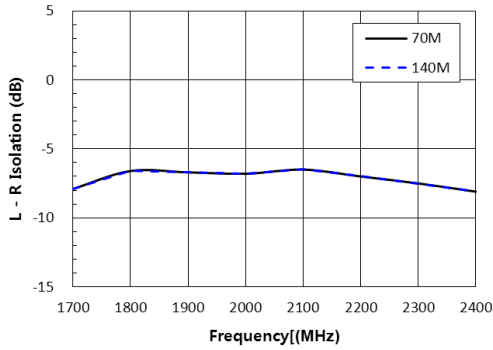
HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz



Mixer MMIC Performances

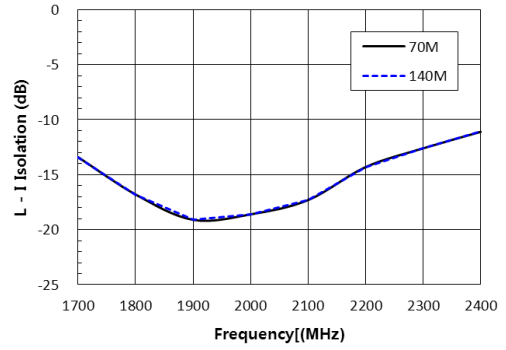
LO - RF Isolation vs. LO Freq

Referenced with LO = 0dBm



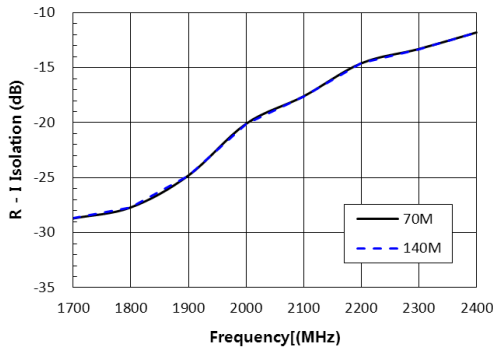
LO - IF Isolation vs. LO Freq

Referenced with LO = 0dBm



RF - IF Isolation vs. LO Freq

Referenced with LO = 0dBm

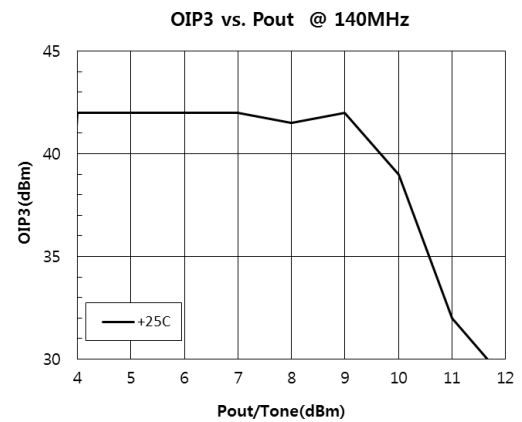
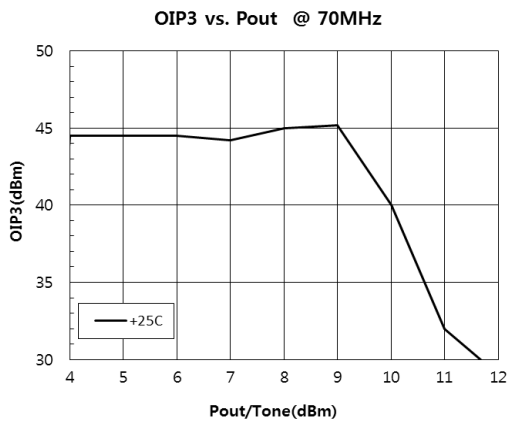
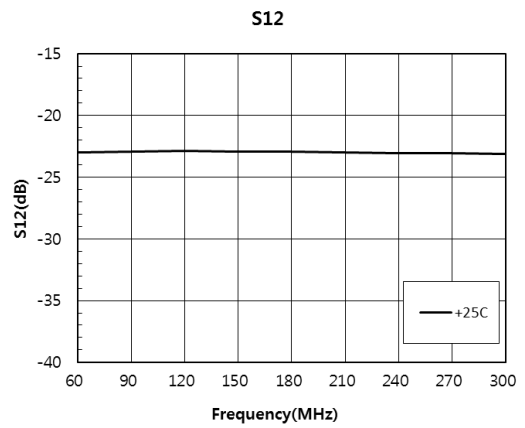
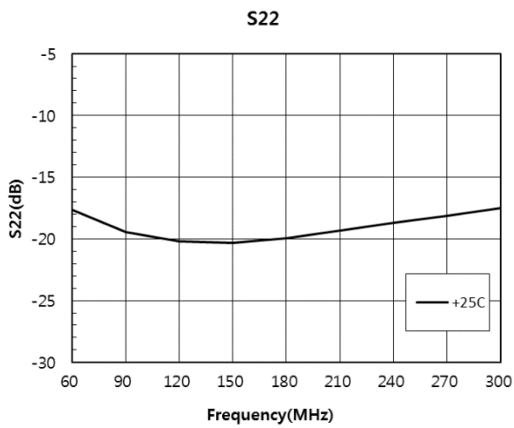
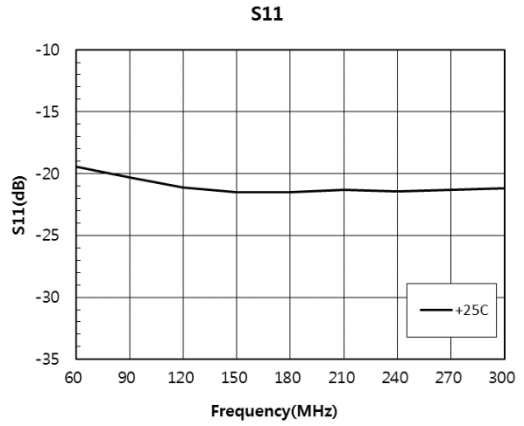
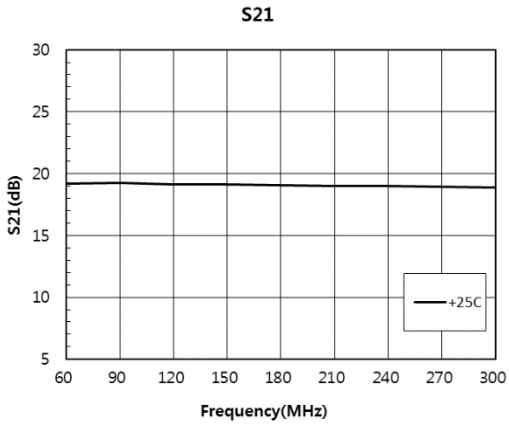


RDC106

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz



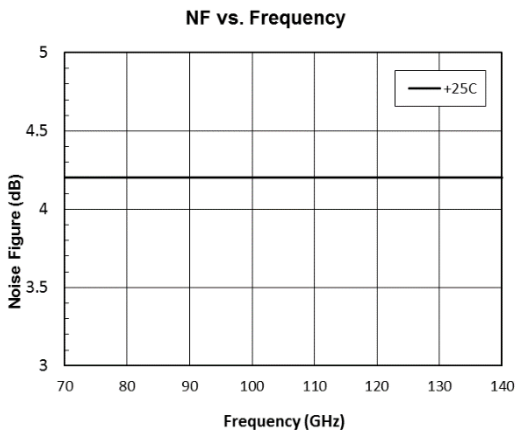
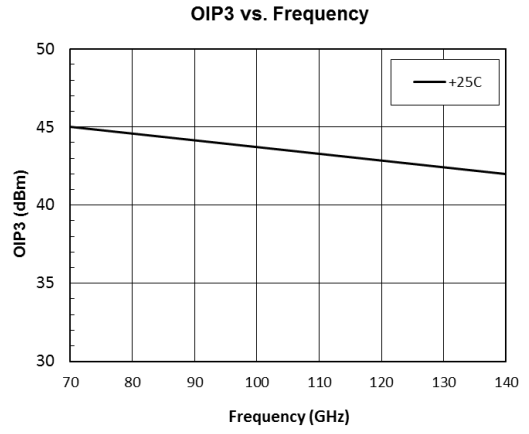
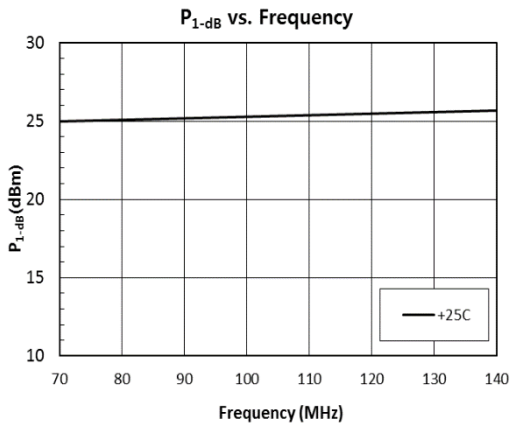
IF Amplifier Performance



RDC106

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz

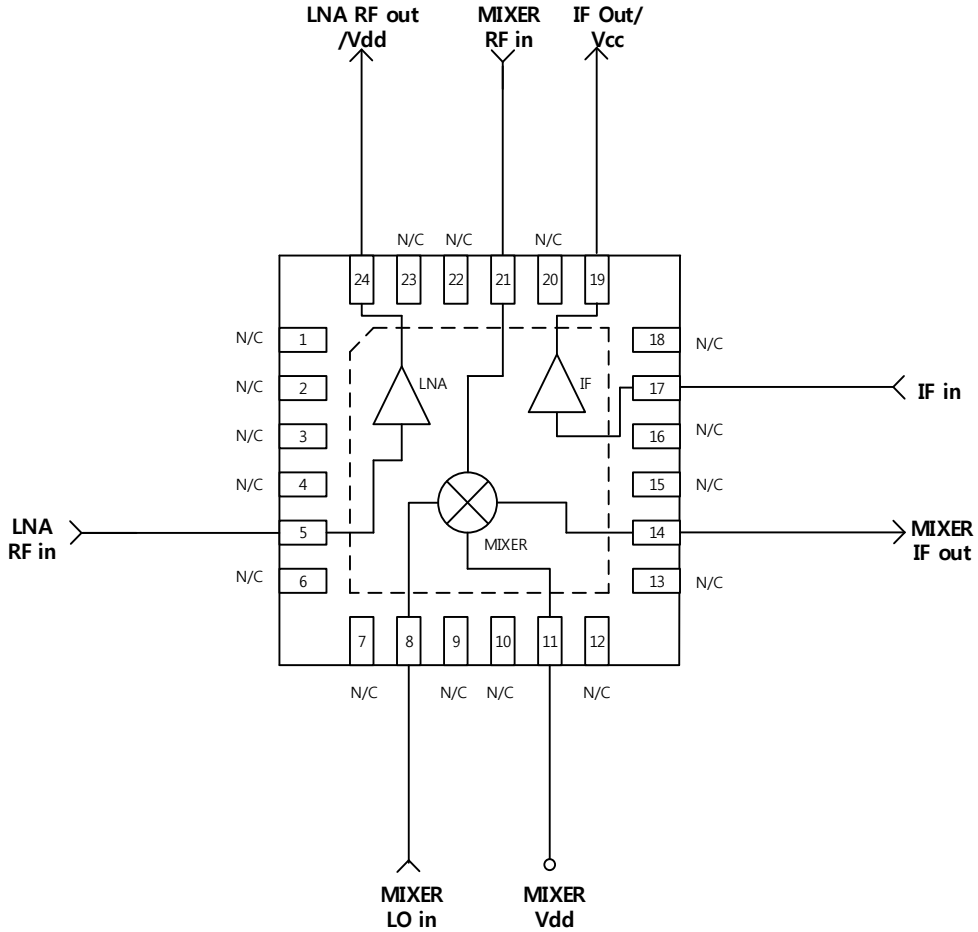
IF Amplifier Performance



RDC106

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz

Pin Configuration and Description



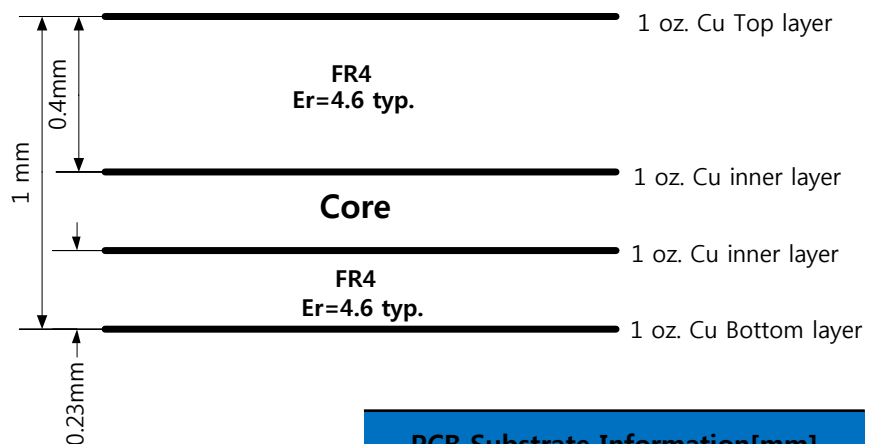
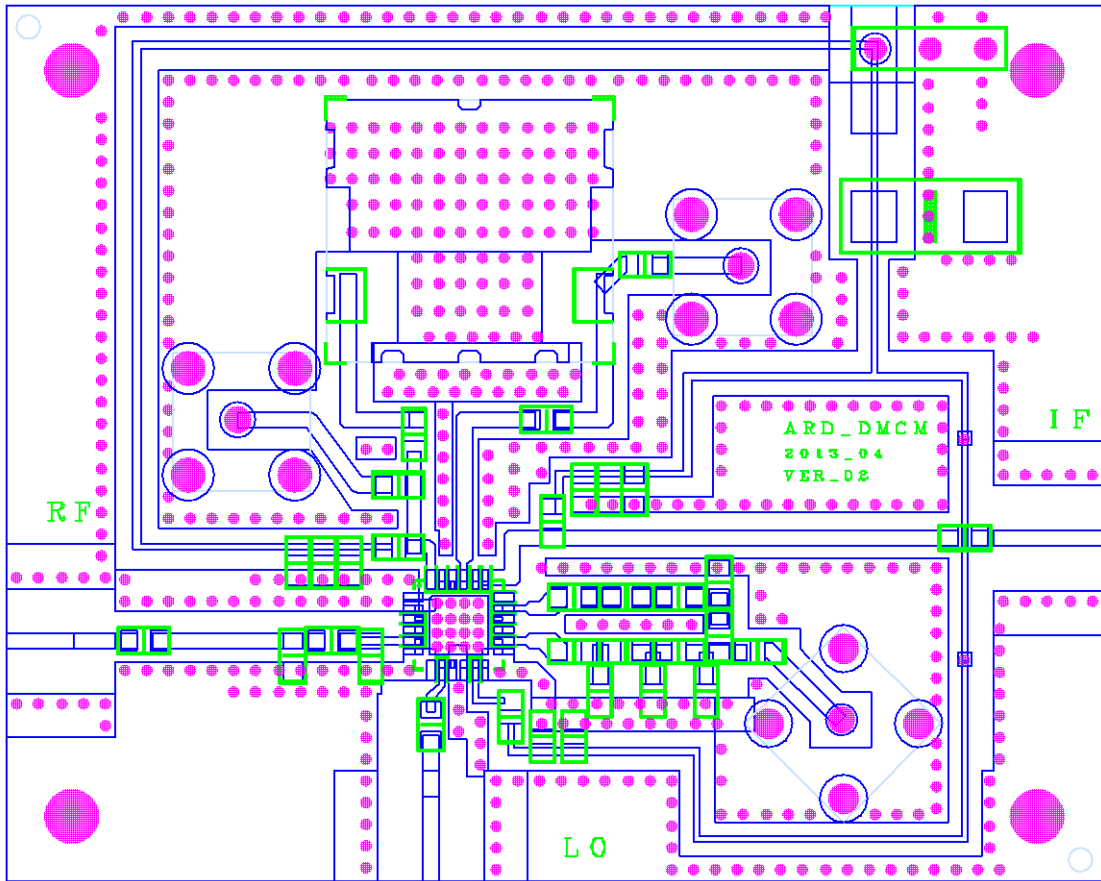
Pin No.	Description
5	LNA RF In
8	Mixer Local oscillator signal In
11	Mixer integrated LO amplifier DC bias
14	Mixer IF signal output
17	IF amplifier Input
19	IF amplifier output/IF amplifier DC bias
21	Mixer RF signal Input
24	LNA RF out/LNA DC bias

RDC106

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz



Evaluation PCB

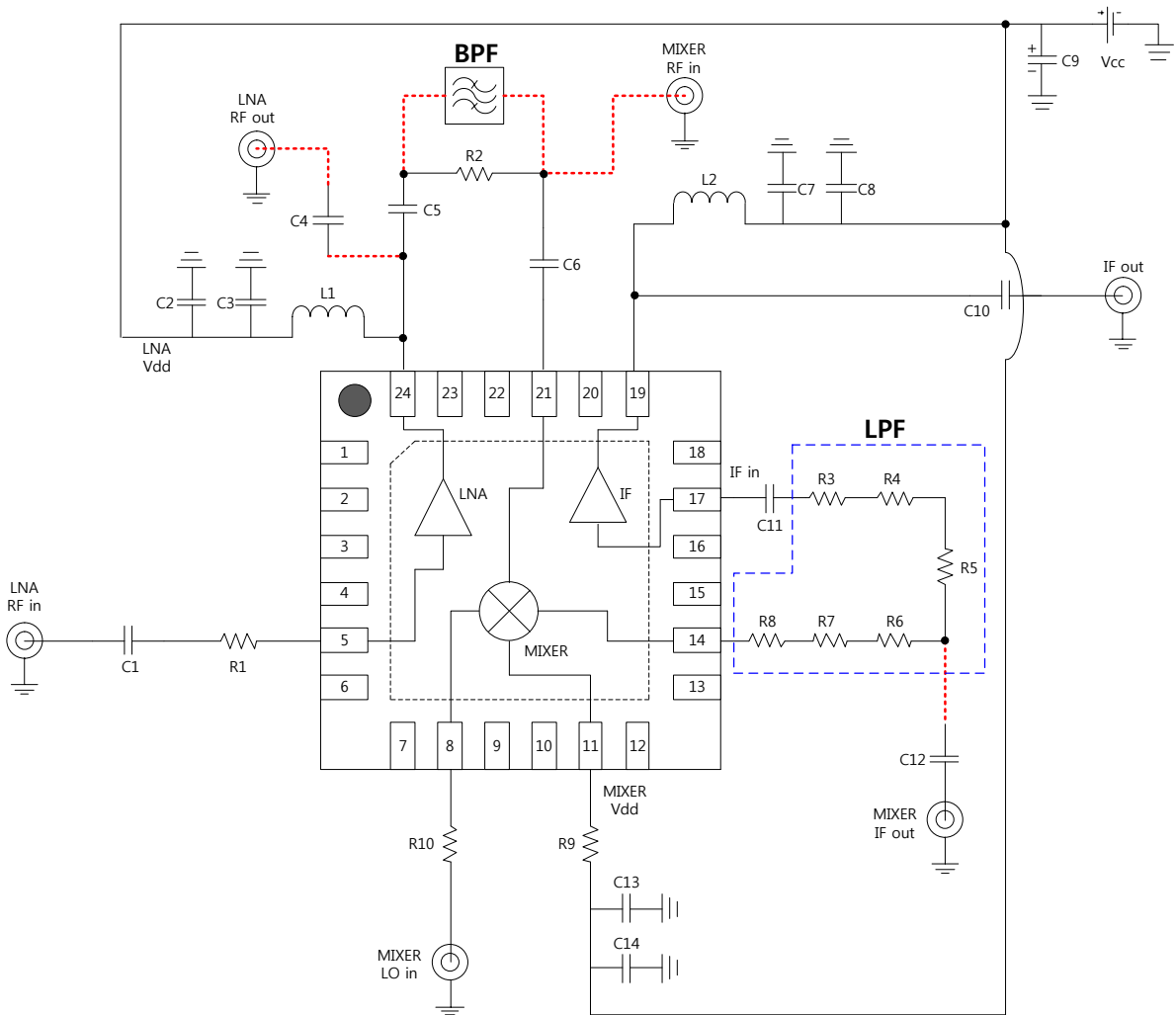


PCB Substrate Information[mm]	
Dielectric Constant	FR-4/4.6
Dielectric Height	0.015[0.4]
Copper Thickness	1 oz.

RDC106

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz

Evaluation PCB



Item	Value	Description
C1, C3, C4, C5, C6, C7, C13	100pF	DC-block or By-pass capacitor/Chip capacitor, 0603 type
C2, C8, C14	0.1uF	By-pass capacitor/Chip capacitor, 0603 type
C9	10uF	Tantalum capacitor, 1206 type
C10, C11, C12	8200pF	DC-block capacitor/Chip capacitor, 0603 type
L1	8.2nH	RF Choke inductor/Chip inductor, 0603 type
L2	680nH	IF Choke inductor/Chip inductor, 0603 type
R1 ~ R10	0 ohm	0 ohm resistor/Chip resistor, 0603 type

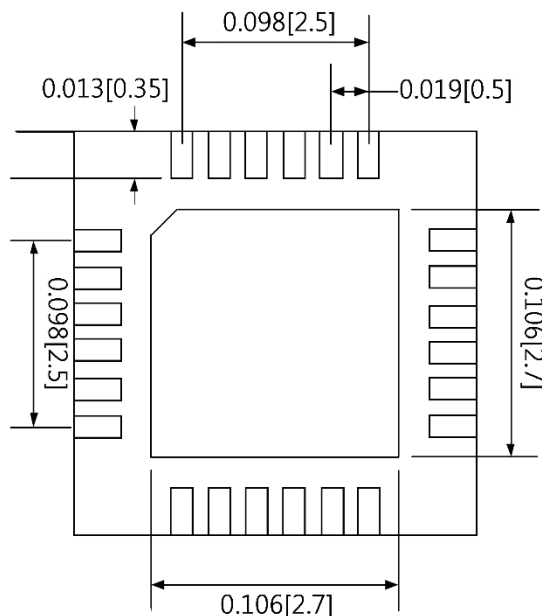
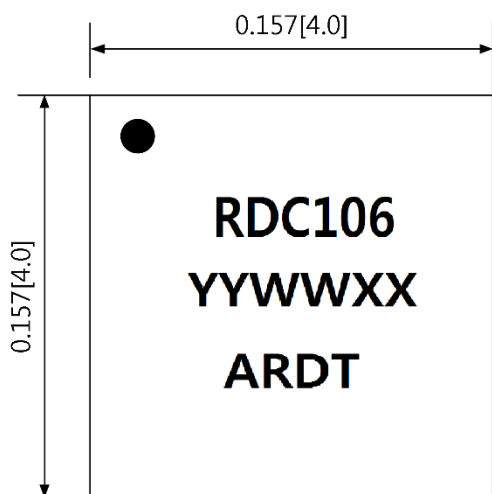
RDC106

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz

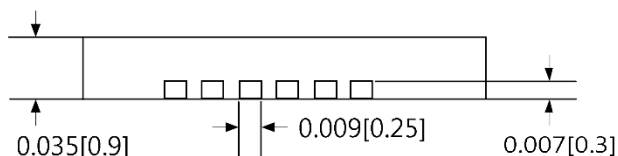


Package Mark and Dimensions

Dimension in inches[Millimeters]



* Part Number : RDC106
**Lot Code : YY = Year
ww = Working Week
XX = Tracking Number



Note

1. All dimensions are in inches[millimeters]. Angles are in degrees.
2. Lead Frame Material : Copper Alloy.
3. The package Top be smaller than the package Bottom

RDC106

HIGH IP3 DOWN-CONVERTOR With
INTEGRATED LNA & IF AMPLIFIER, 1700 – 2400MHz



NOTE

HIGH IIP3 UP-CONVERTOR With INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz

Product Description

RUC122 is a highly integrated up-converter IC that operates from 1.7 to 2.4 GHz. It incorporates a high dynamic ranged and single-balanced mixer core with integrated RF Amplifier, Local Amplifier and IF amplifiers, This integration makes RUC122 ideal for compact transceiver applications such as PCS, GSM, WCDMA, TD-SCDMA, WiMAX and LTE Repeaters and Base Stations. This product provides high dynamic range performance in a low profile lead-free/RoHS-compliant Quad Flat No-Lead (QFN) 4x4 mm package. The RUC122 is implemented with reliable and mature GaAs pHEMT and InGaP HBT technology.

Features

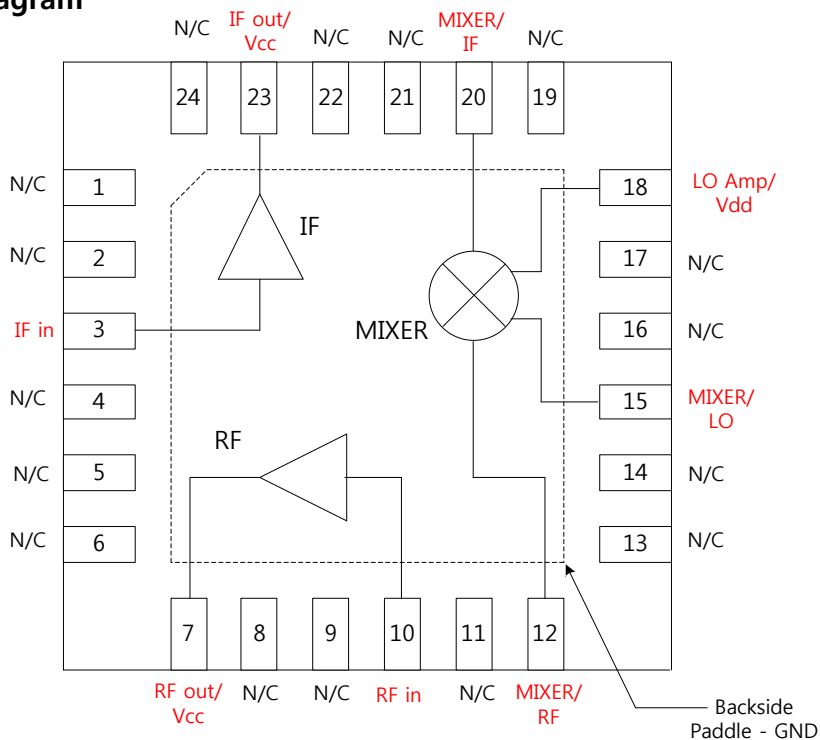
- High dynamic range up-converter with integrated LO , IF, & RF amps
- RF: 1700 – 2400 MHz
- IF: 50 – 300 MHz
- + 32.5 dBm Output IP3 @1.8GHz of RF Amplifier
- + 19.2 dBm Output P1dB @ RF Amplifier
- Pb- free 4mm 24-pin QFN package
- Low- side LO configuration

Applications

- High Dynamic Range Infrastructure system
- GSM GPRS & EDGE
- CDMA & WCDMA
- Cable Modem Termination Systems



Component Diagram



RUC122

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz



Typical Electrical Specification

Parameter	IF Amplifier	Mixer	RF Amplifier	Units
Frequency Range. RF	-	1.7 - 2.4	-	GHz
Frequency Range. LO	-	1.7 - 2.4	-	GHz
Frequency Range. IF	50 – 300			MHz
Conversion Loss	-	8.8	-	dB
Noise Figure(SSB)	-	9	-	dB
LO to RF Isolation	-	-8	-	dB
LO to IF Isolation	-	-13.4	-	dB
RF to IF Isolation	-	-17.2	-	dB
IP3(Input)	-	29.5	-	dBm
Pin1dB	-	20	-	dBm
LO Input Drive Level(Typical)	0			dBm
Small Signal Gain@140MHz/1.8/2.1GHz	27.1	-	20.6/19.7	dB
Input Return Loss@140MHz/1.8/2.1GHz	-28.1	-	-23.5/-11.8	dB
Output Return Loss@140MHz/1.8/2.1GHz	-10.1	-	-15.4/-16.3	dB
Third Order Intercept Point @70MHz/1.8/2.1GHz	38.5	-	32.5/31.0	dBm
Output power at 1-dB Compression	22.0	-	19.2	dBm
Noise Figure	2.8	-	2.9	dB
Device Voltage	5			V
Device current (Icq)	190			mA

Test condition: Vcc=5V, I_b=190mA, Typ., LO = 0dBm, IF = 140MHz, T_L=25°C, Z_s=Z_L=50

RUC122

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz

Absolute Maximum Ratings

Parameter	Rating	Unit
Max RF/IF Input Power	27	dBm
Max LO Drive Input Power	10	dBm
Max Device Voltage(V_D)	6.5	V
Max Operating Dissipated Power	0.5	W
Junction Temperature(T_J)	150	°C
Operating Temperature(T_I)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 0B	
Moisture Sensitivity Level	MSL1	

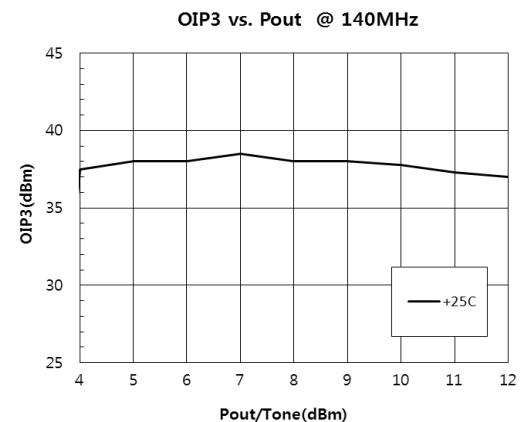
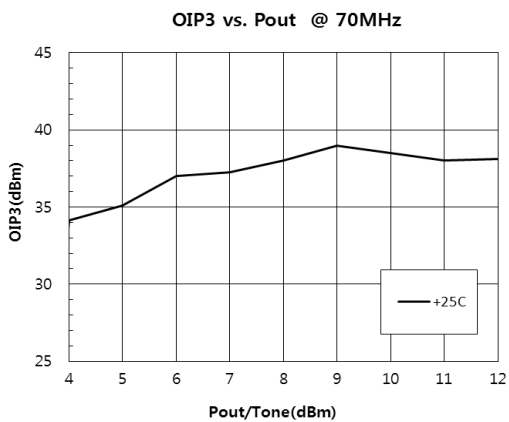
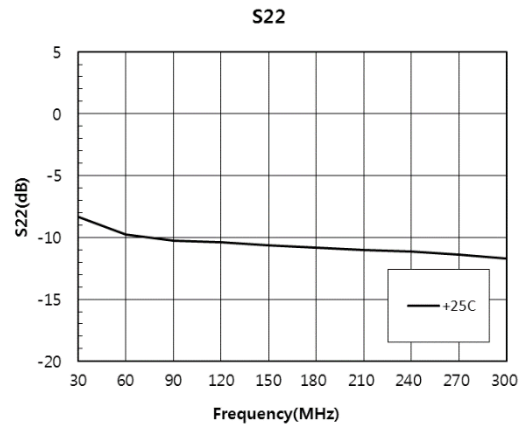
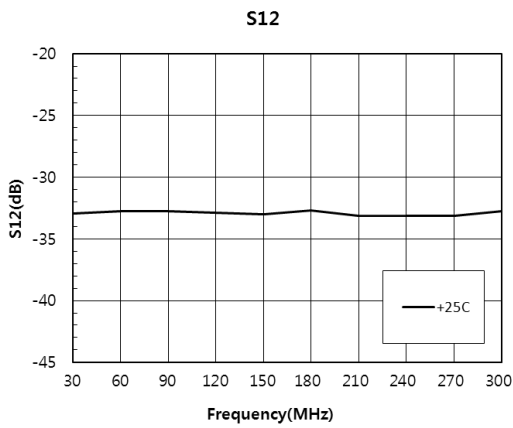
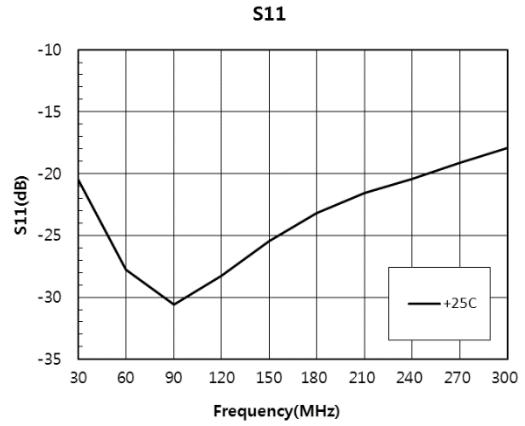
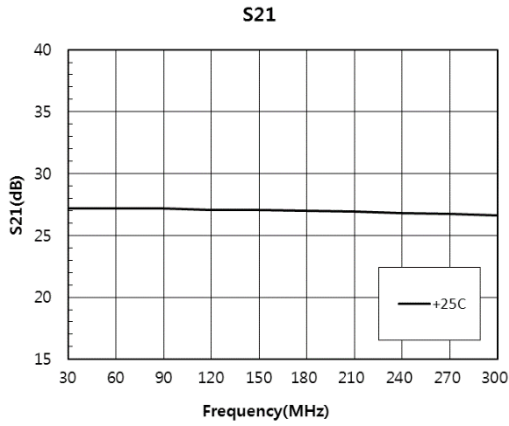


RUC122

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz



IF Amplifier MMIC Performances

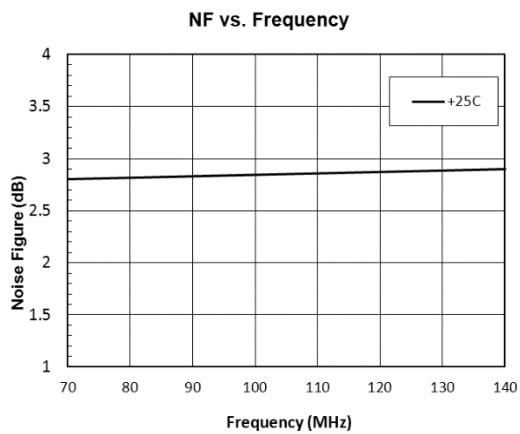
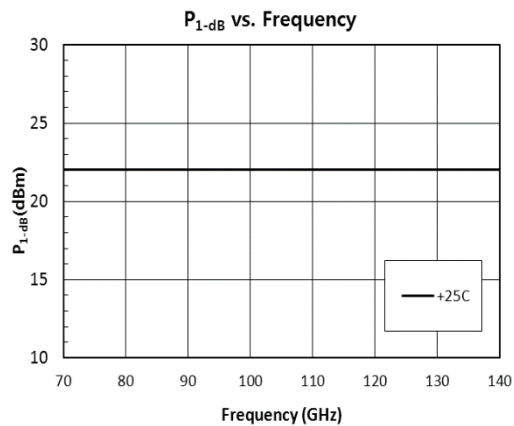
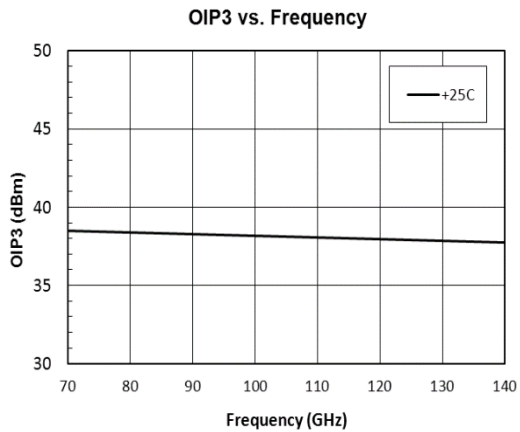


RUC122

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz



IF Amplifier MMIC Performances



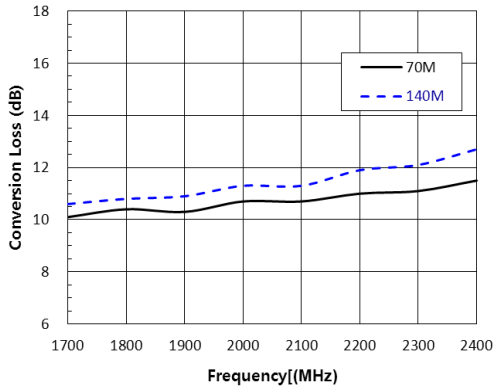
RUC122

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz

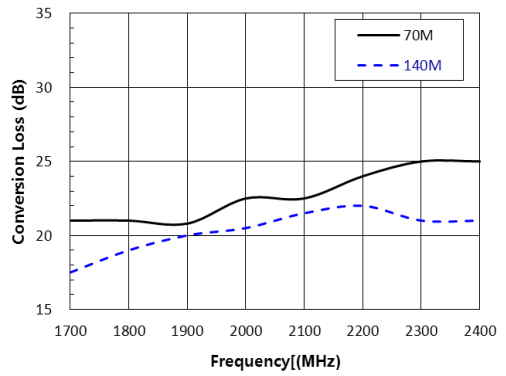


Mixer MMIC Performances

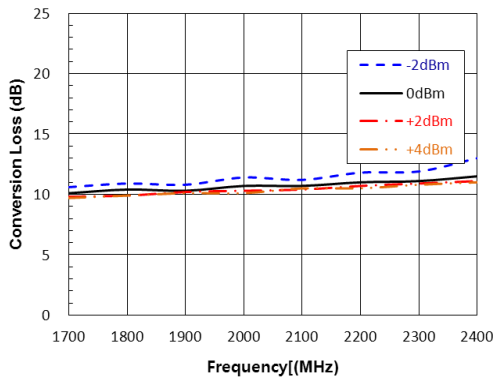
CONVERSION LOSS @ LO = 0dBm



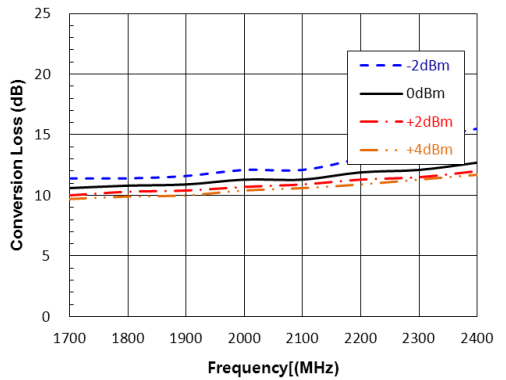
Input IP3 @ LO = 0dBm



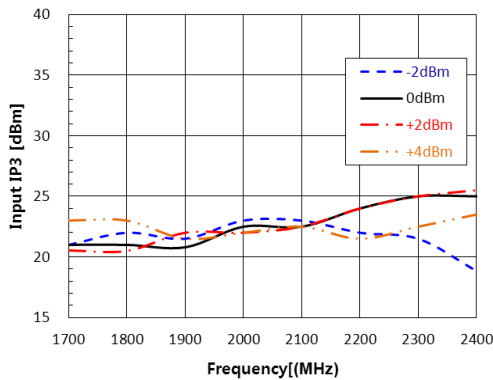
Conversion Loss vs. LO Drive @ IF=70MHz



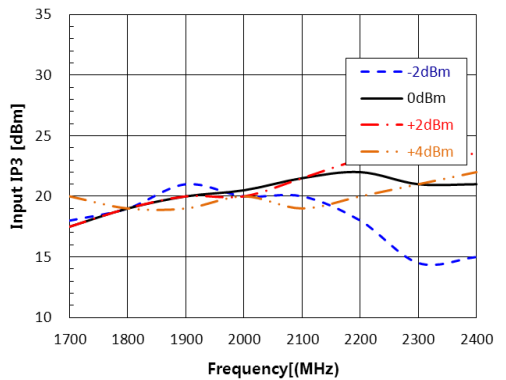
Conversion Loss vs. LO Drive @ IF=140MHz



Input IP3 vs. LO Drive @ IF=70MHz



Input IP3 vs. LO Drive @ IF=140MHz



RUC122

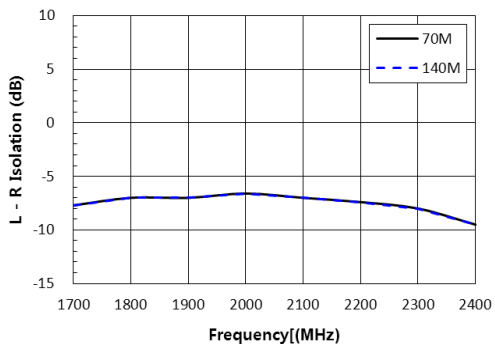
HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz



Mixer MMIC Performance

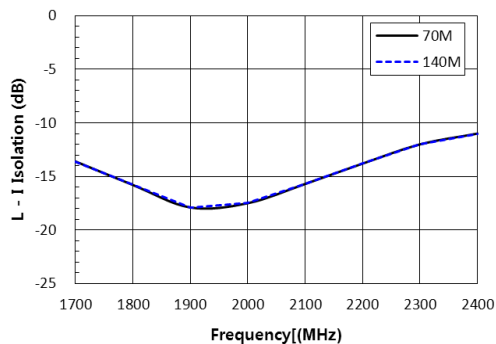
LO - RF Isolation vs. LO Freq

Referenced with LO = 0dBm



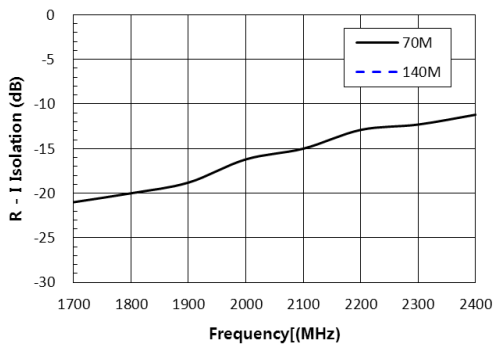
LO - IF Isolation vs. LO Freq

Referenced with LO = 0dBm



RF - IF Isolation vs. LO Freq

Referenced with LO = 0dBm

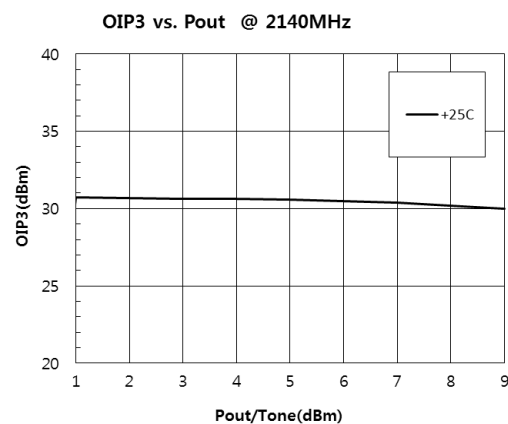
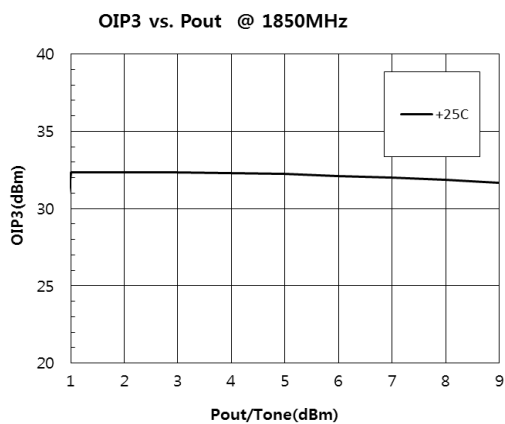
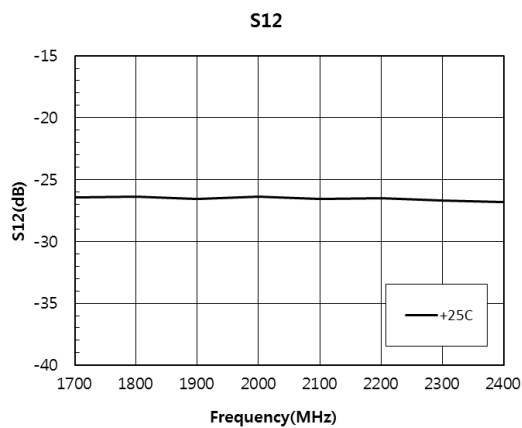
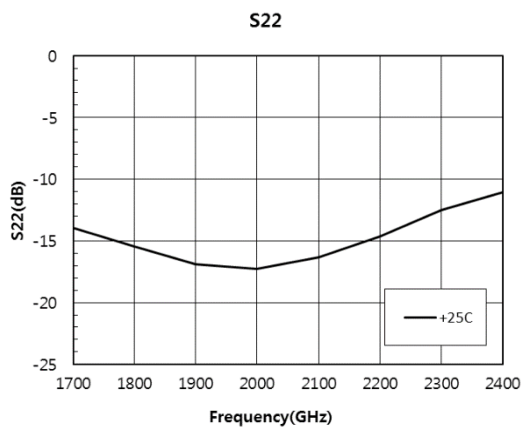
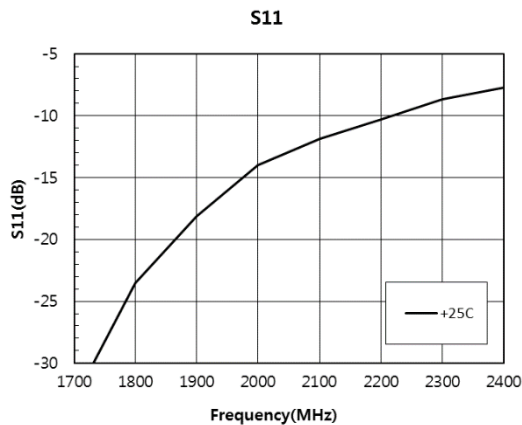
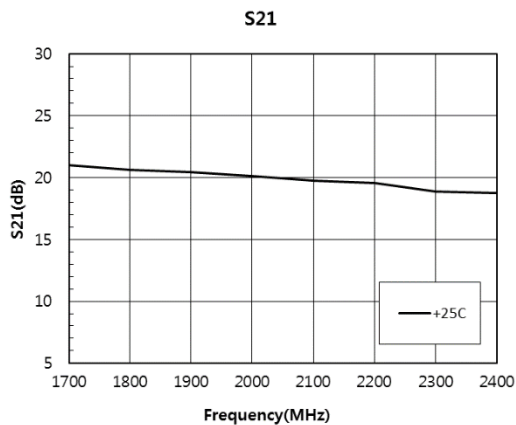


RUC122

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz



RF MMIC Amplifier

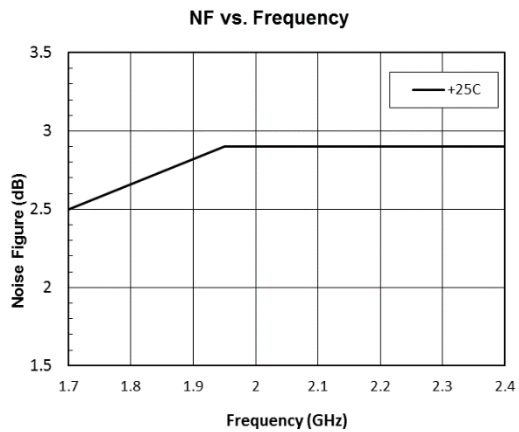
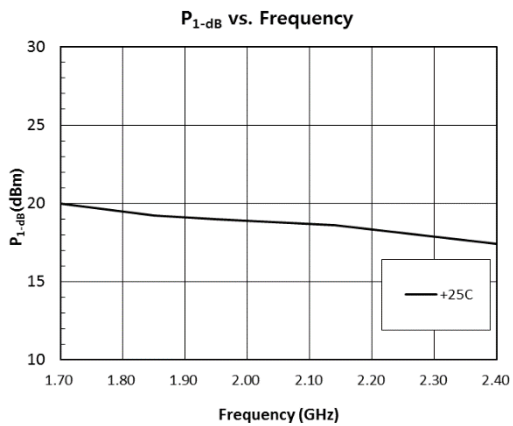


RUC122

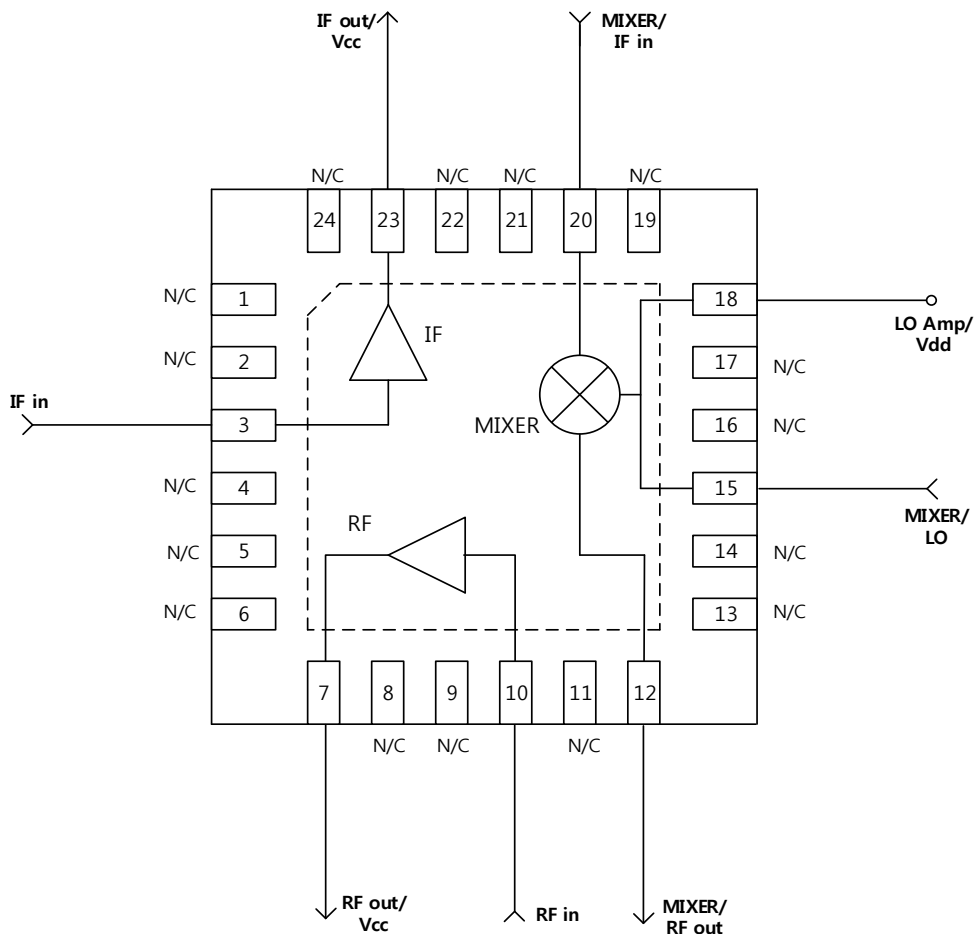
HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz



RF MMIC Amplifier



Pin Configuration and Description



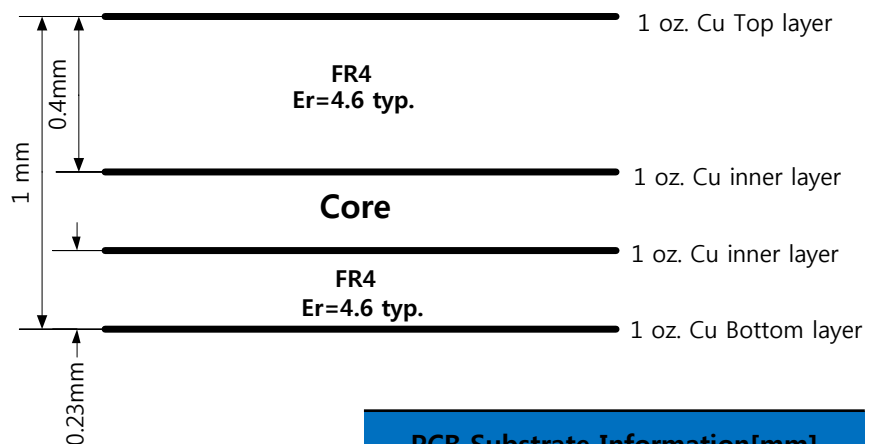
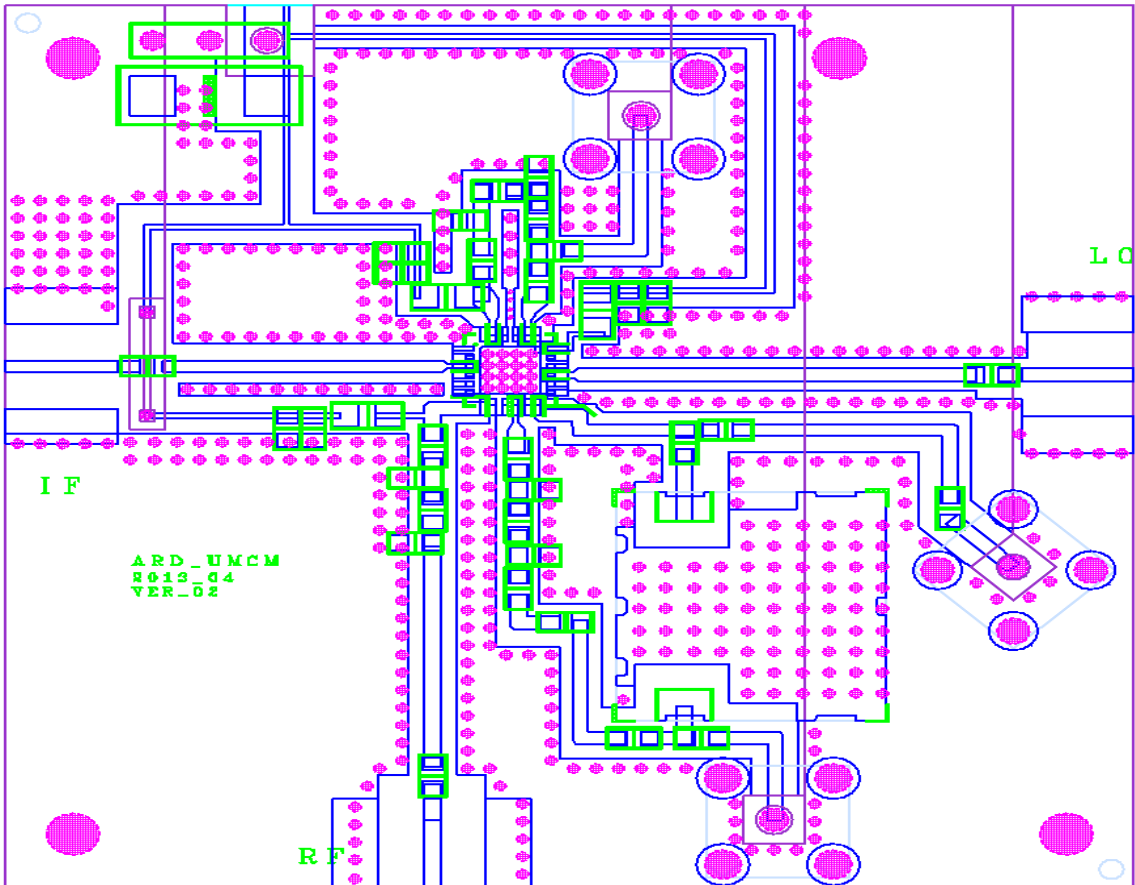
Pin No.	Description
3	IF amplifier signal input
7	RF amplifier RF out/DC bias
10	RF amplifier RF input
12	Mixer RF signal output
15	Mixer Local oscillator signal input
18	Mixer integrated LO amplifier DC bias
20	Mixer IF signal input
23	IF amplifier signal out/DC bias

RUC122

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz



Evaluation PCB

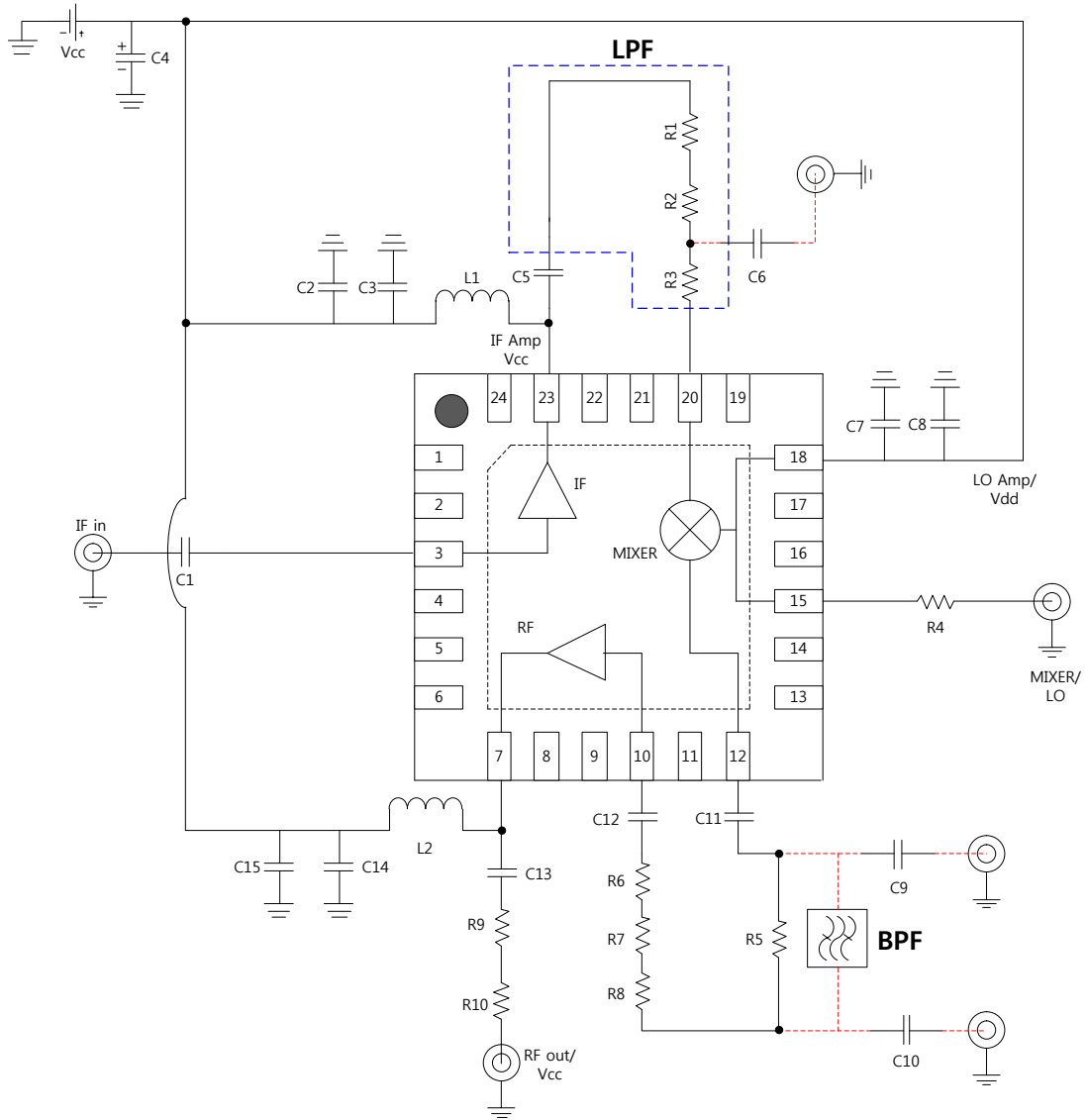


PCB Substrate Information[mm]	
Dielectric Constant	FR-4/4.6
Dielectric Height	0.015[0.4]
Copper Thickness	1 oz.

RUC122

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz

Evaluation PCB



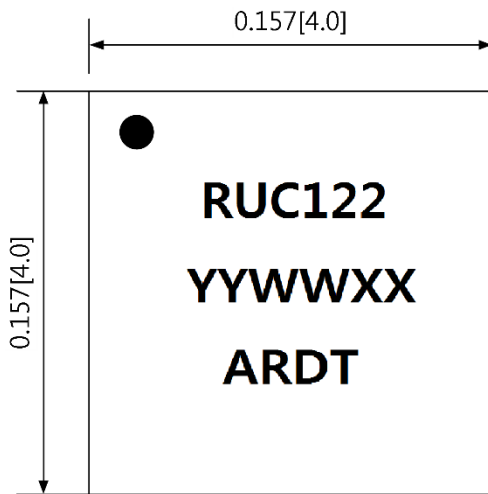
Item	Value	Description
C1, C5,	8200pF	DC-block capacitor/Chip capacitor, 0603 type
C3, C6, C7, C9, C10, C11, C12, C13, C14	100pF	DC-block or By-pass capacitor/Chip capacitor, 0603 type
C4	10uF	Tantalum capacitor, 1206 type
C2, C8, C15	0.1uF	By-pass capacitor/Chip capacitor, 0603 type
L1	1uH	IF Choke inductor/Chip inductor, 0603 type
L2	33nH	RF Choke inductor/Chip inductor, 0603 type
R1 ~ R10	0 ohm	0 ohm resistor/Chip resistor, 0603 type

RUC122

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz

Package Mark and Dimensions

Dimension in inches[Millimeters]

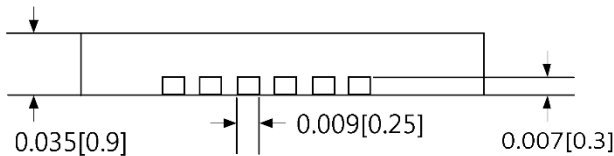
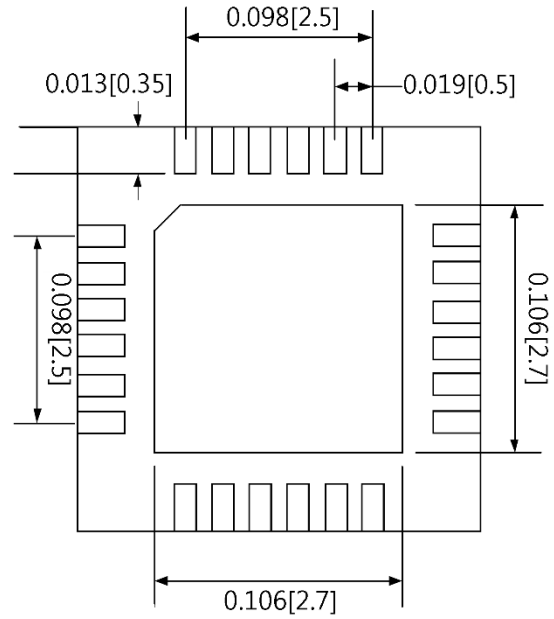


* Part Number : RUC122

**Lot Code : YY = Year

ww = Working Week

XX = Tracking Number



Note

1. All dimensions are in inches[millimeters]. Angles are in degrees.
2. Lead Frame Material : Copper Alloy.
3. The package Top be smaller than the package Bottom

RUC122

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz



NOTE

HIGH IIP3 UP-CONVERTOR With INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz

Product Description

RUC123 is a highly integrated up-converter IC that operates from 1.7 to 2.4 GHz. It incorporates a high dynamic ranged and single-balanced mixer core with integrated RF Amplifier, Local Amplifier and IF amplifiers, This integration makes RUC123 ideal for compact transceiver applications such as PCS, GSM, WCDMA, TD-SCDMA, WiMAX and LTE Repeaters and Base Stations. This product provides high dynamic range performance in a low profile lead-free/RoHS-compliant Quad Flat No-Lead (QFN) 4x4 mm package. The RUC123 is implemented with reliable and mature GaAs pHEMT and InGaP HBT technology.

Features

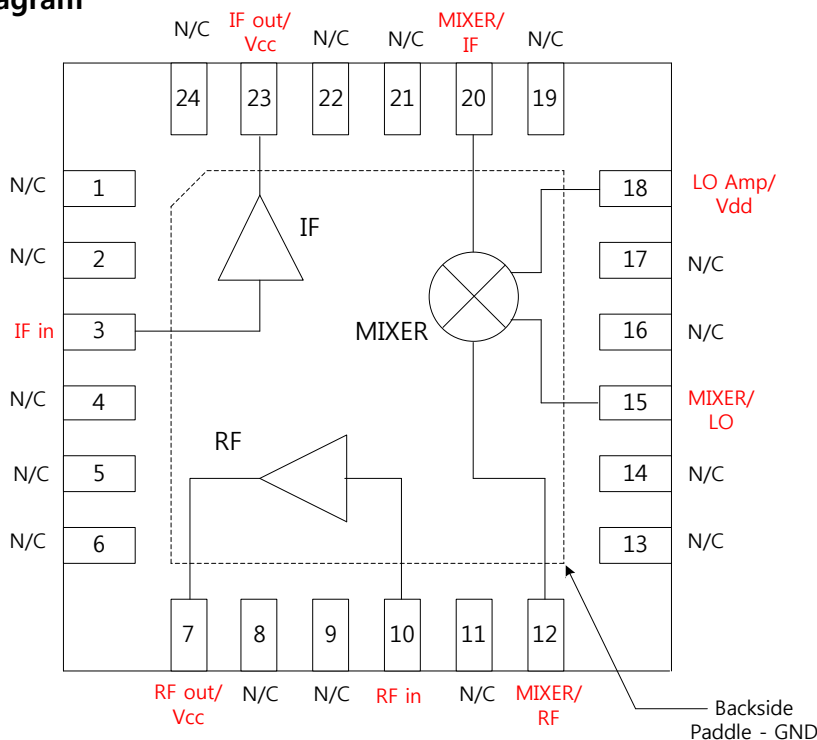
- High dynamic range up-converter with integrated LO , IF, & RF amps
- RF: 1700 – 2400 MHz
- IF: 50 – 300 MHz
- + 32.5 dBm Output IP3 @1.8GHz of RF Amplifier
- + 19.2 dBm Output P1dB @ RF Amplifier
- Pb- free 4mm 24-pin QFN package
- Low- side LO configuration

Applications

- High Dynamic Range Infrastructure system
- GSM GPRS & EDGE
- CDMA & WCDMA
- Cable Modem Termination Systems



Component Diagram



RUC123

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz



Typical Electrical Specification

Parameter	IF Amplifier	Mixer	RF Amplifier	Units
Frequency Range. RF	-	1.7 - 2.4	-	GHz
Frequency Range. LO	-	1.7 - 2.4	-	GHz
Frequency Range. IF	50 – 300			MHz
Conversion Loss	-	11.0	-	dB
Noise Figure(SSB)	-	11.0	-	dB
LO to RF Isolation	-	-8	-	dB
LO to IF Isolation	-	-17.0	-	dB
RF to IF Isolation	-	-20.0	-	dB
IP3(Input)	-	22.5	-	dBm
Pin1dB	-	20	-	dBm
LO Input Drive Level(Typical)	0			dBm
Small Signal Gain@140MHz/1.8/2.1GHz	19.1	-	20.6/19.7	dB
Input Return Loss@140MHz/1.8/2.1GHz	-19.4	-	-23.5/-11.8	dB
Output Return Loss@140MHz/1.8/2.1GHz	-17.6	-	-15.4/-16.3	dB
Third Order Intercept Point @70MHz/1.8/2.1GHz	45	-	32.5/31.0	dBm
Output power at 1-dB Compression	25	-	19.2	dBm
Noise Figure	4.2	-	2.9	dB
Device Voltage	5			V
Device current (Icq)	184			mA

Test condition: Vcc=5V, I_D=184mA, Typ., LO = 0dBm, IF = 70MHz, T_L=25°C, Z_s=Z_L=50

RUC123

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz

Absolute Maximum Ratings

Parameter	Rating	Unit
Max RF/IF Input Power	20	dBm
Max LO Drive Input Power	10	dBm
Max Device Voltage(V_D)	6.5	V
Junction Temperature(T_J)	150	°C
Operating Temperature(T_L)	-40 to +85	°C
Storage Temperature	-65 to +150	°C
ESD Sensitivity(HBM)	Class 0B	
Moisture Sensitivity Level	MSL1	

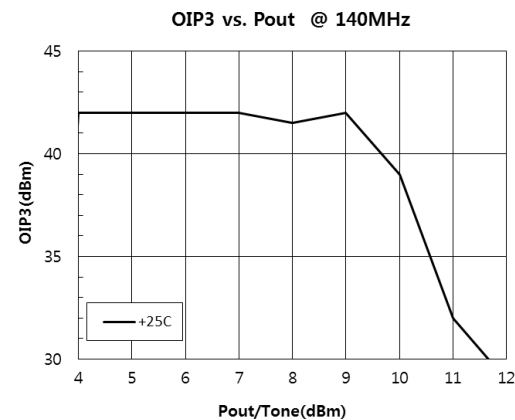
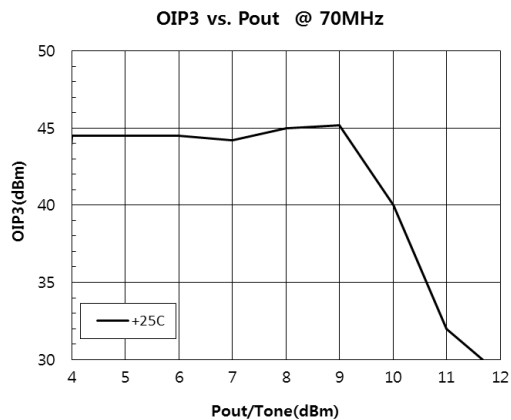
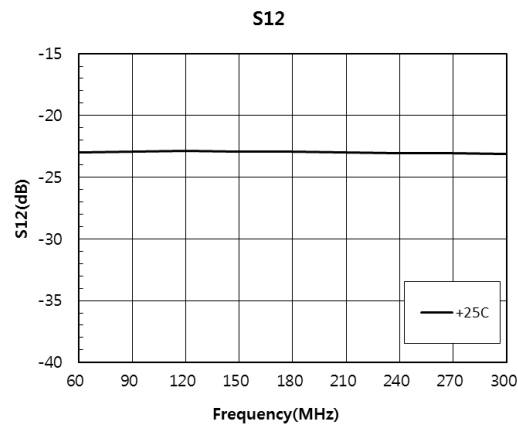
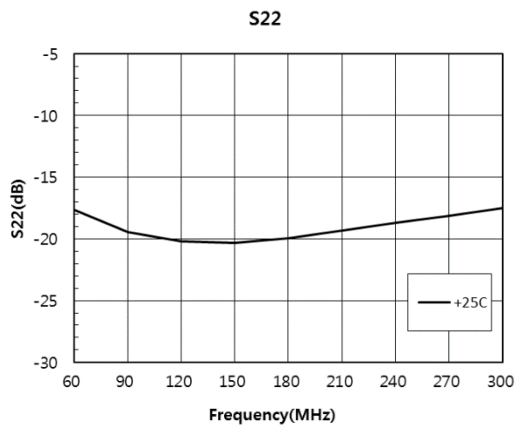
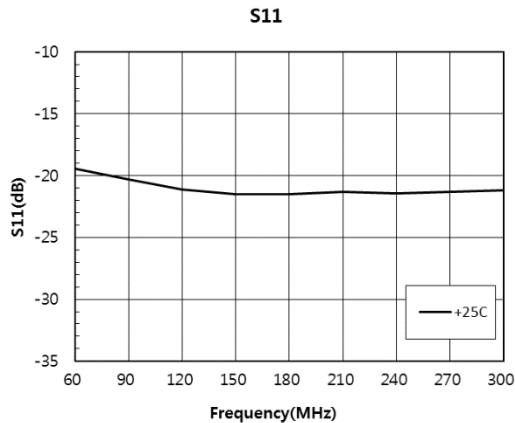
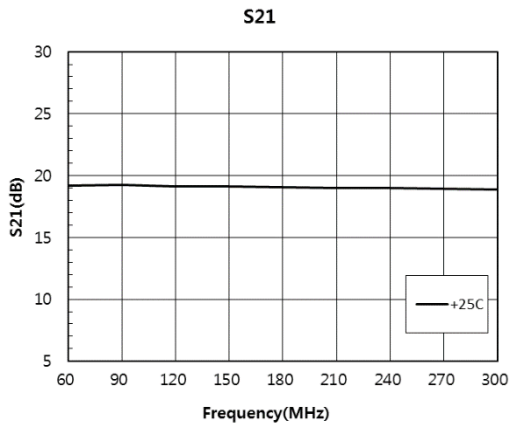


RUC123

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz



IF Amplifier Performance

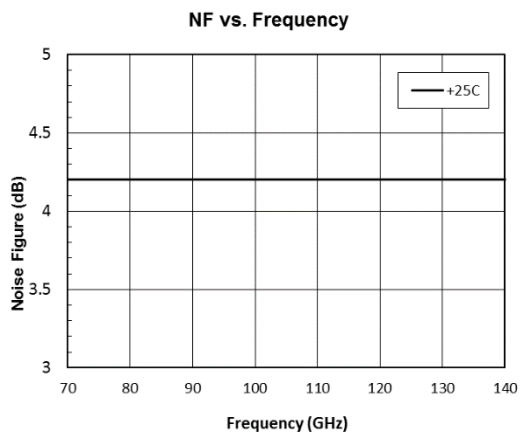
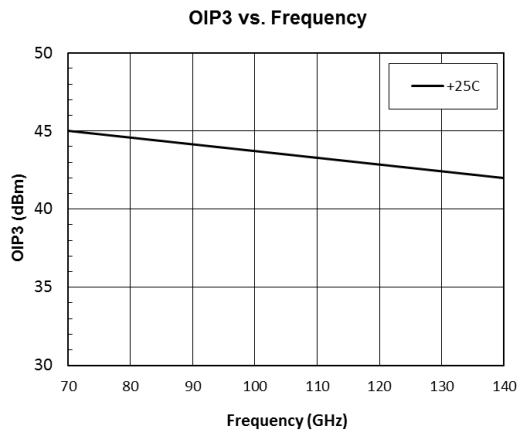
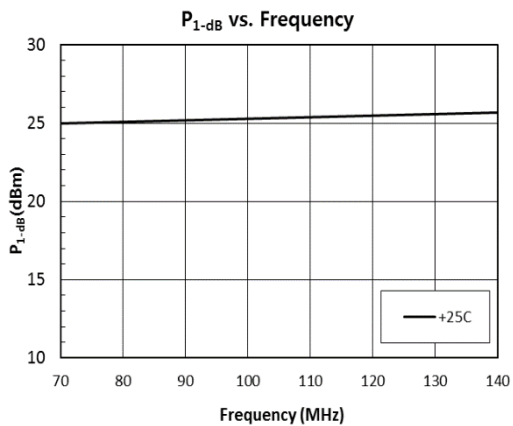


RUC123

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz



IF Amplifier Performance



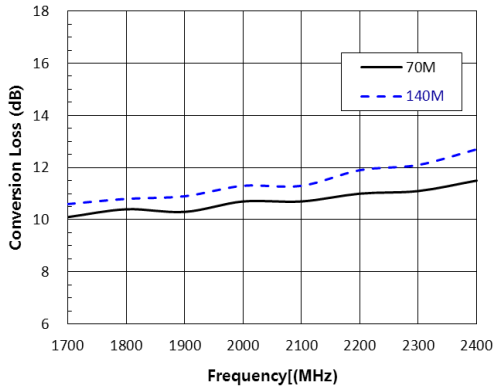
RUC123

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz

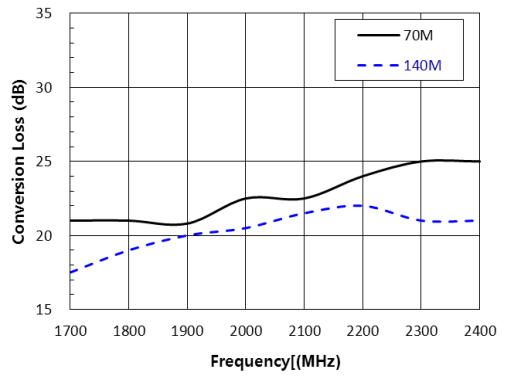


Mixer MMIC Performances

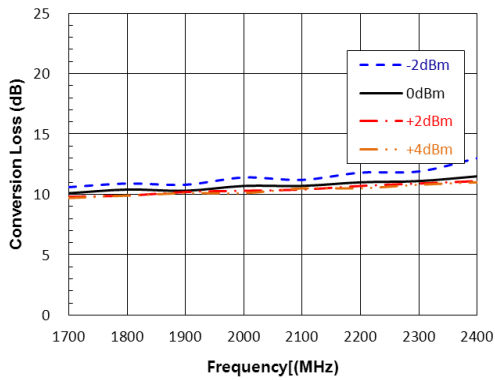
CONVERSION LOSS @ LO = 0dBm



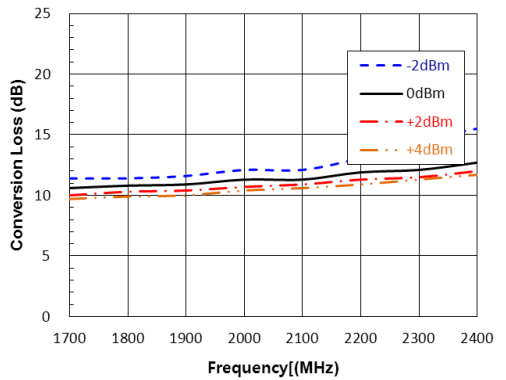
Input IP3 @ LO = 0dBm



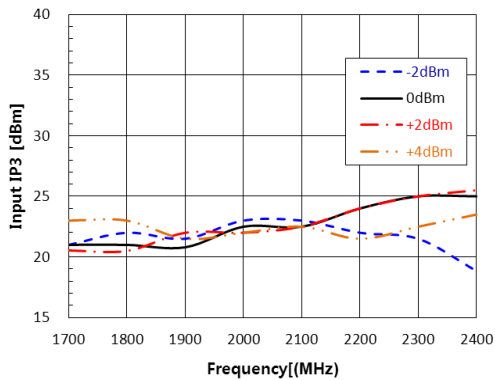
Conversion Loss vs. LO Drive @ IF=70MHz



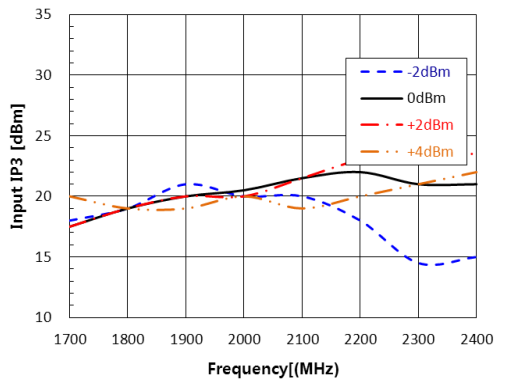
Conversion Loss vs. LO Drive @ IF=140MHz



Input IP3 vs. LO Drive @ IF=70MHz



Input IP3 vs. LO Drive @ IF=140MHz



RUC123

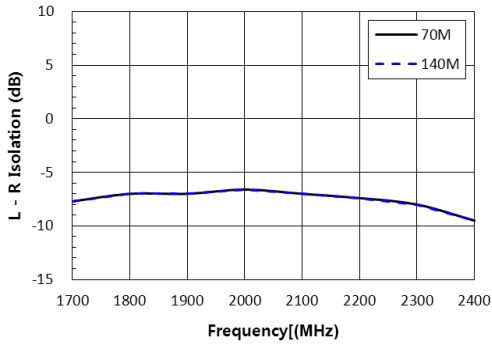
HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz



Mixer MMIC Performance

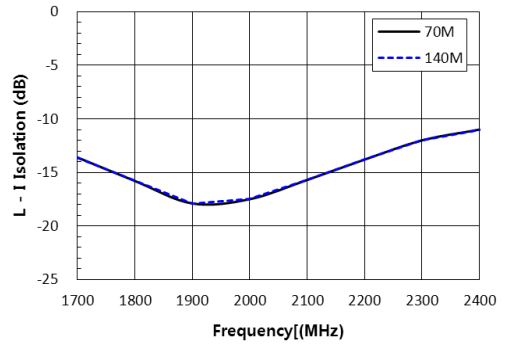
LO - RF Isolation vs. LO Freq

Referenced with LO = 0dBm



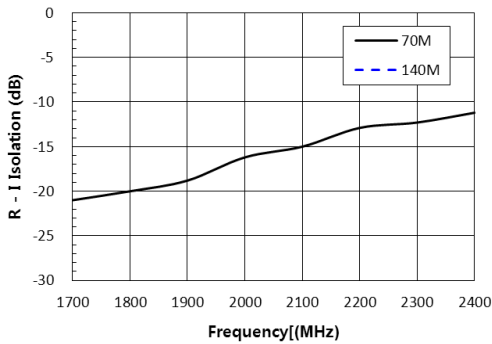
LO - IF Isolation vs. LO Freq

Referenced with LO = 0dBm



RF - IF Isolation vs. LO Freq

Referenced with LO = 0dBm

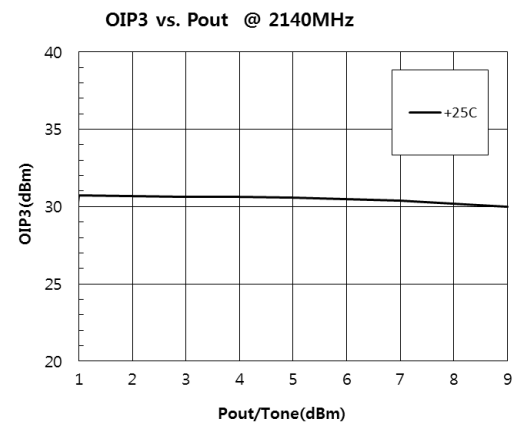
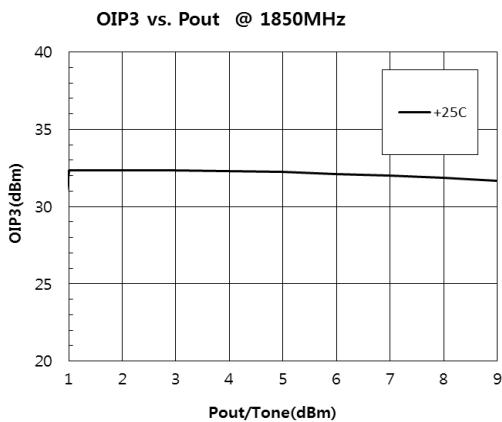
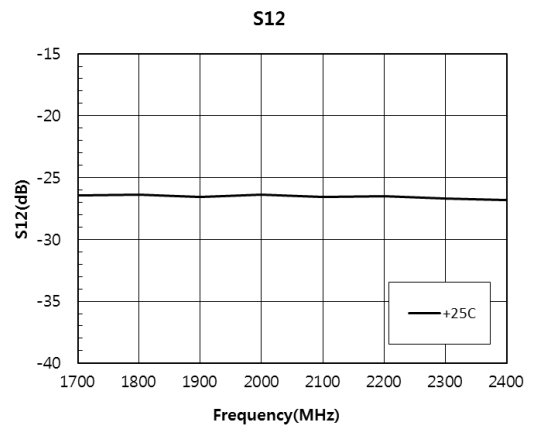
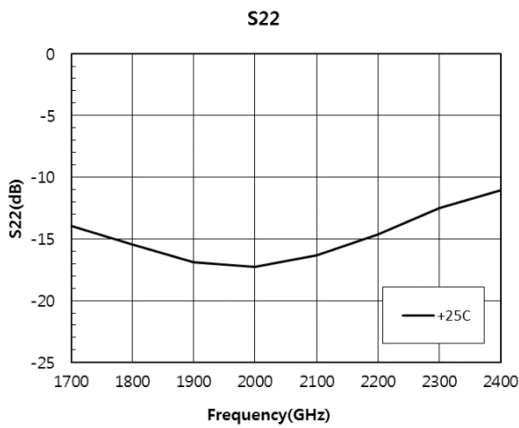
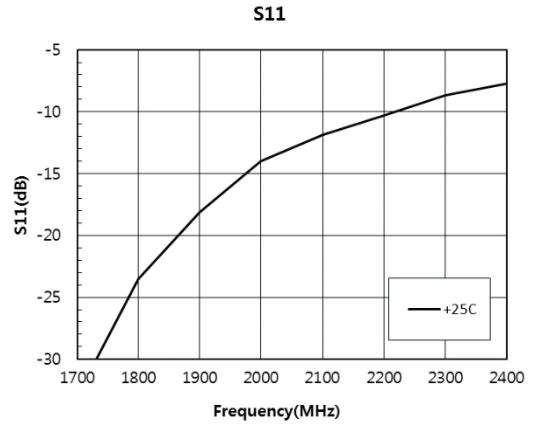
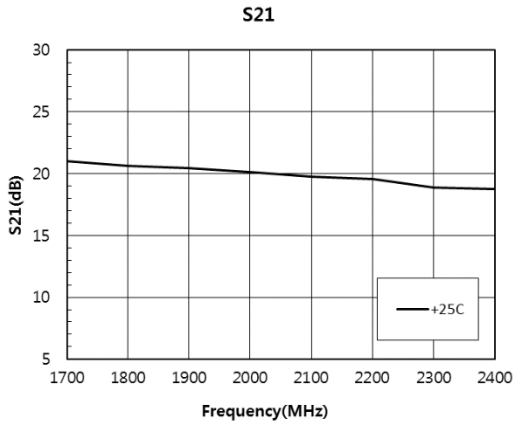


RUC123

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz



RF MMIC Amplifier Performance

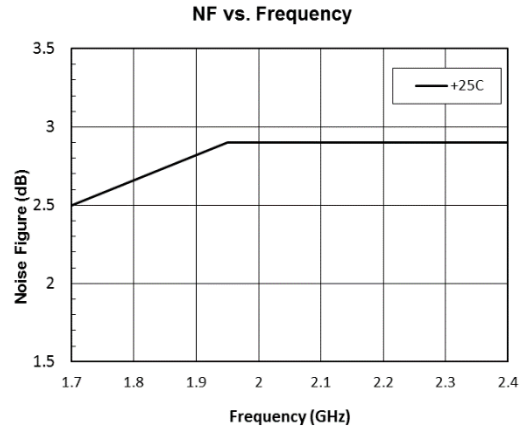
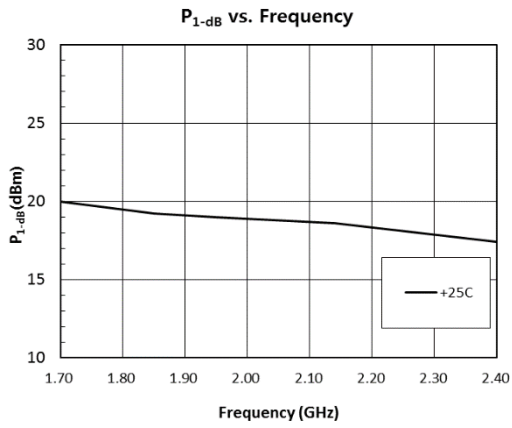


RUC123

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz



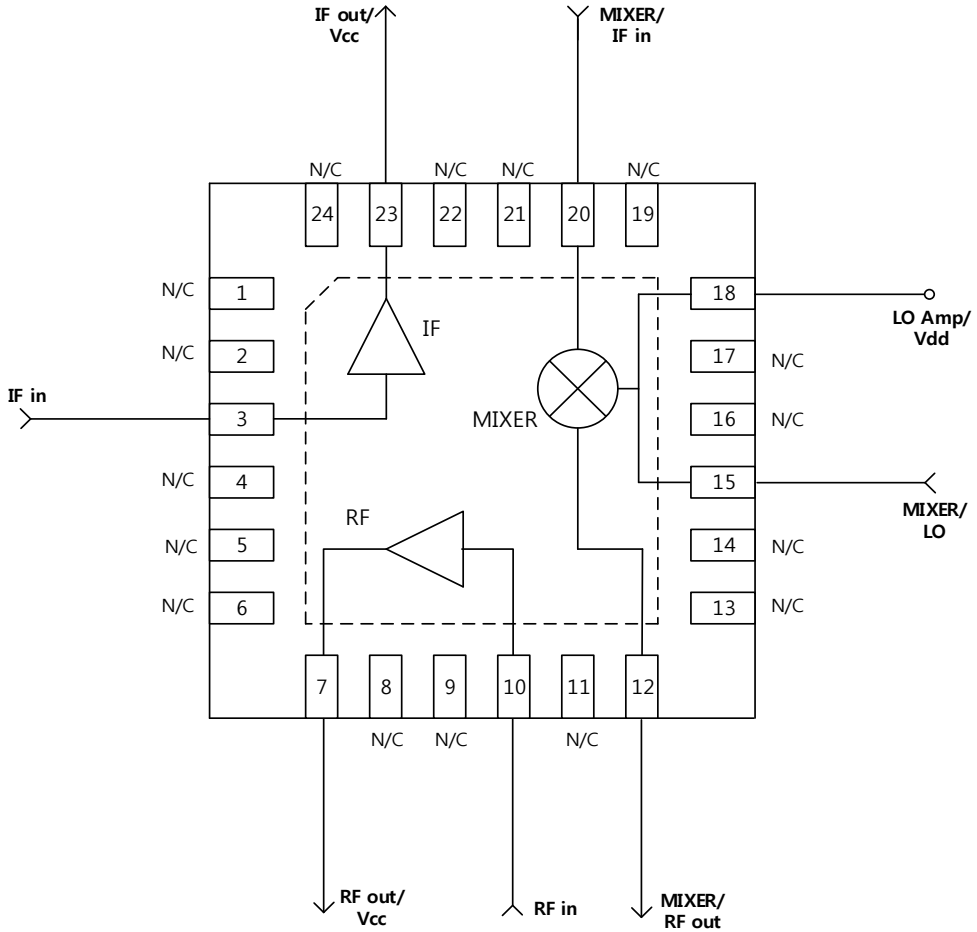
RF MMIC Amplifier Performance



RUC123

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz

Pin Configuration and Description

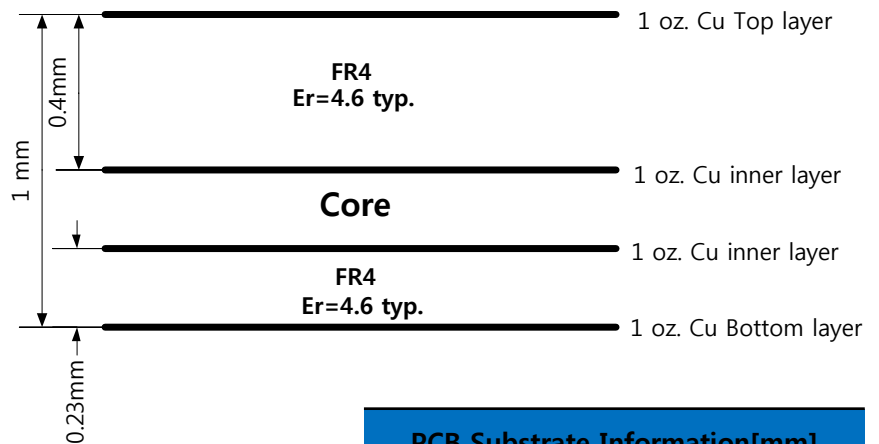
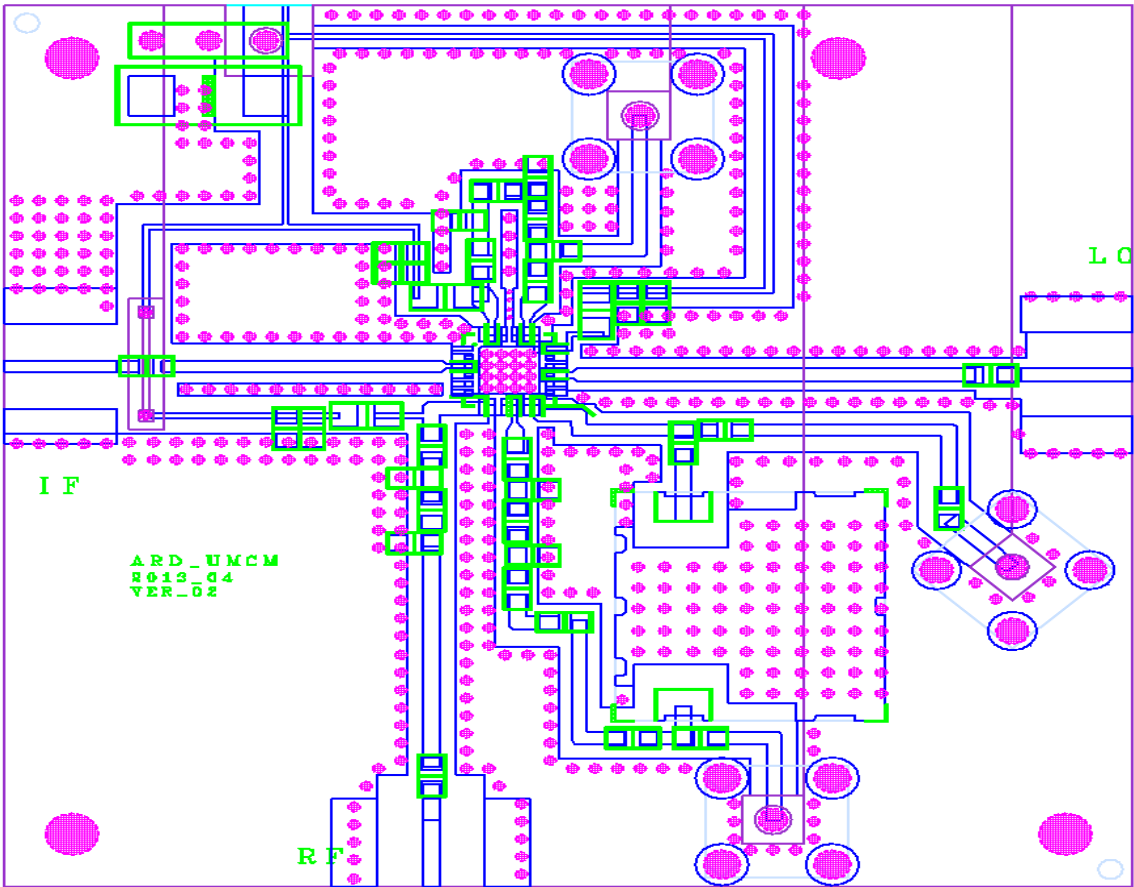


Pin No.	Description
3	IF amplifier signal input
7	RF amplifier RF out/DC bias
10	RF amplifier RF input
12	Mixer RF signal output
15	Mixer Local oscillator signal input
18	Mixer integrated LO amplifier DC bias
20	Mixer IF signal input
23	IF amplifier signal out/DC bias

RUC123

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz

Evaluation PCB

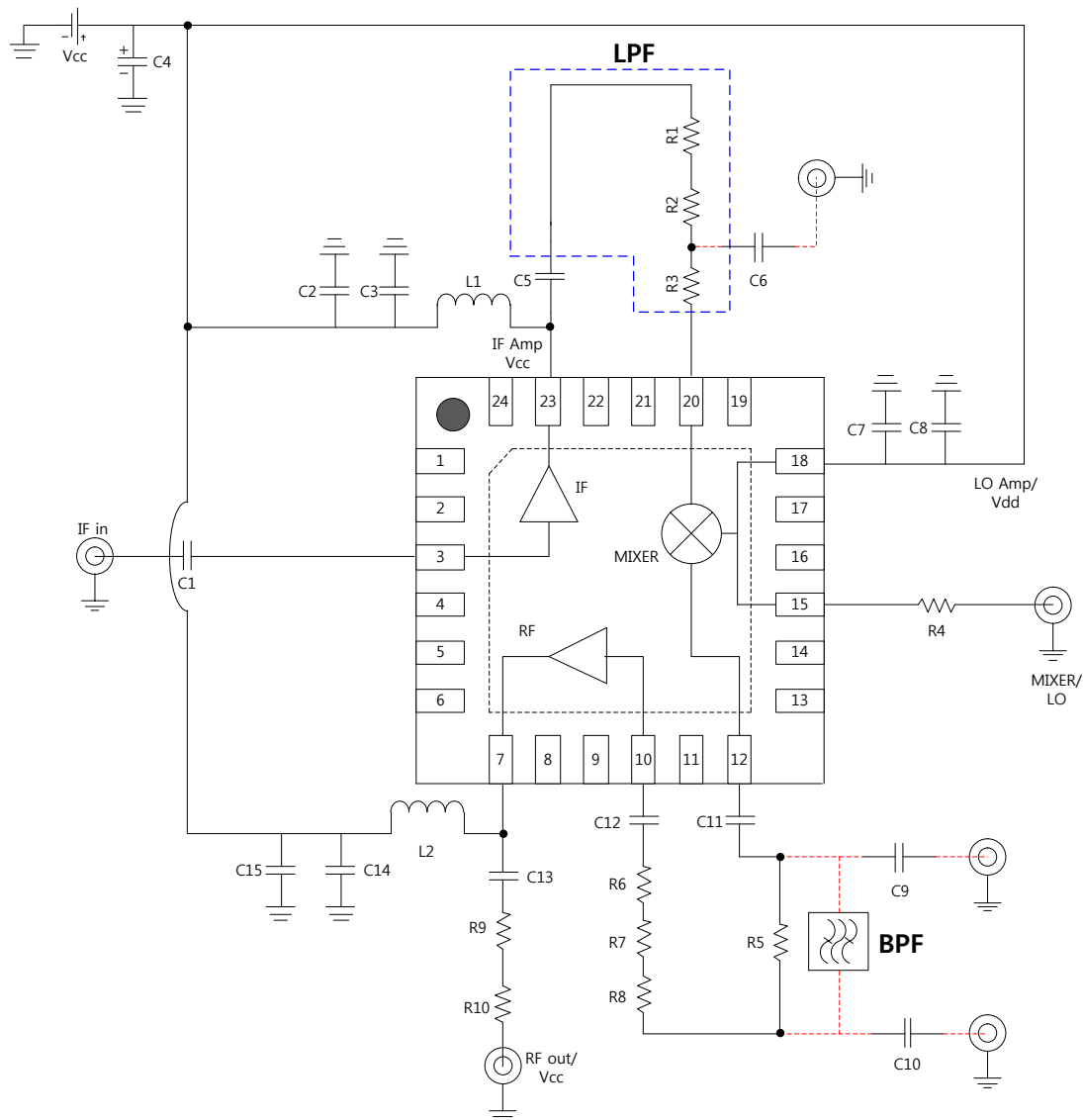


PCB Substrate Information[mm]	
Dielectric Constant	FR-4/4.6
Dielectric Height	0.015[0.4]
Copper Thickness	1 oz.

RUC123

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz

Evaluation PCB



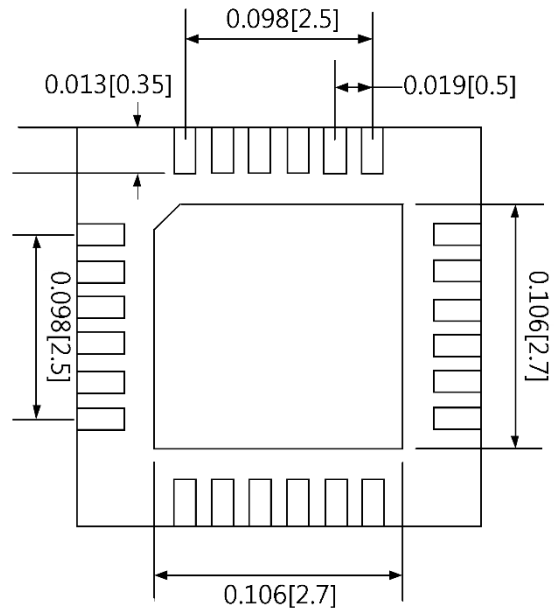
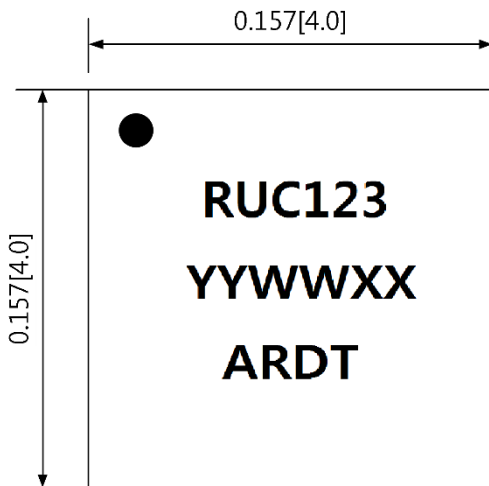
Item	Value	Description
C1, C5,	8200pF	DC-block capacitor/Chip capacitor, 0603 type
C3, C6, C7, C9, C10, C11, C12, C13, C14	100pF	DC-block or By-pass capacitor/Chip capacitor, 0603 type
C4	10uF	Tantalum capacitor, 1206 type
C2, C8, C15	0.1uF	By-pass capacitor/Chip capacitor, 0603 type
L1	680nH	IF Choke inductor/Chip inductor, 0603 type
L2	33nH	RF Choke inductor/Chip inductor, 0603 type
R1 ~ R10	0 ohm	0 ohm resistor/Chip resistor, 0603 type

RUC123

HIGH IP3 UP-CONVERTOR With
INTEGRATED RF & IF AMPLIFIER, 1700 – 2400MHz

Package Mark and Dimensions

Dimension in inches[Millimeters]

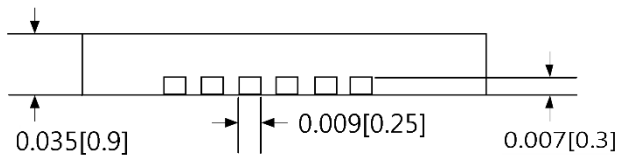


* Part Number : RUC123

**Lot Code : YY = Year

ww = Working Week

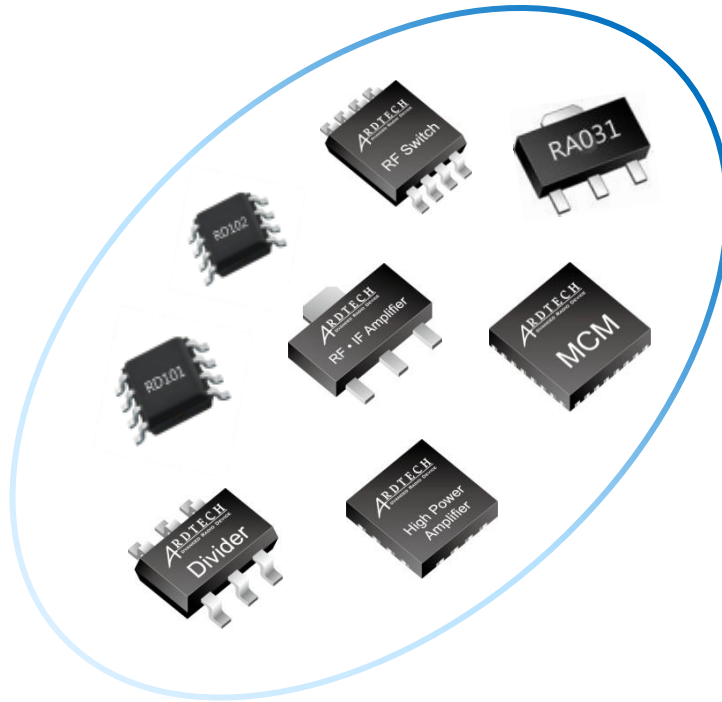
XX = Tracking Number



Note

1. All dimensions are in inches[millimeters]. Angles are in degrees.
2. Lead Frame Material : Copper Alloy.
3. The package Top be smaller than the package Bottom

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